

#### **Mixed Signal ISP Flash MCU Family**

#### **Analog Peripherals**

- 10-Bit ADC ('F360/1/2/6/7/8/9 only)
  - Up to 200 ksps
  - Up to 21 external single-ended or differential inputs
  - VREF from internal VREF, external pin or V<sub>DD</sub>
  - Internal or external start of conversion source
- Built-in temperature sensor
   10-Bit Current Output DAC ('F360/1/2/6/7/8/9 only)
- Two Comparators
  - Programmable hysteresis and response time
  - Configurable as interrupt or reset source
  - Low current (0.4 μA)

#### - Brown-out detector and POR Circuitry On-Chip Debug

- On-chip debug circuitry facilitates full speed, nonintrusive in-system debug (no emulator required)
- Provides breakpoints, single stepping, inspect/modify memory and registers
- Superior performance to emulation systems using ICE-chips, target pods, and sockets
- Low cost, complete development kit

#### **Supply Voltage**

- Range: 2.7–3.6 V (50 MIPS) 3.0–3.6 V (100 MIPS)
- Power saving suspend and shutdown modes

#### High Speed 8051 µC Core

- Pipelined instruction architecture; executes 70% of instructions in 1 or 2 system clocks
- 100 MIPS or 50 MIPS throughput with on-chip PLL
- Expanded interrupt handler
- 2-cycle 16 x 16 MAC engine

#### Memory

- 1280 bytes internal data RAM (256 + 1024)
- 32 kB ('F360/1/2/3/4/5/6/7) or 16 kB ('F368/9) Flash;
   In-system programmable in 1024-byte Sectors—
   1024 bytes are reserved in the 32 kB devices

#### **Digital Peripherals**

- Up to 39 Port I/O; All 5 V tolerant with high sink current
- Hardware enhanced UART, SMBus™, and enhanced SPI™ serial ports
- Four general purpose 16-bit counter/timers
- 16-Bit programmable counter array (PCA) with six capture/compare modules
- Real time clock mode using PCA or timer and external clock source
- External Memory Interface (EMIF)

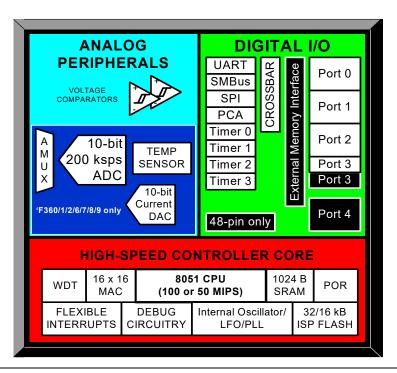
#### **Clock Sources**

- Two internal oscillators:
  - 24.5 MHz with  $\pm 2\%$  accuracy supports crystal-less UART operation
  - 80/40/20/10 kHz low frequency, low power
- Flexible PLL technology
- External oscillator: Crystal, RC, C, or clock (1 or 2 pin modes)
- Can switch between clock sources on-the-fly; useful in power saving modes

#### Packages

- 48-pin TQFP (C8051F360/3)
- 32-pin LQFP (C8051F361/4/6/8)
- 28-pin QFN (C8051F362/5/7/9)

#### Temperature Range: -40 to +85 °C





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24.C2 Interface



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### 1. System Overview

C8051F36x devices are fully integrated mixed-signal System-on-a-Chip MCUs. Highlighted features are listed below. Refer to Table 1.1 for specific product feature selection.

- High-speed pipelined 8051-compatible microcontroller core (up to 100 MIPS)
- In-system, full-speed, non-intrusive debug interface (on-chip)
- True 10-bit 200 ksps 16-channel single-ended/differential ADC with analog multiplexer
- 10-bit Current Output DAC
- 2-cycle 16 by 16 Multiply and Accumulate Engine
- Precision programmable 25 MHz internal oscillator
- Up to 32 kB of on-chip Flash memory—1024 bytes are reserved
- 1024 bytes of on-chip RAM
- External Data Memory Interface with 64 kB address space
- SMBus/I2C, Enhanced UART, and Enhanced SPI serial interfaces implemented in hardware
- Four general-purpose 16-bit timers
- Programmable Counter/Timer Array (PCA) with six capture/compare modules and Watchdog Timer function
- On-chip Power-On Reset, V<sub>DD</sub> Monitor, and Temperature Sensor
- Two on-chip Voltage Comparators
- up to 39 Port I/O (5 V tolerant)

With on-chip Power-On Reset,  $V_{DD}$  Monitor, Watchdog Timer, and clock oscillator, the C8051F36x devices are truly stand-alone System-on-a-Chip solutions. The Flash memory can be reprogrammed even in-circuit, providing non-volatile data storage, and also allowing field upgrades of the 8051 firmware. User software has complete control of all peripherals, and may individually shut down any or all peripherals for power savings.

The on-chip Silicon Labs 2-Wire (C2) Development Interface allows non-intrusive (uses no on-chip resources), full speed, in-circuit debugging using the production MCU installed in the final application. This debug logic supports inspection and modification of memory and registers, setting breakpoints, single stepping, run and halt commands. All analog and digital peripherals are fully functional while debugging using C2. The two C2 interface pins can be shared with user functions, allowing in-system debugging without occupying package pins.

Each device is specified for 3.0 to 3.6 V (100 MIPS) operation or 2.7 to 3.6 V (50 MIPS) operation over the industrial temperature range (-40 to +85 °C). The Port I/O and RST pins are tolerant of input signals up to 5 V. The C8051F36x devices are available in 48-pin TQFP packages, and C8051F36x devices are available in 32-pin LQFP and 28-pin QFN packages (also referred to as MLP or MLF packages). All package types are lead-free (RoHS compliant). See Table 1.1 for ordering part numbers. Block diagrams are included in Figure 1.1, Figure 1.2, and Figure 1.3.



Calibrated Internal 24.5 MHz Oscillator Programmable Counter Array Lead-free (RoHS Compliant) 10-bit Current Output DAC Internal Voltage Reference External Memory Interface Internal 80 kHz Oscillator Ordering Part Number 2-cycle 16 by 16 MAC Analog Comparators Temperature Sensor 10-bit 200ksps ADC Flash Memory (kB) Digital Port I/Os Timers (16-bit) Enhanced SPI MIPS (Peak) RAM (bytes) SMBus/l<sup>2</sup>C Package UART 32 1024 4 ~ 39 ~ 2 ~ TQFP-48 C8051F360-C-GQ 100 ~ ~  $\checkmark$ ~ ~  $\checkmark$ ~ ~ ~ ~  $\checkmark$  $\checkmark$ ~  $\checkmark$  $\checkmark$ 2 100 32 1024 ~ ~ ~ ~ 4 29  $\checkmark$  $\checkmark$ LQFP-32  $\checkmark$ C8051F361-C-GQ1 25 2 100 32 1024  $\checkmark$ ~ ~  $\checkmark$ ~ ~ 4  $\checkmark$  $\checkmark$  $\checkmark$  $\checkmark$  $\checkmark$  $\checkmark$ **QFN-28** C8051F362-C-GM<sup>2</sup> Notes:

Table 1.1. Product Selection Guide

1. Pin compatible with the C8051F310-GQ.

2. Pin compatible with the C8051F311-GM.



Ordering Part Number	MIPS (Peak)	Flash Memory (kB)	RAM (bytes)	2-cycle 16 by 16 MAC	Calibrated Internal 24.5 MHz Oscillator	Internal 80 kHz Oscillator	External Memory Interface	SMBus/I <sup>2</sup> C	Enhanced SPI	UART	Timers (16-bit)	Programmable Counter Array	Digital Port I/Os	10-bit 200ksps ADC	10-bit Current Output DAC	Internal Voltage Reference	Temperature Sensor	Analog Comparators	Lead-free (RoHS Compliant)	Package
C8051F363-C-GQ	100	32	1024	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	~	$\checkmark$	~	4	$\checkmark$	39	_	_	_	—	2	$\checkmark$	TQFP-48
C8051F364-C-GQ <sup>1</sup>	100	32	1024	~	$\checkmark$	$\checkmark$	—	$\checkmark$	$\checkmark$	$\checkmark$	4	$\checkmark$	29	_		-	—	2	$\checkmark$	LQFP-32
C8051F365-C-GM <sup>2</sup>	100	32	1024	~	~	$\checkmark$		$\checkmark$	~	<	4	$\checkmark$	25					2	<	QFN-28
C8051F366-C-GQ <sup>1</sup>	50	32	1024	~	$\checkmark$	$\checkmark$	_	~	$\checkmark$	~	4	$\checkmark$	29	$\checkmark$	$\checkmark$	~	~	2	~	LQFP-32
C8051F367-C-GM <sup>2</sup>	50	32	1024	~	~	~	—	~	~	~	4	$\checkmark$	25	~	$\checkmark$	~	~	2	~	QFN-28
C8051F368-C-GQ <sup>1</sup>	50	16	1024	~	$\checkmark$	$\checkmark$	_	~	$\checkmark$	~	4	$\checkmark$	29	$\checkmark$	$\checkmark$	~	~	2	~	LQFP-32
C8051F369-C-GM <sup>2</sup>	50	16	1024	~	~	$\checkmark$		~	~	~	4	$\checkmark$	25	~	$\checkmark$	~	~	2	~	QFN-28
Notes: 1. Pin compatible with the C8051F310-GQ. 2. Pin compatible with the C8051F311-GM.																				

### Table 1.2. Product Selection Guide (These OPNs are Not Recommended for New Designs)



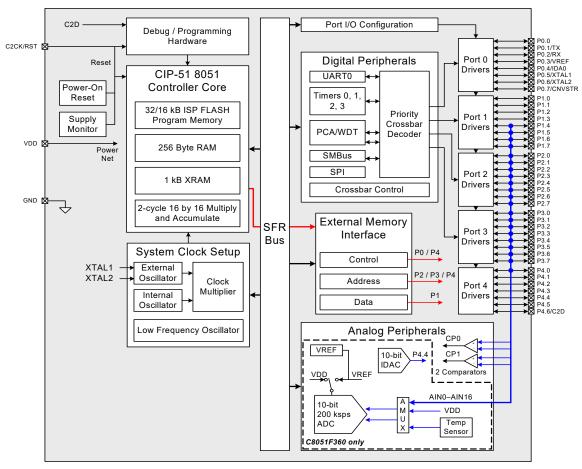
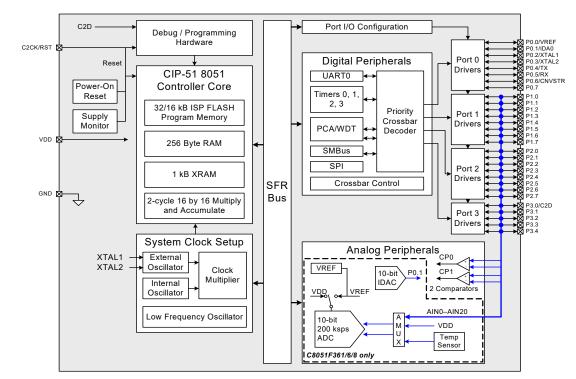
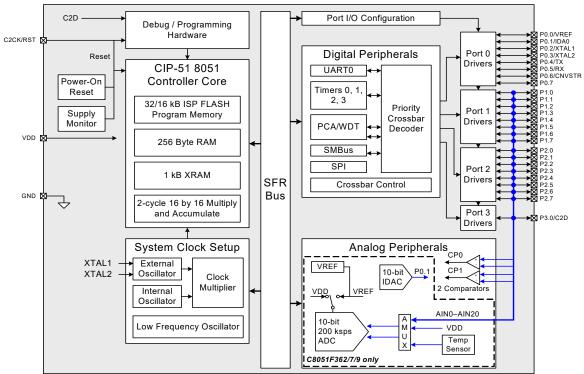


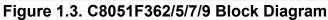
Figure 1.1. C8051F360/3 Block Diagram













### 1.1. CIP-51<sup>™</sup> Microcontroller Core

#### 1.1.1. Fully 8051 Compatible

The C8051F36x family utilizes Silicon Labs' proprietary CIP-51 microcontroller core. The CIP-51 is fully compatible with the MCS-51<sup>™</sup> instruction set; standard 803x/805x assemblers and compilers can be used to develop software. The CIP-51 core offers all the peripherals included with a standard 8052, including four 16-bit counter/timers, a full-duplex UART with extended baud rate configuration, an enhanced SPI port, 1024 bytes of internal RAM, 128 byte Special Function Register (SFR) address space, and up to 39 I/O pins.

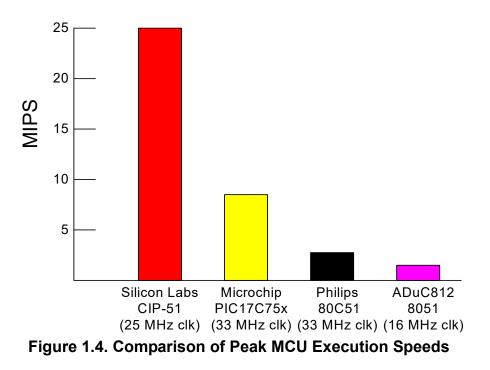
#### 1.1.2. Improved Throughput

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute with a maximum system clock of 12-to-24 MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with only four instructions taking more than four system clock cycles.

The CIP-51 has a total of 109 instructions. The table below shows the total number of instructions that require each execution time.

Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8
Number of Instructions	26	50	5	14	7	3	1	2	1

With the CIP-51's maximum system clock at 100 MHz, it has a peak throughput of 100 MIPS. Figure 1.4 shows a comparison of peak throughputs for various 8-bit microcontroller cores with their maximum system clocks.





#### 1.1.3. Additional Features

The C8051F36x SoC family includes several key enhancements to the CIP-51 core and peripherals to improve performance and ease of use in end applications.

The extended interrupt handler provides 16 interrupt sources into the CIP-51 (as opposed to 7 for the standard 8051), allowing numerous analog and digital peripherals to interrupt the controller. An interrupt driven system requires less intervention by the MCU, giving it more effective throughput. The extra interrupt sources are very useful when building multi-tasking, real-time systems.

Eight reset sources are available: power-on reset circuitry (POR), an on-chip  $V_{DD}$  Monitor (forces reset when power supply voltage drops below  $V_{RST}$  as given in Table 12.1 on page 135), a Watchdog Timer, a Missing Clock Detector, a voltage level detection from Comparator0, a forced software reset, an external reset pin, and an illegal Flash access protection circuit. Each reset source except for the POR, Reset Input Pin, or Flash error may be disabled by the user in software. The WDT may be permanently enabled in software after a power-on reset during MCU initialization.

The internal oscillator factory calibrated to 24.5 MHz  $\pm 2\%$ . This internal oscillator period may be user programmed in ~0.5% increments. An additional low-frequency oscillator is also available which facilitates low-power operation. An external oscillator drive circuit is included, allowing an external crystal, ceramic resonator, capacitor, RC, or CMOS clock source to generate the system clock. If desired, the system clock source may be switched on-the-fly between both internal and external oscillator circuits. An external oscillator can also be extremely useful in low power applications, allowing the MCU to run from a slow (power saving) source, while periodically switching to the fast (up to 25 MHz) internal oscillator as needed. Additionally, an on-chip PLL is provided to achieve higher system clock speeds for increased throughput.

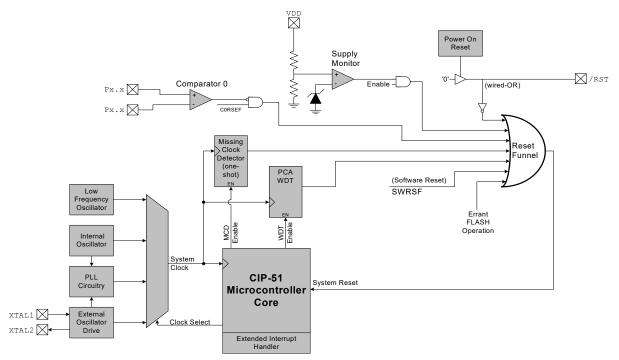


Figure 1.5. On-Chip Clock and Reset



DATA MEMORY

### 1.2. On-Chip Memory

**PROGRAM MEMORY** 

The CIP-51 has a standard 8051 program and data address configuration. It includes 256 bytes of data RAM, with the upper 128 bytes dual-mapped. Indirect addressing accesses the upper 128 bytes of general purpose RAM, and direct addressing accesses the 128 byte SFR address space. The lower 128 bytes of RAM are accessible via direct and indirect addressing. The first 32 bytes are addressable as four banks of general purpose registers, and the next 16 bytes can be byte addressable or bit addressable.

Program memory consists of 32/16 kB of Flash. This memory may be reprogrammed in-system in 1024 byte sectors, and requires no special off-chip programming voltage. See Figure 1.6 for the MCU system memory map.

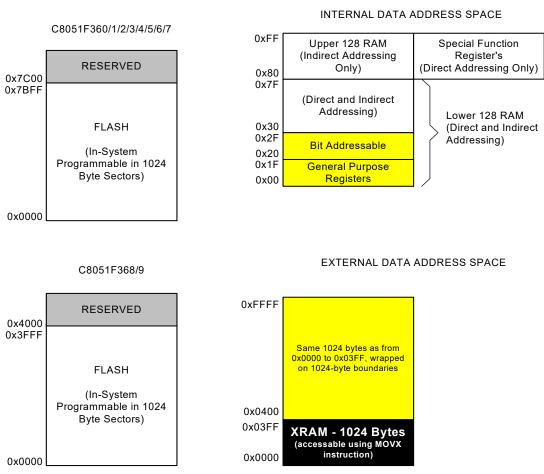


Figure 1.6. On-Board Memory Map

### 1.3. On-Chip Debug Circuitry

The C8051F36x devices include on-chip Silicon Labs 2-Wire (C2) debug circuitry that provides non-intrusive, full speed, in-circuit debugging of the production part *installed in the end application*.

Silicon Labs' debugging system supports inspection and modification of memory and registers, breakpoints, and single stepping. No additional target RAM, program memory, timers, or communications chan-



nels are required. All the digital and analog peripherals are functional and work correctly while debugging. All the peripherals (except for the ADC and SMBus) are stalled when the MCU is halted, during single stepping, or at a breakpoint in order to keep them synchronized.

The C8051F360DK development kit provides all the hardware and software necessary to develop application code and perform in-circuit debugging with the C8051F36x MCUs. The kit includes software with a developer's studio and debugger, an integrated 8051 assembler, and a debug adapter. It also has a target application board with the associated MCU installed and prototyping area, plus the required cables, and wall-mount power supply. The Development Kit requires a PC running Windows98SE or later.

The Silicon Labs IDE interface is a vastly superior developing and debugging configuration, compared to standard MCU emulators that use on-board "ICE Chips" and require the MCU in the application board to be socketed. Silicon Labs' debug paradigm increases ease of use and preserves the performance of the precision analog peripherals.

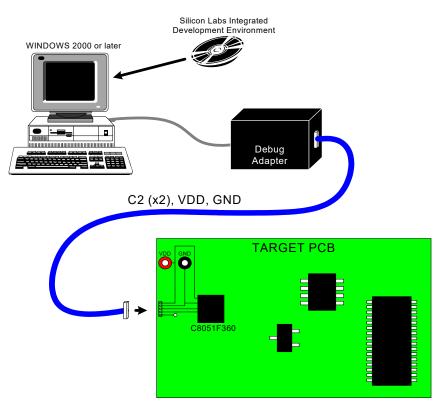


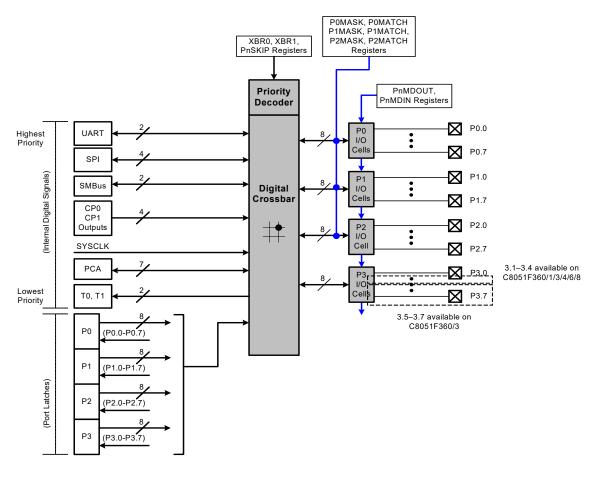
Figure 1.7. Development/In-System Debug Diagram

### 1.4. Programmable Digital I/O and Crossbar

C8051F36x devices include up to 39 I/O pins (four byte-wide Ports and one 7-bit-wide Port). The C8051F36x Ports behave like typical 8051 Ports with a few enhancements. Each Port pin may be configured as an analog input or a digital I/O pin. Pins selected as digital I/Os may additionally be configured for push-pull or open-drain output. The "weak pullups" that are fixed on typical 8051 devices may be globally disabled, providing power savings capabilities.



The Digital Crossbar allows mapping of internal digital system resources to Port I/O pins. (See Figure 1.8.) On-chip counter/timers, serial buses, HW interrupts, comparator output, and other digital signals in the controller can be configured to appear on the Port I/O pins specified in the Crossbar Control registers. This allows the user to select the exact mix of general purpose Port I/O and digital resources needed for the particular application.





### 1.5. Serial Ports

The C8051F36x Family includes an SMBus/I<sup>2</sup>C interface, a full-duplex UART with enhanced baud rate configuration, and an Enhanced SPI interface. Each of the serial buses is fully implemented in hardware and makes extensive use of the CIP-51's interrupts, thus requiring very little CPU intervention.

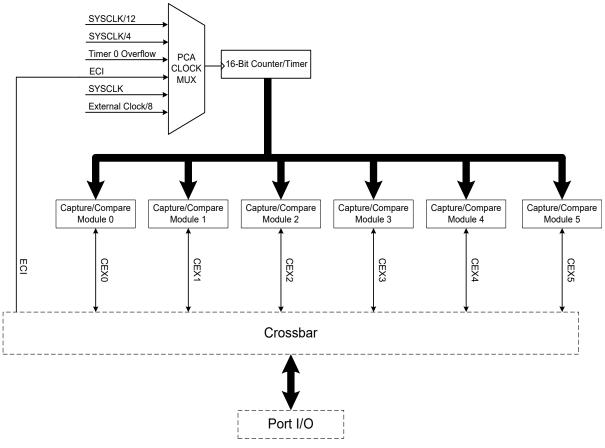
#### 1.6. Programmable Counter Array

An on-chip Programmable Counter/Timer Array (PCA) is included in addition to the four 16-bit general purpose counter/timers. The PCA consists of a dedicated 16-bit counter/timer time base with three programmable capture/compare modules. The PCA clock is derived from one of six sources: the system clock divided by 12, the system clock divided by 4, Timer 0 overflows, an External Clock Input (ECI), the system clock, or the external oscillator clock source divided by 8. The external clock source selection is useful for



real-time clock functionality, where the PCA is clocked by an external source while the internal oscillator drives the system clock.

Each capture/compare module can be configured to operate in one of six modes: Edge-Triggered Capture, Software Timer, High Speed Output, 8- or 16-bit Pulse Width Modulator, or Frequency Output. Additionally, Capture/Compare Module 5 offers watchdog timer (WDT) capabilities. Following a system reset, Module 5 is configured and enabled in WDT mode. The PCA Capture/Compare Module I/O and External Clock Input may be routed to Port I/O via the Digital Crossbar.





### 1.7. 10-Bit Analog to Digital Converter

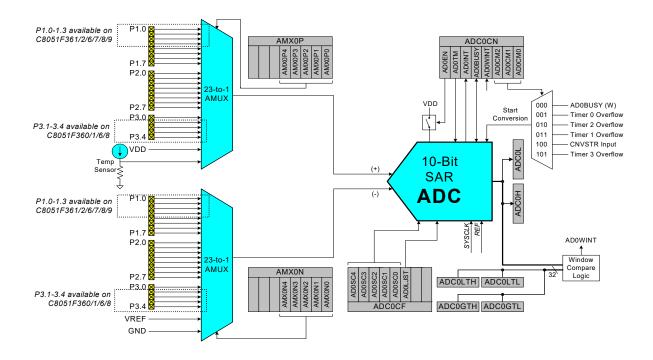
The C8051F360/1/2/6/7/8/9 devices include an on-chip 10-bit SAR ADC with up to 21 channels for the differential input multiplexer. With a maximum throughput of 200 ksps, the ADC offers true 10-bit linearity with an INL and DNL of  $\pm 1$  LSB. The ADC system includes a configurable analog multiplexer that selects both positive and negative ADC inputs. Ports1-3 are available as an ADC inputs; additionally, the on-chip Temperature Sensor output and the power supply voltage (V<sub>DD</sub>) are available as ADC inputs. User firmware may shut down the ADC to save power.

Conversions can be started in six ways: a software command, an overflow of Timer 0, 1, 2, or 3, or an external convert start signal (CNVSTR). This flexibility allows the start of conversion to be triggered by software events, a periodic signal (timer overflows), or external HW signals. Conversion completions are indi-



cated by a status bit and an interrupt (if enabled). The resulting 10-bit data word is latched into the ADC data SFRs upon completion of a conversion.

Window compare registers for the ADC data can be configured to interrupt the controller when ADC data is either within or outside of a specified range. The ADC can monitor a key voltage continuously in background mode, but not interrupt the controller unless the converted data is within/outside the specified range.





#### 1.8. Comparators

C8051F36x devices include two on-chip voltage comparators that are enabled/disabled and configured via user software. Port I/O pins may be configured as comparator inputs via a selection mux. Two comparator outputs may be routed to a Port pin if desired: a latched output and/or an unlatched (asynchronous) output. Comparator response time is programmable, allowing the user to select between high-speed and low-power modes. Positive and negative hysteresis are also configurable.

Comparator interrupts may be generated on rising, falling, or both edges. When in IDLE mode, these interrupts may be used as a "wake-up" source. Comparator0 may also be configured as a reset source. Figure 1.12 shows the Comparator0 block diagram, and Figure 1.13 shows the Comparator1 block diagram.

**Note:** The first Port I/O pins shown in Figure 1.12 and Figure 1.13 are for the 48-pin (C8051F360/3) devices. The second set of Port I/O pins are for the 32-pin and 28-pin (C8051F361/2/4/5/6/7/8/9) devices. Please refer to the CPTnMX registers (SFR Definition 8.2 and SFR Definition 8.5) for more information.



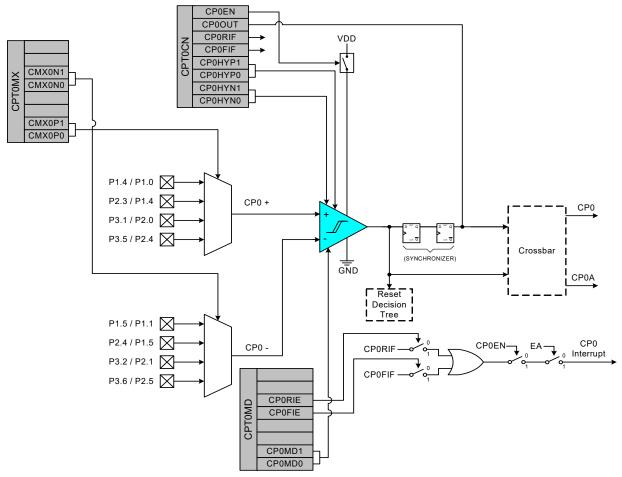


Figure 1.12. Comparator0 Block Diagram



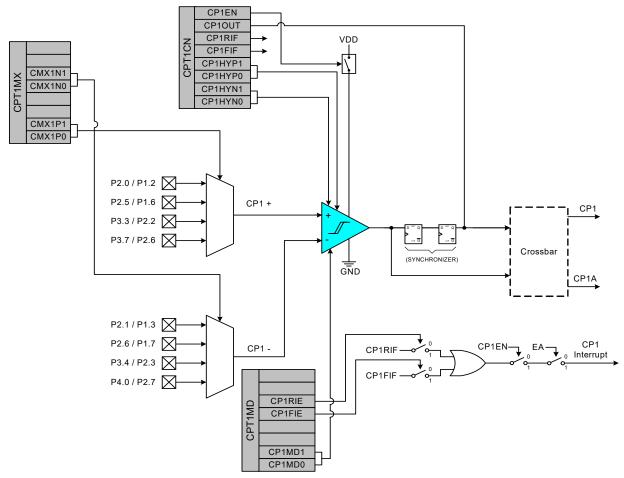
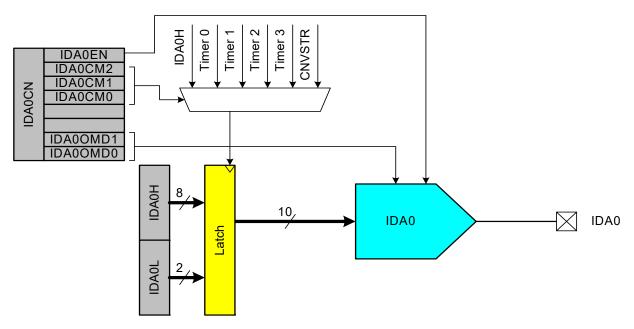


Figure 1.13. Comparator1 Block Diagram

### 1.9. 10-bit Current Output DAC

The C8051F360/1/2/6/7/8/9 devices includes a 10-bit current-mode Digital-to-Analog Converter (IDA0). The maximum current output of the IDA0 can be adjusted for three different current settings; 0.5 mA, 1 mA, and 2 mA. IDA0 features a flexible output update mechanism which allows for seamless full-scale changes and supports jitter-free updates for waveform generation. Three update modes are provided, allowing IDA0 output updates on a write to IDA0H, on a Timer overflow, or on an external pin edge.









### 2. Absolute Maximum Ratings

### Table 2.1. Absolute Maximum Ratings

Parameter	Conditions	Min	Тур	Мах	Units		
Ambient temperature under bias		-55	_	125	°C		
Storage Temperature		-65	—	150	°C		
Voltage on any Port I/O Pin or RST with respect to GND		-0.3	_	5.8	V		
Voltage on $V_{DD}$ with respect to GND		-0.3	_	4.2	V		
Maximum Total current through V <sub>DD</sub> or GND		_	_	500	mA		
Maximum output current sunk by $\overline{RST}$ or any Port pin		—	_	100	mA		
<b>Note:</b> Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.							

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.



### 3. Global Electrical Characteristics

### **Table 3.1. Global Electrical Characteristics**

-40 to +85 °C, 25 MHz system clock unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units
Digital Supply Voltage	SYSCLK = 0 to 50 MHz	2.7	3.0	3.6	V
	SYSCLK > 50 MHz	3.0	3.3	3.6	
Digital Supply RAM Data Retention Voltage		_	1.5	_	V
SYSCLK (System Clock) <sup>1,2</sup>	C8051F360/1/2/3/4/5	0	—	100	MHz
	C8051F366/7/8/9	0	—	50	MHz
Specified Operating Temperature Range		-40	_	+85	°C
Digital Supply Current—CP	U Active (Normal Mode, fetching instruction	ns fron	n Flash	)	-
I <sub>DD</sub> <sup>2</sup>	V <sub>DD</sub> = 3.6 V, F = 100 MHz	—	68	75	mA
	V <sub>DD</sub> = 3.6 V, F = 25 MHz	—	21	25	mA
	V <sub>DD</sub> = 3.0 V, F = 100 MHz	—	54	60	mA
	V <sub>DD</sub> = 3.0 V, F = 25 MHz	_	16	18	mA
	V <sub>DD</sub> = 3.0 V, F = 1 MHz	—	0.48	—	mA
	V <sub>DD</sub> = 3.0 V, F = 80 kHz	_	36	—	μA
I <sub>DD</sub> Supply Sensitivity <sup>3</sup>	F = 25 MHz	—	56		%/V
	F = 1 MHz	—	57	—	%/V
I <sub>DD</sub> Frequency Sensitivity <sup>3,4</sup>	V <sub>DD</sub> = 3.0 V, F <= 20 MHz, T = 25 °C	—	0.45		mA/MHz
	V <sub>DD</sub> = 3.0 V, F > 20 MHz, T = 25 °C	—	0.38	—	mA/MHz
	V <sub>DD</sub> = 3.6 V, F <= 20 MHz, T = 25 °C	—	0.61	—	mA/MHz
	V <sub>DD</sub> = 3.6 V, F > 20 MHz, T = 25 °C	—	0.51	_	mA/MHz
Digital Supply Current—CP	U Inactive (Idle Mode, not fetching instruct	ions fro	m Flas	sh)	
I <sub>DD</sub> <sup>2</sup>	V <sub>DD</sub> = 3.6 V, F = 100 MHz		36	40	mA
	V <sub>DD</sub> = 3.6 V, F = 25 MHz	—	9	12	mA
	V <sub>DD</sub> = 3.0 V, F = 100 MHz	—	30	35	mA
	V <sub>DD</sub> = 3.0 V, F = 25 MHz	—	7	9	mA
	V <sub>DD</sub> = 3.0 V, F = 1 MHz	_	0.24	—	mA
	V <sub>DD</sub> = 3.0 V, F = 80 kHz	_	19	—	μA
I <sub>DD</sub> Supply Sensitivity <sup>3</sup>	F = 25 MHz	—	44	—	%/V
	F = 1 MHz	_	43.7	—	%/V



### Table 3.1. Global Electrical Characteristics (Continued)

-40 to +85 °C, 25 MHz system clock unless otherwise specified.

Parameter	Conditions	Min	Тур	Мах	Units
I <sub>DD</sub> Frequency Sensitivity <sup>3,5</sup>	V <sub>DD</sub> = 3.0 V, F <= 1 MHz, T = 25 °C	_	0.24	_	mA/MHz
	V <sub>DD</sub> = 3.0 V, F > 1 MHz, T = 25 °C	—	0.25	—	mA/MHz
	V <sub>DD</sub> = 3.6 V, F <= 1 MHz, T = 25 °C	—	0.31	—	mA/MHz
	V <sub>DD</sub> = 3.6 V, F > 1 MHz, T = 25 °C	—	0.32	—	mA/MHz
Digital Supply Current (Stop Mode, shutdown)	Oscillator not running, V <sub>DD</sub> Monitor Disabled		0.5		μA

Notes:

1. SYSCLK must be at least 32 kHz to enable debugging.

2. SYSCLK is the internal device clock. For operational speeds in excess of 30 MHz, SYSCLK must be derived from the Phase-Locked Loop (PLL).

3. Based on device characterization data; Not production tested.

4. IDD can be estimated for frequencies ≤ 20 MHz by simply multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate I<sub>DD</sub> for >20 MHz, the estimate should be the current at 25 MHz minus the difference in current indicated by the frequency sensitivity number. For example: V<sub>DD</sub> = 3.0 V; F = 20 MHz, I<sub>DD</sub> = 15.9 mA - (25 MHz - 20 MHz) \* 0.38 mA/MHz = 14 mA.

5. Idle IDD can be estimated for frequencies ≤ 1 MHz by simply multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate Idle I<sub>DD</sub> for >1 MHz, the estimate should be the current at 25 MHz minus the difference in current indicated by the frequency sensitivity number. For example: V<sub>DD</sub> = 3.0 V; F = 5 MHz, Idle I<sub>DD</sub> = 7.2 mA - (25 MHz - 5 MHz) \* 0.25 mA/MHz = 2.2 mA.

Other electrical characteristics tables are found in the data sheet section corresponding to the associated peripherals. For more information on electrical characteristics for a specific peripheral, refer to the page indicated in Table 3.2.



Peripheral Electrical Characteristics	Page No.
ADC0 Electrical Characteristics	63
IDAC Electrical Characteristics	67
Voltage Reference Electrical Characteristics	70
Comparator Electrical Characteristics	80
Reset Electrical Characteristics	135
Flash Electrical Characteristics	145
Internal High Frequency Oscillator Electrical Characteristics	172
Internal Low Frequency Oscillator Electrical Characteristics	173
PLL Frequency Characteristics	183
Port I/O DC Electrical Characteristics	202

 Table 3.2. Index to Electrical Characteristics Tables



# 4. Pinout and Package Definitions

Table 4.1. Pin Definitions for the C8051F36x
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Name	Pin 'F360/3 (48-pin)	Pin 'F361/4/6/8 (32-pin)	Pin 'F362/5/7/9 (28-pin)	Туре	Description
V <sub>DD</sub>	19, 31, 43	4	4		Power Supply Voltage.
GND	18, 30, 42	3	3		Ground.
AGND	6	_	_		Analog Ground.
AV+	7	_	_		Analog Supply Voltage. Must be tied to +2.7 to +3.6 V.
RST/	8	5	5	D I/O	Device Reset. Open-drain output of internal POR or $V_{DD}$ Monitor. An external source can initiate a system reset by driving this pin low for at least 10 $\mu$ s.
C2CK				D I/O	Clock signal for the C2 Debug Interface.
P4.6/	9	_	_	D I/O or A In	Port 4.6. See Section 17 for a complete description.
C2D				D I/O	Bi-directional data signal for the C2 Debug Interface.
P3.0/	_	6	6	D I/O or A In	Port 3.0. See Section 17 for a complete description.
C2D				D I/O	Bi-directional data signal for the C2 Debug Interface.
P0.0	5	2	2	D I/O or A In	Port 0.0. See Section 17 for a complete description.
P0.1	4	1	1	D I/O or A In	Port 0.1. See Section 17 for a complete description.
P0.2	3	32	28	D I/O or A In	Port 0.2. See Section 17 for a complete description.
P0.3	2	31	27	D I/O or A In	Port 0.3. See Section 17 for a complete description.
P0.4	1	30	26	D I/O or A In	Port 0.4. See Section 17 for a complete description.
P0.5	48	29	25	D I/O or A In	Port 0.5. See Section 17 for a complete description.
P0.6	47	28	24	D I/O or A In	Port 0.6. See Section 17 for a complete description.
P0.7	46	27	23	D I/O or A In	Port 0.7. See Section 17 for a complete description.



Name	Pin 'F360/3 (48-pin)	Pin 'F361/4/6/8 (32-pin)	Pin 'F362/5/7/9 (28-pin)	Туре	Description
P1.0	45	26	22	D I/O or A In	Port 1.0. See Section 17 for a complete description.
P1.1	44	25	21	D I/O or A In	Port 1.1. See Section 17 for a complete description.
P1.2	41	24	20	D I/O or A In	Port 1.2. See Section 17 for a complete description.
P1.3	40	23	19	D I/O or A In	Port 1.3. See Section 17 for a complete description.
P1.4	39	22	18	D I/O or A In	Port 1.4. See Section 17 for a complete description.
P1.5	38	21	17	D I/O or A In	Port 1.5. See Section 17 for a complete description.
P1.6	37	20	16	D I/O or A In	Port 1.6. See Section 17 for a complete description.
P1.7	36	19	15	D I/O or A In	Port 1.7. See Section 17 for a complete description.
P2.0	35	18	14	D I/O or A In	Port 2.0. See Section 17 for a complete description.
P2.1	34	17	13	D I/O or A In	Port 2.1. See Section 17 for a complete description.
P2.2	33	16	12	D I/O or A In	Port 2.2. See Section 17 for a complete description.
P2.3	32	15	11	D I/O or A In	Port 2.3. See Section 17 for a complete description.
P2.4	29	14	10	D I/O or A In	Port 2.4. See Section 17 for a complete description.
P2.5	28	13	9	D I/O or A In	Port 2.5. See Section 17 for a complete description.
P2.6	27	12	8	D I/O or A In	Port 2.6. See Section 17 for a complete description.
P2.7	26	11	7	D I/O or A In	Port 2.7. See Section 17 for a complete description.
P3.0	25	—	—	D I/O or A In	Port 3.0. See Section 17 for a complete description.

Table 4.1. Pin Definitions for the C805	51F36x (Continued)



Name	Pin 'F360/3 (48-pin)	Pin 'F361/4/6/8 (32-pin)	Pin 'F362/5/7/9 (28-pin)	Туре	Description
P3.1	24	7	_	D I/O or A In	Port 3.1. See Section 17 for a complete description.
P3.2	23	8	_	D I/O or A In	Port 3.2. See Section 17 for a complete description.
P3.3	22	9	_	D I/O or A In	Port 3.3. See Section 17 for a complete description.
P3.4	21	10	_	D I/O or A In	Port 3.4. See Section 17 for a complete description.
P3.5	20	_	_	D I/O or A In	Port 3.5. See Section 17 for a complete description.
P3.6	17	_	_	D I/O or A In	Port 3.6. See Section 17 for a complete description.
P3.7	16	_	_	D I/O or A In	Port 3.7. See Section 17 for a complete description.
P4.0	15	_	_	D I/O or A In	Port 4.0. See Section 17 for a complete description.
P4.1	14	_	_	D I/O	Port 4.1. See Section 17 for a complete description.
P4.2	13	—	—	D I/O	Port 4.2. See Section 17 for a complete description.
P4.3	12	—	—	D I/O	Port 4.3. See Section 17 for a complete description.
P4.4	11	—	—	D I/O	Port 4.4. See Section 17 for a complete description.
P4.5	10	—		D I/O	Port 4.5. See Section 17 for a complete description.

Table 4.1. Pin Definitions for the C8051F36x (Continued)



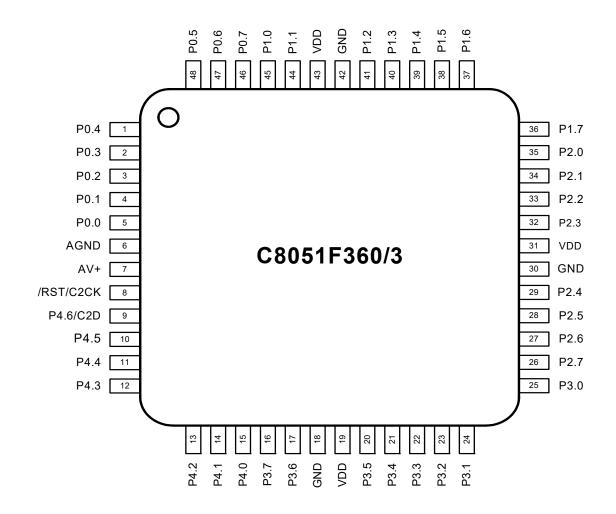


Figure 4.1. TQFP-48 Pinout Diagram (Top View)



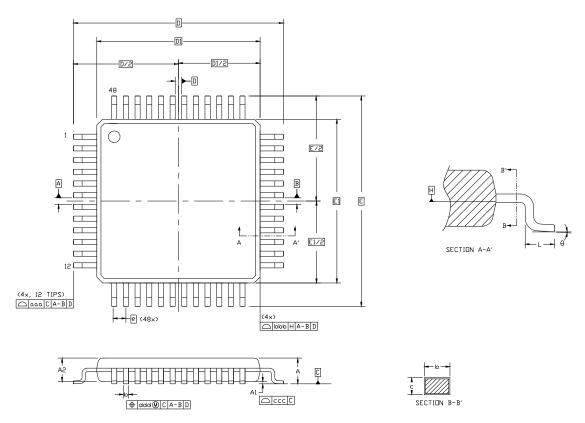


Figure 4.2. TQFP-48 Package Diagram

Min	Nom	Max		Dimension	Min	Nom	Ma
_	—	1.20		E	9.00 BSC.		
0.05	—	0.15		E1	7.00 BSC.		
0.95	1.00	1.05		L	0.45	0.60	0.7
0.17	0.22	0.27		aaa	0.20		
0.09		0.20		bbb	0.20		
	9.00 BSC.			CCC		0.08	
7.00 BSC.				ddd		0.08	
	0.50 BSC.			θ	0°	3.5°	7°
	0.95 0.17 0.09	0.95         1.00           0.17         0.22           0.09         —           9.00 BSC.         7.00 BSC.	0.05         —         0.15           0.95         1.00         1.05           0.17         0.22         0.27           0.09         —         0.20           9.00 BSC.         7.00 BSC.	0.05         —         0.15           0.95         1.00         1.05           0.17         0.22         0.27           0.09         —         0.20           9.00 BSC.         7.00 BSC.	0.05         —         0.15         E1           0.95         1.00         1.05         L           0.17         0.22         0.27         aaa           0.09         —         0.20         bbb           9.00 BSC.         ccc         cddd	0.05         —         0.15         E1           0.95         1.00         1.05         L         0.45           0.17         0.22         0.27         aaa	0.05         —         0.15         E1         7.00 BSC.           0.95         1.00         1.05         L         0.45         0.60           0.17         0.22         0.27         aaa         0.20           0.09         —         0.20         bbb         0.20           9.00 BSC.         ccc         0.08           7.00 BSC.         ddd         0.08

#### Table 4.2. TQFP-48 Package Dimensions

1. All dimensions shown are in millimeters (mm) unless otherwise noted.

2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

3. This drawing conforms to JEDEC outline MS-026, variation ABC.

4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.



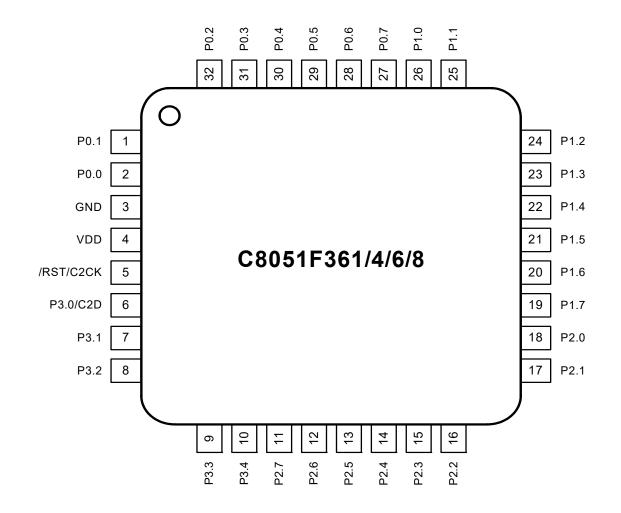


Figure 4.3. LQFP-32 Pinout Diagram (Top View)



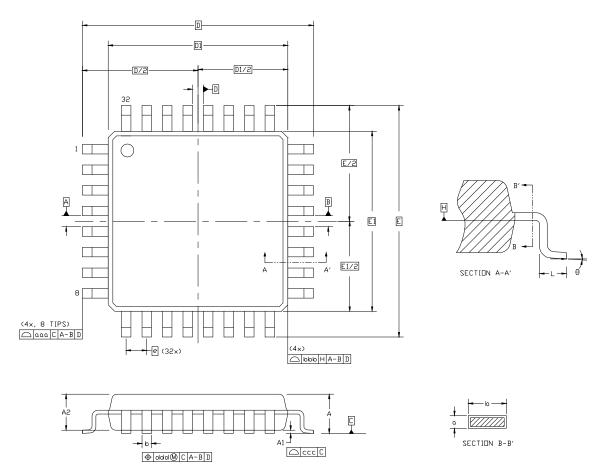


Figure 4.4. LQFP-32 Package Diagram

Dimension	Min	Nom	Max	Dimension	Min	Nom	Max
А	_	—	1.60	E	9.00 BSC.		
A1	0.05	—	0.15	E1	7.00 BSC.		
A2	1.35	1.40	1.45	L	0.45	0.60	0.75
b	0.30	0.37	0.45	aaa	0.20		
С	0.09	—	0.20	bbb	0.20		
D		9.00 BSC.		CCC		0.10	
D1	7.00 BSC.			ddd		0.20	
е		0.80 BSC.		θ	0°	3.5°	7°

#### Table 4.3. LQFP-32 Package Dimensions

Notes:

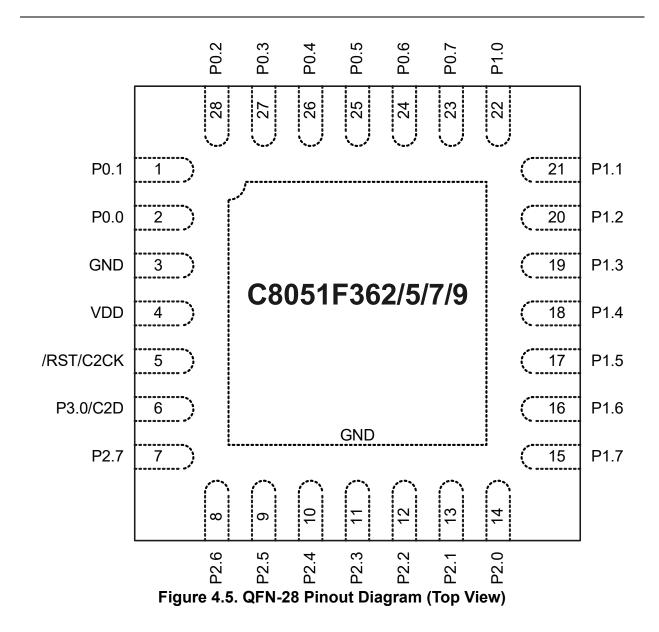
1. All dimensions shown are in millimeters (mm) unless otherwise noted.

2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

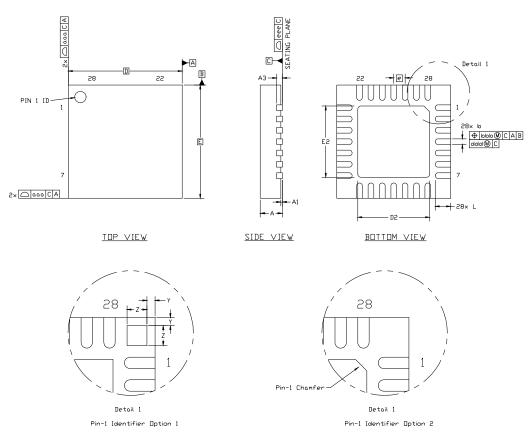
3. This drawing conforms to JEDEC outline MS-026, variation BBA.

**4.** Recommended card reflow profile is per the JEDEC/IPC J-STD-020B specification for Small Body Components.











Dimension	Min	Nom	Max	]	Dimension	Min	Nom	Max
А	0.80	0.90	1.00		E2	2.90	3.15	3.35
A1	0.03	0.07	0.11		L	0.45	0.55	0.65
A3	0.25 REF				aaa	0.15		
b	0.18	0.25	0.30		bbb	0.10		
D	5.00 BSC.				ddd		0.05	
D2	2.90	3.15	3.35		eee		0.08	
е	0.50 BSC.				Z	0.435		
E		5.00 BSC.		1	Y		0.18	

### Table 4.4. QFN-28 Package Dimensions

Notes:

- **1.** All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
- **3.** This drawing conforms to JEDEC outline MO-243, variation VHHD except for custom features D2, E2, L, Z, and Y which are toleranced per supplier designation.
- **4.** Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.



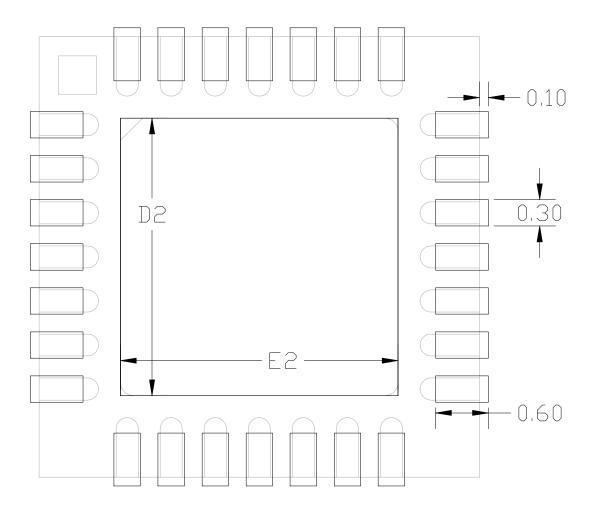


Figure 4.7. Typical QFN-28 Landing Diagram



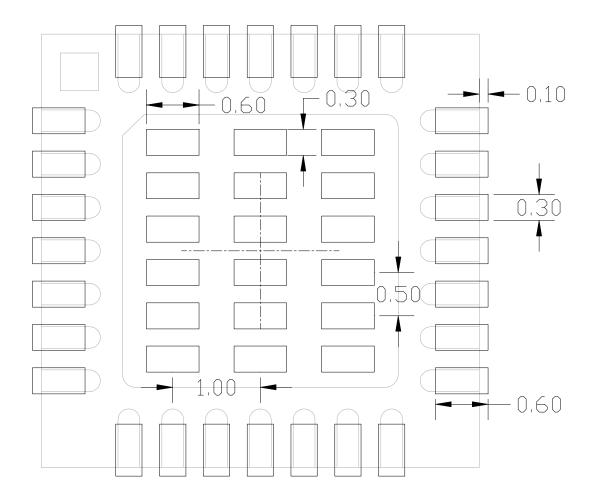


Figure 4.8. QFN-28 Solder Paste Recommendation



# 5. 10-Bit ADC (ADC0, C8051F360/1/2/6/7/8/9)

The ADC0 subsystem for the C8051F360/1/2/6/7/8/9 consists of two analog multiplexers (referred to collectively as AMUX0) with 23 total input selections, and a 200 ksps, 10-bit successive-approximation-register ADC with integrated track-and-hold and programmable window detector. The AMUX0, data conversion modes, and window detector are all configurable under software control via the Special Function Registers shown in Figure 5.1. ADC0 operates in both Single-ended and Differential modes, and may be configured to measure P1.0-P3.4 (where available), the Temperature Sensor output, or V<sub>DD</sub> with respect to P1.0-P3.4, VREF, or GND. The ADC0 subsystem is enabled only when the AD0EN bit in the ADC0 Control register (ADC0CN) is set to logic '1'. The ADC0 subsystem is in low power shutdown when this bit is logic '0'.

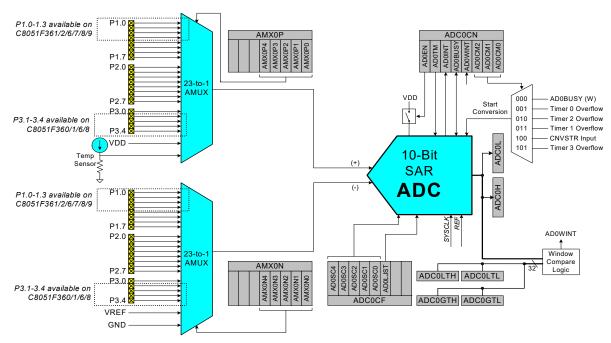


Figure 5.1. ADC0 Functional Block Diagram



#### 5.1. Analog Multiplexer

AMUX0 selects the positive and negative inputs to the ADC. Any of the following may be selected as the positive input: the AMUX0 Port I/O inputs, the on-chip temperature sensor, or the positive power supply  $(V_{DD})$ . Any of the following may be selected as the negative input: the AMUX0 Port I/O inputs, VREF, or GND. When GND is selected as the negative input, ADC0 operates in Single-ended Mode; all other times, ADC0 operates in Differential Mode. The ADC0 input channels are selected in the AMX0P and AMX0N registers as described in SFR Definition 5.1 and SFR Definition 5.2.

The conversion code format differs between Single-ended and Differential modes. The registers ADC0H and ADC0L contain the high and low bytes of the output conversion code from the ADC at the completion of each conversion. Data can be right-justified or left-justified, depending on the setting of the AD0LJST bit (ADC0CN.0). When in Single-ended Mode, conversion codes are represented as 10-bit unsigned integers. Inputs are measured from '0' to VREF \* 1023/1024. Example codes are shown below for both right-justified and left-justified data. Unused bits in the ADC0H and ADC0L registers are set to '0'.

Input Voltage	Right-Justified ADC0H:ADC0L (AD0LJST = 0)	Left-Justified ADC0H:ADC0L (AD0LJST = 1)
VREF x 1023/1024	0x03FF	0xFFC0
VREF x 512/1024	0x0200	0x8000
VREF x 256/1024	0x0100	0x4000
0	0x0000	0x0000

When in Differential Mode, conversion codes are represented as 10-bit signed 2's complement numbers. Inputs are measured from -VREF to VREF \* 511/512. Example codes are shown below for both right-justified and left-justified data. For right-justified data, the unused MSBs of ADC0H are a sign-extension of the data word. For left-justified data, the unused LSBs in the ADC0L register are set to '0'.

Input Voltage	Right-Justified ADC0H:ADC0L (AD0LJST = 0)	Left-Justified ADC0H:ADC0L (AD0LJST = 1)
VREF x 511/512	0x01FF	0x7FC0
VREF x 256/512	0x0100	0x4000
0	0x0000	0x0000
–VREF x 256/512	0xFF00	0xC000
-VREF	0xFE00	0x8000

**Important Note About ADC0 Input Configuration:** Port pins selected as ADC0 inputs should be configured as analog inputs, and should be skipped by the Digital Crossbar. To configure a Port pin for analog input, set to '0' the corresponding bit in register PnMDIN (for n = 0,1,2,3). To force the Crossbar to skip a Port pin, set to '1' the corresponding bit in register PnSKIP (for n = 0,1,2,3). See Section "17. Port Input/ Output" on page 184 for more Port I/O configuration details.



#### 5.2. Temperature Sensor

The typical temperature sensor transfer function is shown in Figure 5.2. The output voltage ( $V_{TEMP}$ ) is the positive ADC input when the temperature sensor is selected by bits AMX0P4-0 in register AMX0P.

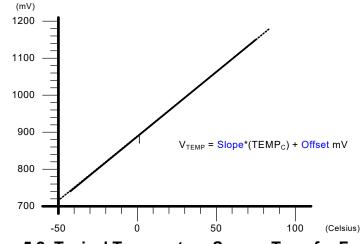


Figure 5.2. Typical Temperature Sensor Transfer Function

The uncalibrated temperature sensor output is extremely linear and suitable for relative temperature measurements (see Table 5.1 for linearity specifications). For absolute temperature measurements, gain and/ or offset calibration is recommended. Typically a 1-point calibration includes the following steps:

- Step 1. Control/measure the ambient temperature (this temperature must be known).
- Step 2. Power the device, and delay for a few seconds to allow for self-heating.
- Step 3. Perform an ADC conversion with the temperature sensor selected as the positive input and GND selected as the negative input.
- Step 4. Calculate the offset and/or gain characteristics, and store these values in non-volatile memory for use with subsequent temperature sensor measurements.

Figure 5.3 shows the typical temperature sensor error assuming a 1-point calibration at 25 °C. Note that parameters which affect ADC measurement, in particular the voltage reference value, will also affect temperature measurement.



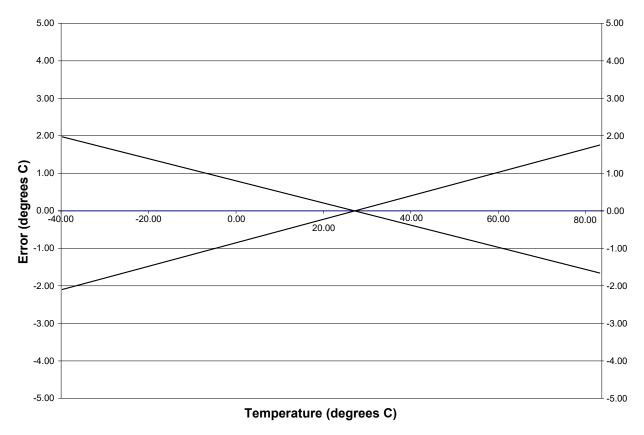


Figure 5.3. Temperature Sensor Error with 1-Point Calibration



#### 5.3. Modes of Operation

ADC0 has a maximum conversion speed of 200 ksps. The ADC0 conversion clock is a divided version of the system clock, determined by the AD0SC bits in the ADC0CF register (system clock divided by (AD0SC + 1) for  $0 \le AD0SC \le 31$ ).

#### 5.3.1. Starting a Conversion

A conversion can be initiated in one of five ways, depending on the programmed states of the ADC0 Start of Conversion Mode bits (AD0CM2-0) in register ADC0CN. Conversions may be initiated by one of the following:

- 1. Writing a '1' to the AD0BUSY bit of register ADC0CN
- 2. A Timer 0 overflow (i.e., timed continuous conversions)
- 3. A Timer 2 overflow
- 4. A Timer 1 overflow
- 5. A rising edge on the CNVSTR input signal
- 6. A Timer 3 overflow

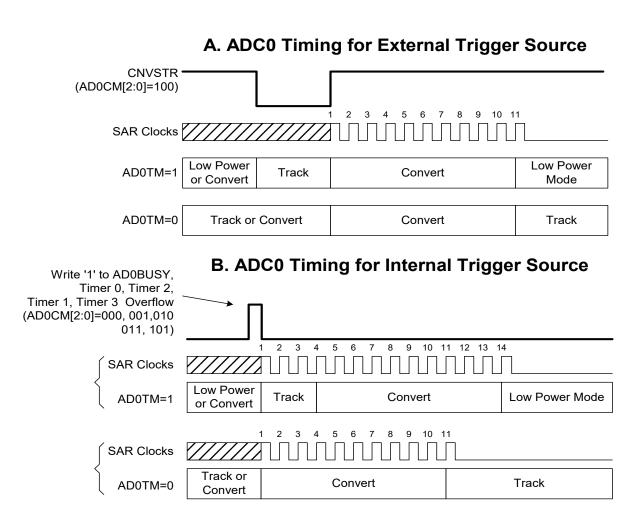
Writing a '1' to AD0BUSY provides software control of ADC0 whereby conversions are performed "ondemand". During conversion, the AD0BUSY bit is set to logic '1' and reset to logic '0' when the conversion is complete. The falling edge of AD0BUSY triggers an interrupt (when enabled) and sets the ADC0 interrupt flag (AD0INT). Note: When polling for ADC conversion completions, the ADC0 interrupt flag (AD0INT) should be used. Converted data is available in the ADC0 data registers, ADC0H:ADC0L, when bit AD0INT is logic '1'. Note that when Timer 2 or Timer 3 overflows are used as the conversion source, Low Byte overflows are used if Timer 2/3 is in 8-bit mode; High byte overflows are used if Timer 2/3 is in 16-bit mode. See Section "21. Timers" on page 248 for timer configuration.

**Important Note About Using CNVSTR:** The CNVSTR input pin also functions as Port pin P0.7 on the C8051F360 devices and Port pin P0.6 on the C8051F361/2/6/7/8/9 devices. When the CNVSTR input is used as the ADC0 conversion source, the corresponding port pin should be skipped by the Digital Crossbar. To configure the Crossbar to skip the port pin, set the appropriate bit to '1' in register P0SKIP. See Section "17. Port Input/Output" on page 184 for details on Port I/O configuration.



#### 5.3.2. Tracking Modes

According to Table 5.1, each ADC0 conversion must be preceded by a minimum tracking time for the converted result to be accurate. The AD0TM bit in register ADC0CN controls the ADC0 track-and-hold mode. In its default state, the ADC0 input is continuously tracked, except when a conversion is in progress. When the AD0TM bit is logic '1', ADC0 operates in low-power track-and-hold mode. In this mode, each conversion is preceded by a tracking period of 3 SAR clocks (after the start-of-conversion signal). When the CNVSTR signal is used to initiate conversions in low-power tracking mode, ADC0 tracks only when CNVSTR is low; conversion begins on the rising edge of CNVSTR (see Figure 5.4). Tracking can also be disabled (shutdown) when the device is in low power standby or sleep modes. Low-power track-and-hold mode is also useful when AMUX settings are frequently changed, due to the settling time requirements described in Section "5.3.3. Settling Time Requirements" on page 54.







#### 5.3.3. Settling Time Requirements

When the ADC0 input configuration is changed (i.e., a different AMUX0 selection is made), a minimum tracking time is required before an accurate conversion can be performed. This tracking time is determined by the AMUX0 resistance, the ADC0 sampling capacitance, any external source resistance, and the accuracy required for the conversion. In low-power tracking mode, three SAR clocks are used for tracking at the start of every conversion. For most applications, these three SAR clocks will meet the minimum tracking time requirements.

Figure 5.5 shows the equivalent ADC0 input circuits for both Differential and Single-ended modes. Notice that the equivalent time constant for both input circuits is the same. The required ADC0 settling time for a given settling accuracy (SA) may be approximated by Equation 5.1. When measuring the Temperature Sensor output or  $V_{DD}$  with respect to GND,  $R_{TOTAL}$  reduces to  $R_{MUX}$ . See Table 5.1 for ADC0 minimum settling time requirements.

### **Equation 5.1. ADC0 Settling Time Requirements**

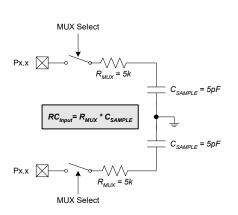
$$t = \ln\left(\frac{2^n}{SA}\right) \times R_{TOTAL} C_{SAMPLE}$$

Where:

SA is the settling accuracy, given as a fraction of an LSB (for example, 0.25 to settle within 1/4 LSB) *t* is the required settling time in seconds

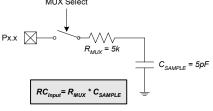
 $R_{TOTAL}$  is the sum of the AMUX0 resistance and any external source resistance.

*n* is the ADC resolution in bits (10).



**Differential Mode** 





### Figure 5.5. ADC0 Equivalent Input Circuits



#### SFR Definition 5.1. AMX0P: AMUX0 Positive Channel Select

R	R	R	R/W	R/W	R/W	R/W	R/W	Reset Value		
-	-	-	AMX0P4	AMX0P3	AMX0P2	AMX0P1	AMX0P0	00000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0			
	UNUSED. R AMX0P4–0:									
		AMX0P4	-0		ADC0 Pos	sitive Input				
		00000 <sup>(1</sup>				.0 <sup>(1)</sup>				
		00001 <sup>(1</sup>				.1 <sup>(1)</sup>				
		00010 <sup>(1</sup>				.2 <sup>(1)</sup>				
		00011 <sup>(1</sup>				.2 .3 <sup>(1)</sup>				
		00100				1.4				
		00101				1.5				
		00110			P	1.6				
		00111			P1.7					
		01000			P2.0					
		01001			P2.1 P2.2					
		01010 01011			P2.3 P2.4 P2.5 P2.6 P2.7 P3.0					
		01100								
		01101								
		01110								
		01111								
		10000								
		10001 <sup>(2</sup>			P3.1 <sup>(2)</sup>					
		10010 <sup>(2</sup>			P3.	.2 <sup>(2)</sup>				
		10011 <sup>(2</sup>	2)		P3.3 <sup>(2)</sup>					
	10100 <sup>(2)</sup> 10101–11101 11110				.4 <sup>(2)</sup>					
					RVED					
					Sensor					
		11111			V	DD				
	RESE 2. Only a	ERVED on C applies to C	8051F361/2/6 8051F360 (4 8051F360/1/6 9 (28-pin) dev	8-pin) device 5/8 (48-pin an			ERVED			



## SFR Definition 5.2. AMX0N: AMUX0 Negative Channel Select

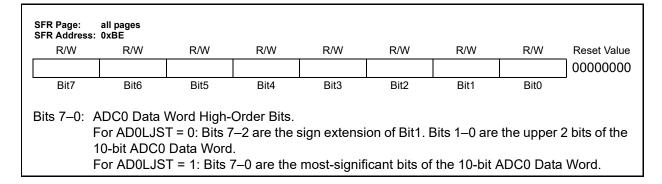
R	R	R	R/W	R/W	R/W	R/W	R/W	Reset Valu		
-	-	-	AMX0N4	AMX0N3	AMX0N2	AMX0N1	AMX0N0	0000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	-		
ь. <b>7</b> г.		000	\\ <i>\\</i> .:							
	UNUSED. Ro AMX0N4–0:									
	Note that wh					CO operate	es in Sinale	-ended		
	mode. For al			-			-			
[		AMX0N4			ADC0 Neg	-	t			
		00000 <sup>(1</sup>	)		P1.	.0 <sup>(1)</sup>				
		00001 <sup>(1</sup>	)		P1.	.1 <sup>(1)</sup>				
		00010 <sup>(1</sup>	)		P1.	.2 <sup>(1)</sup>				
		00011 <sup>(1</sup>	)		P1.	.3 <sup>(1)</sup>				
		00100			P	1.4				
		00101			P	1.5				
		00110			P	1.6				
		00111			P1.7					
		01000			P2.0 P2.1					
		01001								
		01010		P2.2						
		01011 01100			P2.3 P2.4 P2.5 P2.6 P2.7					
·		01100								
		01110								
		01111								
		10000				3.0				
		10001 <sup>(2</sup>	)		P3	.1 <sup>(2)</sup>				
		10010 <sup>(2</sup>		P3.2 <sup>(2)</sup>						
		10011 <sup>(2</sup>			P3	.3 <sup>(2)</sup>				
		10100 <sup>(2</sup>								
		10101-111				RVED				
		11110				REF				
	11111				G	ND				
·	Notes:									
			8051F361/2/6			); selection				
			:8051F360 (4 8051F360/1/6			loction PES				
			9 (28-pin) dev		iu 52-piii), se					



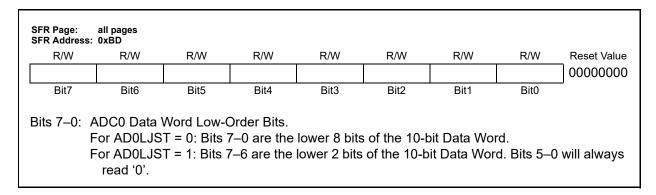
SFR Page: SFR Address	all pages 0xBC									
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
AD0SC4	AD0SC3	AD0SC2	AD0SC1	AD0SC0	AD0LJST	-	-	11111000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_		
Bits 7–3: AD0SC4–0: ADC0 SAR Conversion Clock Period Bits. SAR Conversion clock is derived from system clock by the following equation, where <i>AD0SC</i> refers to the 5-bit value held in bits AD0SC4–0. SAR Conversion clock require- ments are given in Table 5.1. $AD0SC = \frac{SYSCLK}{CLK_{SAR}} - 1$										
Bit 2: AD0LJST: ADC0 Left Justify Select. 0: Data in ADC0H:ADC0L registers are right-justified. 1: Data in ADC0H:ADC0L registers are left-justified. Bits 1–0: UNUSED. Read = 00b; Write = don't care.										

### SFR Definition 5.3. ADC0CF: ADC0 Configuration

### SFR Definition 5.4. ADC0H: ADC0 Data Word MSB



### SFR Definition 5.5. ADC0L: ADC0 Data Word LSB





R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
AD0EN	AD0TM	AD0INT	AD0BUSY	AD0WINT	AD0CM2	AD0CM1	AD0CM0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	1
Bit 7:	AD0EN: AD0	C0 Enable	Bit.					
	0: ADC0 Dis	abled. ADC	C0 is in low-p	ower shutde	own.			
	1: ADC0 Ena					rsions.		
Bit 6:	AD0TM: AD0	C0 Track M	lode Bit.					
	0: Normal Tra	ack Mode:	When ADC0	is enabled,	tracking is	continuous	unless a co	nversion is
	in progress.							
	1: Low-powe					bits (see b	elow).	
Bit 5:	AD0INT: AD0							
	0: ADC0 has	•			since the las	st time AD0I	NT was clea	ared.
	1: ADC0 has	•		ersion.				
Bit 4:	ADOBUSY: A	ADC0 Busy	Bit.					
	Read:							IT : 4 4
	0: ADC0 con				i is not curre	entiy in prog	ress. ADUIr	NI IS SELL
	1: ADC0 con	•	edge of AD0	0031.				
	Write:		in progress.					
	0: No Effect.							
	1: Initiates A	DC0 Conve	ersion if AD0	CM2-0 = 00	0b			
Bit 3:	ADOWINT: A							
	0: ADC0 Wir					d since this	flaq was las	t cleared.
	1: ADC0 Wir						5	
Bits 2–0:	AD0CM2-0:	•						
	When AD0TI	M = 0:						
	000: ADC0 c	onversion	initiated on e	very write c	f '1' to AD0	BUSY.		
	001: ADC0 c	onversion	initiated on o	verflow of T	ïmer 0.			
	010: ADC0 c	onversion	initiated on o	verflow of T	ïmer 2.			
	011: ADC0 c							
	100: ADC0 c					NVSTR.		
	101: ADC0 c		initiated on o	verflow of T	imer 3.			
	11x: Reserve							
	When AD0TI				N and last		aka fallawa	م م م
	000: Tracking versior	-	on write of 1		sr and lasts	5 3 SAR CIO	cks, lollowe	a by con-
	001: Tracking	g initiated o	on overflow o	f Timer 0 ar	nd lasts 3 S/	AR clocks, f	ollowed by o	conversio
	010: Tracking	g initiated o	on overflow o	f Timer 2 ar	nd lasts 3 S/	AR clocks, f	ollowed by o	conversio
	011: Tracking	g initiated o	on overflow o	f Timer 1 ar	nd lasts 3 S/	AR clocks, f	ollowed by o	conversio
	100: ADC0 ti edge.	racks only v	when CNVS	FR input is I	ogic low; co	nversion sta	arts on rising	g CNVSTF
			~	( <b>T</b> ) 0				
	101: Tracking	d initiated c	on overflow o	t limer 3 ar	nd lasts 3 S/	AR clocks. †	ollowed by a	conversion

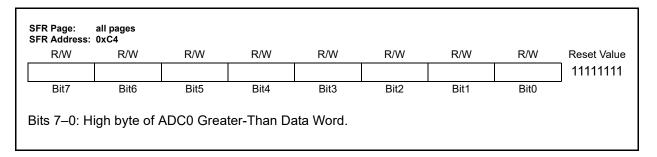
# SFR Definition 5.6. ADC0CN: ADC0 Control



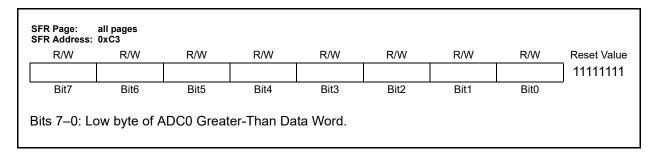
#### 5.4. Programmable Window Detector

The ADC Programmable Window Detector continuously compares the ADC0 output registers to user-programmed limits, and notifies the system when a desired condition is detected. This is especially effective in an interrupt-driven system, saving code space and CPU bandwidth while delivering faster system response times. The window detector interrupt flag (AD0WINT in register ADC0CN) can also be used in polled mode. The ADC0 Greater-Than (ADC0GTH, ADC0GTL) and Less-Than (ADC0LTH, ADC0LTL) registers hold the comparison values. The window detector flag can be programmed to indicate when measured data is inside or outside of the user-programmed limits, depending on the contents of the ADC0 Less-Than and ADC0 Greater-Than registers.

#### SFR Definition 5.7. ADC0GTH: ADC0 Greater-Than Data High Byte

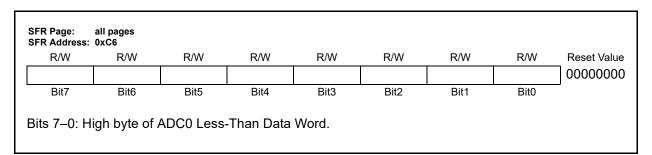


## SFR Definition 5.8. ADC0GTL: ADC0 Greater-Than Data Low Byte

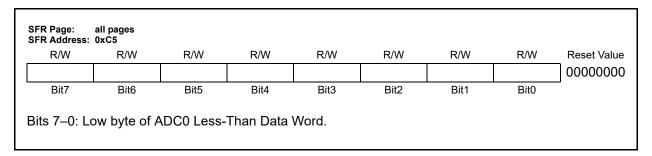




### SFR Definition 5.9. ADC0LTH: ADC0 Less-Than Data High Byte



# SFR Definition 5.10. ADC0LTL: ADC0 Less-Than Data Low Byte





#### 5.4.1. Window Detector In Single-Ended Mode

Figure 5.6 shows two example window comparisons for right-justified, single-ended data, with ADC0LTH:ADC0LTL = 0x0080 (128d) and ADC0GTH:ADC0GTL = 0x0040 (64d). In single-ended mode, the input voltage can range from '0' to VREF x (1023/1024) with respect to GND, and is represented by a 10-bit unsigned integer value. In the left example, an AD0WINT interrupt will be generated if the ADC0 conversion word (ADC0H:ADC0L) is within the range defined by ADC0GTH:ADC0GTL and ADC0LTH:ADC0LTL (if 0x0040 < ADC0H:ADC0L < 0x0080). In the right example, and AD0WINT interrupt will be generated if the ADC0 conversion word is outside of the range defined by the ADC0GT and ADC0LT registers (if ADC0H:ADC0L < 0x0040 or ADC0H:ADC0L > 0x0080). Figure 5.7 shows an example using left-justified data with the same comparison values.

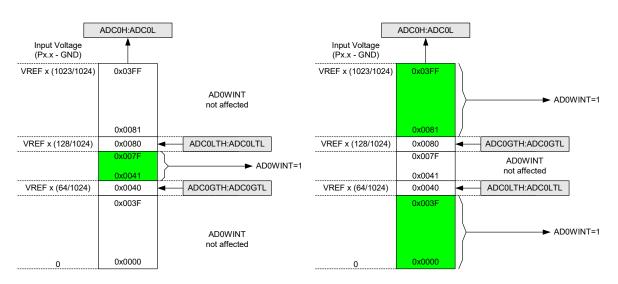


Figure 5.6. ADC Window Compare Example: Right-Justified Single-Ended Data

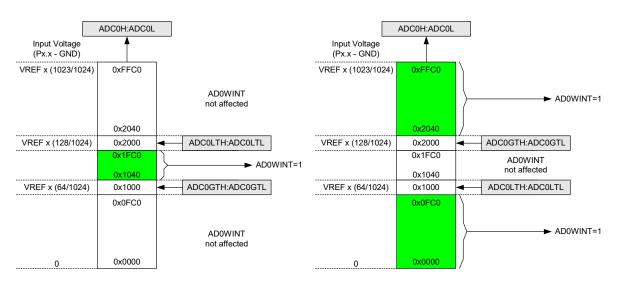


Figure 5.7. ADC Window Compare Example: Left-Justified Single-Ended Data



#### 5.4.2. Window Detector In Differential Mode

Figure 5.8 shows two example window comparisons for right-justified, differential data, with ADC0LTH:ADC0LTL = 0x0040 (+64d) and ADC0GTH:ADC0GTH = 0xFFFF (-1d). In differential mode, the measurable voltage between the input pins is between -VREF and VREF\*(511/512). Output codes are represented as 10-bit 2's complement signed integers. In the left example, an AD0WINT interrupt will be generated if the ADC0 conversion word (ADC0H:ADC0L) is within the range defined by ADC0GTH:ADC0GTL and ADC0LTH:ADC0LTL (if 0xFFFF (-1d) < ADC0H:ADC0L < 0x0040 (64d)). In the right example, an AD0WINT interrupt will be generated if the ADC0 conversion word is outside of the range defined by the ADC0GT and ADC0LT registers (if ADC0H:ADC0L < 0xFFFF (-1d) or ADC0H:ADC0L > 0x0040 (+64d)). Figure 5.9 shows an example using left-justified data with the same comparison values.

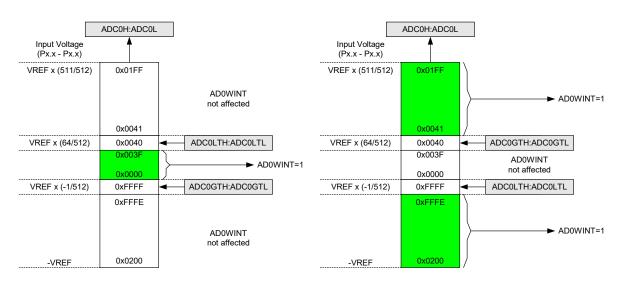


Figure 5.8. ADC Window Compare Example: Right-Justified Differential Data

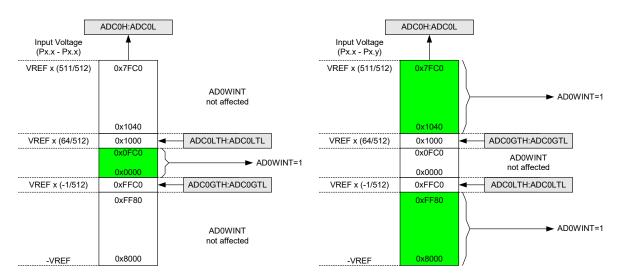


Figure 5.9. ADC Window Compare Example: Left-Justified Differential Data



## Table 5.1. ADC0 Electrical Characteristics

V<sub>DD</sub> = 3.0 V, VREF = 2.40 V (REFSL=0), -40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units
DC Accuracy					
Resolution			10		bits
Integral Nonlinearity			±0.5	±1	LSB
Differential Nonlinearity	Guaranteed Monotonic	—	±0.5	±1	LSB
Offset Error		-12	3	12	LSB
Full Scale Error	Differential mode	-5	1	5	LSB
Dynamic Performance (10 kHz	sine-wave Single-ended inpu	it, 0 to 1 dl	B below Fu	II Scale, 2	200 ksps)
Signal-to-Noise Plus Distortion		53	58	—	dB
Total Harmonic Distortion	Up to the 5 <sup>th</sup> harmonic	—	-75	—	dB
Spurious-Free Dynamic Range			75		dB
Conversion Rate					
SAR Conversion Clock				3	MHz
Conversion Time in SAR Clocks		13			clocks
Track/Hold Acquisition Time		300			ns
Throughput Rate				200	ksps
Analog Inputs					
ADC Input Voltage Range	Single Ended (AIN+ – GND) Differential (AIN+ – AIN–)	0 -VREF		VREF VREF	V V
Absolute Pin Voltage with respect to GND	Single Ended or Differential	0		V <sub>DD</sub>	V
Input Capacitance		—	5		pF
Temperature Sensor					
Linearity*			±0.2		°C
Slope		—	2.18	<u> </u>	mV/ºC
Slope Error*			±172		µV/⁰C
Offset	(Temp = 0 °C)	—	802	—	mV
Offset Error*		—	±18.5	—	mV
Power Specifications				1	
Power Supply Current (V <sub>DD</sub> supplied to ADC0)	Operating Mode, 200 ksps		450	900	μΑ
Power Supply Rejection		—	3		mV/V
*Note: Represents one standard de	viation from the mean. Includes AD	DC offset, aa	in, and linea	rity variatio	ns.



# 6. 10-Bit Current Mode DAC (IDA0, C8051F360/1/2/6/7/8/9)

The C8051F360/1/2/6/7/8/9 devices include a 10-bit current-mode Digital-to-Analog Converter (IDAC). The maximum current output of the IDAC can be adjusted for three different current settings; 0.5 mA, 1 mA, and 2 mA. The IDAC is enabled or disabled with the IDA0EN bit in the IDA0 Control Register (see SFR Definition 6.1). When IDA0EN is set to '0', the IDAC port pin (P0.4 for C8051F360, P0.1 for C8051F361/2/6/7/8/9) behaves as a normal GPIO pin. When IDA0EN is set to '1', the digital output drivers and weak pullup for the IDAC pin are automatically disabled, and the pin is connected to the IDAC output. An internal bandgap bias generator is used to generate a reference current for the IDAC whenever it is enabled. When using the IDAC, the appropriate bit in the P0SKIP register should be set to '1' to force the Crossbar to skip the IDAC pin.

## 6.1. IDA0 Output Scheduling

IDA0 features a flexible output update mechanism which allows for seamless full-scale changes and supports jitter-free updates for waveform generation. Three update modes are provided, allowing IDAC output updates on a write to IDA0H, on a Timer overflow, or on an external pin edge.

### 6.1.1. Update Output On-Demand

In its default mode (IDA0CN.[6:4] = '111') the IDA0 output is updated "on-demand" on a write to the highbyte of the IDA0 data register (IDA0H). It is important to note that writes to IDA0L are held in this mode, and have no effect on the IDA0 output until a write to IDA0H takes place. If writing a full 10-bit word to the IDAC data registers, the 10-bit data word is written to the low byte (IDA0L) and high byte (IDA0H) data registers. **Data is latched into IDA0 after a write to the IDA0H register, so the write sequence should be IDA0L followed by IDA0H** if the full 10-bit resolution is required. The IDAC can be used in 8-bit mode by initializing IDA0L to the desired value (typically 0x00), and writing data to only IDA0H (see Section 6.2 for information on the format of the 10-bit IDAC data word within the 16-bit SFR space).

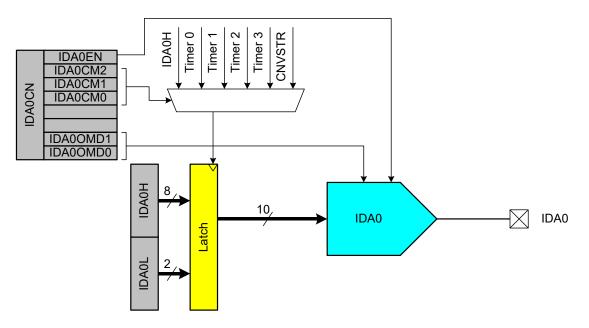


Figure 6.1. IDA0 Functional Block Diagram



#### 6.1.2. Update Output Based on Timer Overflow

Similar to the ADC operation, in which an ADC conversion can be initiated by a timer overflow independently of the processor, the IDAC outputs can use a Timer overflow to schedule an output update event. This feature is useful in systems where the IDAC is used to generate a waveform of a defined sampling rate by eliminating the effects of variable interrupt latency and instruction execution on the timing of the IDAC output. When the IDA0CM bits (IDA0CN.[6:4]) are set to '000', '001', '010' or '011', writes to both IDAC data registers (IDA0L and IDA0H) are held until an associated Timer overflow event (Timer 0, Timer 1, Timer 2 or Timer 3, respectively) occurs, at which time the IDA0H:IDA0L contents are copied to the IDAC input latches, allowing the IDAC output to change to the new value.

#### 6.1.3. Update Output Based on CNVSTR Edge

The IDAC output can also be configured to update on a rising edge, falling edge, or both edges of the external CNVSTR signal. When the IDA0CM bits (IDA0CN.[6:4]) are set to '100', '101', or '110', writes to both IDAC data registers (IDA0L and IDA0H) are held until an edge occurs on the CNVSTR input pin. The particular setting of the IDA0CM bits determines whether IDAC outputs are updated on rising, falling, or both edges of CNVSTR. When a corresponding edge occurs, the IDA0H:IDA0L contents are copied to the IDAC input latches, allowing the IDAC output to change to the new value.

#### 6.2. IDAC Output Mapping

The IDAC data registers (IDA0H and IDA0L) are left-justified, meaning that the eight MSBs of the IDAC output word are mapped to bits 7–0 of the IDA0H register, and the two LSBs of the IDAC output word are mapped to bits 7 and 6 of the IDA0L register. The data word mapping for the IDAC is shown in Figure 6.2.

IDA0H							IDA0L								
D9	D8	D7	D6	D5	D4	D3	D2	D1	D0						
	t Data (D9–D	Word 0)	ID	Outpu A0OM		rent ] = '1x'		Out  IDA0O	put Cւ MD[1։		1'			;urrent ∣:0] = '(	
	0x000	)		0 mA				0 mA					0 m	A	
	0x00′	1		1/1024 x 2 mA				1/1024 x 1 mA				1/1024 x 0.5 mA			
0x200			512/1024 x 2 mA				512/1024 x 1 mA				512/1024 x 0.5 mA			A	
	0x3FF			1023/1024 x 2 mA				1023/1024 x 1 mA				1023/1024 x 0.5 mA			

#### Figure 6.2. IDA0 Data Word Mapping

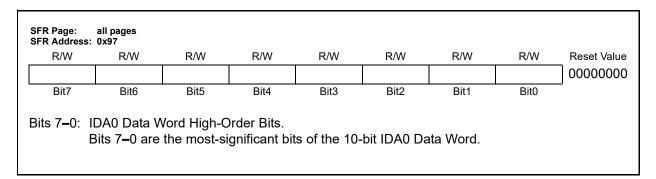
The full-scale output current of the IDAC is selected using the IDA0OMD bits (IDA0CN[1:0]). By default, the IDAC is set to a full-scale output current of 2 mA. The IDA0OMD bits can also be configured to provide full-scale output currents of 1 mA or 0.5 mA, as shown in SFR Definition 6.1.



R/W	R/W	R/W	R/W	R	R	R/W	R/W	Reset Value
IDA0EN		IDA0CM		-	-	IDA0	OMD	01110010
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	IDA0EN: ID/	A0 Enable.						
	0: IDA0 Disa	abled.						
	1: IDA0 Ena	bled.						
Bits 6 <b>–</b> 4:	IDA0CM[2:0	]: IDA0 Upd	ate Source	Select bits				
	000: DAC ou							
	001: DAC ou	• •						
	010: DAC ou							
	011: DAC ou	itput update	s on Timer	3 overflow.				
	100: DAC ou	utput update	s on rising	edge of CN	IVSTR.			
	101: DAC ou	utput update	es on falling	edge of Cl	NVSTR.			
	110: DAC οι	utput update	s on any e	dge of CNV	STR.			
	111: DAC ou	itput update	s on write t	o IDA0H. (c	default)			
Bits 3–2:	UNUSED. R	ead = 00b.	Write = dor	i't care.	ŗ			
Bits 1–0:	IDA00MD[1	:0]: IDA0 Ou	utput Mode	Select bits.				
	00: 0.5 mÅ f	ull-scale ou	tput current					
	01: 1.0 mA f	ull-scale ou	tput current					
	1x: 2.0 mA f		•					

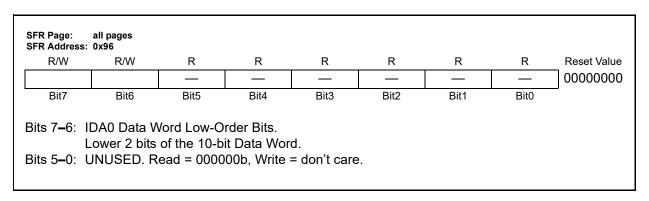
## SFR Definition 6.1. IDA0CN: IDA0 Control

# SFR Definition 6.2. IDA0H: IDA0 Data Word MSB





## SFR Definition 6.3. IDA0L: IDA0 Data Word LSB



#### **Table 6.1. IDAC Electrical Characteristics**

-40 to +85 °C, V<sub>DD</sub> = 3.0 V Full-scale output current set to 2 mA unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units
	Static Performance				
Resolution			10		bits
Integral Nonlinearity		—	±0.5	±2	LSB
Differential Nonlinearity	Guaranteed Monotonic	—	±0.5	±1	LSB
Output Compliance Range		—	—	V <sub>DD</sub> – 1.2	V
Offset Error		—	0		LSB
Full Scale Error	2 mA Full Scale Output Current	-15	0	15	LSB
Full Scale Error Tempco		—	30	_	ppm/°C
V <sub>DD</sub> Power Supply Rejection Ratio		_	6.5	—	µA/V
	Dynamic Performance	•			
Output Settling Time to 1/2 LSB	IDA0H:L = 0x3FF to 0x000	_	5		μs
Startup Time		—	5	_	μs
Gain Variation	1 mA Full Scale Output Current 0.5 mA Full Scale Output Current	_	±1 ±1		% %
	Power Consumption				
Power Supply Current (V <sub>DD</sub> supplied to IDAC)	2 mA Full Scale Output Current 1 mA Full Scale Output Current 0.5 mA Full Scale Output Current		2140 1140 640		μΑ μΑ μΑ



# 7. Voltage Reference (C8051F360/1/2/6/7/8/9)

The Voltage reference MUX on the C8051F360/1/2/6/7/8/9 devices is configurable to use an externally connected voltage reference, the internal reference voltage generator, or the V<sub>DD</sub> power supply voltage (see Figure 7.1). The REFSL bit in the Reference Control register (REF0CN) selects the reference source. For an external source or the internal reference, REFSL should be set to '0'. To use V<sub>DD</sub> as the reference source, REFSL should be set to '1'.

The BIASE bit enables the internal voltage bias generator, which is used by the ADC, Temperature Sensor, internal oscillators, and Current DAC. This bias is enabled when any of the aforementioned peripherals are enabled. The bias generator may be enabled manually by writing a '1' to the BIASE bit in register REF0CN; see SFR Definition 7.1 for REF0CN register details. The electrical specifications for the voltage reference circuit are given in Table 7.1.

The internal voltage reference circuit consists of a 1.2 V, temperature stable bandgap voltage reference generator and a gain-of-two output buffer amplifier. The internal voltage reference can be driven out on the VREF pin by setting the REFBE bit in register REF0CN to a '1' (see SFR Definition 7.1). The maximum load seen by the VREF pin must be less than 200  $\mu$ A to GND. When using the internal voltage reference, bypass capacitors of 0.1  $\mu$ F and 4.7  $\mu$ F are recommended from the VREF pin to GND. If the internal reference is not used, the REFBE bit should be cleared to '0'. Electrical specifications for the internal voltage reference are given in Table 7.1.

**Important Note about the VREF Pin:** Port pin P0.3 on the C8051F360 device and P0.0 on C8051F361/2/6/7/89 devices is used as the external VREF input and as an output for the internal VREF. When using either an external voltage reference or the internal reference circuitry, the port pin should be configured as an analog pin, and skipped by the Digital Crossbar. To configure the port pin as an analog pin, set the appropriate bit to '0' in register P0MDIN. To configure the Crossbar to skip the VREF port pin, set the appropriate bit to '1' in register P0SKIP. Refer to Section "17. Port Input/Output" on page 184 for

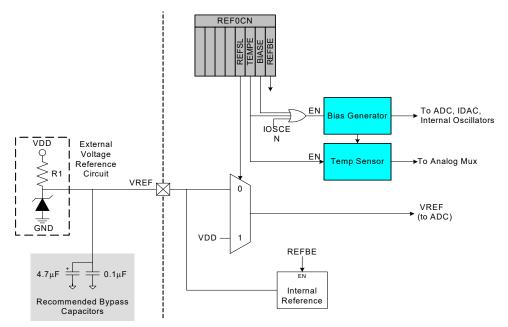


Figure 7.1. Voltage Reference Functional Block Diagram



complete Port I/O configuration details. The TEMPE bit in register REF0CN enables/disables the temperature sensor. While disabled, the temperature sensor defaults to a high impedance state and any ADC0 measurements performed on the sensor result in meaningless data.

R	R	R	R	R/W	R/W	R/W	R/W	Reset Value
-	-	-	-	REFSL	TEMPE	BIASE	REFBE	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	-
				1				
	UNUSED. R		,					
Bit 3:	REFSL: Volta	•						
	This bit seled				ige referenc	e.		
	0: VREF pin	used as vo	ltage refere	ence.				
	1: V <sub>DD</sub> used	as voltage	reference.					
Bit 2:	TEMPE: Ten	nperature S	Sensor Enat	ole Bit.				
	0: Internal Te	•						
	1: Internal Te	•						
Bit 1:	BIASE: Inter	•			Bit			
Dit 11	0: Internal Bi	•						
	1: Internal Bi							
Bit 0:	REFBE: Inte			Enabla Bit				
DIL U.	0: Internal R							
	•••••••••••••••••							
	1: Internal R	atoronco K	uttor onable	ntornal N	unitada rata	rence drive	n on the VE	



# Table 7.1. Voltage Reference Electrical Characteristics

 $V_{DD}$  = 3.0 V; -40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Тур	Мах	Units					
Internal Reference (REFBE = 1)										
Output Voltage	25 °C ambient	2.35	2.42	2.50	V					
VREF Short-Circuit Current				10	mA					
VREF Temperature Coefficient			25		ppm/°C					
Load Regulation	Load = 0 to 200 µA to AGND		3	—	μV/μΑ					
VREF Turn-on Time 1	4.7 μF tantalum, 0.1 μF ceramic bypass		7.5	_	ms					
VREF Turn-on Time 2	0.1 μF ceramic bypass		200	_	μs					
Power Supply Rejection		_	1.4	—	mV/V					
	External Reference (REFBE = 0	)								
Input Voltage Range		0	_	V <sub>DD</sub>	V					
Input Current	Sample Rate = 200 ksps; VREF = 3.0 V		3	_	μA					
	Power Specifications									
ADC Bias Generator	BIASE = '1' or AD0EN = '1' or IOSCEN = '1'	_	100	150	μA					
Reference Bias Generator	REFBE = '1' or TEMPE = '1' or IDA0EN = '1'		30	50	μA					



# 8. Comparators

C8051F36x devices include two on-chip programmable voltage comparators, Comparator0 and Comparator1, shown in Figure 8.1 and Figure 8.2 (**Note:** the port pin Comparator inputs differ between C8051F36x devices. The first Port I/O pin shown is for C8051F360/3 devices).

The comparators offer programmable response time and hysteresis, an analog input multiplexer, and two outputs that are optionally available at the Port pins: a synchronous "latched" output (CP0 and CP1), or an asynchronous "raw" output (CP0A and CP1A). The asynchronous CP0A and CP1A signals are available even when the system clock is not active. This allows the Comparators to operate and generate an output with the device in STOP mode. When assigned to a Port pin, the Comparator outputs may be configured as open drain or push-pull (see Section "17.2. Port I/O Initialization" on page 188). Comparator0 may also be used as a reset source (see Section "12.5. Comparator0 Reset" on page 132).

The Comparator inputs are selected in the CPT0MX and CPT1MX registers (SFR Definition 8.2 and SFR Definition 8.5). The CMXnP1–CMXnP0 bits select the Comparator positive input; the CMXnN1–CMXnN0 bits select the Comparator negative input.

**Important Note About Comparator Inputs:** The Port pins selected as comparator inputs should be configured as analog inputs in their associated Port configuration register, and configured to be skipped by the Crossbar (for details on Port configuration, see Section "17.3. General Purpose Port I/O" on page 191).

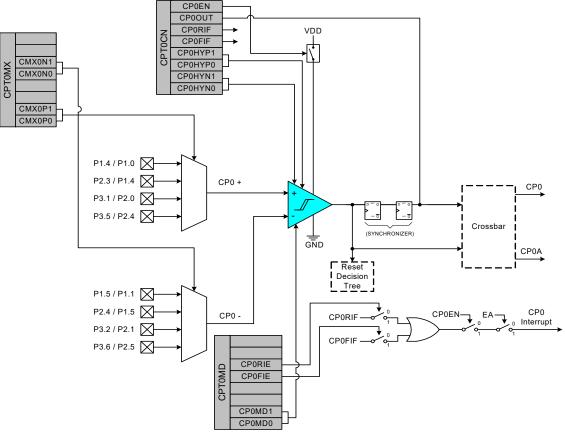


Figure 8.1. Comparator0 Functional Block Diagram



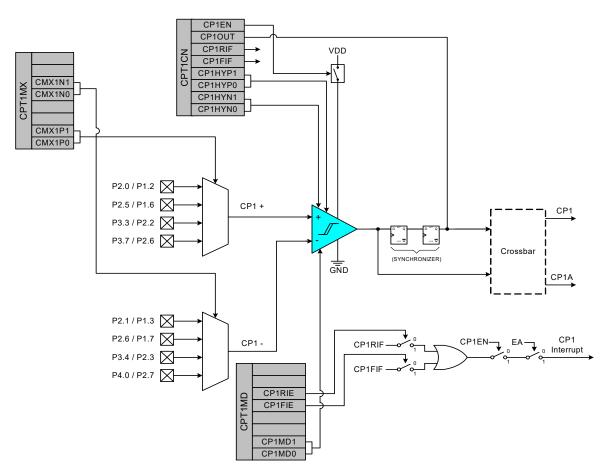


Figure 8.2. Comparator1 Functional Block Diagram

A Comparator output can be polled in software, used as an interrupt source, and/or routed to a Port pin. When routed to a Port pin, the Comparator outputs are available asynchronous or synchronous to the system clock; the asynchronous outputs are available even in STOP mode (with no system clock active). When disabled, the Comparator outputs (if assigned to a Port I/O pin via the Crossbar) default to the logic low state, and their supply current falls to less than 100 nA. See Section "17.1. Priority Crossbar Decoder" on page 186 for details on configuring Comparator outputs via the digital Crossbar. Comparator inputs can be externally driven from -0.25 V to (V<sub>DD</sub>) + 0.25 V without damage or upset. The complete Comparator electrical specifications are given in Table 8.1.

The Comparator response time may be configured in software via the CPT0MD and CPT1MD registers (see SFR Definition 8.3 and SFR Definition 8.6). Selecting a longer response time reduces the Comparator supply current. See Table 8.1 for complete timing and power consumption specifications.



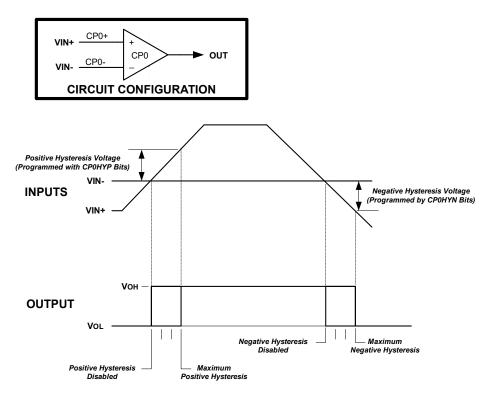


Figure 8.3. Comparator Hysteresis Plot

The Comparator hysteresis is software-programmable via the Comparator Control registers CPT0CN and CPT1CN. The user can program both the amount of hysteresis voltage (referred to the input voltage) and the positive and negative-going symmetry of this hysteresis around the threshold voltage.

The Comparator hysteresis is programmed using Bits3–0 in the Comparator Control registers CPT0CN and CPT1CN (shown in SFR Definition 8.1 and SFR Definition 8.4). The amount of negative hysteresis voltage is determined by the settings of the CP0HYN and CP1HYN bits. As shown in Figure 8.3, settings of 20, 10 or 5 mV of negative hysteresis can be programmed, or negative hysteresis can be disabled. In a similar way, the amount of positive hysteresis is determined by the setting the CP0HYP and CP1HYP bits.

Comparator interrupts can be generated on both rising-edge and falling-edge output transitions. (For Interrupt enable and priority control, see Section "10. Interrupt Handler" on page 108). The CP0FIF or CP1FIF flag is set to logic '1' upon a Comparator falling-edge occurrence, and the CP0RIF or CP1RIF flag is set to logic '1' upon the Comparator rising-edge occurrence. Once set, these bits remain set until cleared by software. The Comparator rising-edge interrupt mask is enabled by setting CP0RIE or CP1RIE to a logic '1'. The Comparator falling-edge interrupt mask is enabled by setting CP0FIE or CP1FIE to a logic '1'.

The output state of the Comparator can be obtained at any time by reading the CP0OUT or CP1OUT bit. The Comparator is enabled by setting the CP0EN or CP1EN bit to logic '1', and is disabled by clearing this bit to logic '0'.

Note that false rising edges and falling edges can be detected when the comparator is first powered on or if changes are made to the hysteresis or response time control bits. Therefore, it is recommended that the rising-edge and falling-edge flags be explicitly cleared to logic '0' a short time after the comparator is enabled or its mode bits have been changed. This Power Up Time is specified in Table 8.1 on page 80.



SFR Page: SFR Addres	all pages s: 0x9B							
R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
CP0EN	CP0OUT	CP0RIF	CP0FIF	CP0HYP1	CP0HYP0	CP0HYN1	CP0HYN0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	CP0EN: Cor 0: Comparat	•						
	1: Comparator0 Enabled.							
Bit 6:	CPOOUT: Co			te Flag.				
	0: Voltage or							
	1: Voltage or					h ft	_	
Bit 5:	CPORIF: Co	•		•				
	0: No Comparat				since this ha	ig was last	cleared.	
Bit 4:	CP0FIF: Cor		0		t he cleared	hv softwar	<u>م</u>	
Dit 4.	0: No Compa							
	1: Comparat					ag was las	t olcarca.	
Bits 3-2	CP0HYP1-C	-	-		Control Bite	2		
Dito 0 2.	00: Positive	•		e riyotereok		5.		
	01: Positive							
	10: Positive							
	11: Positive							
Bits 1–0:	CP0HYN1-0	•		ve Hvsteres	is Control Bi	ts.		
	00: Negative			,				
	01: Negative							
	10: Negative							
	11: Negative							
	Ū.	2						

# SFR Definition 8.1. CPT0CN: Comparator0 Control



## SFR Definition 8.2. CPT0MX: Comparator0 MUX Selection

	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	CMX0N1	CMX0N0	-	-	CMX0P1	CMX0P0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
3its 7 <b>–</b> 6:	UNUSED.	Read = 11b	, Write = don	't care.				
Bits 5 <b>–</b> 4:	CMX0N1-	CMX0N0: C	omparator0 N	legative In	put MUX S	elect.		
	These bits	select which	η Port pin is ι	used as the	e Comparat	or0 negative	e input.	
		Γ	C8051F	360/3	C8051E	361/2/4/5/6/	7/8/9	
	CMX0N1	CMX0N0	Negativ			gative Input		
	0	0	P1	•		P1.1		
	0	1	P2.4			P1.5		
	1	0	P3	.2		P2.1		
	1	1	P3	.6		P2.5		
			, Write = don omparator0 F			laat		
DIIS I=0.			η Port pin is ι				innut	
		Sciect Willow			oompara		input.	
		СМХОРО	C8051F	360/3	C8051F	361/2/4/5/6/	7/8/9	
	CMVOD4		Positive	Innut	Po	sitive Input		
	CMX0P1		FUSILIVE	; input				
	<b>СМХОР1</b> 0	0	P1.			P1.0		
				.4		P1.0 P1.4		
	0	0	P1.	.4 .3				
	0	0	P1. P2.	.4 .3 .1		P1.4		



R	s: 0x9D R	R/W	R/W	R	R	R/W	R/W	Reset Value
_	-	CPORIE	CP0FIE	_	_	CP0MD1	CP0MD0	00000010
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	]
Bits 7 <b>–</b> 6 <sup>.</sup>	UNUSED. F	Read = 00b	Write = dor	't care				
Bit 5:	CPORIE: Co				nahle			
Dit 0.	0: Compara	•		•				
	1: Compara	•	•	•				
Bit 4:	CP0FIE: Cc	•	•	•				
υπ <del>4</del> .	0: Compara	•	0 0	•				
	1: Compara							
Bits 3-2.	UNUSED. F	-	-	•	•			
	CP0MD1-C	,			t			
Dito i 0.	These bits s		•					
			sponse and		latoro.			
	Mode	CP0MD1	CP0MD0	CP0 Res	ponse Tim	ie (TYP)		
	0	0	0		100 ns			
	1	0	1		175 ns			
		1	0		320 ns			
	2		0		020 110			

# SFR Definition 8.3. CPT0MD: Comparator0 Mode Selection



R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
CP1EN	CP10UT	CP1RIF	CP1FIF	CP1HYP1	CP1HYP0	CP1HYN1	CP1HYN0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	CP1EN: Cor	nparator1 E	nable Bit.					
	0: Comparat	•						
	1: Comparator1 Enabled.							
Bit 6:	CP10UT: Co	omparator1	Output Sta	te Flag.				
	0: Voltage or	າ CP1+ < C	P1 <b>-</b> .	-				
	1: Voltage or	n CP1+ > C	P1 <b>–</b> .					
Bit 5:	CP1RIF: Co	mparator1 I	Rising-Edge	e Flag. Must	be cleared	by softwar	e.	
	0: No Compa	arator1 Risi	ng Edge ha	is occurred	since this fla	ag was last	cleared.	
	1: Comparat	or1 Rising l	Edge has o	ccurred.				
Bit 4:	CP1FIF: Cor							
	0: No Compa				since this fla	ag was las	t cleared.	
	1: Comparat	•	•					
Bits 3–2:	CP1HYP1-0	•		e Hysteresis	S Control Bits	S.		
	00: Positive							
	01: Positive							
	10: Positive							
	11: Positive I							
Bits 1–0:	CP1HYN1-C			ve Hysteres	is Control Bi	its.		
	00: Negative							
	01: Negative							
	10: Negative							
	11: Negative	Livotorogia	-20 mV					

# SFR Definition 8.4. CPT1CN: Comparator1 Control



# SFR Definition 8.5. CPT1MX: Comparator1 MUX Selection

	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	CMX1N1	CMX1N0	-	-	CMX1P1	CMX1P0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
3its 7 <b>–</b> 6:	UNUSED.	Read = 11b	, Write = don	't care.				
Bits 5 <b>–</b> 4:	CMX1N1-	CMX1N0: C	omparator1 I	Vegative I	nput MUX S	elect.		
	These bits	select which	ר Port pin is ו	used as th	e Comparat	or1 negative	e input.	
			C8051F	360/3	C8051E36	1/2/4/5/6/7/	R/9	
	CMX1N1	CMX1N0	Negative			tive Input		
	0	0	P2.	•	-	P1.3		
	0	1	P2.6 P1.7					
	1	0	P3.4	4		P2.3		
	1	1	P4.0	)		P2.7		
D:4_ 0_0.	UNUSED	Read = $11b$	, Write = don	't care.				
	CMX1P1-	CMX1P0: C	omparator1 F ר Port pin is ו	used as th	e Comparat	or1 positive		
	CMX1P1– These bits	CMX1P0: Co select whicl	omparator1 F n Port pin is t C8051F	used as th <b>360/3</b>	e Comparat	or1 positive		
	CMX1P1-	CMX1P0: C	omparator1 F n Port pin is u C8051F Positive	used as th 360/3 Input	e Comparat	or1 positive 61/2/4/5/6/7/ tive Input		
	CMX1P1– These bits CMX1P1 0	CMX1P0: Co select whicl	omparator1 F n Port pin is u C8051F3 Positive P2.0	used as th 360/3 Input	C8051F36	or1 positive 61/2/4/5/6/7/ tive Input P1.2		
	CMX1P1– These bits CMX1P1 0 0	CMX1P0: Co select which CMX1P0 - 0 1	omparator1 F n Port pin is u C8051F Positive P2.0 P2.3	used as th <b>360/3</b> Input 5	C8051F36	or1 positive 51/2/4/5/6/7/ tive Input P1.2 P1.6		
	CMX1P1– These bits CMX1P1 0	CMX1P0: Co select which CMX1P0 0	omparator1 F n Port pin is u C8051F3 Positive P2.0	used as th <b>360/3</b> <b>Input</b> 5 3	C8051F36	or1 positive 61/2/4/5/6/7/ tive Input P1.2		



R	R	R/W	R/W	R	R	R/W	R/W	Reset Value
-	-	CP1RIE	CP1FIE	-	-	CP1MD1	CP1MD0	00000010
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Rite 7_6:	UNUSED. R	aad - 00b V	Nrito - don'	teare				
Bit 5:	CP1RIE: Co				nabla			
DIL D.		•		•				
	0: Comparator1 Rising-edge interrupt disabled.							
	1: Comparator1 Rising-edge interrupt enabled.							
Bit 4:	<ul> <li>t 4: CP1FIE: Comparator1 Falling-Edge Interrupt Enable.</li> <li>0: Comparator1 Falling-edge interrupt disabled.</li> </ul>							
	•	•	•					
	1: Comparat	•	•					
	UNUSED. R							
Bits 1 <b>–</b> 0:	CP1MD1-CI		•					
	These bits se	elect the res	ponse time	for Compa	rator1.			
	Mode	CP1MD1	CP1MD0	CP1 Re	esponse Ti	me (TYP)		
	0	0	0		100 ns			
	1	0	1		175 ns			
	2	1	0		320 ns			
	3	1	1		1050 ns			

## SFR Definition 8.6. CPT1MD: Comparator1 Mode Selection



### **Table 8.1. Comparator Electrical Characteristics**

 $V_{DD}$  = 3.0 V, -40 to +85 °C unless otherwise noted.

Parameter	Conditions	Min	Тур	Max	Units
Response Time:	CPx+ – CPx– = 100 mV	—	100	—	ns
Mode 0, Vcm <sup>*</sup> = 1.5 V	CPx+-CPx-=-100 mV	—	250	—	ns
Response Time:	CPx+ – CPx– = 100 mV	—	175	—	ns
Mode 1, Vcm <sup>*</sup> = 1.5 V	CPx+ – CPx– = –100 mV	-	500	—	ns
Response Time:	CPx+ – CPx– = 100 mV	—	320	—	ns
Mode 2, Vcm <sup>*</sup> = 1.5 V	CPx+-CPx-=-100  mV	_	1100	—	ns
Response Time:	CPx+ – CPx– = 100 mV	—	1050	—	ns
Mode 3, Vcm <sup>*</sup> = 1.5 V	CPx+-CPx-=-100  mV	—	5200	—	ns
Common-Mode Rejection Ratio		—	1.26	5	mV/V
Positive Hysteresis 1	CPxHYP1-0 = 00	—	0	1	mV
Positive Hysteresis 2	CPxHYP1-0 = 01	1	5	10	mV
Positive Hysteresis 3	CPxHYP1–0 = 10	6	10	20	mV
Positive Hysteresis 4	CPxHYP1–0 = 11	12	20	30	mV
Negative Hysteresis 1	CPxHYN1-0 = 00	—	0	1	mV
Negative Hysteresis 2	CPxHYN1–0 = 01	1	5	10	mV
Negative Hysteresis 3	CPxHYN1–0 = 10	6	10	20	mV
Negative Hysteresis 4	CPxHYN1–0 = 11	12	20	30	mV
Inverting or Non-Inverting Input Voltage Range		-0.25		V <sub>DD</sub> + 0.25	V
Input Capacitance		—	4	—	pF
Input Bias Current		—	0.001	—	nA
Input Offset Voltage		-5		+5	mV
Power Supply	·	·			
Power Supply Rejection			0.3	—	mV/V
Power-up Time		_	10	—	μs
	Mode 0	_	11.4	20	μA
Supply Current at DC	Mode 1	—	4.6	10	μA
Supply Sulten at DS	Mode 2	—	1.9	5	μA
	Mode 3	—	0.4	2.5	μA
*Note: Vcm is the common-mode vo	oltage on CPx+ and CPx–.	-		·1	



# 9. CIP-51 Microcontroller

The MCU system controller core is the CIP-51 microcontroller. The CIP-51 is fully compatible with the MCS-51<sup>™</sup> instruction set; standard 803x/805x assemblers and compilers can be used to develop software. The MCU family has a superset of all the peripherals included with a standard 8051. Included are five 16-bit counter/timers (see description in Section 21), one full-duplex UART (see description in Section 19), 256 bytes of internal RAM, 128 byte Special Function Register (SFR) address space (see Section 9.4.6), and up to four byte-wide and one 7-bit-wide I/O Ports (see description in Section 17). The CIP-51 also includes on-chip debug hardware (see description in Section 24), and interfaces directly with the MCU's analog and digital subsystems providing a complete data acquisition or control-system solution in a single integrated circuit.

The CIP-51 Microcontroller core implements the standard 8051 organization and peripherals as well as additional custom peripherals and functions to extend its capability (see Figure 9.1 for a block diagram).

- Fully Compatible with MCS-51 Instruction Set
- 100 or 50 MIPS Peak Using the On-Chip PLL
- 256 Bytes of Internal RAM
- 8/4 Byte-Wide I/O Ports

The CIP-51 includes the following features:

### 9.1. Performance

- Extended Interrupt Handler

- Reset Input
- Power Management Modes
- On-chip Debug Logic

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute, and usually have a maximum system clock of 12 MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with no instructions taking more than eight system clock cycles.

With the CIP-51's system clock running at 100 MHz, it has a peak throughput of 100 MIPS. The CIP-51 has a total of 109 instructions. The table below shows the total number of instructions that require each execution time.

Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8
Number of Instructions	26	50	5	14	7	3	1	2	1



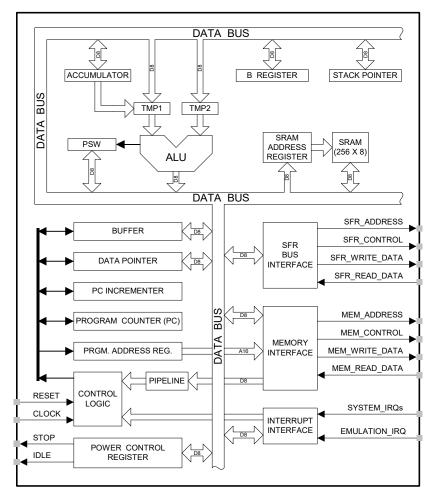


Figure 9.1. CIP-51 Block Diagram

# 9.2. Programming and Debugging Support

A C2-based serial interface is provided for in-system programming of the Flash program memory and communication with on-chip debug support logic. The re-programmable Flash can also be read and changed by the application software using the MOVC and MOVX instructions. This feature allows program memory to be used for non-volatile data storage as well as updating program code under software control.

The on-chip debug support logic facilitates full speed in-circuit debugging, allowing the setting of hardware breakpoints and watch points, starting, stopping and single stepping through program execution (including interrupt service routines), examination of the program's call stack, and reading/writing the contents of registers and memory. This method of on-chip debug is completely non-intrusive and non-invasive, requiring no RAM, Stack, timers, or other on-chip resources.

The CIP-51 is supported by development tools from Silicon Labs and third party vendors. Silicon Labs provides an integrated development environment (IDE) including editor, macro assembler, debugger and programmer. The IDE's debugger and programmer interface to the CIP-51 via its C2 interface to provide fast and efficient in-system device programming and debugging. Third party macro assemblers and C compilers are also available.



### 9.3. Instruction Set

The instruction set of the CIP-51 System Controller is fully compatible with the standard MCS-51<sup>™</sup> instruction set; standard 8051 development tools can be used to develop software for the CIP-51. All CIP-51 instructions are the binary and functional equivalent of their MCS-51<sup>™</sup> counterparts, including opcodes, addressing modes and effect on PSW flags. However, instruction timing is different than that of the standard 8051.

#### 9.3.1. Instruction and CPU Timing

In many 8051 implementations, a distinction is made between machine cycles and clock cycles, with machine cycles varying from 2 to 12 clock cycles in length. However, the CIP-51 implementation is based solely on clock cycle timing. All instruction timings are specified in terms of clock cycles.

Due to the pipelined architecture of the CIP-51, most instructions execute in the same number of clock cycles as there are program bytes in the instruction. Conditional branch instructions take one less clock cycle to complete when the branch is not taken as opposed to when the branch is taken. Table 9.1 is the CIP-51 Instruction Set Summary, which includes the mnemonic, number of bytes, and number of clock cycles for each instruction.

#### 9.3.2. MOVX Instruction and Program Memory

In the CIP-51, the MOVX instruction serves three purposes: accessing on-chip XRAM, accessing off-chip XRAM, and accessing on-chip program Flash memory. The Flash access feature provides a mechanism for user software to update program code and use the program memory space for non-volatile data storage (see Section "13. Flash Memory" on page 136). The External Memory Interface provides a fast access to off-chip XRAM (or memory-mapped peripherals) via the MOVX instruction. Refer to Section "15. External Data Memory Interface and On-Chip XRAM" on page 154 for details.

Mnemonic	Description	Bytes	Clock Cycles
	Arithmetic Operations		•
ADD A, Rn	Add register to A	1	1
ADD A, direct	Add direct byte to A	2	2
ADD A, @Ri	Add indirect RAM to A	1	2
ADD A, #data	Add immediate to A	2	2
ADDC A, Rn	Add register to A with carry	1	1
ADDC A, direct	Add direct byte to A with carry	2	2
ADDC A, @Ri	Add indirect RAM to A with carry	1	2
ADDC A, #data	Add immediate to A with carry	2	2
SUBB A, Rn	Subtract register from A with borrow	1	1
SUBB A, direct	Subtract direct byte from A with borrow	2	2
SUBB A, @Ri	Subtract indirect RAM from A with borrow	1	2
SUBB A, #data	Subtract immediate from A with borrow	2	2
INC A	Increment A	1	1
INC Rn	Increment register	1	1
INC direct	Increment direct byte	2	2
INC @Ri	Increment indirect RAM	1	2



•	,	Oleak
Description	Bytes	Clock Cycles
	1	1
0	1	1
	2	2
	1	2
		1
	1	4
	1	8
	1	1
• •		
	1	1
AND direct byte to A	2	2
AND indirect RAM to A	1	2
AND immediate to A	2	2
AND A to direct byte	2	2
AND immediate to direct byte	3	3
OR Register to A	1	1
OR direct byte to A	2	2
OR indirect RAM to A	1	2
OR immediate to A	2	2
OR A to direct byte	2	2
	3	3
-	1	1
	2	2
Exclusive-OR indirect RAM to A	1	2
Exclusive-OR immediate to A	2	2
Exclusive-OR A to direct byte	2	2
-	3	3
Clear A	1	1
Complement A	1	1
Rotate A left	1	1
Rotate A left through Carry	1	1
	1	1
	1	1
	1	1
Data Transfer		
Move Register to A	1	1
		2
		2
		2
		1
-		2
		2
5		2
		2
Move direct byte to direct byte	3	3
	Description           Decrement A           Decrement direct byte           Decrement indirect RAM           Increment Data Pointer           Multiply A and B           Divide A by B           Decimal adjust A           Logical Operations           AND Register to A           AND direct byte to A           AND indirect RAM to A           OR Register to A           OR direct byte to A           OR indirect RAM to A           OR indirect RAM to A           OR indirect byte           OR indirect byte to A           OR indirect byte           OR indirect byte           Declariate to direct byte           Exclusive-OR Register to A           Exclusive-OR indirect RAM to A           Exclusive-OR indirect RAM to A           Exclusive-OR inmediate to direct byte           Clear A           Complement A           Rotate A left           Rotate A right           Rota	Decrement A1Decrement register1Decrement indirect BAM1Increment Data Pointer1Multiply A and B1Divide A by B1Decimal adjust A1Logical OperationsAND Register to A1AND indirect RAM to A1AND indirect RAM to A2AND indirect RAM to A2AND indirect RAM to A1OR Register to A1OR Register to A2OR Register to A2OR Register to A2OR Register to A1OR Register to A2OR Register to A2OR Register to A2OR Register to A2OR indirect RAM to A1OR direct byte to A2OR indirect RAM to A1Exclusive-OR Register to A1Exclusive-OR Register to A1Exclusive-OR interct byte to A2Exclusive-OR interct byte to A2Exclusive-OR interct byte to A2Exclusive-OR Register to A1Exclusive-OR interct byte to A2Exclusive-OR interct byte to A2Exclusive-OR interct byte3Clear A1Complement A1Rotate A left1Rotate A left1Rotate A right1Move indirect RAM to A1Move indirect RAM to A1Move indirect RAM to A1Move indirect RAM to A1 </td

# Table 9.1. CIP-51 Instruction Set Summary (Continued)



Mnemonic	Description	Bytes	Clock Cycles
MOV direct, @Ri	Move indirect RAM to direct byte	2	2
MOV direct, #data	Move immediate to direct byte	3	3
MOV @Ri, A	Move A to indirect RAM	1	2
MOV @Ri, direct	Move direct byte to indirect RAM	2	2
MOV @Ri, #data	Move immediate to indirect RAM	2	2
MOV DPTR, #data16	Load DPTR with 16-bit constant	3	3
MOVC A, @A+DPTR	Move code byte relative DPTR to A	1	3
MOVC A, @A+PC	Move code byte relative PC to A	1	3
MOVX A, @Ri	Move external data (8-bit address) to A	1	3
MOVX @Ri, A	Move A to external data (8-bit address)	1	3
MOVX A, @DPTR	Move external data (16-bit address) to A	1	3
MOVX @DPTR, A	Move A to external data (16-bit address)	1	3
PUSH direct	Push direct byte onto stack	2	2
POP direct	Pop direct byte from stack	2	2
XCH A, Rn	Exchange Register with A	1	1
XCH A, direct	Exchange direct byte with A	2	2
XCH A, @Ri	Exchange indirect RAM with A	1	2
XCHD A, @Ri	Exchange low nibble of indirect RAM with A	1	2
	Boolean Manipulation		
CLR C	Clear Carry	1	1
CLR bit	Clear direct bit	2	2
SETB C	Set Carry	1	1
SETB bit	Set direct bit	2	2
CPL C	Complement Carry	1	1
CPL bit	Complement direct bit	2	2
ANL C, bit	AND direct bit to Carry	2	2
ANL C, /bit	AND complement of direct bit to Carry	2	2
ORL C, bit	OR direct bit to carry	2	2
ORL C, /bit	OR complement of direct bit to Carry	2	2
MOV C, bit	Move direct bit to Carry	2	2
MOV bit, C	Move Carry to direct bit	2	2
JC rel	Jump if Carry is set	2	2/3*
JNC rel	Jump if Carry is not set	2	2/3*
JB bit, rel	Jump if direct bit is set	3	3/4*
JNB bit, rel	Jump if direct bit is not set	3	3/4*
JBC bit, rel	Jump if direct bit is set and clear bit	3	3/4*
	Program Branching		•
ACALL addr11	Absolute subroutine call	2	3*
LCALL addr16	Long subroutine call	3	4*
RET	Return from subroutine	1	5*
RETI	Return from interrupt	1	5*
AJMP addr11	Absolute jump	2	3*
LJMP addr16	Long jump	3	4*
SJMP rel	Short jump (relative address)	2	3*
JMP @A+DPTR	Jump indirect relative to DPTR	1	3*

# Table 9.1. CIP-51 Instruction Set Summary (Continued)



Mnemonic	Description	Bytes	Clock Cycles
JZ rel	Jump if A equals zero	2	2/3*
JNZ rel	Jump if A does not equal zero	2	2/3*
CJNE A, direct, rel	Compare direct byte to A and jump if not equal	3	3/4*
CJNE A, #data, rel	Compare immediate to A and jump if not equal	3	3/4*
CJNE Rn, #data, rel	Compare immediate to Register and jump if not equal	3	3/4*
CJNE @Ri, #data, rel	Compare immediate to indirect and jump if not equal	3	4/5*
DJNZ Rn, rel	Decrement Register and jump if not zero	2	2/3*
DJNZ direct, rel	Decrement direct byte and jump if not zero	3	3/4*
NOP	No operation	1	1
	incur a cache-miss penalty if the branch target location . See Section "14. Branch Target Cache" on page 146		

# Table 9.1. CIP-51 Instruction Set Summary (Continued)

#### Notes on Registers, Operands and Addressing Modes:

Rn - Register R0-R7 of the currently selected register bank.

**@Ri** - Data RAM location addressed indirectly through R0 or R1.

**rel** - 8-bit, signed (2s complement) offset relative to the first byte of the following instruction. Used by SJMP and all conditional jumps.

**direct** - 8-bit internal data location's address. This could be a direct-access Data RAM location (0x00-0x7F) or an SFR (0x80-0xFF).

#data - 8-bit constant

#data16 - 16-bit constant

bit - Direct-accessed bit in Data RAM or SFR

**addr11** - 11-bit destination address used by ACALL and AJMP. The destination must be within the same 2K-byte page of program memory as the first byte of the following instruction.

**addr16** - 16-bit destination address used by LCALL and LJMP. The destination may be anywhere within the 64K-byte program memory space.

There is one unused opcode (0xA5) that performs the same function as NOP. All mnemonics copyrighted © Intel Corporation 1980.



## 9.4. Memory Organization

The memory organization of the CIP-51 System Controller is similar to that of a standard 8051. There are two separate memory spaces: program memory and data memory. Program and data memory share the same address space but are accessed via different instruction types. There are 256 bytes of internal data memory and 32k bytes (C8051F360/1/2/3/4/5/6/7) or 16k bytes (C8051F368/9) of internal program memory address space implemented within the CIP-51. The CIP-51 memory organization is shown in Figure 9.2.

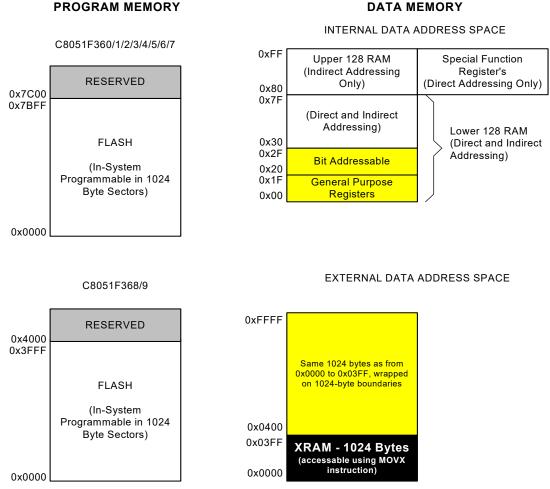


Figure 9.2. Memory Map

### 9.4.1. Program Memory

The CIP-51 core has a 64 kB program memory space. The C8051F360/1/2/3/4/5/6/7 implement 32 kB of this program memory space as in-system, re-programmable Flash memory, organized in a contiguous block from addresses 0x0000 to 0x7BFF. Addresses above 0x7BFF are reserved on the 32 kB devices. The C8051F368/9 implement 16 kB of Flash from addresses 0x0000 to 0x3FFF.

Program memory is normally assumed to be read-only. However, the CIP-51 can write to program memory by setting the Program Store Write Enable bit (PSCTL.0) and using the MOVX instruction. This feature provides a mechanism for the CIP-51 to update program code and use the program memory space for non-volatile data storage. Refer to Section "13. Flash Memory" on page 136 for further details.



### 9.4.2. Data Memory

The CIP-51 implements 256 bytes of internal RAM mapped into the data memory space from 0x00 through 0xFF. The lower 128 bytes of data memory are used for general purpose registers and memory. Either direct or indirect addressing may be used to access the lower 128 bytes of data memory. Locations 0x00 through 0x1F are addressable as four banks of general purpose registers, each bank consisting of eight byte-wide registers. The next 16 bytes, locations 0x20 through 0x2F, may either be addressed as bytes or as 128 bit locations accessible with the direct addressing mode.

The upper 128 bytes of data memory are accessible only by indirect addressing. This region occupies the same address space as the Special Function Registers (SFR) but is physically separate from the SFR space. The addressing mode used by an instruction when accessing locations above 0x7F determines whether the CPU accesses the upper 128 bytes of data memory space or the SFR's. Instructions that use direct addressing will access the SFR space. Instructions using indirect addressing above 0x7F access the upper 128 bytes of data memory. Figure 9.2 illustrates the data memory organization of the CIP-51.

#### 9.4.3. General Purpose Registers

The lower 32 bytes of data memory, locations 0x00 through 0x1F, may be addressed as four banks of general-purpose registers. Each bank consists of eight byte-wide registers designated R0 through R7. Only one of these banks may be enabled at a time. Two bits in the program status word, RS0 (PSW.3) and RS1 (PSW.4), select the active register bank (see description of the PSW in SFR Definition 9.8). This allows fast context switching when entering subroutines and interrupt service routines. Indirect addressing modes use registers R0 and R1 as index registers.

#### 9.4.4. Bit Addressable Locations

In addition to direct access to data memory organized as bytes, the sixteen data memory locations at 0x20 through 0x2F are also accessible as 128 individually addressable bits. Each bit has a bit address from 0x00 to 0x7F. Bit 0 of the byte at 0x20 has bit address 0x00 while bit 7 of the byte at 0x20 has bit address 0x07. Bit 7 of the byte at 0x2F has bit address 0x7F. A bit access is distinguished from a full byte access by the type of instruction used (bit source or destination operands as opposed to a byte source or destination). The MCS-51<sup>™</sup> assembly language allows an alternate notation for bit addressing of the form XX.B where XX is the byte address and B is the bit position within the byte.

For example, the instruction:

MOV C, 22.3h

moves the Boolean value at 0x13 (bit 3 of the byte at location 0x22) into the Carry flag.

#### 9.4.5. Stack

A programmer's stack can be located anywhere in the 256 byte data memory. The stack area is designated using the Stack Pointer (SP, address 0x81) SFR. The SP will point to the last location used. The next value pushed on the stack is placed at SP+1 and then SP is incremented. A reset initializes the stack pointer to location 0x07; therefore, the first value pushed on the stack is placed at location 0x08, which is also the first register (R0) of register bank 1. Thus, if more than one register bank is to be used, the SP should be initialized to a location in the data memory not being used for data storage. The stack depth can extend up to 256 bytes.

The MCUs also have built-in hardware for a stack record which is accessed by the debug logic. The stack record is a 32-bit shift register, where each PUSH or increment SP pushes one record bit onto the register,



and each CALL pushes two record bits onto the register. (A POP or decrement SP pops one record bit, and a RET pops two record bits, also.) The stack record circuitry can also detect an overflow or underflow on the 32-bit shift register, and can notify the debug software even with the MCU running at speed.

#### 9.4.6. Special Function Registers

The direct-access data memory locations from 0x80 to 0xFF constitute the special function registers (SFR's). The SFR's provide control and data exchange with the CIP-51's resources and peripherals. The CIP-51 duplicates the SFR's found in a typical 8051 implementation as well as implementing additional SFR's used to configure and access the sub-systems unique to the MCU. This allows the addition of new functionality while retaining compatibility with the MCS-51<sup>™</sup> instruction set. Table 9.2 lists the SFR's implemented in the CIP-51 System Controller.

The SFR registers are accessed whenever the direct addressing mode is used to access memory locations from 0x80 to 0xFF. SFR's with addresses ending in 0x0 or 0x8 (e.g. P0, TCON, P1, SCON, IE, etc.) are bit-addressable as well as byte-addressable. All other SFR's are byte-addressable only. Unoccupied addresses in the SFR space are reserved for future use. Accessing these areas will have an indeterminate effect and should be avoided. Refer to the corresponding pages of the data sheet, as indicated in Table 9.3, for a detailed description of each register.

#### 9.4.6.1. SFR Paging

The CIP-51 features *SFR paging*, allowing the device to map many SFR's into the 0x80 to 0xFF memory address space. The SFR memory space has 256 *pages*. In this way, each memory location from 0x80 to 0xFF can access up to 256 SFR's. The C8051F36x family of devices utilizes two SFR pages: 0 and F. SFR pages are selected using the Special Function Register Page Selection register, SFRPAGE (see SFR Definition 9.2). The procedure for reading and writing an SFR is as follows:

- 1. Select the appropriate SFR page number using the SFRPAGE register.
- 2. Use direct accessing mode to read or write the special function register (MOV instruction).

#### 9.4.6.2. Interrupts and SFR Paging

When an interrupt occurs, the SFR Page Register will automatically switch to SFR page 0, where all registers containing the interrupt flag bits are accessible. The automatic SFR Page switch function conveniently removes the burden of switching SFR pages from the interrupt service routine. Upon execution of the RETI instruction, the SFR page is automatically restored to the SFR Page in use prior to the interrupt. This is accomplished via a three-byte SFR Page Stack. The top byte of the stack is SFRPAGE, the current SFR Page. The second byte of the SFR Page Stack is SFRNEXT. The third, or bottom byte of the SFR Page Stack is SFRLAST. On interrupt, the current SFRPAGE value is pushed to the SFRNEXT byte, and the value of SFRNEXT is pushed to SFRLAST. Hardware then loads SFRPAGE with the SFR Page containing the flag bit associated with the interrupt. On a return from interrupt, the SFR Page Stack is popped resulting in the value of SFRNEXT returning to the SFRPAGE register, thereby restoring the SFR page context without software intervention. The value in SFRLAST (0x00 if there is no SFR Page value in the bottom of the stack) of the stack is placed in SFRNEXT register. If desired, the values stored in SFRNEXT and SFR-LAST may be modified during an interrupt, enabling the CPU to return to a different SFR Page upon execution of the RETI instruction (on interrupt exit). Modifying registers in the SFR Page Stack does not cause a push or pop of the stack. Only interrupt calls and returns will cause push/pop operations on the SFR Page Stack.



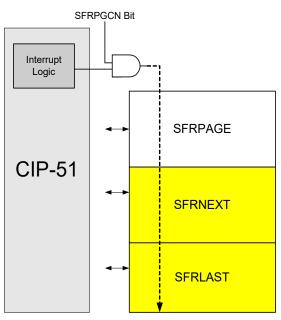


Figure 9.3. SFR Page Stack

Automatic hardware switching of the SFR Page on interrupts may be enabled or disabled as desired using the SFR Automatic Page Control Enable Bit located in the SFR Page Control Register (SFR0CN). This function defaults to 'enabled' upon reset. In this way, the autoswitching function will be enabled unless disabled in software.

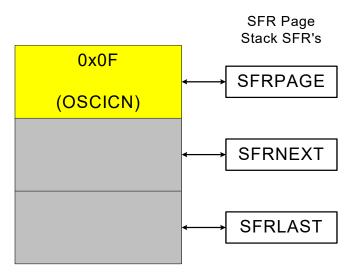
A summary of the SFR locations (address and SFR page) is provided in Table 9.2. in the form of an SFR memory map. Each memory location in the map has an SFR page row, denoting the page in which that SFR resides. Note that certain SFR's are accessible from ALL SFR pages, and are denoted by the background shading in the table. For example, the Port I/O registers P0, P1, P2, and P3 all have a shaded background, indicating these SFR's are accessible from all SFR pages regardless of the SFRPAGE register value.



#### 9.4.6.3. SFR Page Stack Example

The following is an example that shows the operation of the SFR Page Stack during interrupts.

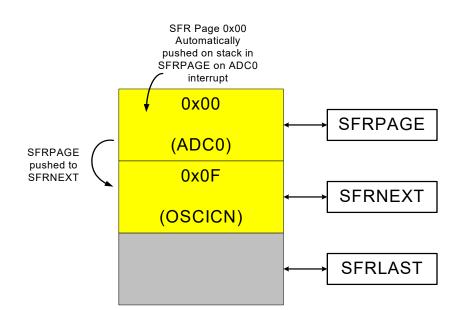
In this example, the SFR Page Control is left in the default enabled state (i.e., SFRPGEN = 1), and the CIP-51 is executing in-line code that is writing values to OSCICN (SFR "OSCICN", located at address 0xB6 on SFR Page 0x0F). The device is also using the Programmable Counter Array (PCA) and the 10-bit ADC (ADC0) window comparator to monitor a voltage. The PCA is timing a critical control function in its interrupt service routine (ISR), so its interrupt is enabled and is set to *high* priority. The ADC0 is monitoring a voltage that is less important, but to minimize the software overhead its window comparator is being used with an associated ISR that is set to *low* priority. At this point, the SFR page is set to access the OSCICN SFR (SFRPAGE = 0x0F). See Figure 9.4 below.



### Figure 9.4. SFR Page Stack While Using SFR Page 0x0F To Access OSCICN

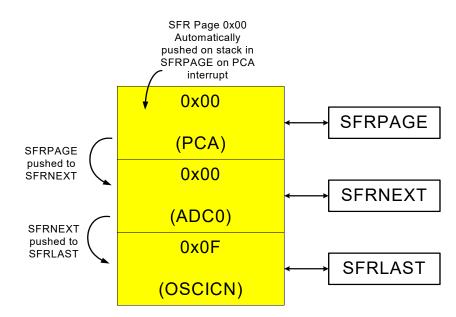
While CIP-51 executes in-line code (writing values to OSCICN in this example), ADC0 Window Comparator Interrupt occurs. The CIP-51 vectors to the ADC0 Window Comparator ISR and pushes the current SFR Page value (SFR Page 0x0F) into SFRNEXT in the SFR Page Stack. SFR page 0x00 is then automatically placed in the SFRPAGE register. SFRPAGE is considered the "top" of the SFR Page Stack. Software can now access the ADC0 SFR's. Software may switch to any SFR Page by writing a new value to the SFRPAGE register at any time during the ADC0 ISR to access SFR's that are not on SFR Page 0x00. See Figure 9.5 below.





### Figure 9.5. SFR Page Stack After ADC0 Window Comparator Interrupt Occurs

While in the ADC0 ISR, a PCA interrupt occurs. Recall the PCA interrupt is configured as a *high* priority interrupt, while the ADC0 interrupt is configured as a *low* priority interrupt. Thus, the CIP-51 will now vector to the high priority PCA ISR. Upon doing so, the CIP-51 will automatically place SFR page 0x00 into the SFRPAGE register. The value that was in the SFRPAGE register before the PCA interrupt (SFR Page 0x00 for ADC0) is pushed down the stack into SFRNEXT. Likewise, the value that was in the SFRNEXT register before the PCA interrupt (in this case SFR Page 0x0F for OSCICN) is pushed down to the SFRLAST register, the "bottom" of the stack. Note that a value stored in SFRLAST (via a previous software write to the SFRLAST register) will be overwritten. See Figure 9.6 below.



## Figure 9.6. SFR Page Stack Upon PCA Interrupt Occurring During an ADC0 ISR



On exit from the PCA interrupt service routine, the CIP-51 will return to the ADC0 Window Comparator ISR. On execution of the RETI instruction, SFR Page 0x00 used to access the PCA registers will be automatically popped off of the SFR Page Stack, and the contents of the SFRNEXT register will be moved to the SFRPAGE register. Software in the ADC0 ISR can continue to access SFR's as it did prior to the PCA interrupt. Likewise, the contents of SFRLAST are moved to the SFRNEXT register. Recall this was the SFR Page value 0x0F being used to access OSCICN before the ADC0 interrupt occurred. See Figure 9.7 below.

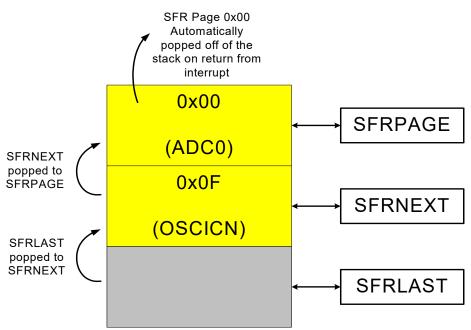
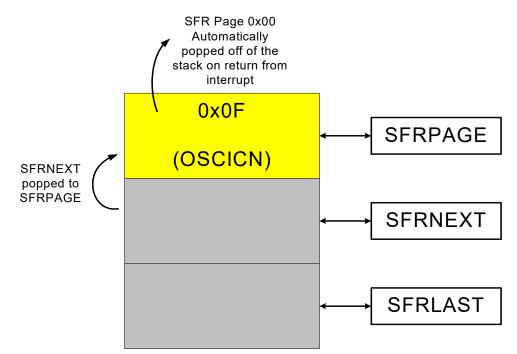


Figure 9.7. SFR Page Stack Upon Return From PCA Interrupt



On the execution of the RETI instruction in the ADC0 Window Comparator ISR, the value in SFRPAGE register is overwritten with the contents of SFRNEXT. The CIP-51 may now access the OSCICN SFR bits as it did prior to the interrupts occurring. See Figure 9.8 below.



## Figure 9.8. SFR Page Stack Upon Return From ADC2 Window Interrupt

Note that in the above example, all three bytes in the SFR Page Stack are accessible via the SFRPAGE, SFRNEXT, and SFRLAST special function registers. If the stack is altered while servicing an interrupt, it is possible to return to a different SFR Page upon interrupt exit than selected prior to the interrupt call. Direct access to the SFR Page stack can be useful to enable real-time operating systems to control and manage context switching between multiple tasks.

Push operations on the SFR Page Stack only occur on interrupt service, and pop operations only occur on interrupt exit (execution on the RETI instruction). The automatic switching of the SFRPAGE and operation of the SFR Page Stack as described above can be disabled in software by clearing the SFR Automatic Page Enable Bit (SFRPGEN) in the SFR Page Control Register (SFR0CN). See SFR Definition 9.1.



## SFR Definition 9.1. SFR0CN: SFR Page Control

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	SFRPGEN	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	,
n O	natically swi : SFR Auto 0.	tch to SFR matic Pagir	page 0. Thi ng disabled.	is bit is used C8051 cor	d to control e will not au	this autopa tomatically	ervice routine ging functior change to S omatically sv	n. SFR page

# SFR Definition 9.2. SFRPAGE: SFR Page

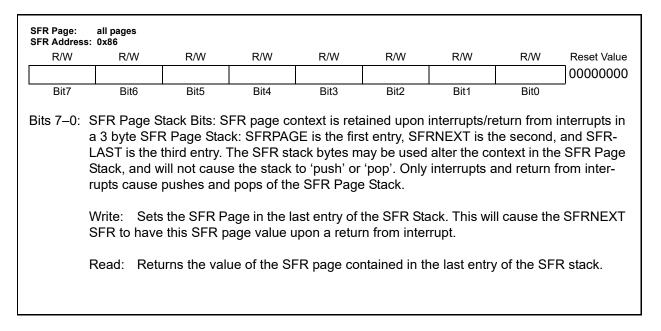
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
\         	fying SFR's. Write: Sets th Read: Byte is When enable switch to SFR (unless SFR SFRPAGE is caused by in	he SFR Pages the SFR p ed in the SF R Page 0x0 Stack was the top by	FR Page Cc 00 and retur altered befo te of the SF	ontrol Regist n to the pre pre a return R Page Sta	ter (SFR0Cl vious SFR   ing from the ick, and pus	page upon e interrupt). sh/pop ever	return fron nts of this ຄ	n interrupt



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
								0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Jii 7-0.	a 3 byte SFI LAST is the Stack, and v	R Page Stac third entry. vill not caus	ck: SFRPAC The SFR sta e the stack	GE is the firs ack bytes m to 'push' or	st entry, SFI ay be used 'pop'. Only	RNEXT is th alter the co	ne second intext in th	, and SFR- e SFR Pag
<i>ins 1–</i> 0.	a 3 byte SFI LAST is the	R Page Stac third entry. vill not caus pushes and the SFR P	ck: SFRPAC The SFR st e the stack I pops of the age contair	GE is the first ack bytes m to 'push' or e SFR Page ned in the se	st entry, SFI hay be used 'pop'. Only e Stack. econd byte	RNEXT is th alter the co interrupts a of the SFR	ne second ontext in th and return Stack. Thi	e SFR Page from inter-

# SFR Definition 9.3. SFRNEXT: SFR Next Register

# SFR Definition 9.4. SFRLAST: SFR Last Register





ADDRESS	<mark>SFR Page</mark>	0(8)	1(9)	2(A)	3(B)	4(C)	5(D)	6(E)	7(F)
F8	0 F	SPI0CN	PCA0L	PCA0H	PCA0CPL0	PCA0CPH0	PCA0CPL4	PCA0CPH4	VDM0CN
F0	0 F	В	MAC0BL P0MDIN	MAC0BH P1MDIN	P0MAT P2MDIN	P0MASK P3MDIN	PCA0CPL5	PCA0CPH5	- EMI0TC
E8	0 F	ADC0CN	PCA0CPL1	PCA0CPH1	PCA0CPL2	PCA0CPH2	PCA0CPL3	PCA0CPH3	RSTSRC
E0	0 F	ACC	P1MAT XBR0	P1MASK XBR1	- -	IT01CF	- SFR0CN	EIE1	EIE2
D8	0 F	PCA0CN	PCA0MD	PCA0CPM0	PCA0CPM1	PCA0CPM2	PCA0CPM3	PCA0CPM4	PCA0CPM5
D0	0 F	PSW	REF0CN	MAC0ACC0 CCH0LC	MAC0ACC1 CCH0MA	MAC0ACC2 P0SKIP	MAC0ACC3 P1SKIP	MAC0OVR P2SKIP	MAC0CF P3SKIP
C8	0 F	TMR2CN	- CCH0TN	TMR2RLL	TMR2RLH	TMR2L	TMR2H	- EIP1	MAC0STA EIP2
C0	0 F	SMB0CN	SMB0CF	SMB0DAT	ADC0GTL	ADC0GTH	ADC0LTL	ADC0LTH	- EMI0CF
B8	0 F	IP	IDA0CN	AMX0N	AMX0P	ADC0CF	ADC0L	ADC0H	- OSCICL
B0	0 F	P3	P2MAT PLL0MUL	P2MASK PLL0FLT	- PLL0CN	-	P4	FLSCL OSCXCN	FLKEY OSCICN
A8	0 F	IE	- PLL0DIV	EMI0CN	-	- FLSTAT	- OSCLCN	MAC0RNDL P4MDOUT	MAC0RNDH P3MDOUT
A0	0 F	P2	SPI0CFG	SPI0CKR	SPI0DAT	MAC0AL P0MDOUT	MAC0AH P1MDOUT	- P2MDOUT	SFRPAGE
98	0 F	SCON0	SBUF0	CPT1CN	CPT0CN	CPT1MD	CPT0MD	CPT1MX	CPT0MX
90	0 F	P1	TMR3CN	TMR3RLL	TMR3RLH	TMR3L	TMR3H	IDA0L	IDA0H
88	0 F	TCON	TMOD	TL0	TL1	TH0	TH1	CKCON	PSCTL CLKSEL
80	0 F	P0	SP	DPL	DPH	- CCH0CN	SFRNEXT	SFRLAST	PCON
		0(8)	1(9)	2(A)	3(B)	4(C)	5(D)	6(E)	7(F)
		bit-addressable	shaded SI	Rs are acces	sible on all S	FR Pages reg	pardless of the	e contents of	SFRPAGE

Table 9.2. Special Function Register (SFR) Memory Map



SFRs are listed in alphabetical order. All undefined SFR locations are reserved.

Register	Address	SFR Page	Description	Page No.
ACC	0xE0	All Pages	Accumulator	page 105
ADC0CF	0xBC	All Pages	ADC0 Configuration	page 57 <sup>1</sup>
ADC0CN	0xE8	All Pages	ADC0 Control	page 58 <sup>1</sup>
ADC0GTH	0xC4	All Pages	ADC0 Greater-Than High Byte	page 59 <sup>1</sup>
ADC0GTL	0xC3	All Pages	ADC0 Greater-Than Low Byte	page 59 <sup>1</sup>
ADC0H	0xBE	All Pages	ADC0 Data Word High Byte	page 57 <sup>1</sup>
ADC0L	0xBD	All Pages	ADC0 Data Word Low Byte	page 57 <sup>1</sup>
ADC0LTH	0xC6	All Pages	ADC0 Less-Than High Byte	page 60 <sup>1</sup>
ADC0LTL	0xC5	All Pages	ADC0 Less-Than Low Byte	page 60 <sup>1</sup>
AMX0N	0xBA	All Pages	AMUX0 Negative Channel Select	page 56 <sup>1</sup>
AMX0P	0xBB	All Pages	AMUX0 Positive Channel Select	page 55 <sup>1</sup>
В	0xF0	All Pages	B Register	page 105
CCH0CN	0x84	F	Cache Control	page 150
CCH0LC	0xD2	F	Cache Lock	page 152
CCH0MA	0xD3	F	Cache Miss Accumulator	page 153
CCH0TN	0xC9	F	Cache Tuning	page 151
CKCON	0x8E	All Pages	Clock Control	page 255
CLKSEL	0x8F	F	System Clock Select	page 175
CPT0CN	0x9B	All Pages	Comparator0 Control	page 74
CPT0MD	0x9D	All Pages	Comparator0 Configuration	page 76
CPT0MX	0x9F	All Pages	Comparator0 MUX Selection	page 75
CPT1CN	0x9A	All Pages	Comparator1 Control	page 77
CPT1MD	0x9C	All Pages	Comparator1 Configuration	page 79
CPT1MX	0x9E	All Pages	Comparator1 MUX Selection	page 78
DPH	0x83	All Pages	Data Pointer High Byte	page 103
DPL	0x82	All Pages	Data Pointer Low Byte	page 103
EIE1	0xE6	All Pages	Extended Interrupt Enable 1	page 113
EIE2	0xE7	All Pages	Extended Interrupt Enable 2	page 115
EIP1	0xCE	F	Extended Interrupt Priority 1	page 114
EIP2	0xCF	F	Extended Interrupt Priority 2	page 115



SFRs are listed in alphabetical order. All undefined SFR locations are reserved.

Register	Address	SFR Page	Description	Page No.
EMI0CF	0xC7	F	EMIF Configuration	page 157 <sup>2</sup>
EMI0CN	0xAA	All Pages	EMIF Control	page 156 <sup>2</sup>
EMI0TC	0xF7	F	EMIF Timing Control	page 162 <sup>2</sup>
FLKEY	0xB7	0	Flash Lock and Key	page 143
FLSCL	0xB6	0	Flash Scale	page 144
FLSTAT	0xAC	F	Flash Status	page 153
IDA0CN	0xB9	All Pages	IDAC0 Control	page 66 <sup>1</sup>
IDA0H	0x97	All Pages	IDAC0 High Byte	page 66 <sup>1</sup>
IDA0L	0x96	All Pages	IDAC0 Low Byte	page 67 <sup>1</sup>
IE	0xA8	All Pages	Interrupt Enable	page 111
IP	0xB8	All Pages	Interrupt Priority	page 112
IT01CF	0xE4	All Pages	INT0/INT1 Configuration	page 117
MAC0ACC0	0xD2	0	MAC0 Accumulator Byte 0 (LSB)	page 127
MAC0ACC1	0xD3	0	MAC0 Accumulator Byte 1	page 126
MAC0ACC2	0xD4	0	MAC0 Accumulator Byte 2	page 126
MAC0ACC3	0xD5	0	MAC0 Accumulator Byte 3 (MSB)	page 126
MAC0AH	0xA5	0	MAC0 A Register High Byte	page 124
MAC0AL	0xA4	0	MAC0 A Register Low Byte	page 125
MAC0BH	0xF2	0	MAC0 B Register High Byte	page 125
MAC0BL	0xF1	0	MAC0 B Register Low Byte	page 125
MAC0CF	0xD7	0	MAC0 Configuration	page 123
MAC0OVR	0xD6	0	MAC0 Accumulator Overflow	page 127
MAC0RNDH	0xAF	0	MAC0 Rounding Register High Byte	page 127
MAC0RNDL	0xAE	0	MAC0 Rounding Register Low Byte	page 128
MAC0STA	0xCF	0	MAC0 Status Register	page 124
OSCICL	0xBF	F	Internal Oscillator Calibration	page 171
OSCICN	0xB7	F	Internal Oscillator Control	page 172
OSCLCN	0xAD	F	Internal L-F Oscillator Control	page 173
OSCXCN	0xB6	F	External Oscillator Control	page 176
P0	0x80	All Pages	Port 0 Latch	page 191
P0MASK	0xF4	0	Port 0 Mask	page 193



SFRs are listed in alphabetical order. All undefined SFR locations are reserved.

Register	Address	SFR Page	Description	Page No.
POMAT	0xF3	0	Port 0 Match	page 193
P0MDIN	0xF1	F	Port 0 Input Mode	page 192
P0MDOUT	0xA4	F	Port 0 Output Mode Configuration	page 192
P0SKIP	0xD4	F	Port 0 Skip	page 193
P1	0x90	All Pages	Port 1 Latch	page 194
P1MASK	0xE2	0	Port 1 Mask	page 196
P1MAT	0xE1	0	Port 1 Match	page 195
P1MDIN	0xF2	F	Port 1 Input Mode	page 194
P1MDOUT	0xA5	F	Port 1 Output Mode Configuration	page 195
P1SKIP	0xD5	F	Port 1 Skip	page 195
P2	0xA0	All Pages	Port 2 Latch	page 196
P2MASK	0xB2	0	Port 2 Mask	page 198
P2MAT	0xB1	0	Port 2 Match	page 198
P2MDIN	0xF3	F	Port 2 Input Mode	page 197
P2MDOUT	0xA6	F	Port 2 Output Mode Configuration	page 197
P2SKIP	0xD6	F	Port 2 Skip	page 198
P3	0xB0	All Pages	Port 3 Latch	page 199
P3MDIN	0xF4	F	Port 3 Input Mode	page 199
P3MDOUT	0xAF	F	Port 3 Output Mode Configuration	page 200
P3SKIP	0xD7	F	Port 3 Skip	page 200
P4	0xB5	All Pages	Port 4 Latch	page 201
P4MDOUT	0xAE	F	Port 4 Output Mode Configuration	page 201
PCA0CN	0xD8	All Pages	PCA Control	page 277
PCA0CPH0	0xFC	All Pages	PCA Module 0 Capture/Compare High Byte	page 281
PCA0CPH1	0xEA	All Pages	PCA Module 1 Capture/Compare High Byte	page 281
PCA0CPH2	0xEC	All Pages	PCA Module 2 Capture/Compare High Byte	page 281
PCA0CPH3	0xEE	All Pages	PCA Module 3 Capture/Compare High Byte	page 281
PCA0CPH4	0xFE	All Pages	PCA Module 4 Capture/Compare High Byte	page 281
PCA0CPH5	0xF6	All Pages	PCA Module 5 Capture/Compare High Byte	page 281
PCA0CPL0	0xFB	All Pages	PCA Module 0 Capture/Compare Low Byte	page 280
PCA0CPL1	0xE9	All Pages	PCA Module 1 Capture/Compare Low Byte	page 280

1. Refers to a register in the C8051F360/1/2/6/7/8/9 only.



SFRs are listed in alphabetical order. All undefined SFR locations are reserved.

Register	Address	SFR Page	Description	Page No.
PCA0CPL2	0xEB	All Pages	PCA Module 2 Capture/Compare Low Byte	page 280
PCA0CPL3	0xED	All Pages	PCA Module 3 Capture/Compare Low Byte	page 280
PCA0CPL4	0xFD	All Pages	PCA Module 4 Capture/Compare Low Byte	page 280
PCA0CPL5	0xF5	All Pages	PCA Module 5 Capture/Compare Low Byte	page 280
PCA0CPM0	0xDA	All Pages	PCA Module 0 Mode	page 279
PCA0CPM1	0xDB	All Pages	PCA Module 1 Mode	page 279
PCA0CPM2	0xDC	All Pages	PCA Module 2 Mode	page 279
PCA0CPM3	0xDD	All Pages	PCA Module 3 Mode	page 279
PCA0CPM4	0xDE	All Pages	PCA Module 4 Mode	page 279
PCA0CPM5	0xDF	All Pages	PCA Module 5 Mode	page 279
PCA0H	0xFA	All Pages	PCA Counter High Byte	page 280
PCA0L	0xF9	All Pages	PCA Counter Low Byte	page 280
PCA0MD	0xD9	All Pages	PCA Mode	page 278
PCON	0x87	All Pages	Power Control	page 107
PLL0CN	0xB3	F	PLL Control	page 181
PLL0DIV	0xA9	F	PLL Divider	page 181
PLL0FLT	0xB2	F	PLL Filter	page 182
PLL0MUL	0xB1	F	PLL Multiplier	page 182
PSCTL	0x8F	0	Flash Write/Erase Control	page 143
PSW	0xD0	All Pages	Program Status Word	page 104
REF0CN	0xD1	All Pages	Voltage Reference Control	page 69 <sup>1</sup>
RSTSRC	0xEF	All Pages	Reset Source	page 134
SBUF0	0x99	All Pages	UART 0 Data Buffer	page 227
SCON0	0x98	All Pages	UART 0 Control	page 226
SFR0CN	0xE5	F	SFR Page Control	page 95
SFRLAST	0x86	All Pages	SFR Stack Last Page	page 96
SFRNEXT	0x85	All Pages	SFR Stack Next Page	page 96
SFRPAGE	0xA7	All Pages	SFR Page Select	page 95
SMB0CF	0xC1	All Pages	SMBus Configuration	page 209
SMB0CN	0xC0	All Pages	SMBus Control	page 211
SMB0DAT	0xC2	All Pages	SMBus Data	page 213

**1.** Refers to a register in the C8051F360/1/2/6/7/8/9 only.



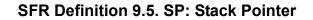
SFRs are listed in alphabetical order. All undefined SFR locations are reserved.

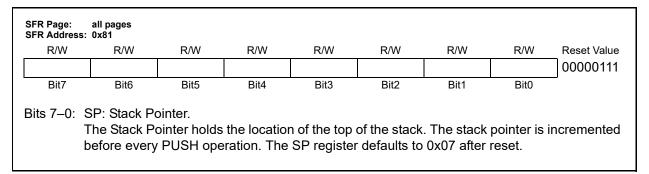
Register	Address	SFR Page	Description	Page No.
SP	0x81	All Pages	Stack Pointer	page 103
SPI0CFG	0xA1	All Pages	SPI Configuration	page 242
SPI0CKR	0xA2	All Pages	SPI Clock Rate Control	page 244
SPI0CN	0xF8	All Pages	SPI Control	page 243
SPI0DAT	0xA3	All Pages	SPI Data	page 244
TCON	0x88	All Pages	Timer/Counter Control	page 253
TH0	0x8C	All Pages	Timer/Counter 0 High Byte	page 256
TH1	0x8D	All Pages	Timer/Counter 1 High Byte	page 256
TL0	0x8A	All Pages	Timer/Counter 0 Low Byte	page 256
TL1	0x8B	All Pages	Timer/Counter 1 Low Byte	page 256
TMOD	0x89	All Pages	Timer/Counter Mode	page 254
TMR2CN	0xC8	All Pages	Timer/Counter 2 Control	page 259
TMR2H	0xCD	All Pages	Timer/Counter 2 High Byte	page 260
TMR2L	0xCC	All Pages	Timer/Counter 2 Low Byte	page 260
TMR2RLH	0xCB	All Pages	Timer 2 Reload Register High Byte	page 260
TMR2RLL	0xCA	All Pages	Timer 2 Reload Register Low Byte	page 260
TMR3CN	0x91	All Pages	Timer 3 Control	page 263
TMR3H	0x95	All Pages	Timer 3 High Byte	page 264
TMR3L	0x94	All Pages	Timer 3 Low Byte	page 264
TMR3RLH	0x93	All Pages	Timer 3 Reload Register High Byte	page 264
TMR3RLL	0x92	All Pages	Timer 3 Reload Register Low Byte	page 264
VDM0CN	0xFF	All Pages	V <sub>DD</sub> Monitor Control	page 132
XBR0	0xE1	F	Port I/O Crossbar Control 0	page 189
XBR1	0xE2	F	Port I/O Crossbar Control 1	page 190



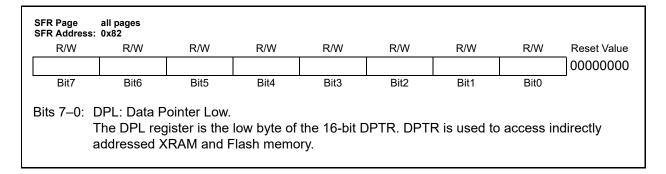
### 9.4.7. Register Descriptions

Following are descriptions of SFRs related to the operation of the CIP-51 System Controller. Reserved bits should not be set to logic '1'. Future product versions may use these bits to implement new features in which case the reset value of the bit will be logic '0', selecting the feature's default state. Detailed descriptions of the remaining SFRs are included in the sections of the data sheet associated with their corresponding system function.

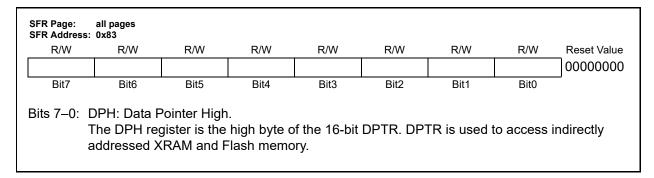








# SFR Definition 9.7. DPH: Data Pointer High Byte



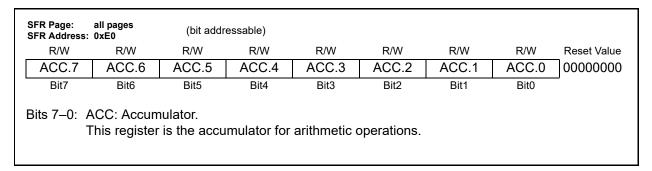


SFR Page: SFR Addres	all pages s: 0xD0	(bit ad	ddressable)					
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R	Reset Value
CY	AC	F0	RS1	RS0	OV	F1	PARITY	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
Bit 7:	CY: Carry							
			e last arithmet				ddition) or a	a borrow
	·	,	ared to 0 by all	other arith	metic ope	erations.		
Bit 6:	AC: Auxilia						<i>,</i>	
			e last arithmeti					
			high order nib	ble. It is cle	eared to 0	by all other	arithmetic c	perations.
Bit 5:	F0: User F		bla ganaral nu	rnooo flog	for use u	ndor ooffwor	o control	
Dito 1 2:			ble, general pι βank Select.	irpose nag	for use u	nder sollware	e control.	
DIIS 4–3.		•	ch register ban	k is used d	urina roai	istor accosso		
	THESE DILS	Select Will	Si legister ball	k is useu u	uning regi	ISIEI ALLESSE	.5.	
	RS1	RS0 I	Register Bank	Addr	ess			
	0	0	0	0x00-	0x07			
	0	1	1	0x08–	0x0F			
	1	0	2	0x10-	0x17			
	1	1	3	0x18–	0x1F			
Bit 2:	OV: Overfl	ow Flag.						
		•	der the followin	g circumst	ances:			
	• An ADD,	ADDC, or	SUBB instructi	on causes	a sign-ch	ange overflov	W.	
	• A MUL in	struction re	sults in an ove	erflow (resu	ilt is great	er than 255).		
			uses a divide-b					
	The OV bit	is cleared	to 0 by the AD	D, ADDC,	SUBB, M	UL, and DIV	instructions	in all other
	cases.							
Bit 1:	F1: User F							
			ble, general pu	irpose flag	tor use u	nder software	e control.	
Bit 0:	PARITY: P			alat laita : 4	h	بالمقمع أمرح والرا	and alarse	d <b>:f t</b> he error
	is even.		e sum of the ei	yni dits in i	ne accum	iulator is odd	and cleare	u ii ine sum
	15 EVEII.							

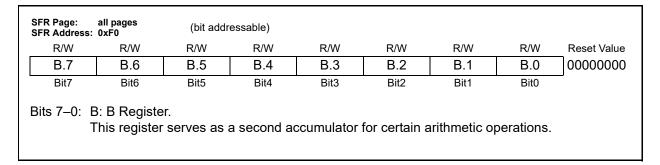
# SFR Definition 9.8. PSW: Program Status Word



## SFR Definition 9.9. ACC: Accumulator



# SFR Definition 9.10. B: B Register



### 9.5. Power Management Modes

The CIP-51 core has two software programmable power management modes: Idle and Stop. Idle mode halts the CPU while leaving the external peripherals and internal clocks active. In Stop mode, the CPU is halted, all interrupts and timers (except the Missing Clock Detector) are inactive, and the system clock is stopped. Since clocks are running in Idle mode, power consumption is dependent upon the system clock frequency and the number of peripherals left in active mode before entering Idle. Stop mode consumes the least power. SFR Definition 9.11 describes the Power Control Register (PCON) used to control the CIP-51's power management modes.

Although the CIP-51 has Idle and Stop modes built in (as with any standard 8051 architecture), power management of the entire MCU is better accomplished by enabling/disabling individual peripherals as needed. Each analog peripheral can be disabled when not in use and put into low power mode. Digital peripherals, such as timers or serial buses, draw little power whenever they are not in use. Turning off the Flash memory saves power, similar to entering Idle mode. Turning off the oscillator saves even more power, but requires a reset to restart the MCU.

The C8051F36x devices feature an additional low-power SUSPEND mode, which stops the internal oscillator until an awakening event occurs. See Section "16.1.1. Internal Oscillator Suspend Mode" on page 171 for more information.



### 9.5.1. Idle Mode

Setting the Idle Mode Select bit (PCON.0) causes the CIP-51 to halt the CPU and enter Idle mode as soon as the instruction that sets the bit completes. All internal registers and memory maintain their original data. All analog and digital peripherals can remain active during Idle mode.

Idle mode is terminated when an enabled interrupt or  $\overline{\text{RST}}$  is asserted. The assertion of an enabled interrupt will cause the Idle Mode Selection bit (PCON.0) to be cleared and the CPU to resume operation. The pending interrupt will be serviced and the next instruction to be executed after the return from interrupt (RETI) will be the instruction immediately following the one that set the Idle Mode Select bit. If Idle mode is terminated by an internal or external reset, the CIP-51 performs a normal reset sequence and begins program execution at address 0x0000.

If enabled, the WDT will eventually cause an internal watchdog reset and thereby terminate the Idle mode. This feature protects the system from an unintended permanent shutdown in the event of an inadvertent write to the PCON register. If this behavior is not desired, the WDT may be disabled by software prior to entering the Idle mode if the WDT was initially configured to allow this operation. This provides the opportunity for additional power savings, allowing the system to remain in the Idle mode indefinitely, waiting for an external stimulus to wake up the system. Refer to Section 22.3 for more information on the use and configuration of the WDT.

Note: Any instruction which sets the IDLE bit should be immediately followed by an instruction which has two or more opcode bytes. For example:

// in `C':
PCON |= 0x01; // Set IDLE bit
PCON = PCON; // ... Followed by a 3-cycle Dummy Instruction
; in assembly:
ORL PCON, #01h ; Set IDLE bit
MOV PCON, PCON ; ... Followed by a 3-cycle Dummy Instruction

If the instruction following the write to the IDLE bit is a single-byte instruction and an interrupt occurs during the execution of the instruction of the instruction which sets the IDLE bit, the CPU may not wake from IDLE mode when a future interrupt occurs.

#### 9.5.2. Stop Mode

Setting the Stop Mode Select bit (PCON.1) causes the CIP-51 to enter Stop mode as soon as the instruction that sets the bit completes. In Stop mode, the CPU and oscillators are stopped, effectively shutting down all digital peripherals. Each analog peripheral must be shut down individually prior to entering Stop Mode. Stop mode can only be terminated by an internal or external reset. On reset, the CIP-51 performs the normal reset sequence and begins program execution at address 0x0000.

If enabled, the Missing Clock Detector will cause an internal reset and thereby terminate the Stop mode. The Missing Clock Detector should be disabled if the CPU is to be put to sleep for longer than the MCD timeout of 100  $\mu$ s.

#### 9.5.3. Suspend Mode

The C8051F36x devices feature a low-power SUSPEND mode, which stops the internal oscillator until an awakening event occurs. See Section "16.1.1. Internal Oscillator Suspend Mode" on page 171.



## SFR Definition 9.11. PCON: Power Control

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
Reserved	d Reserved	Reserved	Reserved	Reserved	Reserved	STOP	IDLE	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
Bit 0:	1: CIP-51 for IDLE: IDLE I	Node Selec	t.	,	s oπ oscillat DIDLE mode	,	vill always	read '0'.



# 10. Interrupt Handler

The C8051F36x family includes an extended interrupt system supporting a total of 16 interrupt sources with two priority levels. The allocation of interrupt sources between on-chip peripherals and external input pins varies according to the specific version of the device. Each interrupt source has one or more associated interrupt-pending flag(s) located in an SFR. When a peripheral or external source meets a valid interrupt condition, the associated interrupt-pending flag is set to logic '1'.

If interrupts are enabled for the source, an interrupt request is generated when the interrupt-pending flag is set. As soon as execution of the current instruction is complete, the CPU generates an LCALL to a predetermined address to begin execution of an interrupt service routine (ISR). Each ISR must end with an RETI instruction, which returns program execution to the next instruction that would have been executed if the interrupt request had not occurred. If interrupts are not enabled, the interrupt-pending flag is ignored by the hardware and program execution continues as normal. (The interrupt-pending flag is set to logic '1' regard-less of the interrupt's enable/disable state.)

Each interrupt source can be individually enabled or disabled through the use of an associated interrupt enable bit in the Interrupt Enable and Extended Interrupt Enable SFRs. However, interrupts must first be globally enabled by setting the EA bit (IE.7) to logic '1' before the individual interrupt enables are recognized. Setting the EA bit to logic '0' disables all interrupt sources regardless of the individual interrupt-enable settings. Note that interrupts which occur when the EA bit is set to logic '0' will be held in a pending state, and will not be serviced until the EA bit is set back to logic '1'.

**Note**: Any instruction that clears a bit to disable an interrupt should be immediately followed by an instruction that has two or more opcode bytes. Using EA (global interrupt enable) as an example:

```
// in 'C':
EA = 0; // clear EA bit.
EA = 0; // this is a dummy instruction with two-byte opcode.
; in assembly:
CLR EA ; clear EA bit.
CLR EA ; this is a dummy instruction with two-byte opcode.
```

For example, if an interrupt is posted during the execution phase of a "CLR EA" opcode (or any instruction which clears a bit to disable an interrupt source), and the instruction is followed by a single-cycle instruction, the interrupt may be taken. However, a read of the enable bit will return a '0' inside the interrupt service routine. When the bit-clearing opcode is followed by a multi-cycle instruction, the interrupt will not be taken.

Some interrupt-pending flags are automatically cleared by the hardware when the CPU vectors to the ISR. However, most are not cleared by the hardware and must be cleared by software before returning from the ISR. If an interrupt-pending flag remains set after the CPU completes the return-from-interrupt (RETI) instruction, a new interrupt request will be generated immediately and the CPU will re-enter the ISR after the completion of the next instruction.

## 10.1. MCU Interrupt Sources and Vectors

The C8051F36x MCUs support 16 interrupt sources. Software can simulate an interrupt by setting any interrupt-pending flag to logic '1'. If interrupts are enabled for the flag, an interrupt request will be generated and the CPU will vector to the ISR address associated with the interrupt-pending flag. MCU interrupt sources, associated vector addresses, priority order, and control bits are summarized in Table 10.1 on page 109. Refer to the data sheet section associated with a particular on-chip peripheral for information regarding valid interrupt conditions for the peripheral and the behavior of its interrupt-pending flag(s).



#### **10.2.** Interrupt Priorities

Each interrupt source can be individually programmed to one of two priority levels: low or high. A low priority interrupt service routine can be preempted by a high priority interrupt. A high priority interrupt cannot be preempted. Each interrupt has an associated interrupt priority bit in an SFR (IP, EIP1, or EIP2) used to configure its priority level. Low priority is the default. If two interrupts are recognized simultaneously, the interrupt with the higher priority is serviced first. If both interrupts have the same priority level, a fixed priority order is used to arbitrate, given in Table 10.1.

#### 10.3. Interrupt Latency

Interrupt response time depends on the state of the CPU when the interrupt occurs. Pending interrupts are sampled and priority decoded each system clock cycle. Therefore, the fastest possible response time is 5 system clock cycles: 1 clock cycle to detect the interrupt and 4 clock cycles to complete the LCALL to the ISR. Additional clock cycles will be required if a cache miss occurs (see Section 14 for more details). If an interrupt is pending when a RETI is executed, a single instruction is executed before an LCALL is made to service the pending interrupt. Therefore, the maximum response time for an interrupt (when no other interrupt is currently being serviced or the new interrupt is of greater priority) is when the CPU is performing an RETI instruction followed by a DIV as the next instruction, and a cache miss event also occurs. If the CPU is executing an ISR for an interrupt with equal or higher priority, the new interrupt will not be serviced until the current ISR completes, including the RETI and following instruction.

Interrupt Source	Interrupt Vector	Priority Order	Pending Flag	Bit addressable?	Cleared by HW?	Enable Flag	Priority Control
Reset	0x0000	Тор	None	N/A	N/A	Always Enabled	Always Highest
External Interrupt 0 (/INT0)	0x0003	0	IE0 (TCON.1)	Y	Y	EX0 (IE.0)	PX0 (IP.0)
Timer 0 Overflow	0x000B	1	TF0 (TCON.5)	Y	Y	ET0 (IE.1)	PT0 (IP.1)
External Interrupt 1 (/INT1)	0x0013	2	IE1 (TCON.3)	Y	Y	EX1 (IE.2)	PX1 (IP.2)
Timer 1 Overflow	0x001B	3	TF1 (TCON.7)	Y	Y	ET1 (IE.3)	PT1 (IP.3)
UART0	0x0023	4	RI0 (SCON0.0) TI0 (SCON0.1)	Y	Ν	ES0 (IE.4)	PS0 (IP.4)
Timer 2 Overflow	0x002B	5	TF2H (TMR2CN.7) TF2L (TMR2CN.6)	Y	Ν	ET2 (IE.5)	PT2 (IP.5)
SPI0	0x0033	6	SPIF (SPI0CN.7) WCOL (SPI0CN.6) MODF (SPI0CN.5) RXOVRN (SPI0CN.4)	Y	Ν	ESPI0 (IE.6)	PSPI0 (IP.6)
SMB0	0x003B	7	SI (SMB0CN.0)	Y	Ν	ESMB0 (EIE1.0)	PSMB0 (EIP1.0)
RESERVED	0x0043	8	N/A	N/A	N/A	N/A	N/A
ADC0 Window Comparator	0x004B	9	AD0WINT (ADC0CN.5)	Y	Ν	EWADC0 (EIE1.2)	PWADC0 (EIP1.2)
ADC0 End of Conversion	0x0053	10	AD0INT (ADC0STA.5)	Y	Ν	EADC0 (EIE1.3)	PADC0 (EIP1.3)

Table 10.1. Interrup	ot Summary
----------------------	------------



Interrupt Source	Interrupt Vector	Priority Order	Pending Flag	Bit addressable?	Cleared by HW?	Enable Flag	Priority Control
Programmable Counter Array	0x005B	11	CF (PCA0CN.7) CCFn (PCA0CN.n)	Y	Ν	EPCA0 (EIE1.4)	PPCA0 (EIP1.4)
Comparator0	0x0063	12	CP0FIF (CPT0CN.4) CP0RIF (CPT0CN.5)	N	Ν	ECP0 (EIE1.5)	PCP0 (EIP1.5)
Comparator1	0x006B	13	CP1FIF (CPT1CN.4) CP1RIF (CPT1CN.5)	Ν	Ν	ECP1 (EIE1.6)	PCP1 (EIP1.6)
Timer 3 Overflow	0x0073	14	TF3H (TMR3CN.7) TF3L (TMR3CN.6)	Ν	Ν	ET3 (EIE1.7)	PT3 (EIP1.7)
RESERVED	0x007B	15	N/A	N/A	N/A	N/A	N/A
Port Match	0x0083	16	N/A	N/A	N/A	EMAT (EIE2.1)	PMAT (EIP2.1)

## Table 10.1. Interrupt Summary (Continued)

### **10.4.** Interrupt Register Descriptions

The SFRs used to enable the interrupt sources and set their priority level are described below. Refer to the data sheet section associated with a particular on-chip peripheral for information regarding valid interrupt conditions for the peripheral and the behavior of its interrupt-pending flag(s).



SFR Addres R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
EA	ESPI0	ET2	ES0	ET1	EX1	ET0	EX0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	EA: Global Ir	nterrupt En:	able					
Bit I .	This bit globa			ll interrupts	. It override	s the individ	ual interru	pt mask set
	tings.	<b>,</b>						
	0: Disable al	l interrupt s	ources.					
	1: Enable ea	•		to its indivi	dual mask s	etting.		
Bit 6:	ESPI0: Enab	•	•			•		
	This bit sets		•	· ·	, .			
	0: Disable al			•				
	1: Enable int			ated by SPI	0.			
Bit 5:	ET2: Enable							
	This bit sets	the maskin	g of the Tin	ner 2 interru	ipt.			
	0: Disable Ti	mer 2 interi	upt.					
	1: Enable int	errupt requ	ests genera	ated by the	TF2L or TF	2H flags.		
Bit 4:	ES0: Enable	UART0 Int	errupt.					
	This bit sets	the maskin	g of the UA	RT0 interru	pt.			
	0: Disable U	ART0 interr	upt.					
	1: Enable UA	ART0 interro	upt.					
Bit 3:	ET1: Enable	Timer 1 Int	errupt.					
	This bit sets			ner 1 interru	ıpt.			
	0: Disable al	Timer 1 in	terrupt.					
	1: Enable int		•	ated by the	TF1 flag.			
Bit 2:	EX1: Enable		•					
	This bit sets		•	al Interrupt	1.			
	0: Disable ex							
	1: Enable int		•	ated by the	/INT1 input.			
Bit 1:	ET0: Enable		•					
	This bit sets		•	ner 0 interru	ipt.			
	0: Disable al		•					
	1: Enable int			ated by the	TF0 flag.			
Bit 0:	EX0: Enable		•					
	This bit sets			al Interrupt	0.			
	0: Disable ex							
	1: Enable int							



SFR Address			ressable)					
R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
_	PSPI0	PT2	PS0	PT1	PX1	PT0	PX0	1000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	UNUSED. R							
Bit 6:	PSPI0: Seria				rupt Priority	Control.		
	This bit sets			•				
	0: SPI0 inter							
	1: SPI0 inter							
Bit 5:	PT2: Timer 2							
	This bit sets				t.			
	0: Timer 2 in	•						
	1: Timer 2 in	•	• •					
Bit 4:	PS0: UARTO							
	This bit sets				i.			
	0: UART0 int							
	1: UART0 int		<b>U</b> 1					
Bit 3:	PT1: Timer 1							
	This bit sets				τ.			
	0: Timer 1 in	•	•					
Bit 2:	1: Timer 1 in PX1: Externa	•	• •					
DIL Z.	This bit sets				t 1 intorrun	+		
	0: External Ir				or i interiup	ι.		
	1: External Ir							
Bit 1:	PT0: Timer 0							
DIC I.	This bit sets				+			
	0: Timer 0 in							
	1: Timer 0 in	•	•					
Bit 0:	PX0: Externa							
210.0.	This bit sets	•			ot 0 interrup	t		
	0: External Ir							
			et to high pi					

## SFR Definition 10.2. IP: Interrupt Priority



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
ET3	ECP1	ECP0	EPCA0	EADC0	EWADC0	-	ESMB0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	-
Bit 7:	ET3: Enable	Timer 3 In	terrupt.					
	This bit sets			ner 3 interro	upt.			
	0: Disable Ti		•					
					TF3L or TF3	H flags.		
Bit 6:	ECP1: Enab	•	· · · ·	•				
	This bit sets		•	1 interrupt.				
	0: Disable C							
			•		CP1RIF or C	P1FIF flag	js.	
Bit 5:	ECP0: Enab	•	· · · ·	•				
	This bit sets		•	0 Interrupt.				
	0: Disable C	•		atad by the				
Bit 4:			0		CP0RIF or C (PCA0) Inter		js.	
DIL 4.	This bit sets	•			· · ·	Tupi.		
	0: Disable al		•	Ao menup	15.			
	1: Enable inf		•	ated by PC	Δ0			
Bit 3:	EADC0: Ena		•					
Dit U.				•	sion Complet	e interrunt	ŀ	
	0: Disable A		•		•			
					AD0INT flag.			
Bit 2:	EWADC0: E							
					v Comparisor	n interrupt.		
	0: Disable A					•		
			•		AD0WINT fla	ıg.		
Bit 1:	UNUSED. R	ead = 0b. V	Vrite = don'	t care.		•		
Bit 0:	ESMB0: Ena	able SMBus	s (SMB0) In	terrupt.				
	This bit sets			1B0 interrup	ot.			
	0: Disable al							
	1: Enable inf		anta maman					

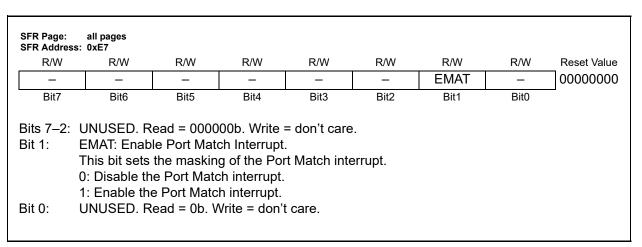
## SFR Definition 10.3. EIE1: Extended Interrupt Enable 1



SFR Addres R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
PT3	PCP1	PCP0	PPCA0	PADC0	PWADC0	_	PSMB0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
Bit 7:	PT3: Timer 3	3 Interrupt F	Priority Cont	trol.				
	This bit sets			•	vt.			
	0: Timer 3 in							
	1: Timer 3 in							
Bit 6:	PCP1: Com				ontrol.			
	This bit sets							
	0: CP1 inter							
	1: CP1 inter	•	• • •					
Bit 5:	PCP0: Com				ontrol.			
	This bit sets			•				
	0: CP0 inter							
	1: CP0 inter							
Bit 4:		•			) Interrupt Pri	ority Cont	rol.	
	This bit sets			•				
	0: PCA0 inte							
<b>.</b>	1: PCA0 inte							
Bit 3:					t Priority Con			
					on Complete			
			•	•	low priority I			
			•	•	high priority			
Bit 2:					pt Priority Co			
					Comparison i			
					low priority le			
				•	high priority l	evel.		
Bit 1:	UNUSED. R				4			
Bit 0:	PSMB0: SM							
	This bit sets							
	0: SMB0 inte 1: SMB0 inte							
	I SIVIBUINTE	ATTUNT SAT 10	o nian priorif	VIEVEI				

## SFR Definition 10.4. EIP1: Extended Interrupt Priority 1





## SFR Definition 10.5. EIE2: Extended Interrupt Enable 2

## SFR Definition 10.6. EIP2: Extended Interrupt Priority 2

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
_	-	-	-	-	_	PMAT	_	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 1:	UNUSED. R PMAT: Port N This bit sets	Match Inter	rupt Priority	Control.				



#### 10.5. External Interrupts

The /INT0 and /INT1 external interrupt sources are configurable as active high or low, edge or level sensitive. The IN0PL (/INT0 Polarity) and IN1PL (/INT1 Polarity) bits in the IT01CF register select active high or active low; the IT0 and IT1 bits in TCON (Section "21.1. Timer 0 and Timer 1" on page 249) select level or edge sensitive. The table below lists the possible configurations.

IT0	IN0PL	/INT0 Interrupt
1	0	Active low, edge sensitive
1	1	Active high, edge sensitive
0	0	Active low, level sensitive
0	1	Active high, level sensitive

IT1	IN1PL	/INT1 Interrupt
1	0	Active low, edge sensitive
1	1	Active high, edge sensitive
0	0	Active low, level sensitive
0	1	Active high, level sensitive

/INT0 and /INT1 are assigned to Port pins as defined in the IT01CF register (see SFR Definition 10.7). Note that /INT0 and /INT0 Port pin assignments are independent of any Crossbar assignments. /INT0 and /INT1 will monitor their assigned Port pins without disturbing the peripheral that was assigned the Port pin via the Crossbar. To assign a Port pin only to /INT0 and/or /INT1, configure the Crossbar to skip the selected pin(s). This is accomplished by setting the associated bit in register XBR0 (see Section "17.1. Priority Crossbar Decoder" on page 186 for complete details on configuring the Crossbar).

IE0 (TCON.1) and IE1 (TCON.3) serve as the interrupt-pending flags for the /INT0 and /INT1 external interrupts, respectively. If an /INT0 or /INT1 external interrupt is configured as edge-sensitive, the corresponding interrupt-pending flag is automatically cleared by the hardware when the CPU vectors to the ISR. When configured as level sensitive, the interrupt-pending flag remains logic '1' while the input is active as defined by the corresponding polarity bit (INOPL or IN1PL); the flag remains logic '0' while the input is inactive. The external interrupt source must hold the input active until the interrupt request is recognized. It must then deactivate the interrupt request before execution of the ISR completes or another interrupt request will be generated.



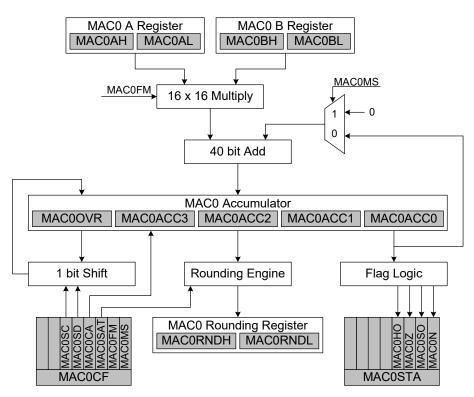
## SFR Definition 10.7. IT01CF: INT0/INT1 Configuration

R/W	s: 0xE4 R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
IN1PL	IN1SL2	IN1SL1	IN1SL0	INOPL	IN0SL2	IN0SL1	INOSLO	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
	r to SFR Definition							upt selection.
Bit 7:	IN1PL: /INT1 0: /INT1 input	is active l						
	1: /INT1 input			Ditt				
Bits 6–4:	IN1SL2-0: /IN				(IN) <del>-</del> ( N) (			
	These bits se		•	-		•	-	
	pendent of the							
	peripheral tha							
	assign the Po	• •	•	-	•	he selected	l pin (accon	nplished by
	setting to '1' t	he corresp	onding bit i	n register F	POSKIP).			
	IN1SL2-0	/INT	1 Port Pin					
	000		P0.0					
	001		P0.1					
	010		P0.2					
	011		P0.3					
	100		P0.4					
	101		P0.5					
	110		P0.6					
	111		P0.7					
			1 0.7					
Bit 3:	IN0PL: /INT0	Polarity						
Dit U.	0: /INT0 interr		velow					
	1: /INT0 interr	•						
Bits 2–0 <sup>.</sup>	INT0SL2-0: /I	•	•	n Bits				
DIG 2 0.	These bits se				/INTO Note	that this n	in assignme	ent is inde-
	pendent of the							
	•				via the Cro	•		•
				it is config		he selected	l pin (accon	nolished by
	assign the Po	rt pin to a j	peripheral if		ured to skip t	he selected	l pin (accon	plished by
		rt pin to a j	peripheral if		ured to skip t	he selected	l pin (accon	nplished by
	assign the Po	rt pin to a p ne corresp	peripheral if		ured to skip t	he selected	l pin (accon	nplished by
	assign the Po setting to '1' th	rt pin to a p ne corresp	peripheral if ponding bit i		ured to skip t	he selected	l pin (accon	nplished by
	assign the Po setting to '1' the INOSL2-0	rt pin to a p ne corresp	beripheral if bonding bit i		ured to skip t	he selected	l pin (accon	plished by
	assign the Po setting to '1' the <b>IN0SL2-0</b> 000	rt pin to a p ne corresp	peripheral if ponding bit in <b>0 Port Pin</b> P0.0		ured to skip t	he selected	l pin (accon	ıplished by
	assign the Po setting to '1' the INOSL2-0 000 001	rt pin to a p ne corresp	operipheral if bonding bit i <b>0 Port Pin</b> P0.0 P0.1		ured to skip t	he selected	l pin (accon	ıplished by
	assign the Po setting to '1' the <b>INOSL2-0</b> 000 001 010	rt pin to a p ne corresp	<b>OPERATE INFORMATION</b>		ured to skip t	he selected	l pin (accon	ıplished by
	assign the Po setting to '1' the <b>INOSL2-0</b> 000 001 010 011	rt pin to a p ne corresp	<b>OPERATE:</b> <b>OPORT PIN</b> <b>P0.0</b> <b>P0.1</b> <b>P0.2</b> <b>P0.3</b>		ured to skip t	he selected	l pin (accon	ıplished by
	assign the Po setting to '1' the <b>INOSL2-0</b> 000 001 010 011 100	rt pin to a p ne corresp	<b>OPERATE:</b> <b>OPORT Pin</b> P0.0 P0.1 P0.2 P0.3 P0.4		ured to skip t	he selected	l pin (accon	ıplished by



# 11. Multiply And Accumulate (MAC0)

The C8051F36x devices include a multiply and accumulate engine which can be used to speed up many mathematical operations. MAC0 contains a 16-by-16 bit multiplier and a 40-bit adder, which can perform integer or fractional multiply-accumulate and multiply operations on signed input values in two SYSCLK cycles. A rounding engine provides a rounded 16-bit fractional result after an additional (third) SYSCLK cycle. MAC0 also contains a 1-bit arithmetic shifter that will left or right-shift the contents of the 40-bit accumulator in a single SYSCLK cycle. Figure 11.1 shows a block diagram of the MAC0 unit and its associated Special Function Registers.





### 11.1. Special Function Registers

There are thirteen Special Function Register (SFR) locations associated with MAC0. Two of these registers are related to configuration and operation, while the other eleven are used to store multi-byte input and output data for MAC0. The Configuration register MAC0CF (SFR Definition 11.1) is used to configure and control MAC0. The Status register MAC0STA (SFR Definition 11.2) contains flags to indicate overflow conditions, as well as zero and negative results. The 16-bit MAC0A (MAC0AH:MAC0AL) and MAC0B (MAC0BH:MAC0BL) registers are used as inputs to the multiplier. The MAC0 Accumulator register is 40 bits long, and consists of five SFRs: MAC0OVR, MAC0ACC3, MAC0ACC2, MAC0ACC1, and MAC0ACC0. The primary results of a MAC0 operation are stored in the Accumulator registers. If they are needed, the rounded results are stored in the 16-bit Rounding Register MAC0RND (MAC0RNDH:MAC0RNDL).



#### **11.2.** Integer and Fractional Math

MAC0 is capable of interpreting the 16-bit inputs stored in MAC0A and MAC0B as signed integers or as signed fractional numbers. When the MAC0FM bit (MAC0CF.1) is cleared to '0', the inputs are treated as 16-bit, 2's complement, integer values. After the operation, the accumulator will contain a 40-bit, 2's complement, integer value. Figure 11.2 shows how integers are stored in the SFRs.

#### MAC0A and MAC0B Bit Weighting

		High	Byte							Low	Byte			
-(2 <sup>15</sup> ) 2 <sup>14</sup>	2 <sup>13</sup>	2 <sup>12</sup>	211	2 <sup>10</sup>	2 <sup>9</sup>	28	27	26	2 <sup>5</sup>	24	2 <sup>3</sup>	2 <sup>2</sup>	2 <sup>1</sup>	20

				M	AC0 A	ccum	ulator	Bit W	eighting					
	N	AC00V	R		MA	AC0A0	CC3 :	MACC	ACC2 :	MAC0	ACC1	: MA	C0AC	C0
-(2 <sup>39</sup> )	2 <sup>38</sup>		2 <sup>33</sup>	232	2 <sup>31</sup>	2 <sup>30</sup>	2 <sup>29</sup>	228	22	24	2 <sup>3</sup>	2 <sup>2</sup>	2 <sup>1</sup>	2 <sup>0</sup>

#### Figure 11.2. Integer Mode Data Representation

When the MAC0FM bit is set to '1', the inputs are treated at 16-bit, 2's complement, fractional values. The decimal point is located between bits 15 and 14 of the data word. After the operation, the accumulator will contain a 40-bit, 2's complement, fractional value, with the decimal point located between bits 31 and 30. Figure 11.3 shows how fractional numbers are stored in the SFRs.

#### MAC0A, and MAC0B Bit Weighting

			High	Byte							Low	Byte				
-1	2-1	2-2	2 <sup>-3</sup>	2-4	2 <sup>-5</sup>	2-6	2-7	2-8	2-9	2-10	2-11	<b>2</b> <sup>-12</sup>	2 <sup>-13</sup>	2-14	2 <sup>-15</sup>	1

#### MAC0 Accumulator Bit Weighting

MAC0OVR	MAC0ACC3 : MAC0ACC2 : MAC0ACC1 : MAC0ACC0	
-(2 <sup>8</sup> ) 2 <sup>7</sup> 2 <sup>2</sup> 2 <sup>1</sup>	$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	31

#### MACORND Bit Weighting

				High	Byte							Low	Byte			
* -2	1	2-1	<b>2</b> -2	2 <sup>-3</sup>	2-4	2-5	2-6	2-7	2-8	2 <sup>-9</sup>	2-10	<b>2</b> <sup>-11</sup>	2-12	2 <sup>-13</sup>	<b>2</b> <sup>-14</sup>	2-15

\* The MACORND register contains the 16 LSBs of a two's complement number. The MACON Flag can be used to determine the sign of the MACORND register.

#### Figure 11.3. Fractional Mode Data Representation



### 11.3. Operating in Multiply and Accumulate Mode

MAC0 operates in Multiply and Accumulate (MAC) mode when the MACOMS bit (MAC0CF.0) is cleared to '0'. When operating in MAC mode, MAC0 performs a 16-by-16 bit multiply on the contents of the MAC0A and MAC0B registers, and adds the result to the contents of the 40-bit MAC0 accumulator. Figure 11.4 shows the MAC0 pipeline. There are three stages in the pipeline, each of which takes exactly one SYSCLK cycle to complete. The MAC operation is initiated with a write to the MAC0BL register. After the MAC0BL register is written, MAC0A and MAC0B are multiplied on the first SYSCLK cycle. During the second stage of the MAC0 pipeline, the results of the multiplication are added to the current accumulator contents, and the result of the addition is stored in the MAC0 accumulator. The status flags in the MAC0STA register are set after the end of the second pipeline stage. During the second stage of the pipeline, the next multiplication are the MAC0RNDL registers at the end of the third pipeline stage. If the MAC0CA bit (MAC0CF.3) is set to '1' when the MAC operation is initiated, the accumulator and all MAC0STA flags will be cleared during the next cycle of the controller's clock (SYSCLK). The MAC0CA bit will clear itself to '0' when the clear operation is complete.

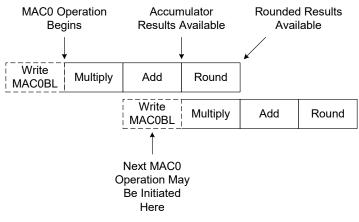


Figure 11.4. MAC0 Pipeline

### 11.4. Operating in Multiply Only Mode

MAC0 operates in Multiply Only mode when the MAC0MS bit (MAC0CF.0) is set to '1'. Multiply Only mode is identical to Multiply and Accumulate mode, except that the multiplication result is added with a value of zero before being stored in the MAC0 accumulator (i.e. it overwrites the current accumulator contents). The result of the multiplication is available in the MAC0 accumulator registers at the end of the second MAC0 pipeline stage (two SYSCLKs after writing to MAC0BL). As in MAC mode, the rounded result is available in the MAC0 Rounding Registers after the third pipeline stage. Note that in Multiply Only mode, the MAC0HO flag is not affected.

### 11.5. Accumulator Shift Operations

MAC0 contains a 1-bit arithmetic shift function which can be used to shift the contents of the 40-bit accumulator left or right by one bit. The accumulator shift is initiated by writing a '1' to the MAC0SC bit (MAC0CF.5), and takes one SYSCLK cycle (the rounded result is available in the MAC0 Rounding Registers after a second SYSCLK cycle, and MAC0SC is cleared to '0'). The direction of the arithmetic shift is controlled by the MAC0SD bit (MAC0CF.4). When this bit is cleared to '0', the MAC0 accumulator will shift left. When the MAC0SD bit is set to '1', the MAC0 accumulator will shift right. Right-shift operations are sign-extended with the current value of bit 39. Note that the status flags in the MAC0STA register are not affected by shift operations.



#### **11.6.** Rounding and Saturation

A Rounding Engine is included, which can be used to provide a rounded result when operating on fractional numbers. MAC0 uses an unbiased rounding algorithm to round the data stored in bits 31–16 of the accumulator, as shown in Table 11.1. Rounding occurs during the third stage of the MAC0 pipeline, after any shift operation, or on a write to the LSB of the accumulator. The rounded results are stored in the rounding registers: MAC0RNDH (SFR Definition 11.12) and MAC0RNDL (SFR Definition 11.13). The accumulator registers are not affected by the rounding engine. Although rounding is primarily used for fractional data, the data in the rounding registers is updated in the same way when operating in integer mode.

Accumulator Bits 15–0 (MAC0ACC1:MAC0ACC0)	Accumulator Bits 31–16 (MAC0ACC3:MAC0ACC2)	Rounding Direction	Rounded Results (MAC0RNDH:MAC0RNDL)
Greater Than 0x8000	Anything	Up	(MAC0ACC3:MAC0ACC2) + 1
Less Than 0x8000	Anything	Down	(MAC0ACC3:MAC0ACC2)
Equal To 0x8000	Odd (LSB = 1)	Up	(MAC0ACC3:MAC0ACC2) + 1
Equal To 0x8000	Even (LSB = 0)	Down	(MAC0ACC3:MAC0ACC2)

The rounding engine can also be used to saturate the results stored in the rounding registers. If the MAC0-SAT bit is set to '1' and the rounding register overflows, the rounding registers will saturate. When a positive overflow occurs, the rounding registers will show a value of 0x7FFF when saturated. For a negative overflow, the rounding registers will show a value of 0x8000 when saturated. If the MAC0SAT bit is cleared to '0', the rounding registers will not saturate.

#### 11.7. Usage Examples

This section details some software examples for using MAC0. Section 11.7.1 shows a series of two MAC operations using fractional numbers. Section 11.7.2 shows a single operation in Multiply Only mode with integer numbers. The last example, shown in Section 11.7.3, demonstrates how the left-shift and right-shift operations can be used to modify the accumulator. All of the examples assume that all of the flags in the MAC0STA register are initially set to '0'.

#### 11.7.1. Multiply and Accumulate Example

The example below implements the equation:

```
(0.5 \times 0.25) + (0.5 \times -0.25) = 0.125 - 0.125 = 0.0
```

MOV	MACOCF,	#0Ah	;	Set to Clear Accumulator, Use fractional numbers
MOV	MACOAH,	#40h	;	Load MACOA register with 4000 hex = $0.5$ decimal
MOV	MACOAL,	#00h		
MOV	MACOBH,	#20h	;	Load MACOB register with 2000 hex = $0.25$ decimal
MOV	MACOBL,	#00h	;	This line initiates the first MAC operation
MOV	MACOBH,	#E0h	;	Load MACOB register with E000 hex = $-0.25$ decimal
MOV	MACOBL,	#00h	;	This line initiates the second MAC operation
NOP				
NOP			;	After this instruction, the Accumulator should be equal to 0,
			;	and the MACOSTA register should be 0x04, indicating a zero
NOP			;	After this instruction, the Rounding register is updated



#### 11.7.2. Multiply Only Example

The example below implements the equation:

 $4660 \times -292 \; = \; -1360720$ 

MOV	MACOCF,	#01h	; Use integer numbers, and multiply only mode (add to zero)
MOV	MACOAH,	#12h	; Load MACOA register with 1234 hex = 4660 decimal
MOV	MACOAL,	#34h	
MOV	MACOBH,	#FEh	; Load MACOB register with FEDC hex = $-292$ decimal
MOV	MACOBL,	#DCh	; This line initiates the Multiply operation
NOP			
NOP			; After this instruction, the Accumulator should be equal to
			; FFFFEB3CB0 hex = $-1360720$ decimal. The MACOSTA register should
			; be 0x01, indicating a negative result.
NOP			; After this instruction, the Rounding register is updated

#### 11.7.3. MAC0 Accumulator Shift Example

The example below shifts the MAC0 accumulator left one bit, and then right two bits:

MOV	MAC00VR, #40h	
MOV	• · · ·	; 4088442211 Hex.
MOV	MACOACC2, #44h	
MOV	MACOACC1, #22h	
MOV	MAC0ACC0, #11h	
MOV	MACOCF, #20h	; Initiate a Left-shift
NOP		; After this instruction, the accumulator should be 0x8110884422
NOP		; The rounding register is updated after this instruction
MOV	MACOCF, #30h	; Initiate a Right-shift
MOV	MACOCF, #30h	; Initiate a second Right-shift
NOP		; After this instruction, the accumulator should be 0xE044221108
NOP		; The rounding register is updated after this instruction



R	R	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	MAC0SC	MAC0SD	MAC0CA	MAC0SAT	MAC0FM	MAC0MS	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bits 7 <b>–</b> 6:	UNUSED: R	ead = 00b,	Write = dor	n't care.				
Bit 5:	MAC0SC: A		-					
	When set to							kt SYSCL
	cycle. The di		```	• ,			OSD bit.	
	This bit is cle				shift is com	olete.		
Bit 4:	MAC0SD: A							
	This bit conti	rols the dire	ction of the	accumulat	or shift activ	ated by the	MAC0SC I	oit.
	0: MAC0 Aco							
	1: MAC0 Aco	cumulator w	vill be shifte	d right.				
Bit 3:	MAC0CA: C							
	This bit is us	ed to reset	MAC0 befo	ore the next	operation.			
	When set to				cleared to z	ero and the	e MAC0 Stat	tus registe
	will be reset	-		•				
	This bit will b				n the reset is	complete.		
Bit 2:	MAC0SAT: S							
	This bit contr							
	Overflow occ							
	of the MAC0				or more detai	ils about ro	unding and	saturatior
	0: Rounding	•		ate.				
	1: Rounding	•						
Bit 1:	MAC0FM: F							
	This bit selee		-		actional Mod	e for MAC	) operations	5.
	0: MAC0 ope		•					
	1: MAC0 ope	erates in Fra	actional Mo	de.				
	MAC0MS: M							
Bit 0:	This bit select	cts between	MAC Mod	e and Multi	ply Only Mod	de.		
Bit 0:								
Bit 0:	0: MAC (Mul	tiply and Ac	cumulate)	Mode.				
Bit O:		tiply and Ac	cumulate)	Mode.				

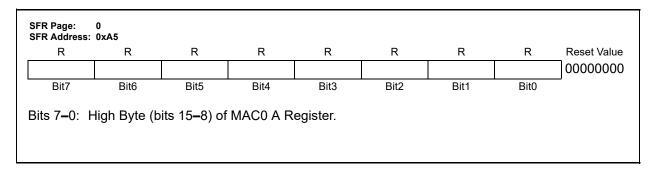
### SFR Definition 11.1. MAC0CF: MAC0 Configuration



R	R	R	R	R/W	R/W	R/W	R/W	Reset Value
_	-	_	_	MAC0HO	MAC0Z	MAC0SO	MACON	00000100
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable
Bits 7 <b>–</b> 4:	UNUSED: R	ead = 0000	b, Write =	don't care.				
Bit 3:	MAC0HO: H							
	This bit is se	t to '1' whe	never an o	verflow out o	f the MAC	0OVR regist	er occurs o	during a
	MAC operati	on (i.e. whe	en MAC0O	VR changes	from 0x7F	to 0x80 or f	rom 0x80	to 0x7F).
	The hard over	erflow flag i	nust be cle	eared in softw	are by dire	ectly writing i	it to '0', or	by resetting
	the MAC log	ic using the	MACOCA	bit in registe	r MAC0CF			
Bit 2:	MAC0Z: Zer	o Flag.		U				
3it 2:	MAC0Z: Zer This bit is se	•	MAC0 oper	-			ue of zero.	If the resul
Bit 2:		t to '1' if a l	•	ation results			ue of zero.	If the resul
3it 2: 3it 1:	This bit is se	t to '1' if a l this bit will	be cleared	ation results			ue of zero.	If the resul
	This bit is se is non-zero, MAC0SO: S This bit is se	t to '1' if a l this bit will oft Overflov t to '1' whe	be cleared v Flag. n a MAC op	ration results to '0'. peration caus	in an Accu ses an ove	imulator valu	e sign bit (b	bit 31) of the
	This bit is se is non-zero, MAC0SO: S	t to '1' if a l this bit will oft Overflov t to '1' whe	be cleared v Flag. n a MAC op	ration results to '0'. peration caus	in an Accu ses an ove	imulator valu	e sign bit (b	bit 31) of the
	This bit is se is non-zero, MAC0SO: S This bit is se MAC0 Accur this bit is cle	t to '1' if a I this bit will oft Overflov t to '1' when nulator. If th ared to '0'.	be cleared v Flag. n a MAC op ne overflow	ration results to '0'. peration caus	in an Accu ses an ove	imulator valu	e sign bit (b	bit 31) of the
	This bit is se is non-zero, MAC0SO: S This bit is se MAC0 Accur this bit is cle MAC0N: Neg	t to '1' if a I this bit will oft Overflov t to '1' when nulator. If th ared to '0'. gative Flag	be cleared v Flag. n a MAC op ne overflow	ration results to '0'. peration caus condition is	in an Accu ses an ove corrected a	imulator valu rflow into the after a subse	e sign bit (b quent MAC	oit 31) of the C operation
Bit 1:	This bit is set is non-zero, MAC0SO: S This bit is set MAC0 Accur this bit is cle MAC0N: Neg If the MAC A	t to '1' if a I this bit will oft Overflov t to '1' when nulator. If th ared to '0'. gative Flag accumulato	be cleared v Flag. n a MAC op ne overflow r result is n	ration results to '0'. peration caus condition is egative, this	in an Accu ses an ove corrected a	imulator valu rflow into the after a subse	e sign bit (b quent MAC	oit 31) of the C operation
Bit 1:	This bit is se is non-zero, MAC0SO: S This bit is se MAC0 Accur this bit is cle MAC0N: Neg	t to '1' if a I this bit will oft Overflov t to '1' when nulator. If th ared to '0'. gative Flag accumulato	be cleared v Flag. n a MAC op ne overflow r result is n	ration results to '0'. peration caus condition is egative, this	in an Accu ses an ove corrected a	imulator valu rflow into the after a subse	e sign bit (b quent MAC	oit 31) of the C operation

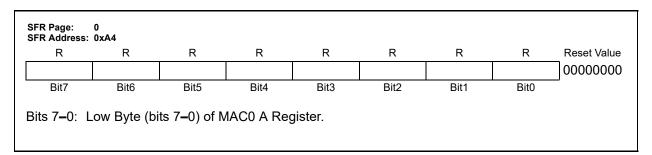
### SFR Definition 11.2. MAC0STA: MAC0 Status

# SFR Definition 11.3. MAC0AH: MAC0 A High Byte

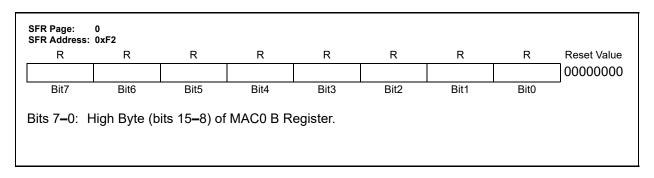




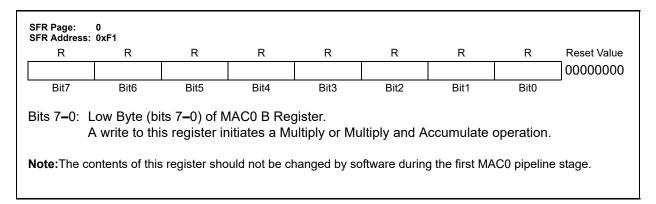
### SFR Definition 11.4. MAC0AL: MAC0 A Low Byte



## SFR Definition 11.5. MAC0BH: MAC0 B High Byte

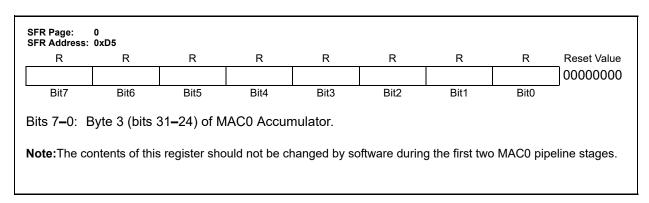


# SFR Definition 11.6. MAC0BL: MAC0 B Low Byte

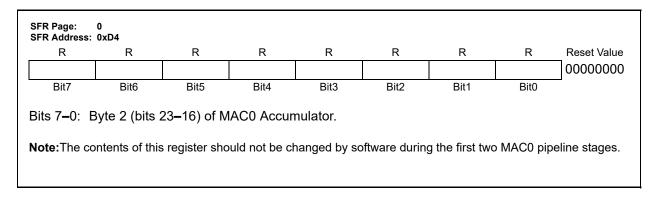




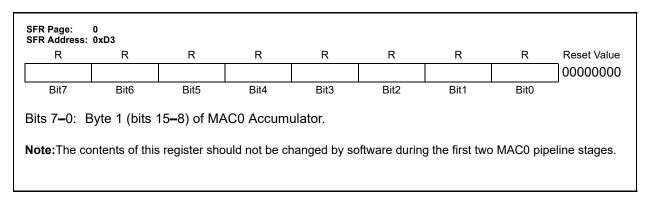
#### SFR Definition 11.7. MAC0ACC3: MAC0 Accumulator Byte 3



### SFR Definition 11.8. MAC0ACC2: MAC0 Accumulator Byte 2

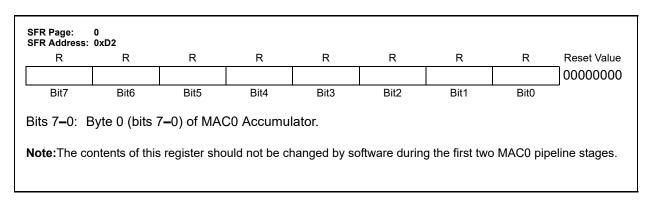


# SFR Definition 11.9. MAC0ACC1: MAC0 Accumulator Byte 1

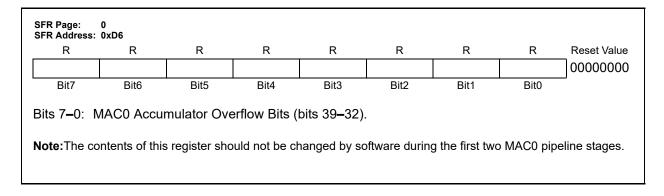




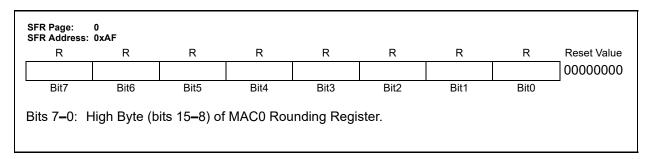
#### SFR Definition 11.10. MAC0ACC0: MAC0 Accumulator Byte 0



### SFR Definition 11.11. MAC0OVR: MAC0 Accumulator Overflow

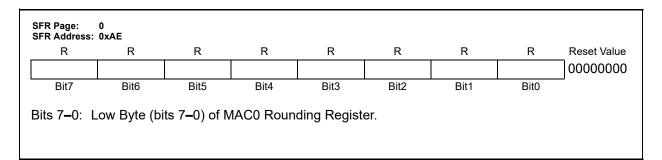


# SFR Definition 11.12. MAC0RNDH: MAC0 Rounding Register High Byte





#### SFR Definition 11.13. MAC0RNDL: MAC0 Rounding Register Low Byte





# 12. Reset Sources

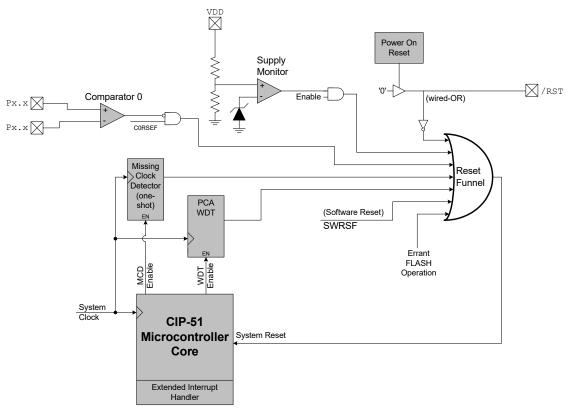
Reset circuitry allows the controller to be easily placed in a predefined default condition. On entry to this reset state, the following occur:

- CIP-51 halts program execution
- Special Function Registers (SFRs) are initialized to their defined reset values
- External Port pins are forced to a known state
- Interrupts and timers are disabled.

All SFRs are reset to the predefined values noted in the SFR detailed descriptions. The contents of internal data memory are unaffected during a reset; any previously stored data is preserved. However, since the stack pointer SFR is reset, the stack is effectively lost, even though the data on the stack is not altered.

The Port I/O latches are reset to 0xFF (all logic ones) in open-drain mode. Weak pullups are enabled during and after the reset. For  $V_{DD}$  Monitor and power-on resets, the  $\overrightarrow{RST}$  pin is driven low until the device exits the reset state.

On exit from the reset state, the program counter (PC) is reset, and the system clock defaults to the internal oscillator. Refer to Section "16. Oscillators" on page 170 for information on selecting and configuring the system clock source. The Watchdog Timer is enabled with the system clock divided by 12 as its clock source (Section "22.3. Watchdog Timer Mode" on page 273 details the use of the Watchdog Timer). Program execution begins at location 0x0000.







#### 12.1. Power-On Reset

During power-up, the device is held in a reset state and the  $\overline{RST}$  pin is driven low until V<sub>DD</sub> settles above V<sub>RST</sub>. A delay occurs before the device is released from reset; the delay decreases as the V<sub>DD</sub> ramp time increases (V<sub>DD</sub> ramp time is defined as how fast V<sub>DD</sub> ramps from 0 V to V<sub>RST</sub>). Figure 12.2. plots the power-on and V<sub>DD</sub> Monitor reset timing. For ramp times less than 1 ms, the power-on reset delay (T<sub>PORDe-lav</sub>) is typically less than 0.3 ms.

**Note:** The maximum  $V_{DD}$  ramp time is 1 ms; slower ramp times may cause the device to be released from reset before  $V_{DD}$  reaches the  $V_{RST}$  level.

On exit from a power-on reset, the PORSF flag (RSTSRC.1) is set by hardware to logic '1'. When PORSF is set, all of the other reset flags in the RSTSRC Register are indeterminate (PORSF is cleared by all other resets). Since all resets cause program execution to begin at the same location (0x0000) software can read the PORSF flag to determine if a power-up was the cause of reset. The content of internal data memory should be assumed to be undefined after a power-on reset. The V<sub>DD</sub> Monitor is enabled following a power-on reset.

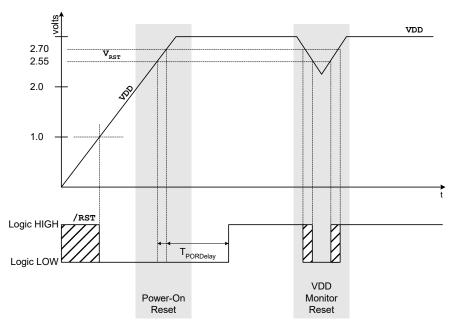


Figure 12.2. Power-On and V<sub>DD</sub> Monitor Reset Timing



### 12.2. Power-Fail Reset/V<sub>DD</sub> Monitor

When a power-down transition or power irregularity causes  $V_{DD}$  to drop below  $V_{RST}$ , the power supply monitor will drive the  $\overline{RST}$  pin low and hold the CIP-51 in a reset state (see Figure 12.2). When  $V_{DD}$  returns to a level above  $V_{RST}$ , the CIP-51 will be released from the reset state. Note that even though internal data memory contents are not altered by the power-fail reset, it is impossible to determine if  $V_{DD}$  dropped below the level required for data retention. If the PORSF flag reads '1', the data may no longer be valid. The  $V_{DD}$  Monitor is enabled after power-on resets; however its defined state (enabled/disabled) is not altered by any other reset source. For example, if the  $V_{DD}$  Monitor is disabled and a software reset is performed, the  $V_{DD}$  Monitor will still be disabled after the reset. To protect the integrity of Flash contents, the VDD Monitor must be enabled and selected as a reset source if software contains routines which erase or write Flash memory. If the VDD Monitor is not enabled, any erase or write performed on Flash memory will cause a Flash Error device reset.

The V<sub>DD</sub> Monitor must be enabled before it is selected as a reset source. Selecting the V<sub>DD</sub> Monitor as a reset source before it is enabled and stabilized may cause a system reset. The procedure for configuring the V<sub>DD</sub> Monitor as a reset source is shown below:

- Step 1. Enable the  $V_{DD}$  Monitor (VDMEN bit in VDM0CN = '1').
- Step 2. Wait for the VDD Monitor to stabilize (approximately 5 μs). Note: This delay should be omitted if software contains routines which erase or write Flash memory.
- Step 3. Select the  $V_{DD}$  Monitor as a reset source (PORSF bit in RSTSRC = '1').

See Table 12.1 for complete electrical characteristics of the  $V_{\text{DD}}$  Monitor.

Note: Software should take care not to inadvertently disable the VDD Monitor as a reset source when writing to RSTSRC to enable other reset sources or to trigger a software reset. All writes to RSTSRC should explicitly set PORSF to '1' to keep the VDD Monitor enabled as a reset source.



SFR Address R/W	R	R	R	R	R	R	R	Reset Value
VDMEN	VDDSTAT	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Variable
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	4
Bit 6:	VDMEN: $V_{DC}$ This bit turns until it is also Monitor must <b>V<sub>DD</sub> Monitor</b> 0: V <sub>DD</sub> Monitor 1: V <sub>DD</sub> Monitor V <sub>DD</sub> STAT: V <sub>I</sub> This bit indica 0: V <sub>DD</sub> is at o 1: V <sub>DD</sub> is abo RESERVED.	the V <sub>DD</sub> Mo selected as be allowed <b>as a reset</b> or Disabled or Enabled. on Status. ates the cur r below the ve the V <sub>DD</sub>	rent power V <sub>DD</sub> Monitor	urce in regis before it is fore it has supply statu or threshold eshold.	selected as selected as stabilized r us (V <sub>DD</sub> Mo	C (SFR Def s a reset so <b>nay genera</b>	inition 12.2) urce. <b>Selec</b> t ate a syster	. The V <sub>DD</sub> t <b>ing the</b>

# SFR Definition 12.1. VDM0CN: V<sub>DD</sub> Monitor Control

#### 12.3. External Reset

The external RST pin provides a means for external circuitry to force the device into a reset state. Asserting an active-low signal on the RST pin generates a reset; an external pullup and/or decoupling of the RST pin may be necessary to avoid erroneous noise-induced resets. See Table 12.1 for complete RST pin specifications. The PINRSF flag (RSTSRC.0) is set on exit from an external reset.

### 12.4. Missing Clock Detector Reset

The Missing Clock Detector (MCD) is a one-shot circuit that is triggered by the system clock. If the system clock remains high or low for more than 100  $\mu$ s, the one-shot will time out and generate a reset. After a MCD reset, the MCDRSF flag (RSTSRC.2) will read '1', signifying the MCD as the reset source; otherwise, this bit reads '0'. Writing a '1' to the MCDRSF bit enables the Missing Clock Detector; writing a '0' disables it. The state of the RST pin is unaffected by this reset.

#### 12.5. Comparator0 Reset

Comparator0 can be configured as a reset source by writing a '1' to the CORSEF flag (RSTSRC.5). Comparator0 should be enabled and allowed to settle prior to writing to CORSEF to prevent any turn-on chatter on the output from generating an unwanted reset. The Comparator0 reset is active-low: if the non-inverting input voltage (on CP0+) is less than the inverting input voltage (on CP0-), the device is put into the reset state. After a Comparator0 reset, the CORSEF flag (RSTSRC.5) will read '1' signifying Comparator0 as the reset source; otherwise, this bit reads '0'. The state of the RST pin is unaffected by this reset.



#### 12.6. PCA Watchdog Timer Reset

The programmable Watchdog Timer (WDT) function of the Programmable Counter Array (PCA) can be used to prevent software from running out of control during a system malfunction. The PCA WDT function can be enabled or disabled by software as described in Section "22.3. Watchdog Timer Mode" on page 273; the WDT is enabled and clocked by SYSCLK / 12 following any reset. If a system malfunction prevents user software from updating the WDT, a reset is generated and the WDTRSF bit (RSTSRC.5) is set to '1'. The state of the RST pin is unaffected by this reset.

#### 12.7. Flash Error Reset

If a Flash read/write/erase or program read targets an illegal address, a system reset is generated. This may occur due to any of the following:

- A Flash write or erase is attempted above user code space. This occurs when PSWE is set to '1' and a MOVX write operation targets an address above address 0x7BFF.
- A Flash read is attempted above user code space. This occurs when a MOVC operation targets an address above address 0x7BFF.
- A Program read is attempted above user code space. This occurs when user code attempts to branch to an address above 0x7BFF.
- A Flash read, write or erase attempt is restricted due to a Flash security setting (see Section "13.2. Security Options" on page 139).
- A Flash write or erase is attempted while the VDD Monitor is disabled.

The FERROR bit (RSTSRC.6) is set following a Flash error reset. The state of the  $\overrightarrow{RST}$  pin is unaffected by this reset.

#### 12.8. Software Reset

Software may force a reset by writing a '1' to the SWRSF bit (RSTSRC.4). The SWRSF bit will read '1' following a software forced reset. The state of the RST pin is unaffected by this reset.



R	R	R/W	R/W	R	R/W	R/W	R	Reset Value			
_	FERROR	C0RSEF	SWRSF	WDTRSF	MCDRSF	PORSF	PINRSF	Variable			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
Note:Fo	r bits that act a										
	read-modify- C0RSEF, SV				the source	enable only	y. [This app	lies to bits:			
Bit 7:	UNUSED. R	ead = 0b V	Vrite = don	't care							
Bit 6:	FERROR: FI	-		t ouro.							
	0: Source of			lash read/wr	ite/erase er	ror.					
	1: Source of										
Bit 5:	CORSEF: Co										
	0: <b>Read:</b> Sou source.	•				: Comparat	tor0 is not a	reset			
	1: <b>Read:</b> Sou	urce of last	reset was	Comparator	). Write: Co	mparator0	is a reset s	ource			
	(active-low).										
Bit 4:	· · /	ftware Rese	et Force an	d Flag.							
		SWRSF: Software Reset Force and Flag. 0: <b>Read:</b> Source of last reset was not a write to the SWRSF bit. <b>Write:</b> No Effect.									
	1: Read: Sou										
Bit 3:	WDTRSF: W						,				
	0: Source of										
	1: Source of	last reset w	as a WDT	timeout.							
Bit 2:	MCDRSF: M	lissing Cloc	k Detector	Flag.							
	0: Read: Sou	urce of last ector disable		not a Missin	g Clock Det	ector timeo	ut. Write: N	lissing			
	1: Read: Sou			a Missing Cl	ock Detecto	r timeout	Nrito: Missi	ing Clock			
	Detector e	nabled; trig	gers a rese	et if a missin							
	PORSF: Pov										
Bit 1:	<b>T</b> 1.1.1.1.14.1.1.1.1			•				u			
Bit 1:	This bit is se	t anytime a	power-on	reset occurs							
Bit 1:	Monitor as a	t anytime a reset sourc	power-on æ. <b>Note: w</b>	reset occurs /riting '1' to	this bit bef	ore the V <sub>D</sub>	D Monitor i	is enabled			
Bit 1:	Monitor as a and stabilize 0: Read: Las	t anytime a reset sourc ed may cau st reset was	power-on æ. <b>Note: w</b> u <b>se a syst</b> e	reset occurs /riting '1' to em reset. Se	this bit bef	<b>fore the V<sub>D</sub></b> /DM0CN (ร	<b>D Monitor</b> i SFR Definiti	i <b>s enabled</b> on 12.1)			
Bit 1:	Monitor as a and stabilize 0: Read: Las reset source	t anytime a reset sourc ed may cau st reset was ce.	power-on æ. <b>Note: w</b> use a syst not a pow	reset occurs vriting '1' to em reset. So er-on or V <sub>DE</sub>	this bit bef ee register \ Monitor res	fore the V <sub>D</sub> /DM0CN (\$ set. <b>Write:</b>	<b>D Monitor</b> i SFR Definiti V <sub>DD</sub> Monito	i <b>s enabled</b> on 12.1)			
Bit 1:	Monitor as a and stabilize 0: Read: Las reset source 1: Read: Las	t anytime a reset sourc ed may cau st reset was ce. st reset was	power-on ce. <b>Note: w</b> use a systen not a power-co	reset occurs vriting '1' to em reset. Se er-on or V <sub>DD</sub> on or V <sub>DD</sub> Mo	this bit bef ee register \ Monitor resonation methods of the second monitor reset;	fore the V <sub>D</sub> /DM0CN (\$ set. <b>Write:</b>	<b>D Monitor</b> i SFR Definiti V <sub>DD</sub> Monito	i <b>s enabled</b> on 12.1)			
	Monitor as a and stabilize 0: Read: Las reset source 1: Read: Las indetermin	t anytime a reset sourc ed may cau st reset was ce. st reset was ate. Write:	power-on e. <b>Note: w</b> <b>use a syst</b> not a pow a power-o V <sub>DD</sub> Monit	reset occurs vriting '1' to em reset. So er-on or V <sub>DE</sub>	this bit bef ee register \ Monitor resonation methods of the second monitor reset;	fore the V <sub>D</sub> /DM0CN (\$ set. <b>Write:</b>	<b>D Monitor</b> i SFR Definiti V <sub>DD</sub> Monito	i <b>s enabled</b> on 12.1)			
Bit 1: Bit 0:	Monitor as a and stabilize 0: Read: Las reset source 1: Read: Las	t anytime a reset source ed may cau st reset was ce. st reset was ate. Write: V Pin Reset	power-on e. <b>Note: w</b> <b>use a syst</b> not a pow a power-c V <sub>DD</sub> Monit Flag.	reset occurs <b>riting '1' to</b> <b>em reset.</b> So er-on or V <sub>DD</sub> on or V <sub>DD</sub> Mo or is a reset _	this bit bef ee register \ Monitor resonation methods of the second monitor reset;	fore the V <sub>D</sub> /DM0CN (\$ set. <b>Write:</b>	<b>D Monitor</b> i SFR Definiti V <sub>DD</sub> Monito	i <b>s enabled</b> on 12.1)			

## SFR Definition 12.2. RSTSRC: Reset Source



#### Table 12.1. Reset Electrical Characteristics

-40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units
RST Output Low Voltage	I <sub>OL</sub> = 8.5 mA, V <sub>DD</sub> = 2.7 V to 3.6 V	_	_	0.6	V
RST Input High Voltage		0.7 x V <sub>DD</sub>	—	—	V
RST Input Low Voltage		—		0.7	V
RST Input Pullup Impedance		—	100	—	kΩ
$V_{DD}$ POR Threshold ( $V_{RST}$ )		2.40	2.55	2.70	V
Missing Clock Detector Time- out	Time from last system clock rising edge to reset initiation	100	400	600	μs
Reset Time Delay	Delay between release of any reset source and code execution at location 0x0000	40	_	_	μs
Minimum RST Low Time to Generate a System Reset		15			μs
V <sub>DD</sub> Monitor Supply Current			19	40	μA



# 13. Flash Memory

All devices include either 32 kB (C8051F360/1/2/3/4/5/6/7) or 16 kB (C8051F368/9) of on-chip, reprogrammable Flash memory for program code or non-volatile data storage. The Flash memory can be programmed in-system through the C2 interface, or by software using the MOVX write instructions. Once cleared to logic '0', a Flash bit must be erased to set it back to logic '1'. Bytes should be erased (set to 0xFF) before being reprogrammed. Flash write and erase operations are automatically timed by hardware for proper execution. During a Flash erase or write, the FLBUSY bit in the FLSTAT register is set to '1' (see SFR Definition 14.5). During this time, instructions that are located in the prefetch buffer or the branch target cache can be executed, but the processor will stall until the erase or write is completed if instruction data must be fetched from Flash memory. Interrupts that have been pre-loaded into the branch target cache can also be serviced at this time, if the current code is also executing from the prefetch engine or cache memory. Any interrupts that are not pre-loaded into cache, or that occur while the core is halted, will be held in a pending state during the Flash write/erase operation, and serviced in priority order once the Flash operation has completed. Refer to Table 13.2 for the electrical characteristics of the Flash memory.

### 13.1. Programming the Flash Memory

The simplest means of programming the Flash memory is through the C2 interface using programming tools provided by Silicon Labs or a third party vendor. This is the only means for programming a non-initialized device. For details on the C2 commands to program Flash memory, see Section "24. C2 Interface" on page 286. For detailed guidelines on writing or erasing Flash from firmware, please see Section "13.3. Flash Write and Erase Guidelines" on page 141.

The Flash memory can be programmed from software using the MOVX write instruction with the address and data byte to be programmed provided as normal operands. Before writing to Flash memory using MOVX, Flash write operations must be enabled by setting the PSWE Program Store Write Enable bit (PSCTL.0) to logic '1'. This directs the MOVX writes to Flash memory instead of to XRAM, which is the default target. The PSWE bit remains set until cleared by software. To avoid errant Flash writes, it is recommended that interrupts be disabled while the PSWE bit is logic '1'.

Flash memory is read using the MOVC instruction. MOVX reads are always directed to XRAM, regardless of the state of PSWE.

Note: To ensure the integrity of the Flash contents, the on-chip  $V_{DD}$  Monitor must be enabled in any system that includes code that writes and/or erases Flash memory from software. Furthermore, there should be no delay between enabling the  $V_{DD}$  Monitor and enabling the  $V_{DD}$  Monitor as a reset source. Any attempt to write or erase Flash memory while the  $V_{DD}$  Monitor disabled will cause a Flash Error device reset.

A write to Flash memory can clear bits but cannot set them; only an erase operation can set bits in Flash. A byte location to be programmed must be erased before a new value can be written.

Write/Erase timing is automatically controlled by hardware. Note that on the 32 k Flash devices, 1024 bytes beginning at location 0x7C00 are reserved. Flash writes and erases targeting the reserved area should be avoided.

#### 13.1.1. Flash Lock and Key Functions

Flash writes and erases by user software are protected with a lock and key function. The Flash Lock and Key Register (FLKEY) must be written with the correct key codes, in sequence, before Flash operations may be performed. The key codes are: 0xA5, 0xF1. The timing does not matter, but the codes must be written in order. If the key codes are written out of order, or the wrong codes are written, Flash writes and



erases will be disabled until the next system reset. Flash writes and erases will also be disabled if a Flash write or erase is attempted before the key codes have been written properly. The Flash lock resets after each write or erase; the key codes must be written again before a following Flash operation can be performed. The FLKEY register is detailed in SFR Definition 13.2.

#### 13.1.2. Erasing Flash Pages From Software

The Flash memory can be programmed by software using the MOVX write instruction with the address and data byte to be programmed provided as normal operands. Before writing to Flash memory using MOVX, Flash write operations must be enabled by: (1) the PSWE and PSEE bits must be set to '1' (this directs the MOVX writes to target Flash memory); and (2) Writing the Flash key codes in sequence to the Flash Lock register (FLKEY). The PSWE bit remains set until cleared by software.

A write to Flash memory can clear bits to logic '0' but cannot set them; only an erase operation can set bits to logic '1' in Flash. **A byte location to be programmed should be erased before a new value is written.** The Flash memory is organized in 1024-byte pages. The erase operation applies to an entire page (setting all bytes in the page to 0xFF). To erase an entire 1024-byte page, perform the following steps:

- Step 1. Disable interrupts (recommended).
- Step 2. Write the first key code to FLKEY: 0xA5.
- Step 3. Write the second key code to FLKEY: 0xF1.
- Step 4. Set PSEE (PSCTL.1) to enable Flash erases.
- Step 5. Set PSWE (PSCTL.0) to redirect MOVX commands to write to Flash.
- Step 6. Use the MOVX instruction to write a data byte to any location within the page to be erased.
- Step 7. Clear PSEE to disable Flash erases.
- Step 8. Clear the PSWE bit to redirect MOVX commands to the XRAM data space.
- Step 9. Re-enable interrupts.

#### 13.1.3. Writing Flash Memory From Software

Bytes in Flash memory can be written one byte at a time, or in small blocks. The CHBLKW bit in register CCH0CN (SFR Definition 14.1) controls whether a single byte or a block of bytes is written to Flash during a write operation. When CHBLKW is cleared to '0', the Flash will be written one byte at a time. When CHBLKW is set to '1', the Flash will be written in blocks of four bytes for addresses in code space. Block writes are performed in the same amount of time as single byte writes, which can save time when storing large amounts of data to Flash memory.

For single-byte writes to Flash, bytes are written individually, and the Flash write is performed after each MOVX write instruction. The recommended procedure for writing Flash in single bytes is as follows:

- Step 1. Disable interrupts.
- Step 2. Clear CHBLKW (register CCH0CN) to select single-byte write mode.
- Step 3. Write the first key code to FLKEY: 0xA5.
- Step 4. Write the second key code to FLKEY: 0xF1.
- Step 5. Set PSWE (register PSCTL) to redirect MOVX commands to write to Flash.
- Step 6. Clear the PSEE bit (register PSCTL).
- Step 7. Use the MOVX instruction to write a data byte to the desired location (repeat as necessary).
- Step 8. Clear the PSWE bit to redirect MOVX commands to the XRAM data space.
- Step 9. Re-enable interrupts.



Steps 3-8 must be repeated for each byte to be written

For block Flash writes, the Flash write procedure is only performed after the last byte of each block is written with the MOVX write instruction. When writing to addresses located in any of the four code banks, a Flash write block is four bytes long, from addresses ending in 00b to addresses ending in 11b. Writes must be performed sequentially (i.e. addresses ending in 00b, 01b, 10b, and 11b must be written in order). The Flash write will be performed following the MOVX write that targets the address ending in 11b. The Flash write will be performed following the MOVX write that targets the address ending in 1b. If any bytes in the block do not need to be updated in Flash, they should be written to 0xFF. The recommended procedure for writing Flash in blocks is as follows:

- Step 1. Disable interrupts.
- Step 2. Set CHBLKW (register CCH0CN) to select block write mode.
- Step 3. Write the first key code to FLKEY: 0xA5.
- Step 4. Write the second key code to FLKEY: 0xF1.
- Step 5. Set PSWE (register PSCTL) to redirect MOVX commands to write to Flash.
- Step 6. Clear the PSEE bit (register PSCTL).
- Step 7. Using the MOVX instruction, write the first data byte to the first block location (ending in 00b).
- Step 8. Clear the PSWE bit to redirect MOVX commands to the XRAM data space.
- Step 9. Write the first key code to FLKEY: 0xA5.
- Step 10. Write the second key code to FLKEY: 0xF1.
- Step 11. Set PSWE (register PSCTL) to redirect MOVX commands to write to Flash.
- Step 12. Clear the PSEE bit (register PSCTL).
- Step 13. Using the MOVX instruction, write the second data byte to the second block location (ending in 01b).
- Step 14. Clear the PSWE bit to redirect MOVX commands to the XRAM data space.
- Step 15. Write the first key code to FLKEY: 0xA5.
- Step 16. Write the second key code to FLKEY: 0xF1.
- Step 17. Set PSWE (register PSCTL) to redirect MOVX commands to write to Flash.
- Step 18. Clear the PSEE bit (register PSCTL).
- Step 19. Using the MOVX instruction, write the third data byte to the third block location (ending in 10b).
- Step 20. Clear the PSWE bit to redirect MOVX commands to the XRAM data space.
- Step 21. Write the first key code to FLKEY: 0xA5.
- Step 22. Write the second key code to FLKEY: 0xF1.
- Step 23. Set PSWE (register PSCTL) to redirect MOVX commands to write to Flash.
- Step 24. Clear the PSEE bit (register PSCTL).
- Step 25. Using the MOVX instruction, write the fourth data byte to the last block location (ending in 11b).
- Step 26. Clear the PSWE bit to redirect MOVX commands to the XRAM data space.
- Step 27. Re-enable interrupts.

Steps 3-26 must be repeated for each block to be written.

#### 13.1.4. Non-volatile Data Storage

The Flash memory can be used for non-volatile data storage as well as program code. This allows data such as calibration coefficients to be calculated and stored at run time. Data is written and erased using the MOVX write instruction (as described in Section 13.1.2 and Section 13.1.3) and read using the MOVC instruction. Note: MOVX read instructions always target XRAM.



#### 13.2. Security Options

The CIP-51 provides security options to protect the Flash memory from inadvertent modification by software as well as to prevent the viewing of proprietary program code and constants. The Program Store Write Enable (bit PSWE in register PSCTL) and the Program Store Erase Enable (bit PSEE in register PSCTL) bits protect the Flash memory from accidental modification by software. PSWE must be explicitly set to '1' before software can modify the Flash memory; both PSWE and PSEE must be set to '1' before software can erase Flash memory. Additional security features prevent proprietary program code and data constants from being read or altered across the C2 interface.

A Security Lock Byte located at the last byte of Flash user space offers protection of the Flash program memory from access (reads, writes, or erases) by unprotected code or the C2 interface. The Flash security mechanism allows the user to lock n 1024-byte Flash pages, starting at page 0 (addresses 0x0000 to 0x03FF), where n is the 1's complement number represented by the Security Lock Byte. Note that the page containing the Flash Security Lock Byte is unlocked when no other Flash pages are locked (all bits of the Lock Byte are '1') and locked when any other Flash pages are locked (any bit of the Lock Byte is '0'). See the example below for an C8051F360.

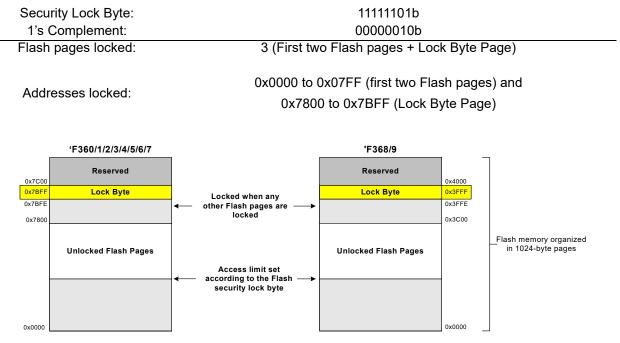


Figure 13.1. Flash Program Memory Map



#### 13.2.1. Summary of Flash Security Options

The level of Flash security depends on the Flash access method. The three Flash access methods that can be restricted are reads, writes, and erases from the C2 debug interface, user firmware executing on unlocked pages, and user firmware executing on locked pages. Table 13.1 summarizes the Flash security features of the C8051F36x devices.

Action	C2 Debug	User Firmware executing from:			
	Interface	an unlocked page	a locked page		
Read, Write or Erase unlocked pages (except page with Lock Byte)	Permitted	Permitted	Permitted		
Read, Write or Erase locked pages (except page with Lock Byte)	Not Permitted	FEDR	Permitted		
Read or Write page containing Lock Byte (if no pages are locked)	Permitted	Permitted	Permitted		
Read or Write page containing Lock Byte (if any page is locked)	Not Permitted	FEDR	Permitted		
Read contents of Lock Byte (if no pages are locked)	Permitted	Permitted	Permitted		
Read contents of Lock Byte (if any page is locked)	Not Permitted	FEDR	Permitted		
Erase page containing Lock Byte (if no pages are locked)	Permitted	FEDR	FEDR		
Erase page containing Lock Byte - Unlock all pages (if any page is locked)	Only C2DE	FEDR	FEDR		
Lock additional pages (change '1's to '0's in the Lock Byte)	Not Permitted	FEDR	FEDR		
Unlock individual pages (change '0's to '1's in the Lock Byte)	Not Permitted	FEDR	FEDR		
Read, Write or Erase Reserved Area	Not Permitted	FEDR	FEDR		

Table '	13.1.	Flash	Security	Summary
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C2DE - C2 Device Erase (Erases all Flash pages including the page containing the Lock Byte) FEDR - Not permitted; Causes Flash Error Device Reset (FERROR bit in RSTSRC is '1' after reset)

All prohibited operations that are performed via the C2 interface are ignored (do not cause device reset).
 Locking any Flash page also locks the page containing the Lock Byte.

- Once written to, the Lock Byte cannot be modified except by performing a C2 Device Erase.
- If user code writes to the Lock Byte, the Lock does not take effect until the next device reset.



#### 13.3. Flash Write and Erase Guidelines

Any system which contains routines which write or erase Flash memory from software involves some risk that the write or erase routines will execute unintentionally if the CPU is operating outside its specified operating range of  $V_{DD}$ , system clock frequency, or temperature. This accidental execution of Flash modi-fying code can result in alteration of Flash memory contents causing a system failure that is only recoverable by re-Flashing the code in the device.

To help prevent the accidental modification of Flash by firmware, the  $V_{DD}$  Monitor must be enabled and enabled as a reset source on C8051F36x devices for the Flash to be successfully modified. If either the  $V_{DD}$  Monitor or the  $V_{DD}$  Monitor reset source is not enabled, a Flash Error Device Reset will be generated when the firmware attempts to modify the Flash.

The following guidelines are recommended for any system that contains routines which write or erase Flash from code.

#### 13.3.1. $V_{DD}$ Maintenance and the $V_{DD}$ Monitor

- 1. If the system power supply is subject to voltage or current "spikes," add sufficient transient protection devices to the power supply to ensure that the supply voltages listed in the Absolute Maximum Ratings table are not exceeded.
- 2. Make certain that the minimum  $V_{DD}$  rise time specification of 1 ms is met. If the system cannot meet this rise time specification, then add an external  $V_{DD}$  brownout circuit to the /RST pin of the device that holds the device in reset until  $V_{DD}$  reaches  $V_{RST}$  and re-asserts /RST if  $V_{DD}$  drops below  $V_{RST}$ . Please see Table 12.1, "Reset Electrical Characteristics," on page 135 for more information on the VDD Monitor Threshold voltage ( $V_{RST}$ ).
- 3. Keep the on-chip V<sub>DD</sub> Monitor enabled and enable the V<sub>DD</sub> Monitor as a reset source as early in code as possible. This should be the first set of instructions executed after the Reset Vector. For 'C'-based systems, this will involve modifying the startup code added by the 'C' compiler. See your compiler documentation for more details. Make certain that there are no delays in software between enabling the V<sub>DD</sub> Monitor and enabling the V<sub>DD</sub> Monitor as a reset source. Code examples showing this can be found in AN201, "Writing to Flash from Firmware", available from the Silicon Laboratories web site.

**Note:** On C8051F36x devices, both the  $V_{DD}$  Monitor and the  $V_{DD}$  Monitor reset source must be enabled to write or erase Flash without generating a Flash Error Device Reset.

- 4. As an added precaution, explicitly enable the V<sub>DD</sub> Monitor and enable the V<sub>DD</sub> Monitor as a reset source inside the functions that write and erase Flash memory. The V<sub>DD</sub> Monitor enable instructions should be placed just after the instruction to set PSWE to a '1', but before the Flash write or erase operation instruction.
- Make certain that all writes to the RSTSRC (Reset Sources) register use direct assignment operators and explicitly DO NOT use the bit-wise operators (such as AND or OR). For example, "RSTSRC = 0x02" is correct, but "RSTSRC |= 0x02" is incorrect.
- 6. Make certain that all writes to the RSTSRC register explicitly set the PORSF bit to a '1'. Areas to check are initialization code which enables other reset sources, such as the Missing Clock Detector or Comparator, for example, and instructions which force a Software Reset. A global search on "RSTSRC" can quickly verify this.



#### 13.3.2. 16.4.2 PSWE Maintenance

- 7. Reduce the number of places in code where the PSWE bit (b0 in PSCTL) is set to a '1'. There should be exactly one routine in code that sets PSWE to a '1' to write Flash bytes and one routine in code that sets both PSWE and PSEE both to a '1' to erase Flash pages.
- 8. Minimize the number of variable accesses while PSWE is set to a '1'. Handle pointer address updates and loop maintenance outside the "PSWE = 1; ... PSWE = 0;" area. Code examples showing this can be found in AN201, "Writing to Flash from Firmware", available from the Silicon Laboratories web site.
- 9. Disable interrupts prior to setting PSWE to a '1' and leave them disabled until after PSWE has been reset to '0'. Any interrupts posted during the Flash write or erase operation will be serviced in priority order after the Flash operation has been completed and interrupts have been re-enabled by software.
- 10. Make certain that the Flash write and erase pointer variables are not located in XRAM. See your compiler documentation for instructions regarding how to explicitly locate variables in different memory areas.
- 11. Add address bounds checking to the routines that write or erase Flash memory to ensure that a routine called with an illegal address does not result in modification of the Flash.

#### 13.3.3. System Clock

- 12. If operating from an external crystal, be advised that crystal performance is susceptible to electrical interference and is sensitive to layout and to changes in temperature. If the system is operating in an electrically noisy environment, use the internal oscillator or use an external CMOS clock.
- 13. If operating from the external oscillator, switch to the internal oscillator during Flash write or erase operations. The external oscillator can continue to run, and the CPU can switch back to the external oscillator after the Flash operation has completed.

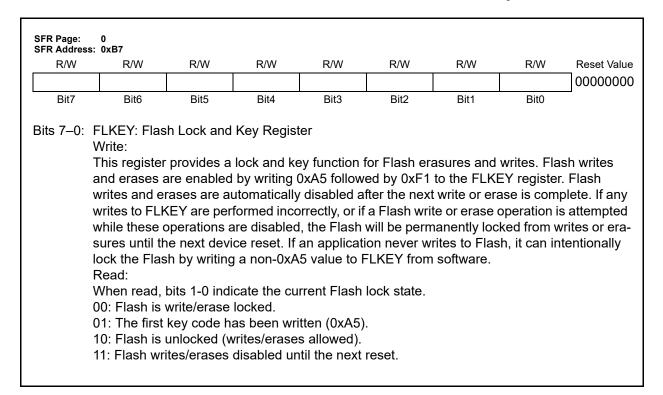
Rev. 1.2



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-	-	—	-	PSEE	PSWE	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
bits 7–2:	UNUSED. R	ead = 0000	00b. Write	= don't care	<del>)</del> .			
Sit 1:	PSEE: Progr							
	Setting this b				sh program	memory to	be erased	brovided
	the PSWE bi							•
				•				
	instruction w	ill erase the	entire pad	e that conta	ains the loca	ation addres	ssed by the	MOVX
	instruction w							
	instruction. T	he value of	f the data by	yte written o	does not ma	atter. Note:	The Flash	page con
	instruction. T taining the I	The value of Read Lock	f the data by <b>Byte and V</b>	yte written o <b>Vrite/Erase</b>	does not ma	atter. Note:	The Flash	page con
	instruction. T taining the I 0: Flash prog	The value of <b>Read Lock</b> gram memo	f the data by <b>Byte and V</b> ory erasure	yte written ( <b>Vrite/Erase</b> disabled.	does not ma	atter. Note:	The Flash	page con-
	instruction. T taining the I 0: Flash prog 1: Flash prog	The value of <b>Read Lock</b> gram memo gram memo	f the data by <b>Byte and V</b> ory erasure ory erasure	yte written o <b>Vrite/Erase</b> disabled. enabled.	does not ma	atter. Note:	The Flash	page con
it O:	instruction. T taining the I 0: Flash prog 1: Flash prog PSWE: Prog	The value of <b>Read Lock</b> gram memo gram memo ram Store V	f the data by <b>Byte and V</b> ory erasure ory erasure Write Enable	yte written o <b>Nrite/Erase</b> disabled. enabled. e.	does not ma e Lock Byte	atter. Note: a cannot be	The Flash erased b	page con y software
it 0:	instruction. T taining the I 0: Flash prog 1: Flash prog PSWE: Prog Setting this b	The value of Read Lock gram memo gram memo ram Store N pit allows w	f the data by <b>Byte and V</b> ory erasure ory erasure Write Enable riting a byte	yte written o <b>Write/Erase</b> disabled. enabled. e. of data to t	does not ma e <b>Lock Byte</b> the Flash pr	atter. Note: a cannot be	The Flash erased b	page con y software
Sit O:	instruction. T taining the I 0: Flash prog 1: Flash prog PSWE: Prog Setting this b write instruct	The value of Read Lock gram memo gram memo ram Store N pit allows w ion. The loo	f the data by Byte and V ory erasure ory erasure Write Enable riting a byte cation must	yte written of <b>Write/Erase</b> disabled. enabled. e. of data to t be erased	does not ma <b>Lock Byte</b> the Flash pr prior to writ	atter. Note: cannot be ogram men ing data.	The Flash e erased b nory using	page con y software the MOVX
Bit O:	instruction. T taining the I 0: Flash prog 1: Flash prog PSWE: Prog Setting this b	The value of Read Lock gram memo gram memo iram Store N pit allows wi cion. The loc lash progra	f the data by Byte and V ory erasure Vrite Enable riting a byte cation must m memory	yte written of <b>Write/Erase</b> disabled. enabled. e. of data to t be erased disabled. M	does not ma <b>Lock Byte</b> the Flash pr prior to writ IOVX write	atter. Note: cannot be ogram men ing data. operations t	The Flash e erased b nory using target Exte	page cor y softwar the MOV> rnal RAM.

#### SFR Definition 13.1. PSCTL: Program Store Read/Write Control

### SFR Definition 13.2. FLKEY: Flash Lock and Key





#### 13.4. Flash Read Timing

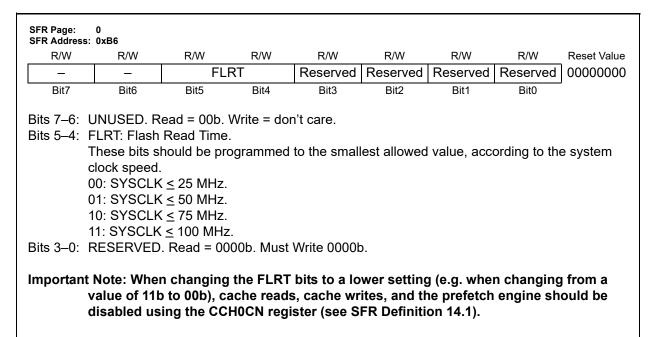
On reset, the C8051F36x Flash read timing is configured for operation with system clocks up to 25 MHz. If the system clock will not be increased above 25 MHz, then the Flash timing registers may be left at their reset value.

For every Flash read or fetch, the system provides an internal Flash read strobe to the Flash memory. The Flash read strobe lasts for one or two system clock cycles, based on the FLRT bits (FLSCL.4 and FLSCL.5). **If the system clock is greater than 25 MHz, the FLRT bit must be changed to the appropriate setting.** Otherwise, data read or fetched from Flash may not represent the actual contents of Flash. When the Flash read strobe is asserted, Flash memory is active. When it is de-asserted, Flash memory is in a low power state.

The recommended procedure for updating FLRT is:

- Step 1. Select SYSCLK to 25 MHz or less.
- Step 2. Disable the prefetch engine (CHPFEN = '0' in CCH0CN register).
- Step 3. Set the FLRT bits to the appropriate setting for the SYSCLK.
- Step 4. Enable the prefetch engine (CHPFEN = '1' in CCH0CN register).

#### SFR Definition 13.3. FLSCL: Flash Memory Control





### **Table 13.2. Flash Electrical Characteristics**

 $V_{DD}$  = 2.7 to 3.6 V; -40 to +85 °C.

Parameter	Conditions	Min	Тур	Мах	Units		
Flash Size	C8051F360/1/2/3/4/5/6/7		32768*				
FIDSIT SIZE	C8051F368/9		16384		Bytes		
Endurance		20 k	250 k		Erase/Write		
Erase Cycle Time		8	10	12	ms		
Write Cycle Time		37	47	57	μs		
*Note: 1024 Bytes at	location 0x7C00 to 0x7FFF are reserve	ed.	•		•		



## 14. Branch Target Cache

The C8051F36x device families incorporate a 32x4 byte branch target cache with a 4-byte prefetch engine. Because the access time of the Flash memory is 40 ns, and the minimum instruction time is 10 ns (C8051F360/1/2/3/4/5/6/7) or 20 ns (C8051F368/9), the branch target cache and prefetch engine are necessary for full-speed code execution. Instructions are read from Flash memory four bytes at a time by the prefetch engine, and given to the CIP-51 processor core to execute. When running linear code (code without any jumps or branches), the prefetch engine alone allows instructions to be executed at full speed. When a code branch occurs, a search is performed for the branch target (destination address) in the cache. If the branch target information is found in the cache (called a "cache hit"), the instruction data is read from the cache and immediately returned to the CIP-51 with no delay in code execution. If the branch target is not found in the cache (called a "cache miss"), the processor may be stalled for up to four clock cycles while the next set of four instructions is retrieved from Flash memory. Each time a cache miss occurs, the requested instruction data is written to the cache if allowed by the current cache settings. A data flow diagram of the interaction between the CIP-51 and the Branch Target Cache and Prefetch Engine is shown in Figure 14.1.

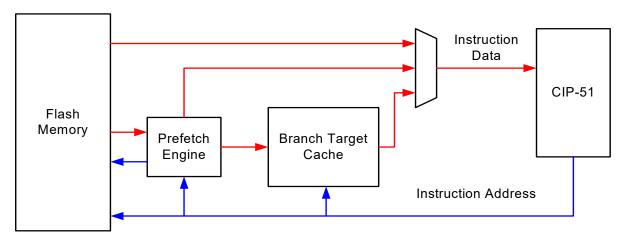


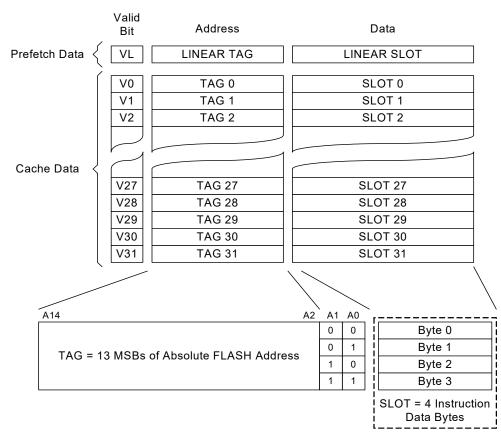
Figure 14.1. Branch Target Cache Data Flow

## 14.1. Cache and Prefetch Operation

The branch target cache maintains two sets of memory locations: "slots" and "tags". A slot is where the cached instruction data from Flash is stored. Each slot holds four consecutive code bytes. A tag contains the 13 most significant bits of the corresponding Flash address for each four-byte slot. Thus, instruction data is always cached along four-byte boundaries in code space. A tag also contains a "valid bit", which indicates whether a cache location contains valid instruction data. A special cache location (called the linear tag and slot), is reserved for use by the prefetch engine. The cache organization is shown in Figure 14.2. Each time a Flash read is requested, the address is compared with all valid cache tag locations (including the linear tag). If any of the tag locations match the requested address, the data from that slot is immediately provided to the CIP-51. If the requested address matches a location that is currently being read by the prefetch engine, the CIP-51 will be stalled until the read is complete. If a match is not found, the current prefetch operation is abandoned, and a new prefetch operation is initiated for the requested instruction data. When the prefetch engine begins reading the next four-byte word from Flash memory. If the newly-fetched data also meets the criteria necessary to be cached, it will be written to the cache in the slot indicated by the current replacement algorithm.



The replacement algorithm is selected with the Cache Algorithm bit, CHALGM (CCH0TN.3). When CHALGM is cleared to '0', the cache will use the rebound algorithm to replace cache locations. The rebound algorithm replaces locations in order from the beginning of cache memory to the end, and then from the end of cache memory to the beginning. When CHALGM is set to '1', the cache will use the pseudo-random algorithm to replace cache locations. The pseudo-random algorithm uses a pseudo-random number to determine which cache location to replace. The cache can be manually emptied by writing a '1' to the CHFLUSH bit (CCH0CN.4).





## 14.2. Cache and Prefetch Optimization

By default, the branch target cache is configured to provide code speed improvements for a broad range of circumstances. **In most applications, the cache control registers should be left in their reset states.** Sometimes it is desirable to optimize the execution time of a specific routine or critical timing loop. The branch target cache includes options to exclude caching of certain types of data, as well as the ability to pre-load and lock time-critical branch locations to optimize execution speed.

The most basic level of cache control is implemented with the Cache Miss Penalty Threshold bits, CHMSTH (CCH0TN.1–0). If the processor is stalled during a prefetch operation for more clock cycles than the number stored in CHMSTH, the requested data will be cached when it becomes available. The CHMSTH bits are set to zero by default, meaning that any time the processor is stalled, the new data will be cached. If, for example, CHMSTH is equal to 2, any cache miss causing a delay of 3 or 4 clock cycles will be cached, while a cache miss causing a delay of 1–2 clock cycles will not be cached.



Certain types of instruction data or certain blocks of code can also be excluded from caching. The destinations of RETI instructions are, by default, excluded from caching. To enable caching of RETI destinations, the CHRETI bit (CCH0CN.3) can be set to '1'. It is generally not beneficial to cache RETI destinations unless the same instruction is likely to be interrupted repeatedly (such as a code loop that is waiting for an interrupt to happen). Instructions that are part of an interrupt service routine (ISR) can also be excluded from caching. By default, ISR instructions are cached, but this can be disabled by clearing the CHISR bit (CCH0CN.2) to '0'. The other information that can be explicitly excluded from caching are the data returned by MOVC instructions. Clearing the CHMOV bit (CCH0CN.1) to '0' will disable caching of MOVC data. If MOVC caching is allowed, it can be restricted to only use slot 0 for the MOVC information (excluding cache push operations). The CHFIXM bit (CCH0TN.2) controls this behavior.

Further cache control can be implemented by disabling all cache writes. Cache writes can be disabled by clearing the CHWREN bit (CCH0CN.7) to '0'. Although normal cache writes (such as those after a cache miss) are disabled, data can still be written to the cache with a cache push operation. Disabling cache writes can be used to prevent a non-critical section of code from changing the cache contents. Note that regardless of the value of CHWREN, a Flash write or erase operation automatically removes the affected bytes from the cache. Cache reads and the prefetch engine can also be individually disabled. Disabling cache reads forces all instructions data to execute from Flash memory or from the prefetch engine. To disable cache reads, the CHRDEN bit (CCH0CN.6) can be cleared to '0'. Note that when cache reads are disabled, cache writes will still occur (if CHWREN is set to '1'). Disabling the prefetch engine is accomplished using the CHPFEN bit (CCH0CN.5). When this bit is cleared to '0', the prefetch engine will be disabled. If both CHPFEN and CHRDEN are '0', code will execute at a fixed rate, as instructions become available from the Flash memory.

Cache locations can also be pre-loaded and locked with time-critical branch destinations. For example, in a system with an ISR that must respond as fast as possible, the entry point for the ISR can be locked into a cache location to minimize the response latency of the ISR. Up to 30 locations can be locked into the cache at one time. Instructions are locked into cache by enabling cache push operations with the CHPUSH bit (CCH0LC.7). When CHPUSH is set to '1', a MOVC instruction will cause the four-byte segment containing the data byte to be written to the cache slot location indicated by CHSLOT (CCH0LC.4-0). CHSLOT is them decremented to point to the next lockable cache location. This process is called a cache push operation. Cache locations that are above CHSLOT are "locked", and cannot be changed by the processor core, as shown in Figure 14.3. Cache locations can be unlocked by using a cache pop operation. A cache pop is performed by writing a '1' to the CHPOP bit (CCH0LC.6). When a cache pop is initiated, the value of CHSLOT is incremented. This unlocks the most recently locked cache location, but does not remove the information from the cache. Note that a cache pop should not be initiated if CHSLOT is equal to 11110b. Doing so may have an adverse effect on cache performance. Important: Although locking cache location 1 is not explicitly disabled by hardware, the entire cache will be unlocked when CHSLOT is equal to 00000b. Therefore, cache locations 1 and 0 must remain unlocked at all times.



			Lock Status
	TAG 0	SLOT 0	UNLOCKED
	TAG 1	SLOT 1	UNLOCKED
Cache Push	TAG 2	SLOT 2	UNLOCKED
Operations			UNLOCKED
Decrement CHSLOT			1
<b>A</b>			
	TAG 26	SLOT 26	UNLOCKED
CHSLOT = 27	TAG 27	SLOT 27	UNLOCKED
	TAG 28	SLOT 28	LOCKED
▼ Cache Pop	TAG 29	SLOT 29	LOCKED
Operations	TAG 30	SLOT 30	LOCKED
Increment	TAG 31	SLOT 31	LOCKED
CHSLOT			-

Figure 14.3. Cache Lock Operation



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
CHWRE		CHPFEN	CHFLSH	CHRETI	CHISR	CHMOVC	CHBLKW	11100110
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	CHWREN: C	Cache Write	Enable.					
	This bit enab	•						
	0: Cache cor	ntents are n	ot allowed	to change, e	except duri	ng Flash wr	ites/erasure	es or cache
	locks.							
	1: Writes to o			wed.				
Bit 6:	CHRDEN: C							
	This bit enab	•						
	0: All instruct				• •	-	ne.	
	1: Instruction			cache (whe	n available	e).		
Bit 5:	CHPFEN: Ca			_				
	This bit enab		0	Э.				
	0: Prefetch e 1: Prefetch e							
Bit 4:	CHFLSH: Ca	•	abieu.					
Dit <del>4</del> .	When writter		is hit clears	the cache (	ontents T	his hit alway	/s reads 'Ω'	
Bit 3:	CHRETI: Ca				Jontento. 1	This bit alway	/3 TCau3 0	
Dit U.	This bit enab				ess to be o	cached		
	0: Destinatio							
	1: RETI dest				caome a.			
Bit 2:	CHISR: Cac	he ISR Ena	ble.	-				
	This bit allow	s instructio	ns which ar	e part of an	Interrupt S	Service Rout	ine (ISR) to	be cached
	0: Instructior			•	•		( )	
	1: Instruction	is in ISRs c	an be cach	ed.		-		
Bit 1:	CHMOVC: C	ache MOV	C Enable.					
	This bit allow	/s data requ	lested by a	MOVC inst	ruction to b	be loaded int	to the cache	e memory.
	0: Data requ	ested by M	OVC instruc	ctions will no	ot be cache	ed.		
	1: Data requ	ested by M	OVC instrue	ctions will be	e loaded in	to cache me	emory.	
Bit 0:	CHBLKW: B							
	This bit allow							
	0: Each byte					•		
	1. Flash hyte	s are writte	n in aroups	of four (for	code spac	e writes).		

## SFR Definition 14.1. CCH0CN: Cache Control



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
	CHM	SCTL		CHALGM	CHFIXM	CHM	ISTH	00000100
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
its 7–4:	CHMSCTL:	Cache Miss	Penalty A	ccumulator	(Bits 4–1).			
	These are bi	ts 4-1 of the	Cache Mis	ss Penalty A	ccumulator.	To read the	ese bits, th	ney must first
	be latched by	y reading th	ne CHMSC	TH bits in th	e CCH0MA	Register (S	See SFR I	Definition
	14.4).	-						
sit 3:	CHÁLGM: C	ache Algor	ithm Select	-				
	This bit seled	-			m.			
	0: Cache use	es Rebound	algorithm					
	1: Cache use		-					
Bit 2:	CHFIXM: Ca	che Fix MC	OVC Enable	ð.				
	This bit force	s MOVC w	rites to the	cache mem	ory to use s	slot 0.		
	0: MOVC da				•		y the CHA	ALGM bit.
	1: MOVC da		•		•			
Bits 1–0:	CHMSTH: C							
	These bits d		•		data will be	cached.		

## SFR Definition 14.2. CCH0TN: Cache Tuning



R/W	R/W	R	R	R	R	R	R	Reset Value
CHPUSH	H CHPOP	RESERVED			CHSLOT			00011111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	CHPUSH: C	ache Push En	able.					
	This bit enal	oles cache pus	sh operatio	ons, which v	will lock info	rmation in	cache slo	ts using
	MOVC instru		•					U
	0: Cache pu	sh operations	are disabl	ed.				
	1: Cache pu	sh operations	are enable	ed. When a	MOVC read	d is execut	ed, the re	quested 4-
	byte segm	ent containing	the data i	is locked in	to the cache	e at the loca	ation indic	ated by
	CHSLOT,	and CHSLOT	is decrem	ented.				
		e than 30 cache	slots shoul		at one time, s	since the en	tire cache v	will be unlock
Bit 6:	when CHSLC	T is equal to 0.	slots shoul		at one time, s	since the ent	tire cache v	will be unlock
Bit 6:	when CHSLC CHPOP: Ca	T is equal to 0. che Pop.		ld be locked				
Bit 6:	when CHSLC CHPOP: Ca Writing a '1'	T is equal to 0. che Pop. to this bit will i	ncrement	ld be locked CHSLOT a	nd then unlo	ock that loc	ation. Thi	is bit always
Bit 6:	when CHSLC CHPOP: Ca Writing a '1' reads '0'. No	T is equal to 0. che Pop. to this bit will i ote that Cache	ncrement Pop opera	ld be locked CHSLOT a ations shou	nd then unle Id not be pe	ock that loc erformed wl	ation. Thi	is bit always .OT =
Bit 6:	when CHSLC CHPOP: Ca Writing a '1' reads '0'. No 11110b. "Pop	oT is equal to 0. che Pop. to this bit will i ote that Cache o"ing more Cac	ncrement Pop opera che slots tl	ld be locked CHSLOT a ations shou	nd then unle Id not be pe	ock that loc erformed wl	ation. Thi	is bit always .OT =
	when CHSLC CHPOP: Ca Writing a '1' reads '0'. No 11110b. "Pop on the Cach	oT is equal to 0. che Pop. to this bit will i ote that Cache o"ing more Cac e performance	ncrement Pop opera che slots tl e.	ld be locked CHSLOT a ations shou han have be	nd then unle Id not be pe	ock that loc erformed wl	ation. Thi	is bit always _OT =
Bit 5:	when CHSLC CHPOP: Ca Writing a '1' reads '0'. No 11110b. "Pop on the Cach RESERVED	T is equal to 0. che Pop. to this bit will i ote that Cache o"ing more Cac e performance 0. Read = 0b. N	ncrement Pop opera che slots tl e. ⁄lust Write	ld be locked CHSLOT a ations shou han have be	nd then unle Id not be pe	ock that loc erformed wl	ation. Thi	is bit always .OT =
Bit 6: Bit 5: Bits 4–0:	when CHSLC CHPOP: Ca Writing a '1' reads '0'. No 11110b. "Poj on the Cach RESERVED CHSLOT: Ca	oT is equal to 0. che Pop. to this bit will i ote that Cache o"ing more Cac e performance	ncrement Pop opera che slots tl e. /lust Write ter.	ld be locked CHSLOT a ations shou han have bo 0b.	nd then unk ld not be pe een "Push"e	ock that loc erformed wl ed will have	ation. Thi hile CHSL indeterm	is bit always .OT = inate results

### SFR Definition 14.3. CCH0LC: Cache Lock Control



R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
CHMSO	V			CHMSCTH				0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	CHMSOV: C	Cache Miss	Penalty Ov	erflow.				
	This bit indic				y Accumula	tor has ove	rflowed si	nce it was
	last written.				-			
	0: The Cach	e Miss Pen	alty Accum	ulator has n	ot overflow	ed since it v	vas last w	ritten.
	1: An overflo	w of the Ca	che Miss P	enalty Accu	mulator has	s occurred s	since it wa	s last writte
				01101109710000				3 last writter
8its 6–0:	CHMSCTH:	Cache Miss		•				
Bits 6–0:	CHMSCTH: These are b		s Penalty A	ccumulator	(bits 11–5)			
3its 6–0:		its 11-5 of th	s Penalty A ne Cache M	ccumulator liss Penalty	(bits 11–5)			
Bits 6–0:	These are b	its 11-5 of th IMSCTL in t	s Penalty A ne Cache M the CCH0T	ccumulator liss Penalty N register.	(bits 11–5) Accumulate	or. The next	t four bits	(bits 4-1) are
3its 6–0:	These are bi stored in CH	its 11-5 of th IMSCTL in t Miss Penalty	s Penalty A ne Cache M the CCH0T y Accumula	ccumulator liss Penalty N register. tor is incren	(bits 11–5) Accumulate nented ever	or. The next	t four bits	(bits 4-1) are processor is
3its 6–0:	These are b stored in CH The Cache N	its 11-5 of th IMSCTL in t Miss Penalty to a cache	s Penalty A ne Cache M the CCH0T y Accumula miss. This i	ccumulator liss Penalty N register. tor is incren	(bits 11–5) Accumulate nented ever	or. The next	t four bits	(bits 4-1) are processor is
3its 6–0:	These are b stored in CH The Cache N delayed due	its 11-5 of th IMSCTL in t Miss Penalty to a cache ecution spee	s Penalty A ne Cache M the CCH0T y Accumula miss. This i ed.	ccumulator liss Penalty N register. tor is incren is primarily u	(bits 11–5) Accumulate nented ever used as a di	or. The next y clock cycl agnostic fe	t four bits le that the ature, whe	(bits 4-1) are processor i en optimizing
3its 6–0:	These are bi stored in CH The Cache M delayed due code for exe	its 11-5 of th IMSCTL in the Miss Penalty to a cache scution spee HMSCTH cl	s Penalty A ne Cache M the CCH0T y Accumula miss. This i ed. lears the low	ccumulator liss Penalty N register. tor is incren is primarily u wer 5 bits of	(bits 11–5) Accumulate nented ever used as a di	or. The next y clock cycl agnostic fe Miss Penal	t four bits le that the ature, whe	(bits 4-1) ard processor is en optimizing ulator.
Bits 6–0:	These are bi stored in CH The Cache M delayed due code for exe Writing to Ch	its 11-5 of th IMSCTL in the Miss Penalty to a cache cution spee HMSCTH cl m CHMSCT	s Penalty A ne Cache M the CCH0T y Accumula miss. This i ed. lears the low Th returns the	ccumulator liss Penalty N register. tor is incren is primarily t wer 5 bits of he current v	(bits 11–5) Accumulate nented ever used as a di the Cache alue of CHI	or. The next y clock cycl agnostic fe Miss Penal MSTCH, an	t four bits le that the ature, whe lty Accum d latches	(bits 4-1) a processor en optimizin ulator. bits 4-1 int

## SFR Definition 14.4. CCH0MA: Cache Miss Accumulator

## SFR Definition 14.5. FLSTAT: Flash Status

R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	FLBUSY	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	,
٦	FLBUSY: Fla Fhis bit indic ): Flash is id	ates when a lle or readin	ıg.	e or erase or rrently in pr	•	in progress	i.	



## 15. External Data Memory Interface and On-Chip XRAM

For C8051F36x devices, 1k Bytes of RAM are included on-chip and mapped into the external data memory space (XRAM). Additionally, an External Memory Interface (EMIF) is available on the C8051F360/3 devices, which can be used to access off-chip data memories and memory-mapped devices connected to the GPIO ports. The external memory space may be accessed using the external move instruction (MOVX) and the data pointer (DPTR), or using the MOVX indirect addressing mode using R0 or R1. If the MOVX instruction is used with an 8-bit address operand (such as @R1), then the high byte of the 16-bit address is provided by the External Memory Interface Control Register (EMIOCN, shown in SFR Definition 15.1). Note: the MOVX instruction can also be used for writing to the FLASH memory. See Section "13. Flash Memory" on page 136 for details. The MOVX instruction accesses XRAM by default.

### 15.1. Accessing XRAM

The XRAM memory space is accessed using the MOVX instruction. The MOVX instruction has two forms, both of which use an indirect addressing method. The first method uses the Data Pointer, DPTR, a 16-bit register which contains the effective address of the XRAM location to be read from or written to. The second method uses R0 or R1 in combination with the EMI0CN register to generate the effective XRAM address. Examples of both of these methods are given below.

#### 15.1.1. 16-Bit MOVX Example

The 16-bit form of the MOVX instruction accesses the memory location pointed to by the contents of the DPTR register. The following series of instructions reads the value of the byte at address 0x1234 into the accumulator A:

MOVDPTR, #1234h; load DPTR with 16-bit address to read (0x1234)MOVXA, @DPTR; load contents of 0x1234 into accumulator A

The above example uses the 16-bit immediate MOV instruction to set the contents of DPTR. Alternately, the DPTR can be accessed through the SFR registers DPH, which contains the upper 8-bits of DPTR, and DPL, which contains the lower 8-bits of DPTR.

#### 15.1.2. 8-Bit MOVX Example

The 8-bit form of the MOVX instruction uses the contents of the EMI0CN SFR to determine the upper 8-bits of the effective address to be accessed and the contents of R0 or R1 to determine the lower 8-bits of the effective address to be accessed. The following series of instructions read the contents of the byte at address 0x1234 into the accumulator A.

MOV	EMIOCN, #12h	; load high byte of address into EMIOCN	
MOV	R0, #34h	; load low byte of address into R0 (or R1)	
MOVX	a, @RO	; load contents of 0x1234 into accumulator A	Ŧ



## **15.2.** Configuring the External Memory Interface

Configuring the External Memory Interface consists of five steps:

- 1. Configure the Output Modes of the associated port pins as either push-pull or open-drain (push-pull is most common), and skip the associated pins in the crossbar.
- 2. Configure Port latches to "park" the EMIF pins in a dormant state (usually by setting them to logic '1').
- 3. Select Multiplexed mode or Non-multiplexed mode.
- 4. Select the memory mode (on-chip only, split mode without bank select, split mode with bank select, or off-chip only).
- 5. Set up timing to interface with off-chip memory or peripherals.

Each of these five steps is explained in detail in the following sections. The Port selection, Multiplexed mode selection, and Mode bits are located in the EMI0CF register shown in SFR Definition 15.2.

#### 15.3. Port Configuration

The External Memory Interface appears on Ports 1, 2 (non-multiplexed mode only), 3, and 4 when it is used for off-chip memory access. When the EMIF is used in multiplexed mode, the Crossbar should be configured to skip over the ALE control line (P0.0) using the P0SKIP register. The other control lines, /RD (P4.4) and /WR (P4.5), are not available on the Crossbar and do not need to be skipped. For more information about configuring the Crossbar, see Section "17.3. General Purpose Port I/O" on page 191. The EMIF pinout is shown in Table 15.1 on page 156.

The External Memory Interface claims the associated Port pins for memory operations ONLY during the execution of an off-chip MOVX instruction. Once the MOVX instruction has completed, control of the Port pins reverts to the Port latches or to the Crossbar settings for those pins. See Section "17. Port Input/Output" on page 184 for more information about the Crossbar and Port operation and configuration. **The Port latches should be explicitly configured to 'park' the External Memory Interface pins in a dormant state, most commonly by setting them to a logic '1'**.

During the execution of the MOVX instruction, the External Memory Interface will explicitly disable the drivers on all Port pins that are acting as Inputs (Data[7:0] during a READ operation, for example). The Output mode of the Port pins (whether the pin is configured as Open-Drain or Push-Pull) is unaffected by the External Memory Interface operation, and remains controlled by the PnMDOUT registers. In most cases, the output modes of all EMIF pins should be configured for push-pull mode.



Multiplexe	d Mode	Non Multiple	exed Mode
Signal Name	Port Pin	Signal Name	Port Pin
/RD	P4.4	/RD	P4.4
/WR	P4.5	/WR	P4.5
ALE	P0.0	ALE	P0.0
D0/A0	P1.0	D0	P1.0
D1/A1	P1.1	D1	P1.1
D2/A2	P1.2	D2	P1.2
D3/A3	P1.3	D3	P1.3
D4/A4	P1.4	D4	P1.4
D5/A5	P1.5	D5	P1.5
D6/A6	P1.6	D6	P1.6
D7/A7	P1.7	D7	P1.7
A8	P3.4	A0	P2.0
A9	P3.5	A1	P2.1
A10	P3.6	A2	P2.2
A11	P3.7	A3	P2.3
A12	P4.0	A4	P2.4
A13	P4.1	A5	P2.5
A14	P4.2	A6	P2.6
A15	P4.3	A7	P2.7
-	-	A8	P3.4
_	-	A9	P3.5
_	-	A10	P3.6
_	-	A11	P3.7
_	-	A12	P4.0
_	-	A13	P4.1
_	-	A14	P4.2
_	_	A15	P4.3

## Table 15.1. EMIF Pinout (C8051F360/3)

## SFR Definition 15.1. EMI0CN: External Memory Interface Control

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
PGSEL7	PGSEL6	PGSEL5	PGSEL4	PGSEL3	PGSEL2	PGSEL1	PGSEL0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	•
T a	The XRAM F ddress whe RAM.	Page Select		e the high b				
T a F C C	The XRAM F address whe RAM. 0x00: 0x000 0x01: 0x010	Page Select en using an 0 to 0x00Ff 0 to 0x01Ff	t Bits provid 8-bit MOV> = =	e the high b				



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
_	—	_	EMD2	EMD1	EMD0	EALE1	EALE0	00000011
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
sits 7–5:	UNUSED. R	ead = 000b	. Write = do	on't care.				
sit 4:	EMD2: EMIF							
	0: EMIF ope	•			mode.			
	1: EMIF ope		•			ess and da	ita pins).	
its 3–2:	EMD1-0: EN	/IF Operat	ing Mode Se	elect.			• •	
	These bits co	ontrol the c	perating mo	ode of the E	xternal Mer	nory Interfa	ice.	
	00: Internal 0	Only: MOV	X accesses	on-chip XR	AM only. Al	I effective a	ddresses a	alias to
		memory sp						
	01: Split Mod	de without l	Bank Select	: Accesses	below the 1	k boundar	y are direc	ted on-chip
	Accesse	s above th	e 1 k bound	ary are dire	cted off-chi	p. 8-bit off-o	chip MOVX	operations
	Accesse use the c	s above th current con	e 1 k bound tents of the .	ary are dire Address Hię	cted off-chi gh port latch	p. 8-bit off-ones to resolv	chip MOVX ve upper ac	operations
	Accesse use the o Note tha	s above th current con t in order to	e 1 k bound tents of the o access off	ary are dire Address Hig -chip space	cted off-chi gh port latch	p. 8-bit off-ones to resolv	chip MOVX ve upper ac	operations
	Accesse use the o Note tha containe	s above th current con t in order to d in the on	e 1 k bound tents of the o access off -chip addres	ary are dire Address Hig -chip space ss space.	cted off-chij gh port latch , EMI0CN r	o. 8-bit off-o nes to resolv nust be set	chip MOVX ve upper ac to a page t	dress byte that is not
	Accesse use the o Note tha containe 10: Split Moo	s above th current con t in order to d in the on de with Bar	e 1 k bound tents of the o access off -chip addres k Select: Ad	ary are dire Address Hig -chip space ss space. ccesses bel	ected off-chip gh port latch e, EMI0CN r low the 1 k l	p. 8-bit off-o nes to resolv nust be set poundary a	chip MOVX ve upper ac to a page t re directed	operations ddress byte that is not on-chip.
	Accesse use the o Note tha containe 10: Split Moo Accesse	s above th current con t in order to d in the on de with Bar s above th	e 1 k bound tents of the o access off -chip addres ik Select: Ad e 1 k bound	ary are dire Address Hig -chip space ss space. ccesses bel ary are dire	ected off-chij gh port latch e, EMI0CN r low the 1 k l ected off-chij	o. 8-bit off-o nes to resolv nust be set poundary a p. 8-bit off-o	chip MOVX ve upper ac to a page f re directed chip MOVX	operations ddress byte that is not on-chip.
	Accesse use the o Note tha containe 10: Split Moo Accesse use the o	s above th current con t in order to d in the on de with Bar s above th contents of	e 1 k bound tents of the o access off -chip addres k Select: Ac e 1 k bound EMI0CN to	ary are dire Address Hig -chip space ss space. ccesses bel ary are dire determine	ected off-chi  gh port latch e, EMI0CN r low the 1 k l ected off-chi  the high-byt	p. 8-bit off- nes to resolv nust be set poundary a p. 8-bit off-c te of the ad	chip MOVX ve upper ac to a page re directed chip MOVX dress.	operations ddress byte that is not on-chip.
	Accesse use the o Note tha containe 10: Split Moo Accesse use the o 11: External	s above th current con t in order to d in the on de with Bar s above th contents of	e 1 k bound tents of the o access off -chip addres k Select: Ac e 1 k bound EMI0CN to	ary are dire Address Hig -chip space ss space. ccesses bel ary are dire determine	ected off-chi  gh port latch e, EMI0CN r low the 1 k l ected off-chi  the high-byt	p. 8-bit off- nes to resolv nust be set poundary a p. 8-bit off-c te of the ad	chip MOVX ve upper ac to a page re directed chip MOVX dress.	operations ddress byte that is not on-chip.
Dita 1 Ou	Accesse use the o Note tha containe 10: Split Moo Accesse use the o 11: External CPU.	s above th current con t in order to d in the on de with Bar s above th contents of Only: MOV	e 1 k bound tents of the , o access off -chip addres k Select: Ac e 1 k bound EMI0CN to 'X accesses	ary are dire Address Hig -chip space ss space. ccesses bel ary are dire determine s off-chip XF	ected off-chi gh port latch e, EMI0CN r low the 1 k l ected off-chi the high-byt RAM only. C	o. 8-bit off- nes to resolv nust be set boundary a o. 8-bit off-c te of the ad on-chip XRA	chip MOVX ve upper ac to a page f re directed chip MOVX dress. AM is not vi	operations ddress byte that is not on-chip.
its 1–0:	Accesse use the o Note tha containe 10: Split Moo Accesse use the o 11: External CPU. EALE1–0: A	s above th current con t in order to d in the on de with Bar s above th contents of Only: MOV LE Pulse-V	e 1 k bound tents of the o access off -chip addres k Select: Ac e 1 k bound EMI0CN to 'X accesses Vidth Select	ary are dire Address Hig -chip space ss space. ccesses bel ary are dire determine s off-chip XF Bits (only h	ected off-chi gh port latch e, EMI0CN r low the 1 k l ected off-chi the high-by RAM only. C nas effect wi	p. 8-bit off- nes to resolv nust be set poundary a p. 8-bit off-o te of the ad n-chip XRA	chip MOVX ve upper ac to a page f re directed chip MOVX dress. AM is not vi	operations ddress byte that is not on-chip.
lits 1–0:	Accesse use the o Note tha containe 10: Split Moo Accesse use the o 11: External CPU. EALE1–0: A 00: ALE high	s above th current con t in order to d in the on de with Bar s above th contents of Only: MOV LE Pulse-V n and ALE	e 1 k bound tents of the o access off -chip addres k Select: Ac e 1 k bound EMI0CN to 'X accesses Vidth Select ow pulse wi	ary are dire Address Hig -chip space ss space. ccesses bel ary are dire determine s off-chip XF Bits (only h idth = 1 SYS	ected off-chi gh port latch e, EMI0CN r low the 1 k l ected off-chi the high-by RAM only. C mas effect wi SCLK cycle.	p. 8-bit off- nes to resolv nust be set boundary a p. 8-bit off-o te of the ad n-chip XRA hen EMD2	chip MOVX ve upper ac to a page f re directed chip MOVX dress. AM is not vi	operations ddress byte that is not on-chip.
3its 1–0:	Accesse use the o Note tha containe 10: Split Moo Accesse use the o 11: External CPU. EALE1–0: A	s above th current con t in order to d in the on de with Bar s above th contents of Only: MOV LE Pulse-V and ALE	e 1 k bound tents of the o access off -chip addres k Select: Ad e 1 k bound EMI0CN to X accesses Vidth Select ow pulse wi ow pulse wi	ary are dire Address Hig -chip space ss space. ccesses bel ary are dire determine off-chip XF Bits (only h idth = 1 SYS idth = 2 SYS	ected off-chi gh port latch e, EMI0CN r low the 1 k l ected off-chi the high-by RAM only. C nas effect wi SCLK cycle SCLK cycle	p. 8-bit off- nes to resolv nust be set poundary a p. 8-bit off-o te of the ad n-chip XRA hen EMD2	chip MOVX ve upper ac to a page f re directed chip MOVX dress. AM is not vi	operations ddress byte that is not on-chip.

## SFR Definition 15.2. EMI0CF: External Memory Configuration



## 15.4. Multiplexed and Non-multiplexed Selection

The External Memory Interface is capable of acting in a Multiplexed mode or a Non-multiplexed mode, depending on the state of the EMD2 (EMI0CF.4) bit.

#### 15.4.1. Multiplexed Configuration

In Multiplexed mode, the Data Bus and the lower 8-bits of the Address Bus share the same Port pins: AD[7:0]. In this mode, an external latch (74HC373 or equivalent logic gate) is used to hold the lower 8-bits of the RAM address. The external latch is controlled by the ALE (Address Latch Enable) signal, which is driven by the External Memory Interface logic. An example of a Multiplexed Configuration is shown in Figure 15.1.

In Multiplexed mode, the external MOVX operation can be broken into two phases delineated by the state of the ALE signal. During the first phase, ALE is high and the lower 8-bits of the Address Bus are presented to AD[7:0]. During this phase, the address latch is configured such that the 'Q' outputs reflect the states of the 'D' inputs. When ALE falls, signaling the beginning of the second phase, the address latch outputs remain fixed and are no longer dependent on the latch inputs. Later in the second phase, the Data Bus controls the state of the AD[7:0] port at the time /RD or /WR is asserted.

See Section "15.6.2. Multiplexed Mode" on page 166 for more information.

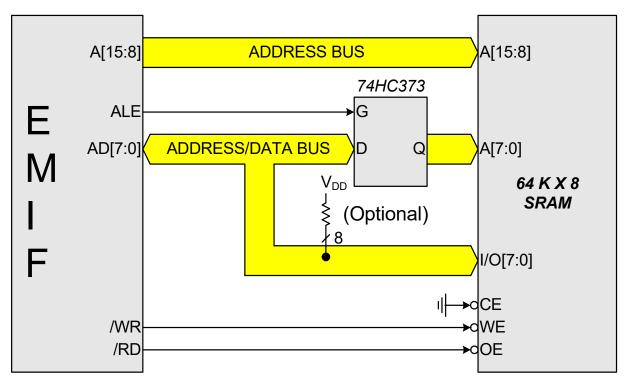


Figure 15.1. Multiplexed Configuration Example



#### 15.4.2. Non-multiplexed Configuration

In Non-multiplexed mode, the Data Bus and the Address Bus pins are not shared. An example of a Non-multiplexed Configuration is shown in Figure 15.2. See Section "15.6.1. Non-multiplexed Mode" on page 163 for more information about Non-multiplexed operation.

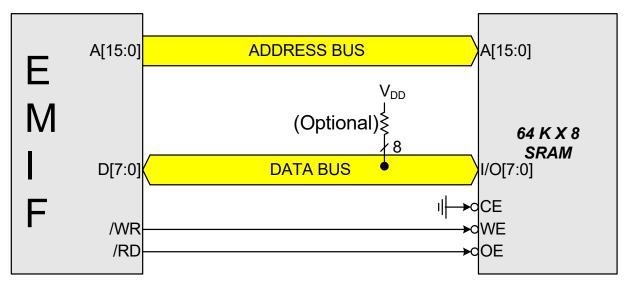


Figure 15.2. Non-multiplexed Configuration Example



## 15.5. Memory Mode Selection

The external data memory space can be configured in one of four modes, shown in Figure 15.3, based on the EMIF Mode bits in the EMI0CF register (SFR Definition 15.2). These modes are summarized below. More information about the different modes can be found in Section "15.6. Timing" on page 161.

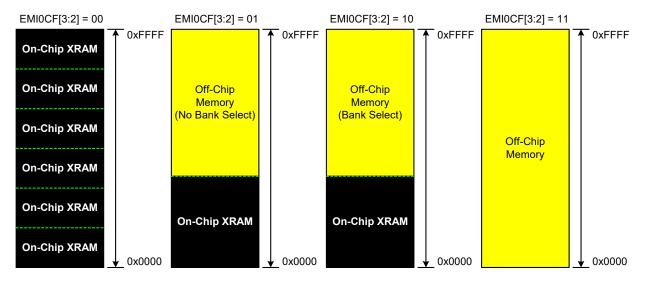


Figure 15.3. EMIF Operating Modes

#### 15.5.1. Internal XRAM Only

When EMI0CF.[3:2] are set to '00', all MOVX instructions will target the internal XRAM space on the device. Memory accesses to addresses beyond the populated space will wrap on 1k boundaries. As an example, the addresses 0x0400 and 0x1000 both evaluate to address 0x0000 in on-chip XRAM space.

- 8-bit MOVX operations use the contents of EMI0CN to determine the high-byte of the effective address and R0 or R1 to determine the low-byte of the effective address.
- 16-bit MOVX operations use the contents of the 16-bit DPTR to determine the effective address.

#### 15.5.2. Split Mode without Bank Select

When EMI0CF.[3:2] are set to '01', the XRAM memory map is split into two areas, on-chip space and off-chip space.

- Effective addresses below the internal XRAM size boundary will access on-chip XRAM space.
- Effective addresses above the internal XRAM size boundary will access off-chip space.
- 8-bit MOVX operations use the contents of EMI0CN to determine whether the memory access is on-chip or off-chip. However, in the "No Bank Select" mode, an 8-bit MOVX operation will not drive the upper 8-bits A[15:8] of the Address Bus during an off-chip access. This allows the user to manipulate the upper address bits at will by setting the Port state directly via the port latches. This behavior is in contrast with "Split Mode with Bank Select" described below. The lower 8-bits of the Address Bus A[7:0] are driven, determined by R0 or R1.
- 16-bit MOVX operations use the contents of DPTR to determine whether the memory access is on-chip or off-chip, and unlike 8-bit MOVX operations, the full 16-bits of the Address Bus A[15:0] are driven during the off-chip transaction.



#### 15.5.3. Split Mode with Bank Select

When EMI0CF.[3:2] are set to '10', the XRAM memory map is split into two areas, on-chip space and off-chip space.

- Effective addresses below the internal XRAM size boundary will access on-chip XRAM space.
- Effective addresses above the internal XRAM size boundary will access off-chip space.
- 8-bit MOVX operations use the contents of EMI0CN to determine whether the memory access is on-chip or off-chip. The upper 8-bits of the Address Bus A[15:8] are determined by EMI0CN, and the lower 8-bits of the Address Bus A[7:0] are determined by R0 or R1. All 16-bits of the Address Bus A[15:0] are driven in "Bank Select" mode.
- 16-bit MOVX operations use the contents of DPTR to determine whether the memory access is on-chip or off-chip, and the full 16-bits of the Address Bus A[15:0] are driven during the off-chip transaction.

#### 15.5.4. External Only

When EMI0CF[3:2] are set to '11', all MOVX operations are directed to off-chip space. On-chip XRAM is not visible to the CPU. This mode is useful for accessing off-chip memory located between 0x0000 and the internal XRAM size boundary.

- 8-bit MOVX operations ignore the contents of EMI0CN. The upper Address bits A[15:8] are not driven (identical behavior to an off-chip access in "Split Mode without Bank Select" described above). This allows the user to manipulate the upper address bits at will by setting the Port state directly. The lower 8-bits of the effective address A[7:0] are determined by the contents of R0 or R1.
- 16-bit MOVX operations use the contents of DPTR to determine the effective address A[15:0]. The full 16-bits of the Address Bus A[15:0] are driven during the off-chip transaction.

#### 15.6. Timing

The timing parameters of the External Memory Interface can be configured to enable connection to devices having different setup and hold time requirements. The Address Setup time, Address Hold time, / RD and /WR strobe widths, and in multiplexed mode, the width of the ALE pulse are all programmable in units of SYSCLK periods through EMI0TC, shown in SFR Definition 15.3, and EMI0CF[1:0].

The timing for an off-chip MOVX instruction can be calculated by adding 4 SYSCLK cycles to the timing parameters defined by the EMI0TC register. Assuming non-multiplexed operation, the minimum execution time for an off-chip XRAM operation is 5 SYSCLK cycles (1 SYSCLK for /RD or /WR pulse + 4 SYSCLKs). For multiplexed operations, the Address Latch Enable signal will require a minimum of 2 additional SYSCLK cycles. Therefore, the minimum execution time for an off-chip XRAM operation in multiplexed mode is 7 SYSCLK cycles (2 for /ALE + 1 for /RD or /WR + 4). The programmable setup and hold times default to the maximum delay settings after a reset. Table 15.2 lists the AC parameters for the External Memory Interface, and Figure 15.4 through Figure 15.9 show the timing diagrams for the different External Memory Interface modes and MOVX operations.



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
EAS1	EAS0	ERW3	EWR2	EWR1	EWR0	EAH1	EAH0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
Bits 7–6:	EAS1-0: EN	1IF Address	s Setup Tim	e Bits.				
	00: Address	setup time	= 0 SYSCL	K cycles.				
	01: Address	setup time	= 1 SYSCL	K cycle.				
	10: Address	setup time	= 2 SYSCL	K cycles.				
	11: Address	setup time	= 3 SYSCL	K cycles.				
8its 5–2:	EWR3-0: EI	MIF /WR ar	nd /RD Puls	e-Width Co	ntrol Bits.			
	0000: /WR a	nd /RD pul	se width = 1	I SYSCLK of	cycle.			
	0001: /WR a	nd /RD pul	se width = 2	2 SYSCLK of	ycles.			
	0010: /WR a	nd /RD pul	se width = 3	3 SYSCLK of	ycles.			
	0011: /WR a	nd /RD puls	se width = 4	SYSCLK	ycles.			
	0100: /WR a	nd /RD pul	se width = 5	5 SYSCLK of	ycles.			
	0101: /WR a	nd /RD pul	se width = 6	SYSCLK of	cycles.			
	0110: /WR a	nd /RD pul:	se width = 7	' SYSCLK o	ycles.			
	0111: /WR a	nd /RD puls	se width = 8	SYSCLK o	ycles.			
	1000: /WR a	nd /RD pul	se width = 9	SYSCLK (	cycles.			
	1001: /WR a	nd /RD pul	se width = 1	10 SYSCLK	cycles.			
	1010: /WR a	nd /RD pul	se width = 1	11 SYSCLK	cycles.			
	1011: /WR a	nd /RD pul:	se width = 1	2 SYSCLK	cycles.			
	1100: /WR a	•						
	1101: /WR a	nd /RD pul	se width = 1	4 SYSCLK	cycles.			
	1110: /WR a							
	1111: /WR a	nd /RD puls	se width = 1	6 SYSCLK	cycles.			
8its 1–0:	EAH1-0: EN	IIF Address	6 Hold Time	Bits.				
	00: Address	hold time =	0 SYSCLK	Ccycles.				
	01: Address							
	10: Address							
	11: Address		0.0000110	, ,				

## SFR Definition 15.3. EMI0TC: External Memory Timing Control



#### 15.6.1. Non-multiplexed Mode

15.6.1.1.16-bit MOVX: EMI0CF[4:2] = '101', '110', or '111'.

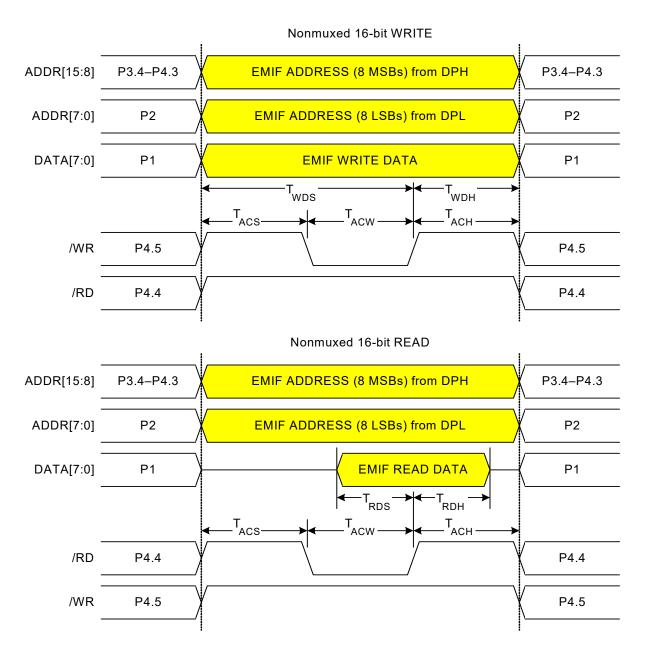
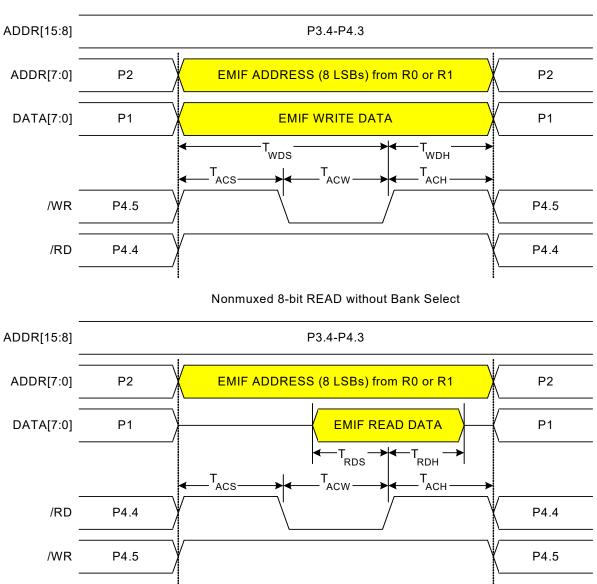


Figure 15.4. Non-multiplexed 16-bit MOVX Timing



#### 15.6.1.2.8-bit MOVX without Bank Select: EMI0CF[4:2] = '101' or '111'.



Nonmuxed 8-bit WRITE without Bank Select

Figure 15.5. Non-multiplexed 8-bit MOVX without Bank Select Timing



#### 15.6.1.3.8-bit MOVX with Bank Select: EMI0CF[4:2] = '110'.

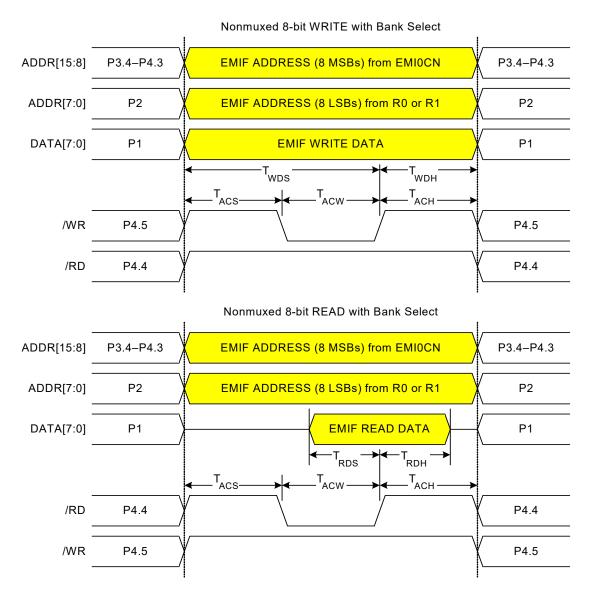


Figure 15.6. Non-multiplexed 8-bit MOVX with Bank Select Timing



## 15.6.2. Multiplexed Mode

### 15.6.2.1.16-bit MOVX: EMI0CF[4:2] = '001', '010', or '011'.

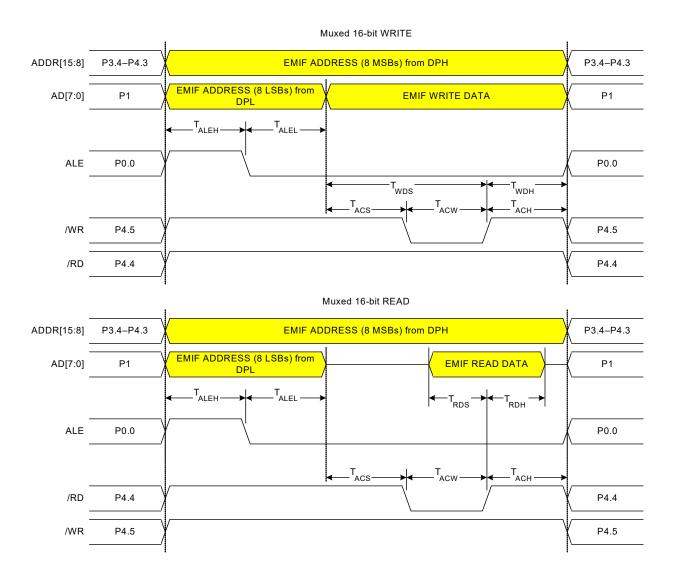
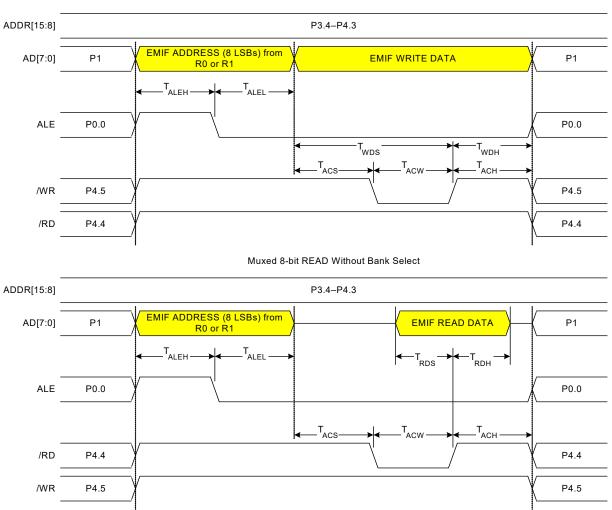


Figure 15.7. Multiplexed 16-bit MOVX Timing



#### 15.6.2.2.8-bit MOVX without Bank Select: EMI0CF[4:2] = '001' or '011'.



Muxed 8-bit WRITE Without Bank Select

Figure 15.8. Multiplexed 8-bit MOVX without Bank Select Timing



#### 15.6.2.3.8-bit MOVX with Bank Select: EMI0CF[4:2] = '010'.

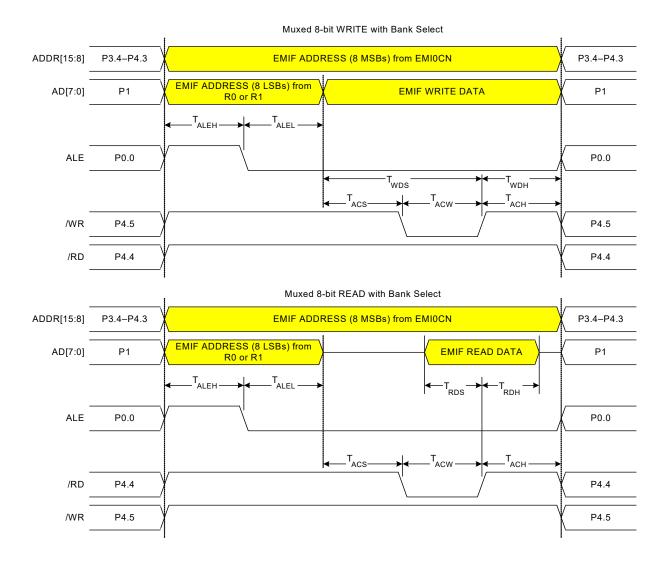


Figure 15.9. Multiplexed 8-bit MOVX with Bank Select Timing



Parameter	Description	Min*	Max*	Units
T <sub>ACS</sub>	Address/Control Setup Time	0	3 x T <sub>SYSCLK</sub>	ns
T <sub>ACW</sub>	Address/Control Pulse Width	1 x T <sub>SYSCLK</sub>	16 x T <sub>SYSCLK</sub>	ns
T <sub>ACH</sub>	Address/Control Hold Time	0	3 x T <sub>SYSCLK</sub>	ns
T <sub>ALEH</sub>	Address Latch Enable High Time	1 x T <sub>SYSCLK</sub>	4 x T <sub>SYSCLK</sub>	ns
T <sub>ALEL</sub>	Address Latch Enable Low Time	1 x T <sub>SYSCLK</sub>	4 x T <sub>SYSCLK</sub>	ns
T <sub>WDS</sub>	Write Data Setup Time	1 x T <sub>SYSCLK</sub>	19 x T <sub>SYSCLK</sub>	ns
T <sub>WDH</sub>	Write Data Hold Time	0	3 x T <sub>SYSCLK</sub>	ns
T <sub>RDS</sub>	Read Data Setup Time	20		ns
T <sub>RDH</sub>	Read Data Hold Time	0		ns
lote: T <sub>SYSCLK</sub>	s equal to one period of the device system clock (S	YSCLK).	1	1

Table 15.2. AC Parameters for External Memory Interface



## 16. Oscillators

The C8051F36x devices include a programmable internal high-frequency oscillator, a programmable internal low-frequency oscillator, and an external oscillator drive circuit. The internal high-frequency oscillator can be enabled, disabled, and calibrated using the OSCICN and OSCICL registers, as shown in Figure 16.1. The internal low-frequency oscillator can be enabled/disabled and calibrated using the OSCLCN register, as shown in SFR Definition 16.3. Both internal oscillators offer a selectable post-scaling feature. The system clock can be sourced by the external oscillator circuit, either internal oscillator, or the on-chip phase-locked loop (PLL). The internal oscillator's electrical specifications are given in Table 16.1 on page 172 and Table 16.2 on page 173.

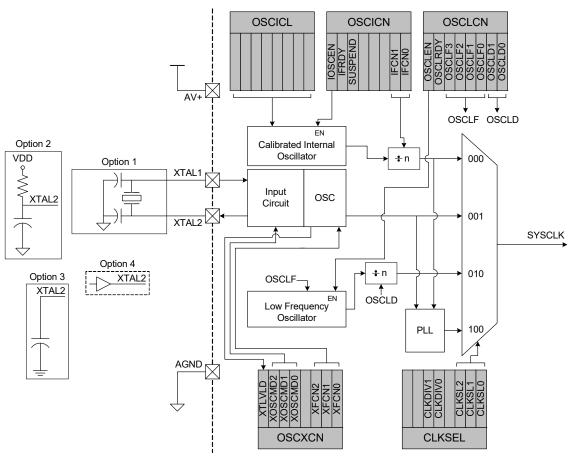


Figure 16.1. Oscillator Diagram

## 16.1. Programmable Internal High-Frequency (H-F) Oscillator

All devices include a calibrated internal high-frequency oscillator that defaults as the system clock after a system reset. The internal oscillator period can be adjusted via the OSCICL register as defined by SFR Definition 16.1. OSCICL is factory calibrated to obtain a 24.5 MHz frequency.

Electrical specifications for the precision internal oscillator are given in Table 16.1 on page 172 and Table 16.2 on page 173. Note that the system clock may be derived from the programmed internal oscillator divided by 1, 2, 4, or 8, as defined by the IFCN bits in register OSCICN. The divide value defaults to 8 following a reset.



#### 16.1.1. Internal Oscillator Suspend Mode

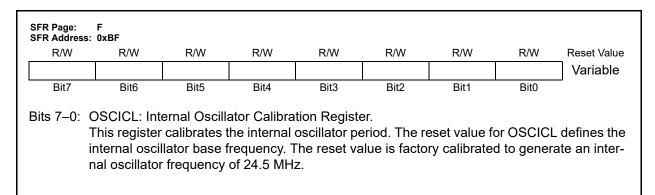
When software writes a logic '1' to SUSPEND (OSCICN.5), the internal oscillator is suspended. If the system clock is derived from the internal oscillator, the input clock to the peripheral or CIP-51 will be stopped until one of the following events occur:

- Port 0 Match Event.
- Port 1 Match Event.
- Port 2 Match Event.
- Comparator 0 enabled and output is logic '0'.
- Comparator 1 enabled and output is logic '0'.

When one of the internal oscillator awakening events occur, the internal oscillator, CIP-51, and affected peripherals resume normal operation, regardless of whether the event also causes an interrupt. The CPU resumes execution at the instruction following the write to SUSPEND.

**Note:** Before entering SUSPEND mode, SYSCLK should be switched to run off of the internal oscillator and not the PLL. When the CPU wakes due to the awakening event, the PLL must be reinitialized before switching back to it as the SYSCLK source.

### SFR Definition 16.1. OSCICL: Internal Oscillator Calibration.





R/W	R	R/W	R	R/W	R/W	R/W	R/W	Reset Value	
IOSCEN	I IFRDY	SUSPEND	Reserved	Reserved	Reserved	IFCN1	IFCN0	11000000	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	-	
Bit 7:	IOSCEN: In	tornal Oacill	tor Enchlo	Dit					
DIL 7.	0: Internal C			DIL.					
	1: Internal C								
Bit 6:	IFRDY: Internal Oscillator Frequency Ready Flag. 0: Internal Oscillator not running at programmed frequency.								
			-		• •	/.			
	1: Internal C	scillator run	ning at prog	grammed fro	equency.	/.			
Bits 5:	1: Internal C SUSPEND:	scillator run Internal Osc	ning at prog illator Susp	grammed fro end Enable	equency. e Bit.				
Bits 5:	1: Internal C SUSPEND: Setting this	Scillator run Internal Osc bit to logic '1	ning at proo illator Susp ' places the	grammed fro bend Enable e internal os	equency. e Bit. scillator in S	USPEND n			
Bits 5:	1: Internal C SUSPEND:	Scillator run Internal Osc bit to logic '1	ning at proo illator Susp ' places the	grammed fro bend Enable e internal os	equency. e Bit. scillator in S	USPEND n			
	1: Internal C SUSPEND: Setting this	Discillator run Internal Osci bit to logic '1 sumes opera	ning at prog illator Susp ' places the ition when o	grammed fro bend Enable e internal os one of the S	equency. e Bit. scillator in S	USPEND n			
Bits 4–2:	1: Internal C SUSPEND: Setting this oscillator res	Oscillator run Internal Osc bit to logic '1 sumes opera 0. Read = 00	ning at prog illator Susp ' places the ation when o 0b. Must W	grammed fro bend Enable e internal os one of the S /rite 000b.	equency. e Bit. scillator in S SUSPEND n	USPEND n			
Bits 4–2:	1: Internal C SUSPEND: Setting this oscillator res RESERVED IFCN1-0: Int	Oscillator run Internal Osc bit to logic '1 sumes opera 0. Read = 00 ternal Oscilla	ning at prog illator Susp ' places the ition when o Ob. Must W ator Freque	grammed fro pend Enable e internal os one of the S /rite 000b. ncy Control	equency. e Bit. scillator in S SUSPEND n	USPEND n			
Bits 4–2:	1: Internal C SUSPEND: Setting this oscillator res RESERVED IFCN1-0: Int 00: Internal	Oscillator run Internal Osci bit to logic '1 sumes opera 0. Read = 00 ternal Oscilla Oscillator is	ning at prog illator Susp ' places the ttion when o 0b. Must W ator Freque divided by	grammed fro pend Enable e internal os one of the S /rite 000b. ncy Control 8. (default)	equency. e Bit. scillator in S SUSPEND n	USPEND n			
	1: Internal C SUSPEND: Setting this oscillator res RESERVED IFCN1-0: Int	Oscillator run Internal Osci bit to logic '1 sumes opera 0. Read = 00 ternal Oscilla Oscillator is Oscillator is	ning at prog illator Susp ition when 0b. Must W ator Freque divided by divided by	grammed fro bend Enable e internal os one of the S /rite 000b. ncy Control 8. (default) 4.	equency. e Bit. scillator in S SUSPEND n	USPEND n			

## SFR Definition 16.2. OSCICN: Internal Oscillator Control

# Table 16.1. Internal High Frequency Oscillator Electrical Characteristics -40°C to +85°C unless otherwise specified.

Parameter	Conditions	Min	Тур	Max	Units
Calibrated Internal Oscillator Frequency		24	24.5	25	MHz
Internal Oscillator Supply Current (from V <sub>DD</sub> )	OSCICN.7 = 1	_	450	600	μA
Power Supply Sensitivity	Constant Temperature		0.12	—	%/V
Temperature Sensitivity	Constant Supply		60	—	ppm/°C
External Clock Frequency		0	—	30	MHz
T <sub>XCH</sub> (External Clock High Time)		15	—	_	ns
T <sub>XCL</sub> (External Clock Low Time)		15		—	ns

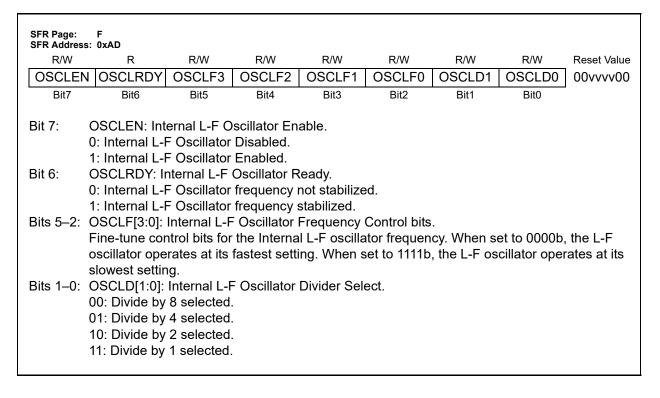
## 16.2. Programmable Internal Low-Frequency (L-F) Oscillator

All C8051F36x devices include a programmable low-frequency internal oscillator, which is calibrated to a nominal frequency of 80 kHz. The low-frequency oscillator circuit includes a divider that can be changed to divide the clock by 1, 2, 4, or 8, using the OSCLD bits in the OSCLCN register (see SFR Definition 16.3). Additionally, the OSCLF bits (OSCLCN5:2) can be used to adjust the oscillator's output frequency.



#### 16.2.1. Calibrating the Internal L-F Oscillator

Timers 2 and 3 include capture functions that can be used to capture the oscillator frequency, when running from a known time base. When either Timer 2 or Timer 3 is configured for L-F Oscillator Capture Mode, a falling edge (Timer 2) or rising edge (Timer 3) of the low-frequency oscillator's output will cause a capture event on the corresponding timer. As a capture event occurs, the current timer value (TMRnH:TMRnL) is copied into the timer reload registers (TMRnRLH:TMRnRLL). By recording the difference between two successive timer capture values, the low-frequency oscillator's period can be calculated. The OSCLF bits can then be adjusted to produce the desired oscillator frequency.



## SFR Definition 16.3. OSCLCN: Internal L-F Oscillator Control

#### Table 16.2. Internal Low Frequency Oscillator Electrical Characteristics

-40°C to +85°C unless otherwise specified.

Parameter	Conditions	Min	Тур	Мах	Units
	OSCLD = 11b	72	80	88	kHz
Oscillator Supply Current (from V <sub>DD</sub> )	25 °C, V <sub>DD</sub> = 3.0 V, OSCLCN.7 = 1	_	5.5	10	μA
Power Supply Sensitivity	Constant Temperature		2.4	—	%/V
Temperature Sensitivity	Constant Supply		30	_	ppm/°C



## 16.3. External Oscillator Drive Circuit

The external oscillator circuit may drive an external crystal, ceramic resonator, capacitor, or RC network. A CMOS clock may also provide a clock input. For a crystal or ceramic resonator configuration, the crystal/ resonator must be wired across the XTAL1 and XTAL2 pins as shown in Option 1 of Figure 16.1. A 10 M $\Omega$  resistor also must be wired across the XTAL1 and XTAL2 pins for the crystal/resonator configuration. In RC, capacitor, or CMOS clock configuration, the clock source should be wired to the XTAL2 pin as shown in Option 2, 3, or 4 of Figure 16.1. The type of external oscillator must be selected in the OSCXCN register, and the frequency control bits (XFCN) must be selected appropriately (see SFR Definition 16.5).

**Important Note on External Oscillator Usage:** Port pins must be configured when using the external oscillator circuit. When the external oscillator drive circuit is enabled in crystal/resonator mode, Port pins P0.5 and P0.6 (C8051F360/3) or P0.2 and P0.3 (C8051F361/2/4/5/6/7/8/9) are used as XTAL1 and XTAL2 respectively. When the external oscillator drive circuit is enabled in capacitor, RC, or CMOS clock mode, Port pin P0.6 (C8051F360/3) or P0.3 (C8051F361/2/4/5/6/7/8/9) is used as XTAL2. The Port I/O Crossbar should be configured to skip the Port pins used by the oscillator circuit; see Section "17.1. Priority Crossbar Decoder" on page 186 for Crossbar configuration. Additionally, when using the external oscillator circuit in crystal/resonator, capacitor, or RC mode, the associated Port pins should be configured as **analog inputs**. In CMOS clock mode, the associated pin should be configured as a **digital input**. See Section "17.2. Port I/O Initialization" on page 188 for details on Port input mode selection.

## 16.4. System Clock Selection

The internal oscillator requires little start-up time, and may be enabled and selected as the system clock in the same write to OSCICN. External crystals and ceramic resonators typically require a start-up time before they are settled and ready for use as the system clock. The Crystal Valid Flag (XTLVLD in register OSCXCN) is set to '1' by hardware when the external oscillator is settled. To avoid reading a false XTLVLD, in crystal mode software should delay at least 1 ms between enabling the external oscillator and checking XTLVLD. RC and C modes typically require no startup time. The PLL also requires time to lock onto the desired frequency, and the PLL Lock Flag (PLLLCK in register PLLOCN) is set to '1' by hardware once the PLL is locked on the correct frequency.

The CLKSL1-0 bits in register CLKSEL select which oscillator source generates the system clock. CLK-SL1-0 must be set to '01' for the system clock to run from the external oscillator; however the external oscillator may still clock certain peripherals, such as the timers and PCA, when the internal oscillator or the PLL is selected as the system clock. The system clock may be switched on-the-fly between the internal and external oscillators or the PLL, so long as the selected oscillator source is enabled and settled.



SFR Address R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
Reserve		-	CLKDIV0	Reserved	CLKSL2	CLKSL1	CLKSL0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	]
Bit 3:	RESERVED CLKDIV1-0: These bits ca crossbar. 00: Output w 01: Output w 10: Output w 11: Output w See Section a port pin. RESERVED CLKSL2–0: \$ 000: SYSCL IFCN bits 001: SYSCL	Output SYS an be used ill be SYSC ill be SYSC ill be SYSC "17. Port In . Read = 0b System Clo K derived fr in OSCICN	SCLK Divide to pre-divid CLK. CLK/2. CLK/4. CLK/8. put/Output" o. Must Writ ck Source S rom the high	e Factor. le SYSCLK d'on page 18 e 0b. Select Bits. n-frequency	4 for more of the form of the	details abou	ut routing th	is output to
	010: SYSCL	K derived fr its in OSCL	om the low			cillator, and	scaled as p	per the
	100: SYSCL	K derived fr	om the PLL					

## SFR Definition 16.4. CLKSEL: System Clock Selection



## SFR Definition 16.5. OSCXCN: External Oscillator Control

R	R/W	R/W	R/W	R	R/W	R/W	R/W	Reset Valu
XTLVL	D XOSCMI	D2 XOSCMD1	XOSCMD0	Reserved	XFCN2	XFCN1	XFCN0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:		Crystal Oscilla						
		y when XOSC						
		Oscillator is u						
		Oscillator is ru 2–0: External	•					
5115 0-4.		nal Oscillator		oue bits.				
		nal CMOS Clo						
		nal CMOS Clo		th divide by	2 stage.			
		Scillator Mode		,	5			
		citor Oscillato						
		al Oscillator M						
		al Oscillator M			ge.			
Bit 3:		ED. Read = 0b						
3its 2–0:		: External Osc ee table belov		lency Contro	I BIts.			
	000-111.8	ee lable belov	v.					
	XFCN	Crystal (XOS		, ,	SCMD = 10	, (	OSCMD =	,
	000		2 kHz		25 kHz		Factor = 0.	
	001		f≤84 kHz		< f ≤ 50 kH		Factor = 2	
	010		≤ 225 kHz		< f ≤ 100 k		Factor = 7	
	011		$f \le 590 \text{ kHz}$		$< f \le 200 \text{ k}$		Factor = 2	
Ļ	100		$f \le 1.5 \text{ MHz}$		$< f \le 400 \text{ k}$		Factor = $6$	
Ļ	101		$f \le 4 \text{ MHz}$		$< f \le 800 \text{ k}$		Factor = $18$	
Ļ	110		$\leq$ 10 MHz		$< f \le 1.6 M$		Factor = $66$	
L	111	10 MHZ <	f ≤ 30 MHz	1.6 MHZ	< f ≤ 3.2 N	IHZ KF	actor = 15	90
CRYSTA		Circuit from Fig	ure 16.1, O	ption 1; XOS	SCMD = 11	x)		
		FCN value to						
RC MOE		om Figure 16.			= 10x)			
		FCN value to i	•	ency range:				
		0 <sup>3</sup> )/(R * C), wh						
		ncy of oscillatio						
		itor value in pl resistor value						
	n – ruliup			(OSCMD = 2)	10x)			
C MODE	Circuit fro		or the oscilla		,			
C MODE	Circuit fro Choose K	Factor (KF) fo	or the oscilla					
C MODE	Choose K f = KF/(C							
C MODE	E (Circuit fro Choose K f = KF/(C f = frequer	Factor (KF) fo * V <sub>DD</sub> ), where	on in MHz	·				



### 16.5. External Crystal Example

If a crystal or ceramic resonator is used as an external oscillator source for the MCU, the circuit should be configured as shown in Figure 16.1, Option 1. The External Oscillator Frequency Control value (XFCN) should be chosen from the Crystal column of the table in SFR Definition 16.5 (OSCXCN register). For example, an 11.0592 MHz crystal requires an XFCN setting of 111b.

When the crystal oscillator is enabled, the oscillator amplitude detection circuit requires a settle time to achieve proper bias. Waiting at least 1 ms between enabling the oscillator and checking the XTLVLD bit will prevent a premature switch to the external oscillator as the system clock. Switching to the external oscillator before the crystal oscillator has stabilized can result in unpredictable behavior. The recommended procedure is:

- Step 1. Force the XTAL1 and XTAL2 pins low by writing 0's to the port latch.
- Step 2. Configure XTAL1 and XTAL2 as analog inputs.
- Step 3. Enable the external oscillator.
- Step 4. Wait at least 1 ms.
- Step 5. Poll for XTLVLD => '1'.
- Step 6. Switch the system clock to the external oscillator.

**Note:** Tuning-fork crystals may require additional settling time before XTLVLD returns a valid result.

The capacitors shown in the external crystal configuration provide the load capacitance required by the crystal for correct oscillation. These capacitors are "in series" as seen by the crystal and "in parallel" with the stray capacitance of the XTAL1 and XTAL2 pins.

**Note:** The load capacitance depends upon the crystal and the manufacturer. Please refer to the crystal data sheet when completing these calculations.

For example, a tuning-fork crystal of 32.768 kHz with a recommended load capacitance of 12.5 pF should use the configuration shown in Figure 16.1, Option 1. The total value of the capacitors and the stray capacitance of the XTAL pins should equal 25 pF. With a stray capacitance of 3 pF per pin, the 22 pF capacitors yield an equivalent capacitance of 12.5 pF across the crystal, as shown in Figure 16.2.

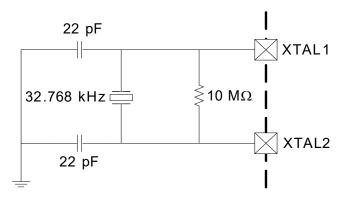


Figure 16.2. 32.768 kHz External Crystal Example

**Important Note on External Crystals:** Crystal oscillator circuits are quite sensitive to PCB layout. The crystal should be placed as close as possible to the XTAL pins on the device. The traces should be as short as possible and shielded with ground plane from any other traces which could introduce noise or interference.



## 16.6. External RC Example

If an RC network is used as an external oscillator source for the MCU, the circuit should be configured as shown in Figure 16.1, Option 2. The capacitor should be no greater than 100 pF; however for very small capacitors, the total capacitance may be dominated by parasitic capacitance in the PCB layout. To determine the required External Oscillator Frequency Control value (XFCN) in the OSCXCN Register, first select the RC network value to produce the desired frequency of oscillation. If the frequency desired is 100 kHz, let R = 246 k $\Omega$  and C = 50 pF:

f = 1.23(10<sup>3</sup>)/RC = 1.23 (10<sup>3</sup>)/[246 x 50] = 0.1 MHz = 100 kHz

Referring to the table in SFR Definition 16.5, the required XFCN setting is 010b. Programming XFCN to a higher setting in RC mode will improve frequency accuracy at a slightly increased external oscillator supply current.

### 16.7. External Capacitor Example

If a capacitor is used as an external oscillator for the MCU, the circuit should be configured as shown in Figure 16.1, Option 3. The capacitor should be no greater than 100 pF; however for very small capacitors, the total capacitance may be dominated by parasitic capacitance in the PCB layout. To determine the required External Oscillator Frequency Control value (XFCN) in the OSCXCN Register, select the capacitor to be used and find the frequency of oscillation from the equations below. Assume  $V_{DD} = 3.0$  V and f = 75 kHz:

f = KF / (C x V<sub>DD</sub>) 0.075 MHz = KF / (C x 3.0)

Since the frequency of roughly 75 kHz is desired, select the K Factor from the table in SFR Definition 16.5 as KF = 7.7:

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 $0.075 \text{ MHz} = 7.7 / (C \times 3.0)$ 

C x 3.0 = 7.7 / 0.075 MHz

C = 102.6 / 3.0 pF = 34.2 pF

Therefore, the XFCN value to use in this example is 010b.



### 16.8. Phase-Locked Loop (PLL)

A Phase-Locked-Loop (PLL) is included, which is used to multiply the internal oscillator or an external clock source to achieve higher CPU operating frequencies. The PLL circuitry is designed to produce an output frequency between 25 MHz and 100 MHz, from a divided reference frequency between 5 MHz and 30 MHz. A block diagram of the PLL is shown in Figure 16.3.

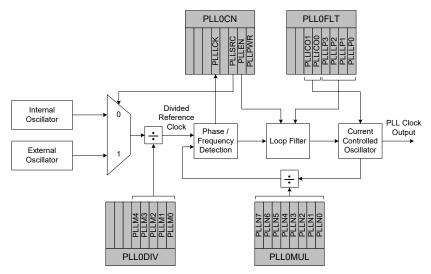


Figure 16.3. PLL Block Diagram

#### 16.8.1. PLL Input Clock and Pre-divider

The PLL circuitry can derive its reference clock from either the internal oscillator or an external clock source. The PLLSRC bit (PLL0CN.2) controls which clock source is used for the reference clock (see SFR Definition 16.6). If PLLSRC is set to '0', the internal oscillator source is used. Note that the internal oscillator divide factor (as specified by bits IFCN1-0 in register OSCICN) will also apply to this clock. When PLL-SRC is set to '1', an external oscillator source will be used. The external oscillator should be active and settled before it is selected as a reference clock for the PLL circuit. The reference clock is divided down prior to the PLL circuit, according to the contents of the PLLM4-0 bits in the PLL Pre-divider Register (PLL0DIV), shown in SFR Definition 16.7.

#### 16.8.2. PLL Multiplication and Output Clock

The PLL circuitry will multiply the divided reference clock by the multiplication factor stored in the PLL0MUL register shown in SFR Definition 16.8. To accomplish this, it uses a feedback loop consisting of a phase/frequency detector, a loop filter, and a current-controlled oscillator (ICO). It is important to configure the loop filter and the ICO for the correct frequency ranges. The PLLLP3–0 bits (PLL0FLT.3–0) should be set according to the divided reference clock frequency. Likewise, the PLLICO1–0 bits (PLL0FLT.5–4) should be set according to the desired output frequency range. SFR Definition 16.9 describes the proper settings to use for the PLLLP3–0 and PLLICO1–0 bits. When the PLL is locked and stable at the desired frequency, the PLLLCK bit (PLL0CN.5) will be set to a '1'. The resulting PLL frequency will be set according to the equation:

PLL Frequency = Reference Frequency  $\times \frac{PLLN}{PLLM}$ 

Where "Reference Frequency" is the selected source clock frequency, PLLN is the PLL Multiplier, and PLLM is the PLL Pre-divider.



#### 16.8.3. Powering on and Initializing the PLL

To set up and use the PLL as the system clock after power-up of the device, the following procedure should be implemented:

- Step 1. Ensure that the reference clock to be used (internal or external) is running and stable.
- Step 2. Set the PLLSRC bit (PLL0CN.2) to select the desired clock source for the PLL.
- Step 3. Program the Flash read timing bits, FLRT (FLSCL.5–4) to the appropriate value for the new clock rate (see Section "13. Flash Memory" on page 136).
- Step 4. Enable power to the PLL by setting PLLPWR (PLL0CN.0) to '1'.
- Step 5. Program the PLL0DIV register to produce the divided reference frequency to the PLL.
- Step 6. Program the PLLLP3–0 bits (PLL0FLT.3–0) to the appropriate range for the divided reference frequency.
- Step 7. Program the PLLICO1–0 bits (PLL0FLT.5–4) to the appropriate range for the PLL output frequency.
- Step 8. Program the PLL0MUL register to the desired clock multiplication factor.
- Step 9. Wait at least 5 µs, to provide a fast frequency lock.
- Step 10. Enable the PLL by setting PLLEN (PLL0CN.1) to '1'.
- Step 11. Poll PLLLCK (PLL0CN.4) until it changes from '0' to '1'.
- Step 12. Switch the System Clock source to the PLL using the CLKSEL register.

If the PLL characteristics need to be changed when the PLL is already running, the following procedure should be implemented:

- Step 1. The system clock should first be switched to either the internal oscillator or an external clock source that is running and stable, using the CLKSEL register.
- Step 2. Ensure that the reference clock to be used for the new PLL setting (internal or external) is running and stable.
- Step 3. Set the PLLSRC bit (PLL0CN.2) to select the new clock source for the PLL.
- Step 4. If moving to a faster frequency, program the Flash read timing bits, FLRT (FLSCL.5–4) to the appropriate value for the new clock rate (see Section "13. Flash Memory" on page 136).
- Step 5. Disable the PLL by setting PLLEN (PLL0CN.1) to '0'.
- Step 6. Program the PLL0DIV register to produce the divided reference frequency to the PLL.
- Step 7. Program the PLLLP3–0 bits (PLL0FLT.3–0) to the appropriate range for the divided reference frequency.
- Step 8. Program the PLLICO1-0 bits (PLL0FLT.5–4) to the appropriate range for the PLL output frequency.
- Step 9. Program the PLLOMUL register to the desired clock multiplication factor.
- Step 10. Enable the PLL by setting PLLEN (PLL0CN.1) to '1'.
- Step 11. Poll PLLLCK (PLL0CN.4) until it changes from '0' to '1'.
- Step 12. Switch the System Clock source to the PLL using the CLKSEL register.
- Step 13. If moving to a slower frequency, program the Flash read timing bits, FLRT (FLSCL.5–4) to the appropriate value for the new clock rate (see Section "13. Flash Memory" on page 136). Important Note: Cache reads, cache writes, and the prefetch engine should be disabled whenever the FLRT bits are changed to a lower setting.



To shut down the PLL, the system clock should be switched to the internal oscillator or a stable external clock source, using the CLKSEL register. Next, disable the PLL by setting PLLEN (PLL0CN.1) to '0'. Finally, the PLL can be powered off, by setting PLLPWR (PLL0CN.0) to '0'. Note that the PLLEN and PLL-PWR bits can be cleared at the same time.

R/W	R/W	R/W	R	R/W	R/W	R/W	R/W	Reset Value
_	-	-	PLLLCK	Reserved	PLLSRC	PLLEN	PLLPWR	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	-
Bits 7–5:	UNUSED. R	ead = 000	o. Write = do	on't care.				
Bit 4:	PLLLCK: PL	L Lock Fla	g.					
	0: PLL Frequ	iency is no	t locked.					
	1: PLL Frequ	iency is lo	cked.					
Bit 3:	RESERVED	. Read = 0	b. Must Writ	e 0b.				
Bit 2:	PLLSRC: PL	L Referen	ce Clock So	urce Select E	Bit.			
	0: PLL Refer	ence Cloc	k Source is l	nternal Oscil	lator.			
	1: PLL Refer	ence Cloc	k Source is l	External Osci	llator.			
Bit 1:	PLLEN: PLL	Enable Bi	t.					
	0: PLL is hel	d in reset.						
	1: PLL is ena	abled. PLL	PWR must b	be '1'.				
Bit 0:	PLLPWR: PI	L Power	Enable.					
	0: PLL bias o	generator i	s de-activate	ed. No static i	power is cor	nsumed.		
	1: PLL bias g							

# SFR Definition 16.6. PLL0CN: PLL Control

#### SFR Definition 16.7. PLL0DIV: PLL Pre-divider

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-	PLLM4	PLLM3	PLLM2	PLLM1	PLLM0	00000001
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
Bits 4–0: F T	JNUSED. Re PLLM4–0: Pl These bits se value, the re he reference	LL Referen elect the pr ference clo	ce Clock Pr e-divide valu ck will be di	e-divider. ue of the PL vided by the				•



#### SFR Definition 16.8. PLL0MUL: PLL Clock Scaler

FR Address: R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
PLLN7	PLLN6	PLLN5	PLLN4	PLLN3	PLLN2	PLLN1	PLLN0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
٦	PLLN7–0: Pl These bits se any non-zero	elect the mu	ultiplication					

### SFR Definition 16.9. PLL0FLT: PLL Filter

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
-	-	PLLICO1	PLLICO0	PLLLP3	PLLLP2	PLLLP1	PLLLP0	0011000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
Bits 7–6:	UNUSED. F	Read = 00b.	Write = don	't care.				
Bits 5–4:	PLLICO1-0:	PLL Currer	nt-Controlled	d Oscillator	Control Bits	i.		
	Selection is	based on th	ne desired o	utput freque	ency, accore	ding to the	following ta	able:
	P	L Output			PLLIC	01-0		
		65–100 MI			00			
		45-80 MF			01			
		30-60 MF			10			
		25-50 MF	17		11			
		25–50 M⊦	lZ		11			
Bits 3–0:	PLLLP3-0: F			Bits.	11			
Bits 3–0:	PLLLP3-0: F Selection is	PLL Loop Fi	Iter Control			cording to t	he following	g table:
Bits 3–0:	Selection is	PLL Loop Fi based on th	Iter Control	LL reference		0	he following	g table:
Bits 3–0:	Selection is	PLL Loop Fi based on th	lter Control ne divided P ence Clock	LL reference	e clock, ac	P3-0	he following	g table:
Bits 3–0:	Selection is Divided	PLL Loop Fi based on th <b>PLL Refer</b>	Iter Control le divided P ence Clock Iz	LL reference	e clock, acc PLLLF	<b>°3-0</b> 1	he following	g table:
Bits 3–0:	Selection is Divided	PLL Loop Fi based on th PLL Refer 19–30 MH	Iter Control le divided P ence Clock Iz /IHz	LL reference	e clock, acc PLLLF 000	<b>23-0</b> 1 1	he following	g table:



# Table 16.3. PLL Frequency Characteristics-40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Тур	Мах	Units
Input Frequency (Divided Reference Frequency)		5		30	MHz
PLL Output Frequency		25		100*	MHz
*Note: The maximum operating frequency of the	e C8051F366/7/8/9 is 50 MH	lz.			

#### Table 16.4. PLL Lock Timing Characteristics

-40 to +85 °C unless otherwise specified

Input	Multiplier	Pliofit	Output	Min	Тур	Max	Units
Frequency	(Pll0mul)	Setting	Frequency				
	20	0x0F	100 MHz		202		μs
	13	0x0F	65 MHz		115		μs
	16	0x1F	80 MHz		241		μs
5 MHz	9	0x1F	45 MHz		116		μs
5 IVIT IZ	12	0x2F	60 MHz		258		μs
	6	0x2F	30 MHz		112		μs
	10	0x3F	50 MHz		263		μs
	5	0x3F	25 MHz		113		μs
	4	0x01	100 MHz		42		μs
	2	0x01	50 MHz		33		μs
	3	0x11	75 MHz		48		μs
25 MHz	2	0x11	50 MHz		17		μs
20 1011 12	2	0x21	50 MHz		42		μs
	1	0x21	25 MHz		33		μs
	2	0x31	50 MHz		60		μs
	1	0x31	25 MHz		25		μs

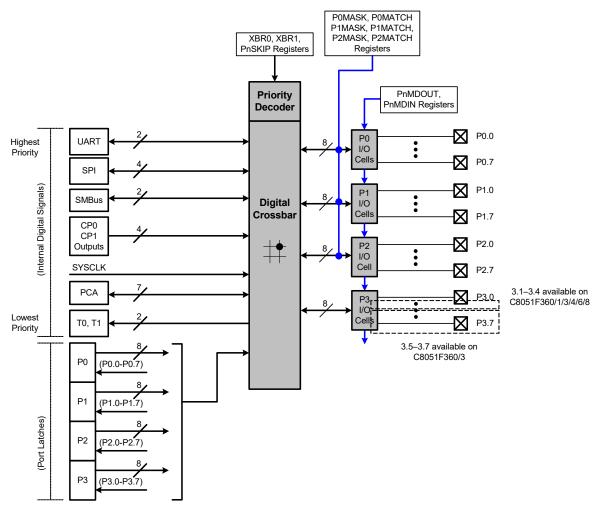


# 17. Port Input/Output

Digital and analog resources are available through up to 39 I/O pins. On the largest devices (C8051F360/3), port pins are organized as four byte-wide Ports and one 7-bit-wide Port. On the other devices (C8051F361/2/4/5/6/7/8/9), port pins are three byte-wide Ports and one partial port. Each of the Port pins can be defined as general-purpose I/O (GPIO) or analog input/output; Port pins P0.0–P3.7 can be assigned to one of the internal digital resources as shown in Figure 17.3. The designer has complete control over which functions are assigned, limited only by the number of physical I/O pins. This resource assignment flexibility is achieved through the use of a Priority Crossbar Decoder. Note that the state of a Port I/O pin can always be read in the corresponding Port latch, regardless of the Crossbar settings.

The Crossbar assigns the selected internal digital resources to the I/O pins based on the peripheral priority order of the Priority Decoder (Figure 17.3 and Figure 17.4). The registers XBR0 and XBR1, defined in SFR Definition 17.1 and SFR Definition 17.2, are used to select internal digital functions.

All Port I/Os are 5 V tolerant (refer to Figure 17.2 for the Port cell circuit). The Port I/O cells are configured as either push-pull or open-drain in the Port Output Mode registers (PnMDOUT, where n = 0, 1, 2, 3, 4). Complete Electrical Specifications for Port I/O are given in Table 17.1 on page 202.







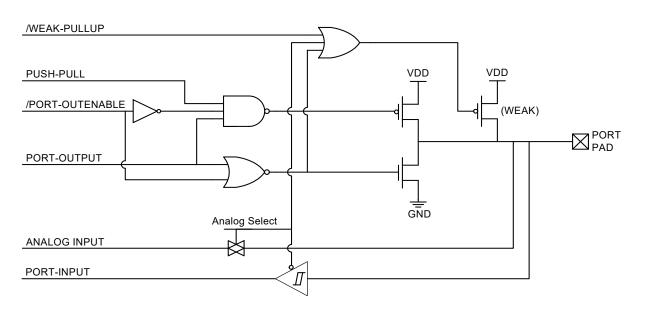


Figure 17.2. Port I/O Cell Block Diagram



#### 17.1. Priority Crossbar Decoder

The Priority Crossbar Decoder (Figure 17.3) assigns a priority to each I/O function, starting at the top with UART0. When a digital resource is selected, the least-significant unassigned Port pin is assigned to that resource (excluding UART0, which will be assigned to specific port pins (P0.1 and P0.2 in the C8051F360/3 devices, P0.4 and P0.5 in the C8051F361/2/4/5/6/7/8/9 devices). If a Port pin is assigned, the Crossbar skips that pin when assigning the next selected resource. Additionally, the Crossbar will skip Port pins whose associated bits in the PnSKIP registers are set. The PnSKIP registers allow software to skip Port pins that are to be used for analog input, dedicated functions, or GPIO.

**Important Note on Crossbar Configuration:** If a Port pin is claimed by a peripheral without use of the Crossbar, its corresponding PnSKIP bit should be set. This applies to the port pins associated with the external oscillator,  $V_{REF}$ , external CNVSTR signal, IDA0, and any selected ADC or comparator inputs. The Crossbar skips selected pins as if they were already assigned, and moves to the next unassigned pin. Figure 17.3 shows the Crossbar Decoder priority with no Port pins skipped (P0SKIP, P1SKIP, P2SKIP, P3SKIP = 0x00); Figure 17.4 shows the Crossbar Decoder priority with the P1.0 and P1.1 pins skipped (P1SKIP = 0x03).

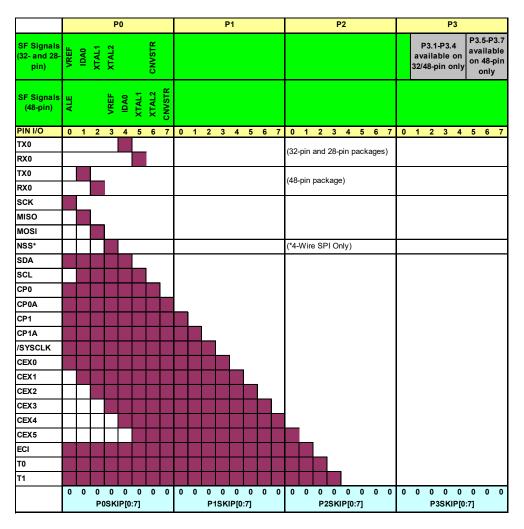


Figure 17.3. Crossbar Priority Decoder with No Pins Skipped



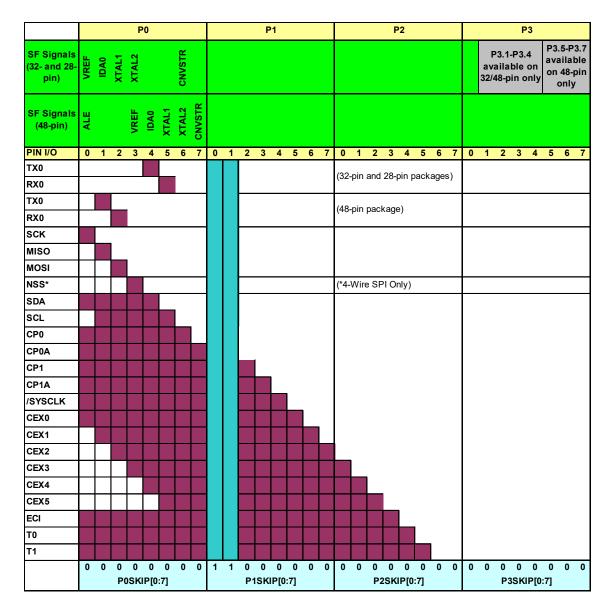


Figure 17.4. Crossbar Priority Decoder with Port Pins Skipped

Registers XBR0 and XBR1 are used to assign the digital I/O resources to the physical I/O Port pins. Note that when the SMBus is selected, the Crossbar assigns both pins associated with the SMBus (SDA and SCL); when the UART is selected, the Crossbar assigns both pins associated with the UART (TX and RX). UART0 pin assignments are fixed for bootloading purposes: UART TX0 is always assigned to P0.1 (C8051F360/3) or P0.4 (C8051F361/2/4/5/6/7/8/9); UART RX0 is always assigned to P0.2 (C8051F361/2/4/5/6/7/8/9). Standard Port I/Os appear contiguously starting at P0.0 after prioritized functions and skipped pins are assigned.

**Important Note:** The SPI can be operated in either 3-wire or 4-wire modes, depending on the state of the NSSMD1-NSSMD0 bits in register SPI0CN. According to the SPI mode, the NSS signal may or may not be routed to a Port pin.



#### 17.2. Port I/O Initialization

Port I/O initialization consists of the following steps:

- Step 1. Select the input mode (analog or digital) for all Port pins, using the Port Input Mode register (PnMDIN).
- Step 2. Select the output mode (open-drain or push-pull) for all Port pins, using the Port Output Mode register (PnMDOUT).
- Step 3. Select any pins to be skipped by the I/O Crossbar using the Port Skip registers (PnSKIP).
- Step 4. Assign Port pins to desired peripherals using the XBRn registers.
- Step 5. Enable the Crossbar (XBARE = '1').

All Port pins must be configured as either analog or digital inputs. Any pins to be used as Comparator or ADC inputs should be configured as an analog inputs. When a pin is configured as an analog input, its weak pullup, digital driver, and digital receiver are disabled. This process saves power and reduces noise on the analog input. Pins configured as digital inputs may still be used by analog peripherals; however, this practice is not recommended.

Additionally, all analog input pins should be configured to be skipped by the Crossbar (accomplished by setting the associated bits in PnSKIP). Port input mode is set in the PnMDIN register, where a '1' indicates a digital input, and a '0' indicates an analog input. All pins default to digital inputs on reset. See SFR Definition 17.4 for the PnMDIN register details.

The output driver characteristics of the I/O pins are defined using the Port Output Mode registers (PnMD-OUT). Each Port Output driver can be configured as either open drain or push-pull. This selection is required even for the digital resources selected in the XBRn registers, and is not automatic. The only exception to this is the SMBus (SDA, SCL) pins, which are configured as open-drain regardless of the PnMDOUT settings. When the WEAKPUD bit in XBR1 is '0', a weak pullup is enabled for all Port I/O configured as open-drain. WEAKPUD does not affect the push-pull Port I/O. Furthermore, the weak pullup is turned off on an output that is driving a '0' and for pins configured for analog input mode to avoid unnecessary power dissipation.

Registers XBR0 and XBR1 must be loaded with the appropriate values to select the digital I/O functions required by the design. Setting the XBARE bit in XBR1 to '1' enables the Crossbar. Until the Crossbar is enabled, the external pins remain as standard Port I/O (in input mode), regardless of the XBRn Register settings. For given XBRn Register settings, one can determine the I/O pin-out using the Priority Decode Table; as an alternative, the Configuration Wizard utility of the Silicon Labs IDE software will determine the Port I/O pin-assignments based on the XBRn Register settings.

The Crossbar must be enabled to use Port pins as standard Port I/O in output mode. **Port output drivers** are disabled while the Crossbar is disabled.



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
CP1AE	-	CP0AE	CP0E	SYSCKE	SMB0E	SPI0E	URT0E	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	CP1AE: Cor	mparator1 A	synchrono	us Output E	nable			
	0: Asynchro							
	1: Asynchro			•				
Bit 6:	CP1E: Com		•	e				
	0: CP1 unav		•					
	1: CP1 route	•						
Bit 5:	CP0AE: Cor				nable			
	0: Asynchro							
	1: Asynchro			•				
Bit 4:	CP0E: Com		•	e				
	0: CP0 unav		•					
	1: CP0 route	•						
Bit 3:	SYSCKE: /S		•					
	0: /SYSCLK							
	1: /SYSCLK							
	the CLKDIV	1–0 bits in r	egister CLł	<sel (see="" s<="" td=""><td>Section Sec</td><td>tion "16. Os</td><td>cillators" o</td><td>n</td></sel>	Section Sec	tion "16. Os	cillators" o	n
	page 170).							
Bit 2:	SMB0E: SM							
	0: SMBus I/0		•	ins.				
	1: SMBus I/		Port pins.					
Bit 1:	SPI0E: SPI							
	0: SPI I/O ur		•					
	1: SPI I/O ro		•	e that the SP	I can be as	signed eithe	er 3 or 4 G	PIO pins.
Bit 0:	URT0E: UAI	•						
	0: UART I/O							
	1: UART TX			oins P0.1 an	d P0.2 (C80	051F360/3)	or P0.4 an	d P0.5
	(C8051F3	CA 10 / A 15 10 17	10/01					

### SFR Definition 17.1. XBR0: Port I/O Crossbar Register 0



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
WEAKP	UD XBARE	T1E	T0E	ECIE		PCA0ME		0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	WEAKPUD: F	Port I/O We	eak Pullup I	Disable.				
	0: Weak Pullu	ips enable	d (except fo	or Ports who	ose I/O are	configured	as analog	input).
	1: Weak Pullu	Ips disable	ed.			-	-	
Bit 6:	XBARE: Cros	sbar Enab	le.					
	0: Crossbar d	isabled.						
	1: Crossbar e	nabled.						
Bit 5:	T1E: T1 Enab	le						
	0: T1 unavaila	able at Por	t pin.					
	1: T1 routed t	o Port pin.						
Bit 4:	T0E: T0 Enab	le						
	0: T0 unavaila	able at Por	t pin.					
	1: T0 routed t	•						
Bit 3:	ECIE: PCA0 I			t Enable				
	0: ECI unavai		•					
	1: ECI routed							
Bits 2–0:	PCA0ME: PC							
	000: All PCA			t pins.				
	001: CEX0 ro							
	010: CEX0, C							
	011: CEX0, C	,		•				
	100: CEX0, C				•			
	101: CEX0, C			EX4 routed EX4, CEX5				

### SFR Definition 17.2. XBR1: Port I/O Crossbar Register 1



### 17.3. General Purpose Port I/O

Port pins that remain unassigned by the Crossbar and are not used by analog peripherals can be used for general purpose I/O. Ports P0-P3 are accessed through corresponding special function registers (SFRs) that are both byte-addressable and bit-addressable. Port 4 (C8051F360/3 only) uses an SFR which is byte-addressable. When writing to a Port, the value written to the SFR is latched to maintain the output data value at each pin. When reading, the logic levels of the Port's input pins are returned regardless of the XBRn settings (i.e., even when the pin is assigned to another signal by the Crossbar, the Port register can always read its corresponding Port I/O pin). The exception to this is the execution of the read-modify-write instructions that target a Port Latch register as the destination. The read-modify-write instructions when operating on a Port SFR are the following: ANL, ORL, XRL, JBC, CPL, INC, DEC, DJNZ and MOV, CLR or SETB, when the destination is an individual bit in a Port SFR. For these instructions, the value of the latch register (not the pin) is read, modified, and written back to the SFR.

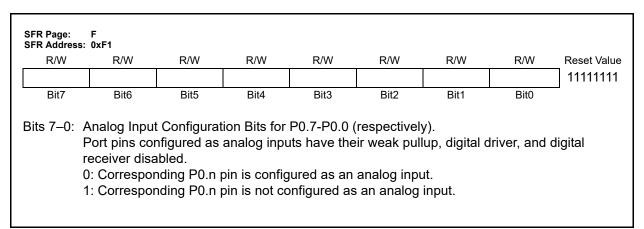
In addition to performing general purpose I/O, P0, P1, and P2 can generate a port match event if the logic levels of the Port's input pins match a software controlled value. A port match event is generated if (P0 & P0MASK) does not equal (P0MATCH & P0MASK), if (P1 & P1MASK) does not equal (P1MATCH & P1MASK), or if (P2 & P2MASK) does not equal (P2MATCH & P2MASK). This allows Software to be notified if a certain change or pattern occurs on P0, P1, or P2 input pins regardless of the XBRn settings. A port match event can cause an interrupt if EMAT (EIE2.1) is set to '1' or cause the internal oscillator to awaken from SUSPEND mode. See Section "16.1.1. Internal Oscillator Suspend Mode" on page 171 for more information.

SFR Definition 17.3. P0: Port0	SFR	Definition	17.3.	P0:	Port0
--------------------------------	-----	------------	-------	-----	-------

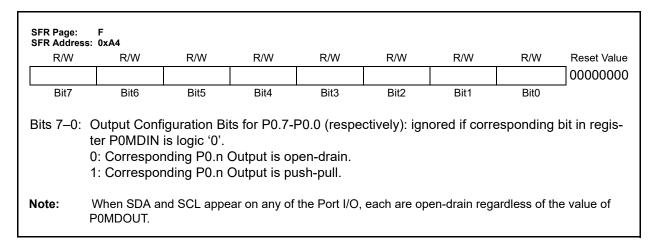
SFR Page: SFR Address:	all pages 0x80	(bit addr	essable)					
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
P0.7	P0.6	P0.5	P0.4	P0.3	P0.2	P0.1	P0.0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
C 1 F C C	Vrite - Outpu : Logic Low : Logic High Read - Alway in when cor 0: P0.n pin is : P0.n pin is	Output. o Output (hi ys reads '0' ofigured as s logic low.	gh impedar if selected	nce if corres as analog i	ponding P0	)MDOUT.n l	,	reads Port





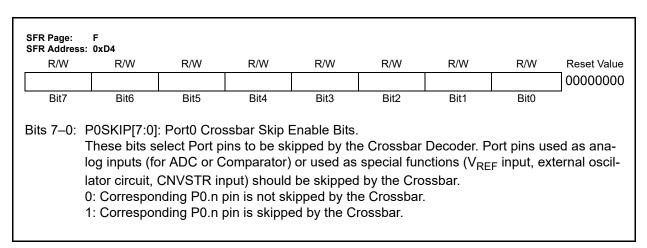


#### SFR Definition 17.5. P0MDOUT: Port0 Output Mode

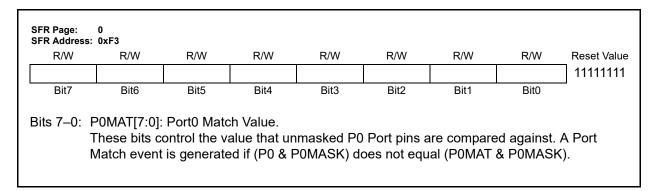




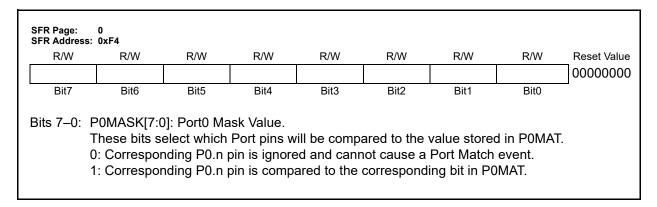
### SFR Definition 17.6. P0SKIP: Port0 Skip



# SFR Definition 17.7. P0MAT: Port0 Match



### SFR Definition 17.8. P0MASK: Port0 Mask

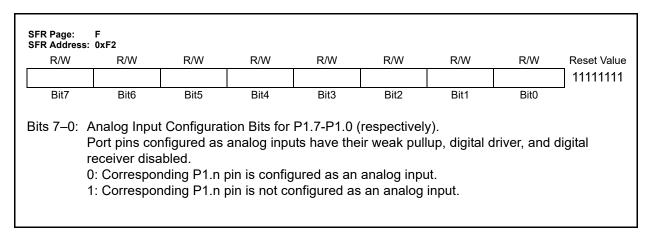




FR Address:	0x90	(bit addi	essable)					
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
P1.7	P1.6	P1.5	P1.4	P1.3	P1.2	P1.1	P1.0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
(	): Logic Low I: Logic High	Output.	•	•	ar Registers		hit = 0	

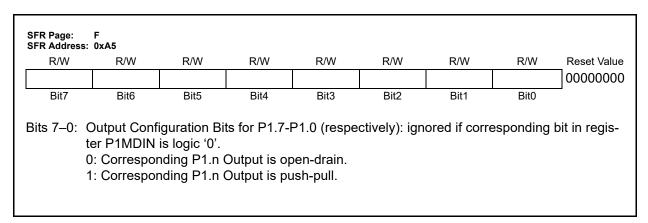
### SFR Definition 17.9. P1: Port1

#### SFR Definition 17.10. P1MDIN: Port1 Input Mode

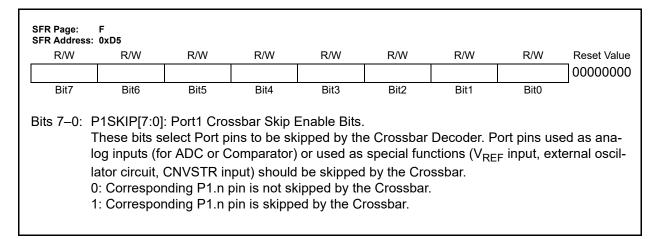




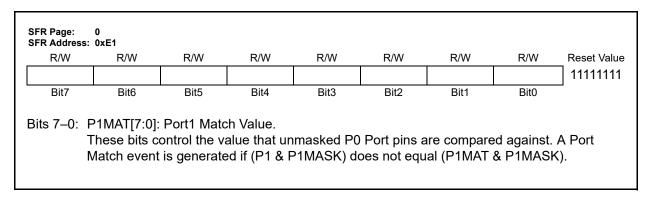
#### SFR Definition 17.11. P1MDOUT: Port1 Output Mode



# SFR Definition 17.12. P1SKIP: Port1 Skip

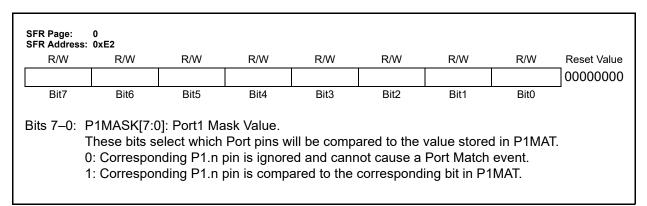


### SFR Definition 17.13. P1MAT: Port1 Match





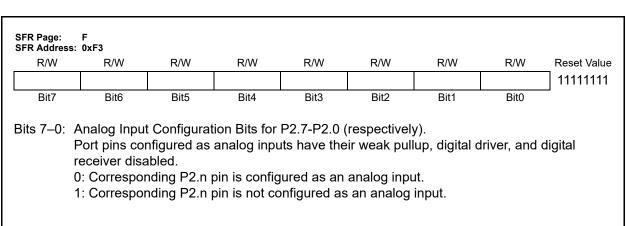
#### SFR Definition 17.14. P1MASK: Port1 Mask



### SFR Definition 17.15. P2: Port2

SFR Address:	all pages 0xA0	(bit addre	essable)					
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
P2.7	P2.6	P2.5	P2.4	P2.3	P2.2	P2.1	P2.0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
	): Logic Low I: Logic High	Output (hi	gh impedan if selected				,	





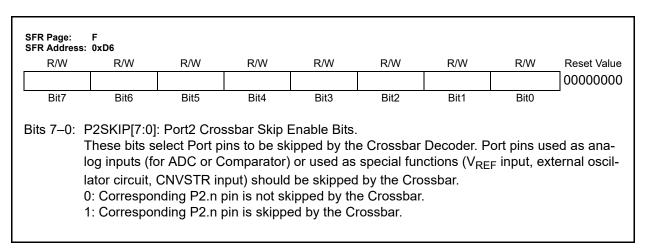
### SFR Definition 17.16. P2MDIN: Port2 Input Mode

# SFR Definition 17.17. P2MDOUT: Port2 Output Mode

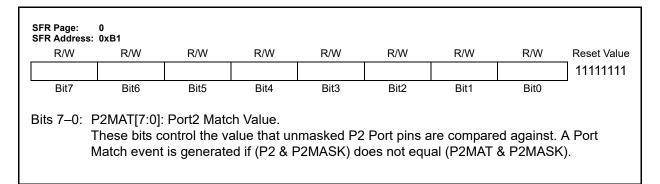
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
t (	Output Confi ter P2MDIN 0: Correspor	is logic '0'. nding P2.n (		en-drain.	ctively): ign	ored if corre	esponding	bit in regis



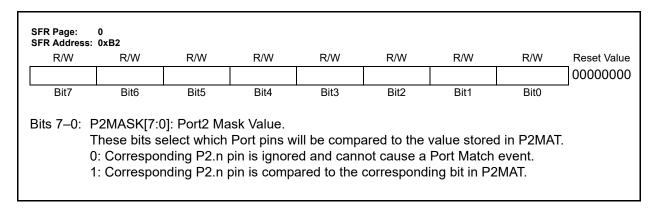
### SFR Definition 17.18. P2SKIP: Port2 Skip



#### SFR Definition 17.19. P2MAT: Port2 Match



#### SFR Definition 17.20. P2MASK: Port2 Mask



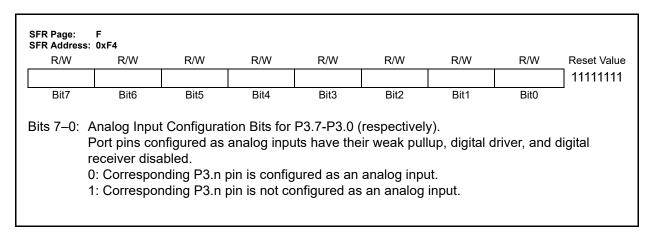
Rev. 1.2



SFR Definition	17.21.	P3:	Port3	

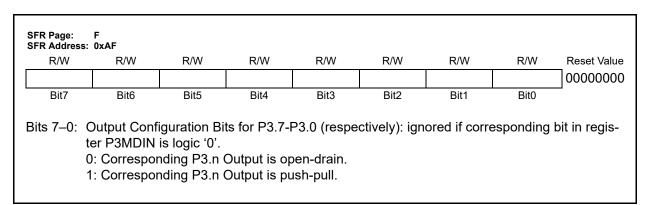
FR Address: R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
P3.7	P3.6	P3.5	P3.4	P3.3	P3.2	P3.1	P3.0	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
(	Write - Outpu ): Logic Low 1: Logic Higl	v Output. n Output (h	igh impedar	nce if corres	sponding P3	3MDOUT.n		
( F F	Write - Outp ): Logic Low	v Output. n Output (h ys reads '0 nfigured as	igh impedar ' if selected	nce if corres as analog i	sponding P3	3MDOUT.n		reads Port

### SFR Definition 17.22. P3MDIN: Port3 Input Mode

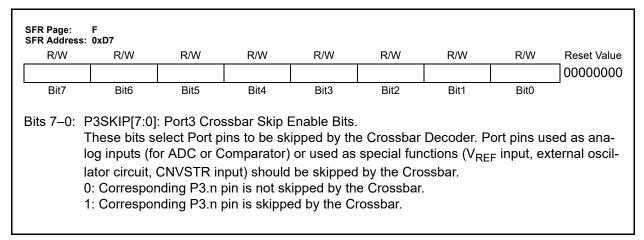




#### SFR Definition 17.23. P3MDOUT: Port3 Output Mode



### SFR Definition 17.24. P3SKIP: Port3 Skip





#### SFR Definition 17.25. P4: Port4

R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
_	P4.6	P4.5	P4.4	P4.3	P4.2	P4.1	P4.0	01111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bits 6–0:	P4.[6:0] Write - Outp	ut appears	Vrite = don't on I/O pins		ar Registers	6.		
6its 6–0:	P4.[6:0] Write - Outpu 0: Logic Low	ut appears of Output.	on I/O pins	per Crossb	Ū		hit = 0)	
its 6–0:	P4.[6:0] Write - Outpu 0: Logic Low 1: Logic Higł	ut appears o Output. n Output (hi	on I/O pins gh impedar	per Crossb	Ū		bit = 0).	
its 6–0:	P4.[6:0] Write - Outpu 0: Logic Low 1: Logic High Read - Direc	ut appears of Output. n Output (hi ctly reads Po	on I/O pins gh impedar	per Crossb	Ū		bit = 0).	
Bits 6–0:	P4.[6:0] Write - Outpu 0: Logic Low 1: Logic Higł	ut appears o Output. n Output (hi stly reads Po s logic low.	on I/O pins gh impedar ort pin.	per Crossb	Ū		bit = 0).	

# SFR Definition 17.26. P4MDOUT: Port4 Output Mode

SFR Page: SFR Address:	F 0xAE							
R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bits 6–0: 0	INUSED. R Dutput Confi : Correspor : Correspor	guration Bil nding P4.n (	s for P4.6-I Dutput is op	P4.0 (respe pen-drain.	ctively).			



#### Table 17.1. Port I/O DC Electrical Characteristics

 $V_{DD}$  = 2.7 to 3.6 V, –40 to +85 °C unless otherwise specified.

Parameters	Conditions	Min	Тур	Max	Units
	I <sub>OH</sub> = –3 mA, Port I/O push-pull	V <sub>DD</sub> – 0.7	—		
Output High Voltage	I <sub>OH</sub> = –10 μA, Port I/O push-pull	V <sub>DD</sub> – 0.1	—	—	V
	I <sub>OH</sub> = –10 mA, Port I/O push-pull	—	V <sub>DD</sub> – 0.8	—	
	I <sub>OL</sub> = 8.5 mA	_	_	0.6	
Output Low Voltage	I <sub>OL</sub> = 10 μA	—	—	0.1	V
	I <sub>OL</sub> = 25 mA	—	1.0	—	
Input High Voltage		2.0		_	V
Input Low Voltage				0.8	V
Input Leakage	Weak Pullup Off	_	_	±1	μA
Current	Weak Pullup On, V <sub>IN</sub> = 0 V	—	25	50	μΑ



# 18. SMBus

The SMBus I/O interface is a two-wire, bi-directional serial bus. The SMBus is compliant with the System Management Bus Specification, version 1.1, and compatible with the I<sup>2</sup>C serial bus. Reads and writes to the interface by the system controller are byte oriented with the SMBus interface autonomously controlling the serial transfer of the data. Data can be transferred at up to 1/10th of the system clock as a master or slave (this can be faster than allowed by the SMBus specification, depending on the system clock used). A method of extending the clock-low duration is available to accommodate devices with different speed capabilities on the same bus.

The SMBus interface may operate as a master and/or slave, and may function on a bus with multiple masters. The SMBus provides control of SDA (serial data), SCL (serial clock) generation and synchronization, arbitration logic, and START/STOP control and generation. Three SFRs are associated with the SMBus: SMB0CF configures the SMBus; SMB0CN controls the status of the SMBus; and SMB0DAT is the data register, used for both transmitting and receiving SMBus data and slave addresses.

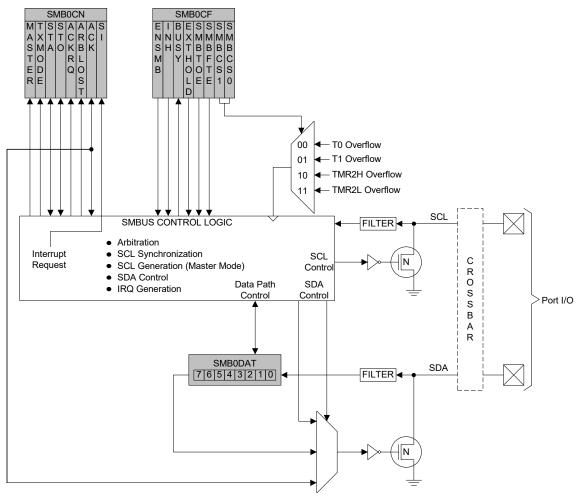


Figure 18.1. SMBus Block Diagram



#### 18.1. Supporting Documents

It is assumed the reader is familiar with or has access to the following supporting documents:

- 1. The I<sup>2</sup>C-Bus and How to Use It (including specifications), Philips Semiconductor.
- 2. The I<sup>2</sup>C-Bus Specification—Version 2.0, Philips Semiconductor.
- 3. System Management Bus Specification—Version 1.1, SBS Implementers Forum.

#### 18.2. SMBus Configuration

Figure 18.2 shows a typical SMBus configuration. The SMBus specification allows any recessive voltage between 3.0 V and 5.0 V; different devices on the bus may operate at different voltage levels. The bi-directional SCL (serial clock) and SDA (serial data) lines must be connected to a positive power supply voltage through a pullup resistor or similar circuit. Every device connected to the bus must have an open-drain or open-collector output for both the SCL and SDA lines, so that both are pulled high (recessive state) when the bus is free. The maximum number of devices on the bus is limited only by the requirement that the rise and fall times on the bus not exceed 300 ns and 1000 ns, respectively.

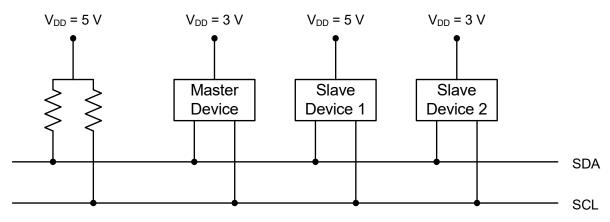


Figure 18.2. Typical SMBus Configuration

#### 18.3. SMBus Operation

Two types of data transfers are possible: data transfers from a master transmitter to an addressed slave receiver (WRITE), and data transfers from an addressed slave transmitter to a master receiver (READ). The master device initiates both types of data transfers and provides the serial clock pulses on SCL. The SMBus interface may operate as a master or a slave, and multiple master devices on the same bus are supported. If two or more masters attempt to initiate a data transfer simultaneously, an arbitration scheme is employed with a single master always winning the arbitration. Note that it is not necessary to specify one device as the Master in a system; any device who transmits a START and a slave address becomes the master for the duration of that transfer.

A typical SMBus transaction consists of a START condition followed by an address byte (Bits7–1: 7-bit slave address; Bit0: R/W direction bit), one or more bytes of data, and a STOP condition. Each byte that is received (by a master or slave) must be acknowledged (ACK) with a low SDA during a high SCL (see Figure 18.3). If the receiving device does not ACK, the transmitting device will read a NACK (not acknowledge), which is a high SDA during a high SCL.



The direction bit (R/W) occupies the least-significant bit position of the address byte. The direction bit is set to logic '1' to indicate a "READ" operation and cleared to logic '0' to indicate a "WRITE" operation.

All transactions are initiated by a master, with one or more addressed slave devices as the target. The master generates the START condition and then transmits the slave address and direction bit. If the transaction is a WRITE operation from the master to the slave, the master transmits the data a byte at a time waiting for an ACK from the slave at the end of each byte. For READ operations, the slave transmits the data waiting for an ACK from the master at the end of each byte. At the end of the data transfer, the master generates a STOP condition to terminate the transaction and free the bus. Figure 18.3 illustrates a typical SMBus transaction.

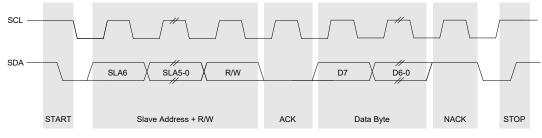


Figure 18.3. SMBus Transaction

#### 18.3.1. Arbitration

A master may start a transfer only if the bus is free. The bus is free after a STOP condition or after the SCL and SDA lines remain high for a specified time (see Section "18.3.4. SCL High (SMBus Free) Timeout" on page 206). In the event that two or more devices attempt to begin a transfer at the same time, an arbitration scheme is employed to force one master to give up the bus. The master devices continue transmitting until one attempts a HIGH while the other transmits a LOW. Since the bus is open-drain, the bus will be pulled LOW. The master attempting the HIGH will detect a LOW SDA and lose the arbitration. The winning master continues its transmission without interruption; the losing master becomes a slave and receives the rest of the transfer if addressed. This arbitration scheme is non-destructive: one device always wins, and no data is lost.

#### 18.3.2. Clock Low Extension

SMBus provides a clock synchronization mechanism, similar to I2C, which allows devices with different speed capabilities to coexist on the bus. A clock-low extension is used during a transfer in order to allow slower slave devices to communicate with faster masters. The slave may temporarily hold the SCL line LOW to extend the clock low period, effectively decreasing the serial clock frequency.

#### 18.3.3. SCL Low Timeout

If the SCL line is held low by a slave device on the bus, no further communication is possible. Furthermore, the master cannot force the SCL line high to correct the error condition. To solve this problem, the SMBus protocol specifies that devices participating in a transfer must detect any clock cycle held low longer than 25 ms as a "timeout" condition. Devices that have detected the timeout condition must reset the communication no later than 10 ms after detecting the timeout condition.

When the SMBTOE bit in SMB0CF is set, Timer 3 is used to detect SCL low timeouts. Timer 3 is forced to reload when SCL is high, and allowed to count when SCL is low. With Timer 3 enabled and configured to



overflow after 25 ms (and SMBTOE set), the Timer 3 interrupt service routine can be used to reset (disable and re-enable) the SMBus in the event of an SCL low timeout.

#### 18.3.4. SCL High (SMBus Free) Timeout

The SMBus specification stipulates that if the SCL and SDA lines remain high for more that 50  $\mu$ s, the bus is designated as free. When the SMBFTE bit in SMB0CF is set, the bus will be considered free if SCL and SDA remain high for more than 10 SMBus clock source periods. If the SMBus is waiting to generate a Master START, the START will be generated following this timeout. Note that a clock source is required for free timeout detection, even in a slave-only implementation.

#### 18.4. Using the SMBus

The SMBus can operate in both Master and Slave modes. The interface provides timing and shifting control for serial transfers; higher level protocol is determined by user software. The SMBus interface provides the following application-independent features:

- Byte-wise serial data transfers
- Clock signal generation on SCL (Master Mode only) and SDA data synchronization
- Timeout/bus error recognition, as defined by the SMB0CF configuration register
- START/STOP timing, detection, and generation
- Bus arbitration
- Interrupt generation
- Status information

SMBus interrupts are generated for each data byte or slave address that is transferred. When transmitting, this interrupt is generated after the ACK cycle so that software may read the received ACK value; when receiving data, this interrupt is generated before the ACK cycle so that software may define the outgoing ACK value. See Section "18.5. SMBus Transfer Modes" on page 214 for more details on transmission sequences.

Interrupts are also generated to indicate the beginning of a transfer when a master (START generated), or the end of a transfer when a slave (STOP detected). Software should read the SMB0CN (SMBus Control register) to find the cause of the SMBus interrupt. The SMB0CN register is described in Section "18.4.2. SMB0CN Control Register" on page 210; Table 18.4 provides a quick SMB0CN decoding reference.

SMBus configuration options include:

- Timeout detection (SCL Low Timeout and/or Bus Free Timeout)
- SDA setup and hold time extensions
- Slave event enable/disable
- Clock source selection

These options are selected in the SMB0CF register, as described in Section "18.4.1. SMBus Configuration Register" on page 207.



#### 18.4.1. SMBus Configuration Register

The SMBus Configuration register (SMB0CF) is used to enable the SMBus Master and/or Slave modes, select the SMBus clock source, and select the SMBus timing and timeout options. When the ENSMB bit is set, the SMBus is enabled for all master and slave events. Slave events may be disabled by setting the INH bit. With slave events inhibited, the SMBus interface will still monitor the SCL and SDA pins; however, the interface will NACK all received addresses and will not generate any slave interrupts. When the INH bit is set, all slave events will be inhibited following the next START (interrupts will continue for the duration of the current transfer).

SMBCS1	SMBCS0	SMBus Clock Source
0	0	Timer 0 Overflow
0	1	Timer 1 Overflow
1	0	Timer 2 High Byte Overflow
1	1	Timer 2 Low Byte Overflow

#### Table 18.1. SMBus Clock Source Selection

The SMBCS1–0 bits select the SMBus clock source, which is used only when operating as a master or when the Free Timeout detection is enabled. When operating as a master, overflows from the selected source determine the absolute minimum SCL low and high times as defined in Equation 18.1. Note that the selected clock source may be shared by other peripherals so long as the timer is left running at all times. For example, Timer 1 overflows may generate the SMBus and UART baud rates simultaneously. Timer configuration is covered in Section "21. Timers" on page 248.

$$T_{HighMin} = T_{LowMin} = \frac{1}{f_{ClockSourceOverflow}}$$

#### Equation 18.1. Minimum SCL High and Low Times

The selected clock source should be configured to establish the minimum SCL High and Low times as per Equation 18.1. When the interface is operating as a master (and SCL is not driven or extended by any other devices on the bus), the typical SMBus bit rate is approximated by Equation 18.2.





Figure 18.4 shows the typical SCL generation described by Equation 18.2. Notice that  $T_{HIGH}$  is typically twice as large as  $T_{LOW}$ . The actual SCL output may vary due to other devices on the bus (SCL may be extended low by slower slave devices, or driven low by contending master devices). The bit rate when operating as a master will never exceed the limits defined by equation Equation 18.1.

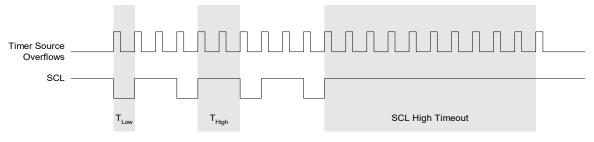


Figure 18.4. Typical SMBus SCL Generation

Setting the EXTHOLD bit extends the minimum setup and hold times for the SDA line. The minimum SDA setup time defines the absolute minimum time that SDA is stable before SCL transitions from low-to-high. The minimum SDA hold time defines the absolute minimum time that the current SDA value remains stable after SCL transitions from high-to-low. EXTHOLD should be set so that the minimum setup and hold times meet the SMBus Specification requirements of 250 ns and 300 ns, respectively. Table 18.2 shows the minimum setup and hold times for the two EXTHOLD settings. Setup and hold time extensions are typically necessary when SYSCLK is above 10 MHz.

EXTHOLD	Minimum SDA Setup Time	Minimum SDA Hold Time
	T <sub>low</sub> – 4 system clocks	
0	or	3 system clocks
	1 system clock + s/w delay*	
1	11 system clocks	12 system clocks
delay occ	if SI is cleared in the same write that	e MSB of all data transfers. The s/w ACK is written and when SI is cleared. t defines the outgoing ACK value, s/w

Table 18.2. Minimum SDA Setup and Hold Times

With the SMBTOE bit set, Timer 3 should be configured to overflow after 25 ms in order to detect SCL low timeouts (see Section "18.3.3. SCL Low Timeout" on page 205). The SMBus interface will force Timer 3 to reload while SCL is high, and allow Timer 3 to count when SCL is low. The Timer 3 interrupt service routine should be used to reset SMBus communication by disabling and re-enabling the SMBus.

SMBus Free Timeout detection can be enabled by setting the SMBFTE bit. When this bit is set, the bus will be considered free if SDA and SCL remain high for more than 10 SMBus clock source periods (see Figure 18.4). When a Free Timeout is detected, the interface will respond as if a STOP was detected (an interrupt will be generated, and STO will be set).



SFR Addres R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	Reset Value
ENSME		BUSY	EXTHOLD		SMBFTE	SMBCS1	SMBCS0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	ENSMB: SM							
	This bit enab			is interface.	When enal	bled, the int	erface const	tantly mon-
	itors the SD		•					
	0: SMBus in							
	1: SMBus in							
Bit 6:	INH: SMBus							
	When this bi		-		-		•	
	occur. This e	-	emoves the	SMBus sla	ve from the	bus. Maste	r Mode inter	rrupts are
	not affected.							
	0: SMBus S							
D:4 C.	1: SMBus S							
Bit 5:	BUSY: SMB				un un afau in iu			ta la ria (O'
	This bit is se when a STC					i progress.	it is cleared	to logic 0
Bit 4:					naion Engh			
DIL 4.	EXTHOLD: This bit cont		•					
	0: SDA Exte		•		-	10.		
	1: SDA Exte	•						
Bit 3:	SMBTOE: S							
Dit 0.	This bit enal					1' the SMF	Bus forces T	imer 3 to
	reload while							
	figured to Sp							
	Timer 3 sho		• •	•				-
	service routi					- ,		
Bit 2:	SMBFTE: S	MBus Free	Timeout De	etection Ena	ble.			
	When this b	it is set to lo	gic '1', the	bus will be o	considered	free if SCL	and SDA re	main high
	for more tha	n 10 SMBu	s clock sou	rce periods.				-
Bits 1–0:	SMBCS1-S	MBCS0: SN	/Bus Clock	Source Sel	ection.			
	These two b	its select th	e SMBus cl	ock source	, which is u	sed to gene	rate the SM	Bus bit
	rate. The se	lected devid	ce should be	e configured	d according	to Equatior	n 18.1.	
		040000	0.14		0			
	SMBCS1	SMBCS0		Bus Clock Fimer 0 Ove				
	n – – – – – – – – – – – – – – – – – – –				NUW			
	0							
	0	1	1	Fimer 1 Ove	rflow			
			Timer		erflow e Overflow			

### SFR Definition 18.1. SMB0CF: SMBus Clock/Configuration



#### 18.4.2. SMB0CN Control Register

SMB0CN is used to control the interface and to provide status information (see SFR Definition 18.2). The higher four bits of SMB0CN (MASTER, TXMODE, STA, and STO) form a status vector that can be used to jump to service routines. MASTER and TXMODE indicate the master/slave state and transmit/receive modes, respectively.

STA and STO indicate that a START and/or STOP has been detected or generated since the last SMBus interrupt. STA and STO are also used to generate START and STOP conditions when operating as a master. Writing a '1' to STA will cause the SMBus interface to enter Master Mode and generate a START when the bus becomes free (STA is not cleared by hardware after the START is generated). Writing a '1' to STO while in Master Mode will cause the interface to generate a STOP and end the current transfer after the next ACK cycle. If STO and STA are both set (while in Master Mode), a STOP followed by a START will be generated.

As a receiver, writing the ACK bit defines the outgoing ACK value; as a transmitter, reading the ACK bit indicates the value received on the last ACK cycle. ACKRQ is set each time a byte is received, indicating that an outgoing ACK value is needed. When ACKRQ is set, software should write the desired outgoing value to the ACK bit before clearing SI. A NACK will be generated if software does not write the ACK bit before clearing SI. SDA will reflect the defined ACK value immediately following a write to the ACK bit; however SCL will remain low until SI is cleared. If a received slave address is not acknowledged, further slave events will be ignored until the next START is detected.

The ARBLOST bit indicates that the interface has lost an arbitration. This may occur anytime the interface is transmitting (master or slave). A lost arbitration while operating as a slave indicates a bus error condition. ARBLOST is cleared by hardware each time SI is cleared.

The SI bit (SMBus Interrupt Flag) is set at the beginning and end of each transfer, after each byte frame, or when an arbitration is lost; see Table 18.3 for more details.

**Important Note About the SI Bit:** The SMBus interface is stalled while SI is set; thus SCL is held low, and the bus is stalled until software clears SI.

Table 18.3 lists all sources for hardware changes to the SMB0CN bits. Refer to Table 18.4 for SMBus status decoding using the SMB0CN register.



SFR Definition	18.2.	SMB0CN:	SMBus	Control
----------------	-------	---------	-------	---------

SFR Address	R	R/W	R/W	R	R	R/W	R/W	Reset Value
MASTER	RTXMODE	STA	STO	ACKRQ	ARBLOST	ACK	SI	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	MASTER: SM	Bus Mast	er/Slave In	dicator.				
	This read-only	/ bit indica	tes when t	he SMBus	is operating a	is a master		
	0: SMBus ope	•						
	1: SMBus ope							
Bit 6:	TXMODE: SM							
	This read-only			ne SMBus	is operating a	is a transm	itter.	
	0: SMBus in F 1: SMBus in T							
Bit 5:	STA: SMBus		i Moue.					
Dit U.	Write:	otart riag.						
	0: No Start ge	nerated.						
	1: When operation		master, a S	START cond	dition is trans	mitted if the	bus is fre	e (If the bus
	is not free, t	he START	is transmi	tted after a	STOP is rece	eived or a t	imeout is o	detected). If
		•	e as an act	ive Master,	a repeated S	TART will b	be generat	ted after the
	_ next ACK cy	/cle.						
	Read:		<u></u>	4 - J				
	0: No Start or	•						
Bit 4:	1: Start or rep STO: SMBus							
Dit <del>4</del> .	Write:	otop i lag.						
	0: No STOP c	ondition is	s transmitte	ed.				
	1: Setting STO	) to logic '	1' causes a	a STOP cor	ndition to be t	ransmitted	after the r	next ACK
	cycle. Wher	the STO	P condition	is generat	ed, hardware	clears STC	) to logic '	0'. If both
		O are set	, a STOP c	ondition is	transmitted fo	ollowed by a	a START o	condition.
	Read:							
	0: No Stop co							
D:+ 2.	1: Stop condit		•	,	or pending (if	In Master N	vlode).	
Bit 3:	ACKRQ: SME This read-only		-	•	MBus has red	coived a by	to and noc	de the ACK
	bit to be writte		-			cived a by		
Bit 2:	ARBLOST: SN							
	This read-only				MBus loses	arbitration v	while operation	ating as a
	transmitter. A							Ū
Bit 1:	ACK: SMBus							
	This bit define							
	ten each time		· ·					
	0: A "not ackn	-	has been r	eceived (if	in Transmitte	r Mode) OF	R will be tra	ansmitted (if
	in Receiver		e heer re-	oived (if in			vill be trees	mitted /if in
	1: An "acknow Receiver Mo	-	s been rec	eivea (II IN	nansmiller IV	ioue) OR W	m be trans	sinittea (ii In
Bit 0:	SI: SMBus Int	,	a					
Dit U.	This bit is set	•	-	ne condition	ns listed in Ta	ble 18.3. S	l must be	cleared by
	software. Whi							



Bit	Set by Hardware When:	Cleared by Hardware When:
MASTER	• A START is generated.	<ul><li>A STOP is generated.</li><li>Arbitration is lost.</li></ul>
TXMODE	<ul> <li>START is generated.</li> <li>SMB0DAT is written before the start of an SMBus frame.</li> </ul>	<ul> <li>A START is detected.</li> <li>Arbitration is lost.</li> <li>SMB0DAT is not written before the start of an SMBus frame.</li> </ul>
STA	• A START followed by an address byte is received.	Must be cleared by software.
STO	<ul> <li>A STOP is detected while addressed as a slave.</li> <li>Arbitration is lost due to a detected STOP.</li> </ul>	• A pending STOP is generated.
ACKRQ	<ul> <li>A byte has been received and an ACK response value is needed.</li> </ul>	After each ACK cycle.
ARBLOST	<ul> <li>A repeated START is detected as a MASTER when STA is low (unwanted repeated START).</li> <li>SCL is sensed low while attempting to gener- ate a STOP or repeated START condition.</li> <li>SDA is sensed low while transmitting a '1' (excluding ACK bits).</li> </ul>	• Each time SI is cleared.
ACK	<ul> <li>The incoming ACK value is low (ACKNOWLEDGE).</li> </ul>	• The incoming ACK value is high (NOT ACKNOWLEDGE).
SI	<ul> <li>A START has been generated.</li> <li>Lost arbitration.</li> <li>A byte has been transmitted and an ACK/NACK received.</li> <li>A byte has been received.</li> <li>A START or repeated START followed by a slave address + R/W has been received.</li> <li>A STOP has been received.</li> </ul>	• Must be cleared by software.

Table 18.3. Sources for Hardware Changes to SMB0CN



#### 18.4.3. Data Register

The SMBus Data register SMB0DAT holds a byte of serial data to be transmitted or one that has just been received. Software may safely read or write to the data register when the SI flag is set. Software should not attempt to access the SMB0DAT register when the SMBus is enabled and the SI flag is cleared to logic '0', as the interface may be in the process of shifting a byte of data into or out of the register.

Data in SMB0DAT is always shifted out MSB first. After a byte has been received, the first bit of received data is located at the MSB of SMB0DAT. While data is being shifted out, data on the bus is simultaneously being shifted in. SMB0DAT always contains the last data byte present on the bus. In the event of lost arbitration, the transition from master transmitter to slave receiver is made with the correct data or address in SMB0DAT.

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
f	SMB0DAT: \$ The SMB0D face or a byt from or write	AT register that has j	contains a ust been re	ceived on th	ne SMBus s	erial interfa	ce. The CF	PU can read

#### SFR Definition 18.3. SMB0DAT: SMBus Data



#### 18.5. SMBus Transfer Modes

The SMBus interface may be configured to operate as master and/or slave. At any particular time, it will be operating in one of the following four modes: Master Transmitter, Master Receiver, Slave Transmitter, or Slave Receiver. The SMBus interface enters Master Mode any time a START is generated, and remains in Master Mode until it loses an arbitration or generates a STOP. An SMBus interrupt is generated at the end of all SMBus byte frames; however, note that the interrupt is generated before the ACK cycle when operating as a receiver, and after the ACK cycle when operating as a transmitter.

#### 18.5.1. Master Transmitter Mode

Serial data is transmitted on SDA while the serial clock is output on SCL. The SMBus interface generates the START condition and transmits the first byte containing the address of the target slave and the data direction bit. In this case the data direction bit (R/W) will be logic '0' (WRITE). The master then transmits one or more bytes of serial data. After each byte is transmitted, an acknowledge bit is generated by the slave. The transfer is ended when the STO bit is set and a STOP is generated. Note that the interface will switch to Master Receiver Mode if SMB0DAT is not written following a Master Transmitter interrupt. Figure 18.5 shows a typical Master Transmitter sequence. Two transmit data bytes are shown, though any number of bytes may be transmitted. Notice that the 'data byte transferred' interrupts occur **after** the ACK cycle in this mode.

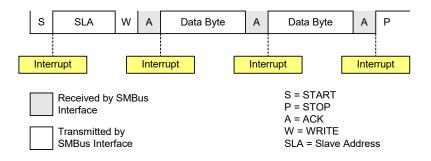


Figure 18.5. Typical Master Transmitter Sequence



#### 18.5.2. Master Receiver Mode

Serial data is received on SDA while the serial clock is output on SCL. The SMBus interface generates the START condition and transmits the first byte containing the address of the target slave and the data direction bit. In this case the data direction bit (R/W) will be logic '1' (READ). Serial data is then received from the slave on SDA while the SMBus outputs the serial clock. The slave transmits one or more bytes of serial data. After each byte is received, ACKRQ is set to '1' and an interrupt is generated. Software must write the ACK bit (SMB0CN.1) to define the outgoing acknowledge value (Note: writing a '1' to the ACK bit generates an ACK; writing a '0' generates a NACK). Software should write a '0' to the ACK bit after the last byte is received, to transmit a NACK. The interface exits Master Receiver Mode after the STO bit is set and a STOP is generated. The interface will switch to Master Transmitter Mode if SMB0DAT is written while an active Master Receiver. Figure 18.6 shows a typical Master Receiver sequence. Two received data bytes are shown, though any number of bytes may be received. Notice that the 'data byte transferred' interrupts occur **before** the ACK cycle in this mode.

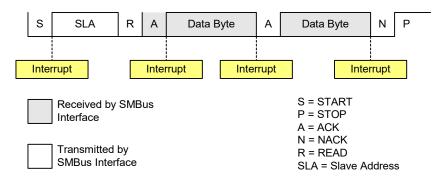


Figure 18.6. Typical Master Receiver Sequence



#### 18.5.3. Slave Receiver Mode

Serial data is received on SDA and the clock is received on SCL. When slave events are enabled (INH = 0), the interface enters Slave Receiver Mode when a START followed by a slave address and direction bit (WRITE in this case) is received. Upon entering Slave Receiver Mode, an interrupt is generated and the ACKRQ bit is set. Software responds to the received slave address with an ACK, or ignores the received slave address with a NACK. If the received slave address is ignored, slave interrupts will be inhibited until the next START is detected. If the received slave address is acknowledged, zero or more data bytes are received. Software must write the ACK bit after each received byte to ACK or NACK the received byte. The interface exits Slave Receiver Mode after receiving a STOP. Note that the interface will switch to Slave Transmitter Mode if SMB0DAT is written while an active Slave Receiver. Figure 18.7 shows a typical Slave Receiver sequence. Two received data bytes are shown, though any number of bytes may be received. Notice that the 'data byte transferred' interrupts occur **before** the ACK cycle in this mode.

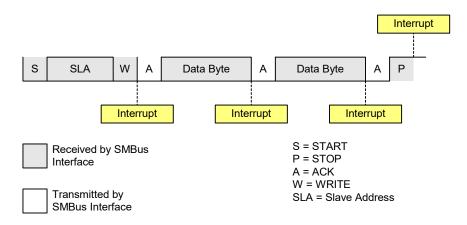


Figure 18.7. Typical Slave Receiver Sequence



#### 18.5.4. Slave Transmitter Mode

Serial data is transmitted on SDA and the clock is received on SCL. When slave events are enabled (INH = 0), the interface enters Slave Receiver Mode (to receive the slave address) when a START followed by a slave address and direction bit (READ in this case) is received. Upon entering Slave Transmitter Mode, an interrupt is generated and the ACKRQ bit is set. Software responds to the received slave address with an ACK, or ignores the received slave address with a NACK. If the received slave address is ignored, slave interrupts will be inhibited until a START is detected. If the received slave address is acknowledged, data should be written to SMB0DAT to be transmitted. The interface enters Slave Transmitter Mode, and transmits one or more bytes of data. After each byte is transmitted, the master sends an acknowledge bit; if the acknowledge bit is an ACK, SMB0DAT should be written to before SI is cleared (Note: an error condition may be generated if SMB0DAT is written following a received NACK while in Slave Transmitter Mode). The interface exits Slave Transmitter Mode after receiving a STOP. Note that the interface will switch to Slave Receiver Mode if SMB0DAT is not written following a Slave Transmitter interrupt. Figure 18.8 shows a typical Slave Transmitter sequence. Two transmitted data bytes are shown, though any number of bytes may be transmitted. Notice that the 'data byte transferred' interrupts occur **after** the ACK cycle in this mode.

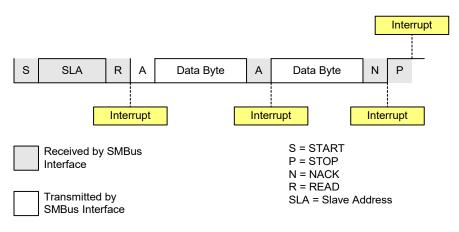


Figure 18.8. Typical Slave Transmitter Sequence



#### 18.6. SMBus Status Decoding

The current SMBus status can be easily decoded using the SMB0CN register. In the table below, STATUS VECTOR refers to the four upper bits of SMB0CN: MASTER, TXMODE, STA, and STO. The shown response options are only the typical responses; application-specific procedures are allowed as long as they conform to the SMBus specification. Highlighted responses are allowed but do not conform to the SMBus specification.

	Valu	es I	Read	d				/alue Vritte	
Mode	Status Vector	ACKRQ	ARBLOST	ACK	Current SMbus State	Typical Response Options	STA	STo	ACK
	1110	0	0	х	A master START was generated.	Load slave address + R/W into SMB0DAT.	0	0	х
		0	0	0	A master data or address byte	Set STA to restart transfer.	1	0	Х
- L		Ŭ			was transmitted; NACK received.	Abort transfer.	0	1	Х
Master Transmitter						Load next data byte into SMB0DAT.	0	0	Х
Tra	1100					End transfer with STOP.	0	1	Х
Mastei	1100	0	0	1	A master data or address byte was transmitted; ACK received.	End transfer with STOP and start another transfer.	1	1	х
						Send repeated START.	1	0	Х
						Switch to Master Receiver Mode (clear SI without writ- ing new data to SMB0DAT).	0	0	Х

Table 18.4. SMBus Status Decoding



	Valu	es I	Read	ł				/alue /ritte	-
Mode	Status Vector	ACKRQ	ARBLOST	ACK	Current SMbus State	Typical Response Options	STA	STo	ACK
						Acknowledge received byte; Read SMB0DAT.	0	0	1
						Send NACK to indicate last byte, and send STOP.	0	1	0
						Send NACK to indicate last byte, and send STOP fol- lowed by START.	1	1	0
ceiver						Send ACK followed by repeated START.	1	0	1
Master Receiver	1000	1	0	х	A master data byte was received; ACK requested.	Send NACK to indicate last byte, and send repeated START.	1	0	0
Σ						Send ACK and switch to Master Transmitter Mode (write to SMB0DAT before clearing SI).	0	0	1
						Send NACK and switch to Master Transmitter Mode (write to SMB0DAT before clearing SI).	0	0	0
er		0	0	0	A slave byte was transmitted; NACK received.	No action required (expect- ing STOP condition).	0	0	Х
ansmitt	0100	0	0	1	A slave byte was transmitted; ACK received.	Load SMB0DAT with next data byte to transmit.	0	0	Х
Slave Transmitter		0	1	х	A Slave byte was transmitted; error detected.	No action required (expect- ing Master to end transfer).	0	0	х
Ŝ	0101	0	х	х	A STOP was detected while an addressed Slave Transmitter.	No action required (transfer complete).	0	0	х

Table 18.4. SMBus Status Decoding (Continued)



## C8051F360/1/2/3/4/5/6/7/8/9

	Valu	ies I	Read	d				/alue Vritte	-
Mode	Status Vector	ACKRQ	ARBLOST	ACK	Current SMbus State	Typical Response Options	STA	STo	ACK
		1	0	x	A slave address was received;	Acknowledge received address.	0	0	1
			0	^	ACK requested.	Do not acknowledge received address.	0	0	0
						Acknowledge received address.	0	0	1
	0010	1	1	x	Lost arbitration as master; slave address received; ACK	Do not acknowledge received address.	0	0	0
					requested.	Reschedule failed transfer; do not acknowledge received address.	1	0	0
ver		0	1	x	Lost arbitration while attempting a	Abort failed transfer.	0	0	Х
ecei		ľ			repeated START.	Reschedule failed transfer.	1	0	Х
Slave Receiver		1	1	х	Lost arbitration while attempting a STOP.	No action required (transfer complete/aborted).	0	0	0
S	0001	0	0	х	A STOP was detected while an addressed slave receiver.	No action required (transfer complete).	0	0	Х
		0	1	x	Lost arbitration due to a detected	Abort transfer.	0	0	Х
			'		STOP.	Reschedule failed transfer.	1	0	Х
		1	0	x	A slave byte was received; ACK	Acknowledge received byte; Read SMB0DAT.	0	0	1
	0000		0		requested.	Do not acknowledge received byte.	0	0	0
		1	1	x	Lost arbitration while transmitting	Abort failed transfer.	0	0	0
					a data byte as master.	Reschedule failed transfer.	1	0	0

Table 18.4. SMBus Status Decoding (Continued)

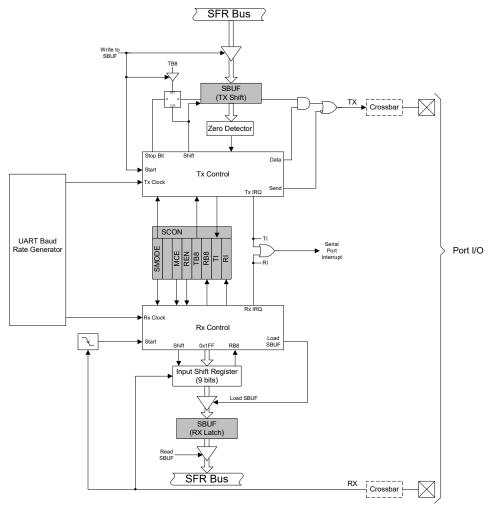


### 19. UART0

UART0 is an asynchronous, full duplex serial port offering modes 1 and 3 of the standard 8051 UART. Enhanced baud rate support allows a wide range of clock sources to generate standard baud rates (details in Section "19.1. Enhanced Baud Rate Generation" on page 222). Received data buffering allows UART0 to start reception of a second incoming data byte before software has finished reading the previous data byte.

UART0 has two associated SFRs: Serial Control Register 0 (SCON0) and Serial Data Buffer 0 (SBUF0). The single SBUF0 location provides access to both transmit and receive registers. Writes to SBUF0 always access the Transmit register. Reads of SBUF0 always access the buffered Receive register; it is not possible to read data from the Transmit register.

With UART0 interrupts enabled, an interrupt is generated each time a transmit is completed (TI0 is set in SCON0), or a data byte has been received (RI0 is set in SCON0). The UART0 interrupt flags are not cleared by hardware when the CPU vectors to the interrupt service routine. They must be cleared manually by software, allowing software to determine the cause of the UART0 interrupt (transmit complete or receive complete).

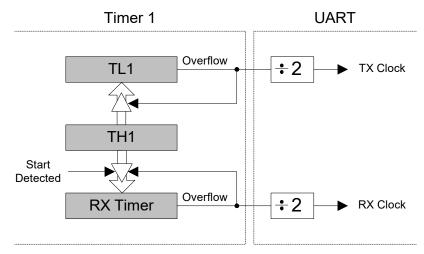






#### 19.1. Enhanced Baud Rate Generation

The UART0 baud rate is generated by Timer 1 in 8-bit auto-reload mode. The TX clock is generated by TL1; the RX clock is generated by a copy of TL1 (shown as RX Timer in Figure 19.2), which is not useraccessible. Both TX and RX Timer overflows are divided by two to generate the TX and RX baud rates. The RX Timer runs when Timer 1 is enabled, and uses the same reload value (TH1). However, an RX Timer reload is forced when a START condition is detected on the RX pin. This allows a receive to begin any time a START is detected, independent of the TX Timer state.





Timer 1 should be configured for Mode 2, 8-bit auto-reload (see Section "21.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload" on page 250). The Timer 1 reload value should be set so that overflows will occur at two times the desired UART baud rate frequency. Note that Timer 1 may be clocked by one of six sources: SYSCLK, SYSCLK / 4, SYSCLK / 12, SYSCLK / 48, the external oscillator clock / 8, or an external input T1. For any given Timer 1 clock source, the UART0 baud rate is determined by Equation 19.1-A and Equation 19.1-B.

A) UartBaudRate = 
$$\frac{1}{2} \times T1_Overflow_Rate$$
  
B) T1\_Overflow\_Rate =  $\frac{T1_{CLK}}{256 - TH1}$ 

#### Equation 19.1. UART0 Baud Rate

Where  $T1_{CLK}$  is the frequency of the clock supplied to Timer 1, and T1H is the high byte of Timer 1 (reload value). Timer 1 clock frequency is selected as described in Section "21. Timers" on page 248. A quick reference for typical baud rates and system clock frequencies is given in Table 19.1 through Table 19.6. Note that the internal oscillator may still generate the system clock when the external oscillator is driving Timer 1.



#### **19.2.** Operational Modes

UART0 provides standard asynchronous, full duplex communication. The UART mode (8-bit or 9-bit) is selected by the S0MODE bit (SCON0.7). Typical UART connection options are shown below.

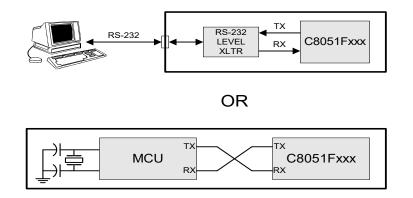


Figure 19.3. UART Interconnect Diagram

#### 19.2.1. 8-Bit UART

8-Bit UART mode uses a total of 10 bits per data byte: one start bit, eight data bits (LSB first), and one stop bit. Data are transmitted LSB first from the TX0 pin and received at the RX0 pin. On receive, the eight data bits are stored in SBUF0 and the stop bit goes into RB80 (SCON0.2).

Data transmission begins when software writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to logic '1'. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: RI0 must be logic '0', and if MCE0 is logic '1', the stop bit must be logic '1'. In the event of a receive data overrun, the first received 8 bits are latched into the SBUF0 receive register and the following overrun data bits are lost.

If these conditions are met, the eight bits of data is stored in SBUF0, the stop bit is stored in RB80 and the RI0 flag is set. If these conditions are not met, SBUF0 and RB80 will not be loaded and the RI0 flag will not be set. An interrupt will occur if enabled when either TI0 or RI0 is set.

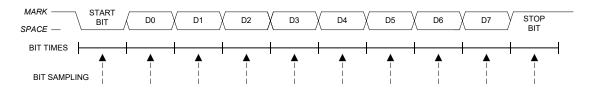


Figure 19.4. 8-Bit UART Timing Diagram



#### 19.2.2. 9-Bit UART

9-bit UART mode uses a total of eleven bits per data byte: a start bit, 8 data bits (LSB first), a programmable ninth data bit, and a stop bit. The state of the ninth transmit data bit is determined by the value in TB80 (SCON0.3), which is assigned by user software. It can be assigned the value of the parity flag (bit P in register PSW) for error detection, or used in multiprocessor communications. On receive, the ninth data bit goes into RB80 (SCON0.2) and the stop bit is ignored.

Data transmission begins when an instruction writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to '1'. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: (1) RI0 must be logic '0', and (2) if MCE0 is logic '1', the 9th bit must be logic '1' (when MCE0 is logic '0', the state of the ninth data bit is unimportant). If these conditions are met, the eight bits of data are stored in SBUF0, the ninth bit is stored in RB80, and the RI0 flag is set to '1'. If the above conditions are not met, SBUF0 and RB80 will not be loaded and the RI0 flag will not be set to '1'. A UART0 interrupt will occur if enabled when either TI0 or RI0 is set to '1'.

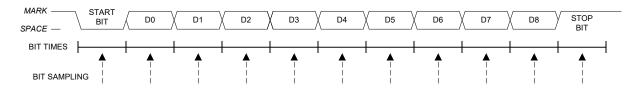


Figure 19.5. 9-Bit UART Timing Diagram



#### **19.3. Multiprocessor Communications**

9-Bit UART mode supports multiprocessor communication between a master processor and one or more slave processors by special use of the ninth data bit. When a master processor wants to transmit to one or more slaves, it first sends an address byte to select the target(s). An address byte differs from a data byte in that its ninth bit is logic '1'; in a data byte, the ninth bit is always set to logic '0'.

Setting the MCE0 bit (SCON0.5) of a slave processor configures its UART such that when a stop bit is received, the UART will generate an interrupt only if the ninth bit is logic '1' (RB80 = 1) signifying an address byte has been received. In the UART interrupt handler, software will compare the received address with the slave's own assigned 8-bit address. If the addresses match, the slave will clear its MCE0 bit to enable interrupts on the reception of the following data byte(s). Slaves that weren't addressed leave their MCE0 bits set and do not generate interrupts on the reception of the following data bytes, thereby ignoring the data. Once the entire message is received, the addressed slave resets its MCE0 bit to ignore all transmissions until it receives the next address byte.

Multiple addresses can be assigned to a single slave and/or a single address can be assigned to multiple slaves, thereby enabling "broadcast" transmissions to more than one slave simultaneously. The master processor can be configured to receive all transmissions or a protocol can be implemented such that the master/slave role is temporarily reversed to enable half-duplex transmission between the original master and slave(s).

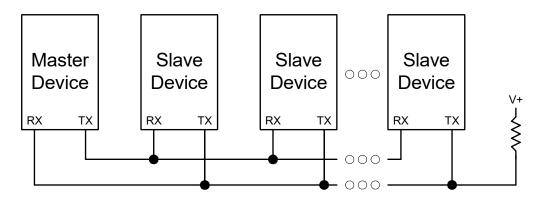


Figure 19.6. UART Multi-Processor Mode Interconnect Diagram



SFR Page: SFR Address	all pages 5: 0x98	,	essable)					
R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
SOMODE	E	MCE0	REN0	TB80	RB80	TI0	RI0	0100000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7:	SOMODE: S							
	This bit sele							
	0: 8-bit UAR							
	1: 9-bit UAR							
Bit 6:	UNUSED. R							
Bit 5:	MCE0: Multi	•						
	The function				rial Port 0 C	peration Mo	ode.	
	S0MODE =							
		•	f stop bit is i	•				
			be activated	•	•	l '1'.		
	S0MODE =	•			Enable.			
		•	f ninth bit is	•				
			d an interru	ot is genera	ted only wh	en the ninth	n bit is logi	c '1'.
Bit 4:	REN0: Rece							
	This bit enal			receiver.				
	0: UART0 re	•						
	1: UART0 re							
Bit 3:	TB80: Ninth							
	The logic lev							RT Mode. I
	is not used i			et or cleare	ed by softwa	are as requi	red.	
Bit 2:	RB80: Ninth							
	RB80 is ass	-	alue of the S	STOP bit in	Mode 0; it i	s assigned t	the value of	of the 9th
	data bit in M							
Bit 1:	TI0: Transm		0					
	Set by hard							
	bit UART Mo							
	interrupt is e		•			tor to the U/	ART0 inter	rupt service
<b>-</b> •	routine. This			anually by s	oftware.			
Bit 0:	RI0: Receive							
	Set to '1' by							
	sampling tim	,		•		•		
	to vector to t	Ine UARIO	interrupt se	rvice routine	e. This bit m	nust be clea	red manua	ally by soft-
	ware.							

#### SFR Definition 19.1. SCON0: Serial Port 0 Control



#### SFR Definition 19.2. SBUF0: Serial (UART0) Port Data Buffer

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
	This SFR ac data is writte			the transmi	t shift regis	and a receiv ter and is he read of SB	eld for seria	al transmis



			Fre	equency: 24.5	MHz		
	Target Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select) <sup>1</sup>	T1M <sup>1</sup>	Timer 1 Reload Value (hex)
	230400	-0.32%	106	SYSCLK	XX <sup>2</sup>	1	0xCB
	115200	-0.32%	212	SYSCLK	XX	1	0x96
	57600	0.15%	426	SYSCLK	XX	1	0x2B
c	28800	-0.32%	848	SYSCLK/4	01	0	0x96
< from Osc.	14400	0.15%	1704	SYSCLK/12	00	0	0xB9
$\times \overline{O}$	9600	-0.32%	2544	SYSCLK/12	00	0	0x96
SYSCL <sup>}</sup> Internal	2400	-0.32%	10176	SYSCLK/48	10	0	0x96
SY Int∈	1200	0.15%	20448	SYSCLK/48	10	0	0x2B
Notes	:						

# Table 19.1. Timer Settings for Standard Baud RatesUsing The Internal 24.5 MHz Oscillator

1. SCA1–SCA0 and T1M bit definitions can be found in Section 21.1.



Target	Frequency: 25.0 MHz									
Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select) <sup>1</sup>	T1M <sup>1</sup>	Timer 1 Reload Value (hex)				
230400	-0.47%	108	SYSCLK	XX <sup>2</sup>	1	0xCA				
115200	0.45%	218	SYSCLK	XX	1	0x93				
57600	-0.01%	434	SYSCLK	XX	1	0x27				
28800	0.45%	872	SYSCLK/4	01	0	0x93				
14400	-0.01%	1736	SYSCLK/4	01	0	0x27				
9600	0.15%	2608	EXTCLK/8	11	0	0x5D				
2400	0.45%	10464	SYSCLK/48	10	0	0x93				
1200	-0.01%	20832	SYSCLK/48	10	0	0x27				
57600	-0.47%	432	EXTCLK/8	11	0	0xE5				
28800	-0.47%	864	EXTCLK/8	11	0	0xCA				
14400	0.45%	1744	EXTCLK/8	11	0	0x93				
9600	0.15%	2608	EXTCLK/8	11	0	0x5D				
	230400 115200 57600 28800 14400 9600 2400 1200 57600 28800 14400	230400       -0.47%         115200       0.45%         57600       -0.01%         28800       0.45%         14400       -0.01%         9600       0.15%         2400       0.45%         1200       -0.01%         57600       -0.47%         28800       -0.47%         14400       0.45%	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	230400        0.47%         108         SYSCLK           115200         0.45%         218         SYSCLK           57600        0.01%         434         SYSCLK           28800         0.45%         872         SYSCLK/4           14400        0.01%         1736         SYSCLK/4           9600         0.15%         2608         EXTCLK/8           2400         0.45%         10464         SYSCLK/48           1200         -0.01%         20832         SYSCLK/48           57600         -0.47%         432         EXTCLK/8           28800         -0.47%         864         EXTCLK/8           14400         0.45%         1744         EXTCLK/8	230400         -0.47%         108         SYSCLK         XX <sup>2</sup> 115200         0.45%         218         SYSCLK         XX           57600         -0.01%         434         SYSCLK         XX           28800         0.45%         872         SYSCLK/4         01           14400         -0.01%         1736         SYSCLK/4         01           9600         0.15%         2608         EXTCLK/8         11           2400         0.45%         10464         SYSCLK/48         10           1200         -0.01%         20832         SYSCLK/48         10           57600         -0.47%         432         EXTCLK/8         11           28800         -0.47%         864         EXTCLK/8         11           14400         0.45%         1744         EXTCLK/8         11	230400         -0.47%         108         SYSCLK         XX <sup>2</sup> 1           115200         0.45%         218         SYSCLK         XX         1           57600         -0.01%         434         SYSCLK         XX         1           28800         0.45%         872         SYSCLK/4         01         0           14400         -0.01%         1736         SYSCLK/4         01         0           9600         0.15%         2608         EXTCLK/8         11         0           2400         0.45%         10464         SYSCLK/48         10         0           1200         -0.01%         20832         SYSCLK/48         10         0           57600         -0.47%         432         EXTCLK/8         11         0           28800         -0.47%         864         EXTCLK/8         11         0           14400         0.45%         1744         EXTCLK/8         11         0				

#### Table 19.2. Timer Settings for Standard Baud Rates Using an External 25.0 MHz Oscillator



			Freq	uency: 22.118	4 MHz		
	Target Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select) <sup>1</sup>	T1M <sup>1</sup>	Timer 1 Reload Value (hex)
¥	230400	0.00%	96	SYSCLK	XX <sup>2</sup>	1	0xD0
Cloc	115200	0.00%	192	SYSCLK	XX	1	0xA0
Timer Clock Osc.	57600	0.00%	384	SYSCLK	XX	1	0x40
Time Osc.	28800	0.00%	768	SYSCLK/12	00	0	0xE0
ind nal	14400	0.00%	1536	SYSCLK/12	00	0	0xC0
-K a xter	9600	0.00%	2304	SYSCLK/12	00	0	0xA0
SCL	2400	0.00%	9216	SYSCLK/48	10	0	0xA0
SYSCLK and 7 from External (	1200	0.00%	18432	SYSCLK/48	10	0	0x40
sc.	230400	0.00%	96	EXTCLK/8	11	0	0xFA
LK from Internal Osc., Clock from External O	115200	0.00%	192	EXTCLK/8	11	0	0xF4
n Exte	57600	0.00%	384	EXTCLK/8	11	0	0xE8
om Ir k fror	28800	0.00%	768	EXTCLK/8	11	0	0xD0
Cloc	14400	0.00%	1536	EXTCLK/8	11	0	0xA0
SYSCLK from Internal Osc., Timer Clock from External O	9600	0.00%	2304	EXTCLK/8	11	0	0x70
Notes:		ad T1N bit dafia	itiana aon ha	found in Section	04.4	1	1

# Table 19.3. Timer Settings for Standard Baud RatesUsing an External 22.1184 MHz Oscillator

1. SCA1–SCA0 and T1M bit definitions can be found in Section 21.1.



			Fred	quency: 18.43	2 MHz		
	Target Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select) <sup>1</sup>	T1M <sup>1</sup>	Timer 1 Reload Value (hex)
$\mathbf{x}$	230400	0.00%	80	SYSCLK	XX <sup>2</sup>	1	0xD8
Cloc	115200	0.00%	160	SYSCLK	XX	1	0xB0
Timer Clock Osc.	57600	0.00%	320	SYSCLK	XX	1	0x60
Time Osc.	28800	0.00%	640	SYSCLK/4	01	0	0xB0
	14400	0.00%	1280	SYSCLK/4	01	0	0x60
SYSCLK and from External	9600	0.00%	1920	SYSCLK/12	00	0	0xB0
SYSCLK from Exte	2400	0.00%	7680	SYSCLK/48	10	0	0xB0
SΥ; fror	1200	0.00%	15360	SYSCLK/48	10	0	0x60
osc.	230400	0.00%	80	EXTCLK/8	11	0	0xFB
SYSCLK from Internal Osc., Timer Clock from External O	115200	0.00%	160	EXTCLK/8	11	0	0xF6
nterna n Exte	57600	0.00%	320	EXTCLK/8	11	0	0xEC
rom Ir sk fror	28800	0.00%	640	EXTCLK/8	11	0	0xD8
CLK fr r Cloc	14400	0.00%	1280	EXTCLK/8	11	0	0xB0
SYS( Timel	9600	0.00%	1920	EXTCLK/8	11	0	0x88
Notes:	0014 0010						

# Table 19.4. Timer Settings for Standard Baud RatesUsing an External 18.432 MHz Oscillator

1. SCA1–SCA0 and T1M bit definitions can be found in Section 21.1.



		Frequency: 11.0592 MHz									
	Target Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select) <sup>1</sup>	T1M <sup>1</sup>	Timer 1 Reload Value (hex)				
¥	230400	0.00%	48	SYSCLK	XX <sup>2</sup>	1	0xE8				
Cloc	115200	0.00%	96	SYSCLK	XX	1	0xD0				
Timer Clock Osc.	57600	0.00%	192	SYSCLK	XX	1	0xA0				
Time Osc.	28800	0.00%	384	SYSCLK	XX	1	0x40				
	14400	0.00%	768	SYSCLK/12	00	0	0xE0				
SYSCLK and from External	9600	0.00%	1152	SYSCLK/12	00	0	0xD0				
SCI n E	2400	0.00%	4608	SYSCLK/12	00	0	0x40				
SY: fror	1200	0.00%	9216	SYSCLK/48	10	0	0xA0				
osc.	230400	0.00%	48	EXTCLK/8	11	0	0xFD				
l Osc ernal	115200	0.00%	96	EXTCLK/8	11	0	0xFA				
LK from Internal Osc., Clock from External O	57600	0.00%	192	EXTCLK/8	11	0	0xF4				
om Ir k fror	28800	0.00%	384	EXTCLK/8	11	0	0xE8				
SYSCLK from Internal Osc., Timer Clock from External O	14400	0.00%	768	EXTCLK/8	11	0	0xD0				
SYSC Timer	9600	0.00%	1152	EXTCLK/8	11	0	0xB8				
Notes:		nd T1M bit dofin	itiana aan ha	found in Section	21.1						

# Table 19.5. Timer Settings for Standard Baud RatesUsing an External 11.0592 MHz Oscillator

1. SCA1–SCA0 and T1M bit definitions can be found in Section 21.1.



Target Baud Rate (bps) 230400	Baud Rate% Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1-SCA0	T1M <sup>1</sup>	Timer 1
230400	0.000/			(pre-scale select) <sup>1</sup>		Reload Value (hex)
	0.00%	16	SYSCLK	XX <sup>2</sup>	1	0xF8
115200	0.00%	32	SYSCLK	XX	1	0xF0
57600	0.00%	64	SYSCLK	XX	1	0xE0
28800	0.00%	128	SYSCLK	XX	1	0xC0
14400	0.00%	256	SYSCLK	XX	1	0x80
9600	0.00%	384	SYSCLK	XX	1	0x40
2400	0.00%	1536	SYSCLK/12	00	0	0xC0
1200	0.00%	3072	SYSCLK/12	00	0	0x80
230400	0.00%	16	EXTCLK/8	11	0	0xFF
115200	0.00%	32	EXTCLK/8	11	0	0xFE
57600	0.00%	64	EXTCLK/8	11	0	0xFC
28800	0.00%	128	EXTCLK/8	11	0	0xF8
14400	0.00%	256	EXTCLK/8	11	0	0xF0
9600	0.00%	384	EXTCLK/8	11	0	0xE8
	28800 14400 9600 2400 1200 230400 115200 57600 28800 14400 9600	28800       0.00%         14400       0.00%         9600       0.00%         2400       0.00%         1200       0.00%         230400       0.00%         115200       0.00%         57600       0.00%         28800       0.00%         14400       0.00%	288000.00%128144000.00%25696000.00%38424000.00%153612000.00%30722304000.00%161152000.00%32576000.00%64288000.00%128144000.00%25696000.00%384	28800         0.00%         128         SYSCLK           14400         0.00%         256         SYSCLK           9600         0.00%         384         SYSCLK           2400         0.00%         1536         SYSCLK/12           1200         0.00%         3072         SYSCLK/12           230400         0.00%         16         EXTCLK/8           115200         0.00%         32         EXTCLK/8           57600         0.00%         64         EXTCLK/8           28800         0.00%         128         EXTCLK/8           14400         0.00%         256         EXTCLK/8	288000.00%128SYSCLKXX144000.00%256SYSCLKXX96000.00%384SYSCLKXX24000.00%1536SYSCLK/120012000.00%3072SYSCLK/12002304000.00%16EXTCLK/8111152000.00%32EXTCLK/811576000.00%64EXTCLK/811288000.00%128EXTCLK/811144000.00%384EXTCLK/81196000.00%384EXTCLK/811	288000.00%128SYSCLKXX1144000.00%256SYSCLKXX196000.00%384SYSCLKXX124000.00%1536SYSCLK/1200012000.00%3072SYSCLK/120002304000.00%16EXTCLK/81101152000.00%32EXTCLK/8110576000.00%64EXTCLK/8110288000.00%128EXTCLK/8110144000.00%256EXTCLK/811096000.00%384EXTCLK/8110

# Table 19.6. Timer Settings for Standard Baud RatesUsing an External 3.6864 MHz Oscillator

1. SCA1–SCA0 and T1M bit definitions can be found in Section 21.1.



Target Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1-SCA0 (pre-scale select) <sup>1</sup>	T1M <sup>1</sup>	Timer 1 Reload Value (hex)
230400	0.45%	218	SYSCLK	XX <sup>2</sup>	1	0x93
115200	-0.01%	434	SYSCLK	XX	1	0x27
57600	0.45%	872	SYSCLK/4	01	0	0x93
28800	-0.01%	1736	SYSCLK/4	01	0	0x27
14400	0.22%	3480	SYSCLK/12	00	0	0x6F
9600	-0.01%	5208	SYSCLK/12	00	0	0x27
2400	-0.01%	20832	SYSCLK/48	10	0	0x27

#### Table 19.7. Timer Settings for Standard Baud Rates Using the PLL

2. X = Don't care.

Table 19 8	Timer Setti	ngs for Stan	dard Baud F	Rates Using	the PLI
		nga ioi olun		values boiling	

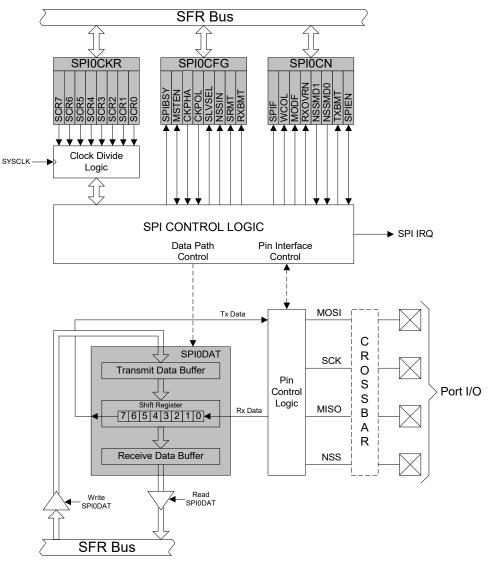
Frequency: 100.0 MHz							
Target Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1-SCA0 (pre-scale select) <sup>1</sup>	T1M <sup>1</sup>	Timer 1 Reload Value (hex)	
230400	-0.01%	434	SYSCLK	XX <sup>2</sup>	1	0x27	
115200	0.45%	872	SYSCLK/4	01	0	0x93	
57600	-0.01%	1736	SYSCLK/4	01	0	0x27	
28800	0.22%	3480	SYSCLK/12	00	0	0x6F	
14400	-0.47%	6912	SYSCLK/48	10	0	0xB8	
9600	0.45%	10464	SYSCLK/48	10	0	0x93	

1. SCA1–SCA0 and T1M bit definitions can be found in Section 21.1.



### 20. Enhanced Serial Peripheral Interface (SPI0)

The Enhanced Serial Peripheral Interface (SPI0) provides access to a flexible, full-duplex synchronous serial bus. SPI0 can operate as a master or slave device in both 3-wire or 4-wire modes, and supports multiple masters and slaves on a single SPI bus. The slave-select (NSS) signal can be configured as an input to select SPI0 in slave mode, or to disable Master Mode operation in a multi-master environment, avoiding contention on the SPI bus when more than one master attempts simultaneous data transfers. NSS can also be configured as a chip-select output in master mode, or disabled for 3-wire operation. Additional general purpose port I/O pins can be used to select multiple slave devices in master mode.







#### 20.1. Signal Descriptions

The four signals used by SPI0 (MOSI, MISO, SCK, NSS) are described below.

#### 20.1.1. Master Out, Slave In (MOSI)

The master-out, slave-in (MOSI) signal is an output from a master device and an input to slave devices. It is used to serially transfer data from the master to the slave. This signal is an output when SPI0 is operating as a master and an input when SPI0 is operating as a slave. Data is transferred most-significant bit first. When configured as a master, MOSI is driven by the MSB of the shift register in both 3- and 4-wire mode.

#### 20.1.2. Master In, Slave Out (MISO)

The master-in, slave-out (MISO) signal is an output from a slave device and an input to the master device. It is used to serially transfer data from the slave to the master. This signal is an input when SPI0 is operating as a master and an output when SPI0 is operating as a slave. Data is transferred most-significant bit first. The MISO pin is placed in a high-impedance state when the SPI module is disabled and when the SPI operates in 4-wire mode as a slave that is not selected. When acting as a slave in 3-wire mode, MISO is always driven by the MSB of the shift register.

#### 20.1.3. Serial Clock (SCK)

The serial clock (SCK) signal is an output from the master device and an input to slave devices. It is used to synchronize the transfer of data between the master and slave on the MOSI and MISO lines. SPI0 generates this signal when operating as a master. The SCK signal is ignored by a SPI slave when the slave is not selected (NSS = 1) in 4-wire slave mode.

#### 20.1.4. Slave Select (NSS)

The function of the slave-select (NSS) signal is dependent on the setting of the NSSMD1 and NSSMD0 bits in the SPI0CN register. There are three possible modes that can be selected with these bits:

- NSSMD[1:0] = 00: 3-Wire Master or 3-Wire Slave Mode: SPI0 operates in 3-wire mode, and NSS is disabled. When operating as a slave device, SPI0 is always selected in 3-wire mode. Since no select signal is present, SPI0 must be the only slave on the bus in 3-wire mode. This is intended for point-to-point communication between a master and one slave.
- 2. NSSMD[1:0] = 01: 4-Wire Slave or Multi-Master Mode: SPI0 operates in 4-wire mode, and NSS is enabled as an input. When operating as a slave, NSS selects the SPI0 device. When operating as a master, a 1-to-0 transition of the NSS signal disables the master function of SPI0 so that multiple master devices can be used on the same SPI bus.
- 3. NSSMD[1:0] = 1x: 4-Wire Master Mode: SPI0 operates in 4-wire mode, and NSS is enabled as an output. The setting of NSSMD0 determines what logic level the NSS pin will output. This configuration should only be used when operating SPI0 as a master device.

See Figure 20.2, Figure 20.3, and Figure 20.4 for typical connection diagrams of the various operational modes. **Note that the setting of NSSMD bits affects the pinout of the device.** When in 3-wire master or 3-wire slave mode, the NSS pin will not be mapped by the crossbar. In all other modes, the NSS signal will be mapped to a pin on the device. See Section "17. Port Input/Output" on page 184 for general purpose port I/O and crossbar information.



#### 20.2. SPI0 Master Mode Operation

A SPI master device initiates all data transfers on a SPI bus. SPI0 is placed in master mode by setting the Master Enable flag (MSTEN, SPI0CN.6). Writing a byte of data to the SPI0 data register (SPI0DAT) when in master mode writes to the transmit buffer. If the SPI shift register is empty, the byte in the transmit buffer is moved to the shift register, and a data transfer begins. The SPI0 master immediately shifts out the data serially on the MOSI line while providing the serial clock on SCK. The SPIF (SPI0CN.7) flag is set to logic '1' at the end of the transfer. If interrupts are enabled, an interrupt request is generated when the SPIF flag is set. While the SPI0 master transfers data to a slave on the MOSI line, the addressed SPI slave device simultaneously transfers the contents of its shift register to the SPI master on the MISO line in a full-duplex operation. Therefore, the SPIF flag serves as both a transmit-complete and receive-data-ready flag. The data byte received from the slave is transferred MSB-first into the master's shift register. When a byte is fully shifted into the register, it is moved to the receive buffer where it can be read by the processor by reading SPI0DAT.

When configured as a master, SPI0 can operate in one of three different modes: multi-master mode, 3-wire single-master mode, and 4-wire single-master mode. The default, multi-master mode is active when NSS-MD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 1. In this mode, NSS is an input to the device, and is used to disable the master SPI0 when another master is accessing the bus. When NSS is pulled low in this mode, MSTEN (SPI0CN.6) and SPIEN (SPI0CN.0) are set to 0 to disable the SPI master device, and a Mode Fault is generated (MODF, SPI0CN.5 = 1). Mode Fault will generate an interrupt if enabled. SPI0 must be manually re-enabled in software under these circumstances. In multi-master systems, devices will typically default to being slave devices while they are not acting as the system master device. In multi-master mode, slave devices can be addressed individually (if needed) using general-purpose I/O pins. Figure 20.2 shows a connection diagram between two master devices in multiple-master mode.

3-wire single-master mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 0. In this mode, NSS is not used, and is not mapped to an external port pin through the crossbar. Any slave devices that must be addressed in this mode should be selected using general-purpose I/O pins. Figure 20.3 shows a connection diagram between a master device in 3-wire master mode and a slave device.

4-wire single-master mode is active when NSSMD1 (SPI0CN.3) = 1. In this mode, NSS is configured as an output pin, and can be used as a slave-select signal for a single SPI device. In this mode, the output value of NSS is controlled (in software) with the bit NSSMD0 (SPI0CN.2). Additional slave devices can be addressed using general-purpose I/O pins. Figure 20.4 shows a connection diagram for a master device in 4-wire master mode and two slave devices.



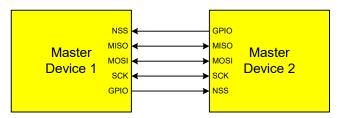


Figure 20.2. Multiple-Master Mode Connection Diagram

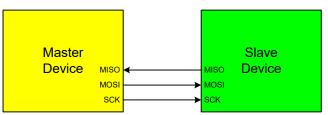


Figure 20.3. 3-Wire Single Master and 3-Wire Single Slave Mode Connection Diagram

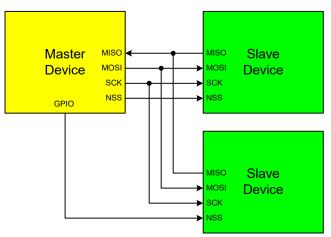


Figure 20.4. 4-Wire Single Master Mode and 4-Wire Slave Mode Connection Diagram



#### 20.3. SPI0 Slave Mode Operation

When SPI0 is enabled and not configured as a master, it will operate as a SPI slave. As a slave, bytes are shifted in through the MOSI pin and out through the MISO pin by a master device controlling the SCK signal. A bit counter in the SPI0 logic counts SCK edges. When 8 bits have been shifted through the shift register, the SPIF flag is set to logic '1', and the byte is copied into the receive buffer. Data is read from the receive buffer by reading SPI0DAT. A slave device cannot initiate transfers. Data to be transferred to the master device is pre-loaded into the shift register by writing to SPI0DAT. Writes to SPI0DAT are double-buffered, and are placed in the transmit buffer first. If the shift register is empty, the contents of the transmit buffer will immediately be transferred into the shift register. When the shift register already contains data, the SPI will load the shift register with the transmit buffer's contents after the last SCK edge of the next (or current) SPI transfer.

When configured as a slave, SPI0 can be configured for 4-wire or 3-wire operation. The default, 4-wire slave mode, is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 1. In 4-wire mode, the NSS signal is routed to a port pin and configured as a digital input. SPI0 is enabled when NSS is logic '0', and disabled when NSS is logic '1'. The bit counter is reset on a falling edge of NSS. Note that the NSS signal must be driven low at least 2 system clocks before the first active edge of SCK for each byte transfer. Figure 20.4 shows a connection diagram between two slave devices in 4-wire slave mode and a master device.

3-wire slave mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 0. NSS is not used in this mode, and is not mapped to an external port pin through the crossbar. Since there is no way of uniquely addressing the device in 3-wire slave mode, SPI0 must be the only slave device present on the bus. It is important to note that in 3-wire slave mode there is no external means of resetting the bit counter that determines when a full byte has been received. The bit counter can only be reset by disabling and re-enabling SPI0 with the SPIEN bit. Figure 20.3 shows a connection diagram between a slave device in 3-wire slave mode and a master device.

#### 20.4. SPI0 Interrupt Sources

When SPI0 interrupts are enabled, the following four flags will generate an interrupt when they are set to logic '1':

All of the following bits must be cleared by software.

- 1. The SPI Interrupt Flag, SPIF (SPI0CN.7) is set to logic '1' at the end of each byte transfer. This flag can occur in all SPI0 modes.
- 2. The Write Collision Flag, WCOL (SPI0CN.6) is set to logic '1' if a write to SPI0DAT is attempted when the transmit buffer has not been emptied to the SPI shift register. When this occurs, the write to SPI0DAT will be ignored, and the transmit buffer will not be written. This flag can occur in all SPI0 modes.
- 3. The Mode Fault Flag MODF (SPI0CN.5) is set to logic '1' when SPI0 is configured as a master, and for multi-master mode and the NSS pin is pulled low. When a Mode Fault occurs, the MSTEN and SPIEN bits in SPI0CN are set to logic '0' to disable SPI0 and allow another master device to access the bus.
- 4. The Receive Overrun Flag RXOVRN (SPI0CN.4) is set to logic '1' when configured as a slave, and a transfer is completed and the receive buffer still holds an unread byte from a previous transfer. The new byte is not transferred to the receive buffer, allowing the previously received data byte to be read. The data byte which caused the overrun is lost.



#### 20.5. Serial Clock Timing

Four combinations of serial clock phase and polarity can be selected using the clock control bits in the SPI0 Configuration Register (SPI0CFG). The CKPHA bit (SPI0CFG.5) selects one of two clock phases (edge used to latch the data). The CKPOL bit (SPI0CFG.4) selects between an active-high or active-low clock. Both master and slave devices must be configured to use the same clock phase and polarity. SPI0 should be disabled (by clearing the SPIEN bit, SPI0CN.0) when changing the clock phase or polarity. The clock and data line relationships for master mode are shown in Figure 20.5. For slave mode, the clock and data relationships are shown in Figure 20.6 and Figure 20.7. Note that CKPHA must be set to '0' on both the master and slave SPI when communicating between two of the following devices: C8051F04x, C8051F06x, C8051F12x, C8051F31x, C8051F32x, C8051F33x, and C8051F36x.

The SPI0 Clock Rate Register (SPI0CKR) as shown in SFR Definition 20.3 controls the master mode serial clock frequency. This register is ignored when operating in slave mode. When the SPI is configured as a master, the maximum data transfer rate (bits/sec) is one-half the system clock frequency or 12.5 MHz, whichever is slower. When the SPI is configured as a slave, the maximum data transfer rate (bits/sec) for full-duplex operation is 1/10 the system clock frequency, provided that the master issues SCK, NSS (in 4-wire slave mode), and the serial input data synchronously with the slave's system clock. If the master issues SCK, NSS, and the serial input data asynchronously, the maximum data transfer rate (bits/sec) must be less than 1/10 the system clock frequency. In the special case where the master only wants to transmit data to the slave and does not need to receive data from the slave (i.e. half-duplex operation), the SPI slave can receive data at a maximum data transfer rate (bits/sec) of 1/4 the system clock frequency. This is provided that the master issues SCK, NSS, and the serial input data transfer rate (bits/sec) of 1/4 the system clock frequency. This is provided that the master issues SCK, NSS, and the serial input data synchronously with the slave's system clock frequency.

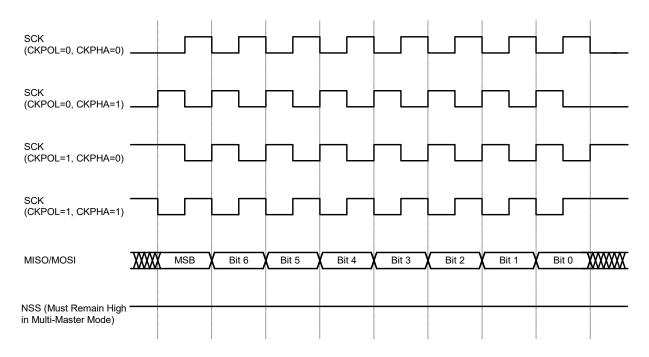
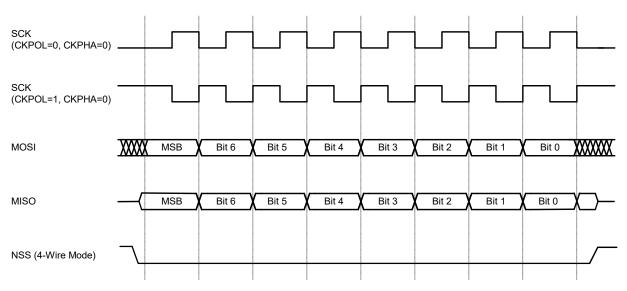


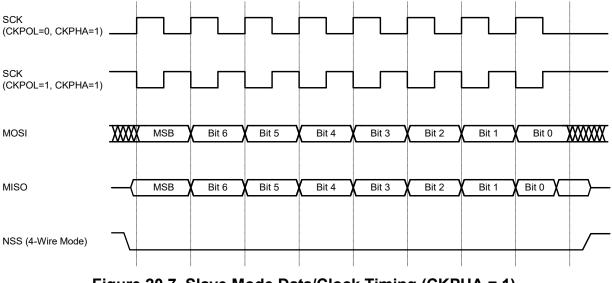
Figure 20.5. Master Mode Data/Clock Timing



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#### 20.6. SPI Special Function Registers

SPI0 is accessed and controlled through four special function registers in the system controller: SPI0CN Control Register, SPI0DAT Data Register, SPI0CFG Configuration Register, and SPI0CKR Clock Rate Register. The four special function registers related to the operation of the SPI0 Bus are described in the following figures.

0000011
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ed slave. I icate the
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t re

#### SFR Definition 20.1. SPI0CFG: SPI0 Configuration



SFR Definition	20.2.	SPI0CN:	SPI0	Control
----------------	-------	---------	------	---------

R/W	R/W	R/W	R/W	R/W	R/W	R	R/W	Reset Value	
SPIF	WCOL	MODF	RXOVRN	NSSMD1	NSSMD0	TXBMT	SPIEN	00000110	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0		
Bit 7: SPIF: SPI0 Interrupt Flag. This bit is set to logic '1' by hardware at the end of a data transfer. If interrupts are enabled, setting this bit causes the CPU to vector to the SPI0 interrupt service routine. This bit is not									
Bit 6:	automatically cleared by hardware. It must be cleared by software. WCOL: Write Collision Flag. This bit is set to logic '1' by hardware (and generates a SPI0 interrupt) to indicate a write to the SPI0 data register was attempted while a data transfer was in progress. It must be								
Bit 5:	cleared by software. MODF: Mode Fault Flag. This bit is set to logic '1' by hardware (and generates a SPI0 interrupt) when a master mode collision is detected (NSS is low, MSTEN = 1, and NSSMD[1:0] = 01). This bit is not auto- matically cleared by hardware. It must be cleared by software.								
Bit 4:	RXOVRN: Receive Overrun Flag (Slave Mode only). This bit is set to logic '1' by hardware (and generates a SPI0 interrupt) when the receive buf- fer still holds unread data from a previous transfer and the last bit of the current transfer is shifted into the SPI0 shift register. This bit is not automatically cleared by hardware. It must								
3its 3 <b>–</b> 2:	<ul> <li>be cleared by software.</li> <li>-2: NSSMD1-NSSMD0: Slave Select Mode. Selects between the following NSS operation modes: (See Section 20.2 and Section 20.3).</li> <li>00: 3-Wire Slave or 3-wire Master Mode. NSS signal is not routed to a port pin.</li> <li>01: 4-Wire Slave or Multi-Master Mode (Default). NSS is always an input to the device.</li> <li>1x: 4-Wire Single-Master Mode. NSS signal is mapped as an output from the device and will assume the value of NSSMD0.</li> </ul>								
Bit 1:	TXBMT: Transmit Buffer Empty. This bit will be set to logic '0' when new data has been written to the transmit buffer. When data in the transmit buffer is transferred to the SPI shift register, this bit will be set to logic '1', indicating that it is safe to write a new byte to the transmit buffer.								
Bit 0:	SPIEN: SPIC This bit enab 0: SPI disabl 1: SPI enable	) Enable. bles/disable led.							

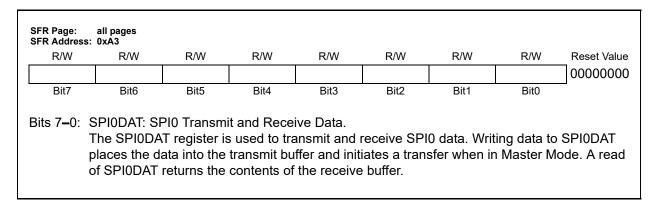


## C8051F360/1/2/3/4/5/6/7/8/9

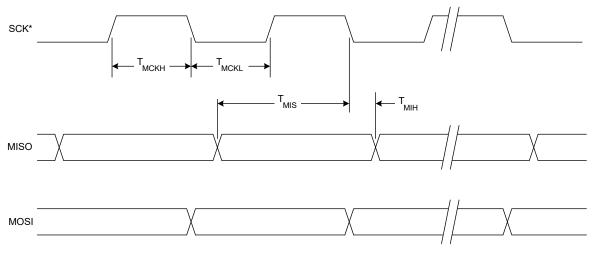
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
SCR7	SCR6	SCR5	SCR4	SCR3	SCR2	SCR1	SCR0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
-	SCR7 <b>–</b> SCR( These bits d for master m	etermine th	e frequency		•			-
(	clock, and is and <i>SPI0CK</i>	given in th	e following	equation, w	here SYSC	<i>LK</i> is the sy		
j	$f_{SCK} = \frac{1}{2 \times 10^{-5}}$	SYSCL (SPI0CF	$\frac{K}{(R+1)}$					
f	for 0 <= SPI	0CKR <= 2	55					
xample: I	f SYSCLK =	2 MHz and	SPIOCKR	= 0x04,				
$f_{SCK} =$	$\frac{2000000}{2 \times (4+1)}$	)						

#### SFR Definition 20.3. SPI0CKR: SPI0 Clock Rate

#### SFR Definition 20.4. SPI0DAT: SPI0 Data

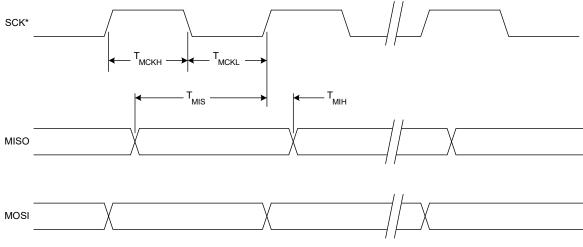






\* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.



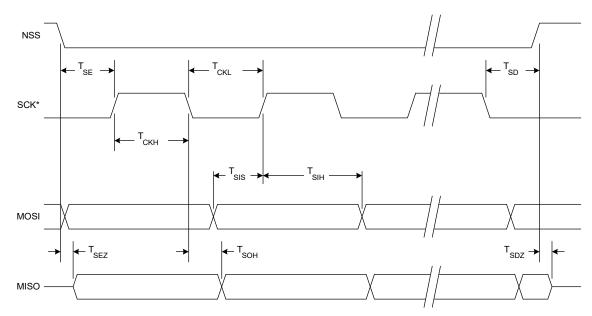


\* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.

### Figure 20.9. SPI Master Timing (CKPHA = 1)

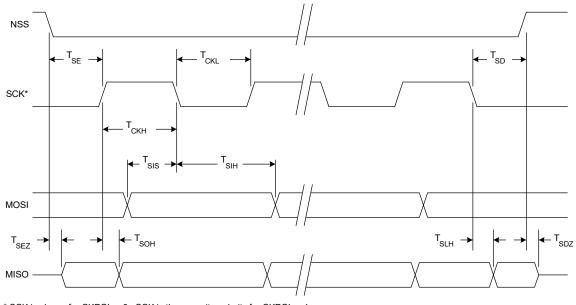


### C8051F360/1/2/3/4/5/6/7/8/9



\* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.





\* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.

#### Figure 20.11. SPI Slave Timing (CKPHA = 1)



Parameter	Description	Min	Max	Units
Master Mode	Timing* (See Figure 20.8 and Figure 20.9)			
Т <sub>МСКН</sub>	SCK High Time	1 x T <sub>SYSCLK</sub>	_	ns
T <sub>MCKL</sub>	SCK Low Time	1 x T <sub>SYSCLK</sub>	—	ns
T <sub>MIS</sub>	MISO Valid to SCK Shift Edge	1 x T <sub>SYSCLK</sub> + 20	—	ns
Т <sub>МІН</sub>	SCK Shift Edge to MISO Change	0	_	ns
Slave Mode 1	iming* (See Figure 20.10 and Figure 20.11)			1
T <sub>SE</sub>	NSS Falling to First SCK Edge	2 x T <sub>SYSCLK</sub>	_	ns
T <sub>SD</sub>	Last SCK Edge to NSS Rising	2 x T <sub>SYSCLK</sub>	—	ns
T <sub>SEZ</sub>	NSS Falling to MISO Valid	—	4 x T <sub>SYSCLK</sub>	ns
T <sub>SDZ</sub>	NSS Rising to MISO High-Z	—	4 x T <sub>SYSCLK</sub>	ns
т <sub>скн</sub>	SCK High Time	5 x T <sub>SYSCLK</sub>	—	ns
Т <sub>СКL</sub>	SCK Low Time	5 x T <sub>SYSCLK</sub>	—	ns
T <sub>SIS</sub>	MOSI Valid to SCK Sample Edge	2 x T <sub>SYSCLK</sub>	—	ns
T <sub>SIH</sub>	SCK Sample Edge to MOSI Change	2 x T <sub>SYSCLK</sub>	—	ns
т <sub>ѕон</sub>	SCK Shift Edge to MISO Change	—	4 x T <sub>SYSCLK</sub>	ns
T <sub>SLH</sub>	Last SCK Edge to MISO Change (CKPHA = 1 ONLY)	6 x T <sub>SYSCLK</sub>	8 x T <sub>SYSCLK</sub>	ns
*Note: T <sub>SYSCU</sub>	$_{\rm K}$ is equal to one period of the device system clock (SN	/SCLK).	1	1

Table 20.1. SPI Slave Timing Parameters



### 21. Timers

Each MCU includes four counter/timers: two are 16-bit counter/timers compatible with those found in the standard 8051, and two are 16-bit auto-reload timer for use with the ADC, SMBus, or for general purpose use. These timers can be used to measure time intervals, count external events and generate periodic interrupt requests. Timer 0 and Timer 1 are nearly identical and have four primary modes of operation. Timer 2 and Timer 3 offer 16-bit and split 8-bit timer functionality with auto-reload.

Timer 0 and Timer 1 Modes:	Timer 2 Modes:	Timer 3 Modes:	
13-bit counter/timer	16-bit timer with auto-reload	16-bit timer with auto-reload	
16-bit counter/timer	To-bit limer with auto-reload		
8-bit counter/timer with auto-			
reload	Two 8-bit timers with auto-reload	Two 8-bit timers with auto-reload	
Two 8-bit counter/timers (Timer 0			
only)			

Timers 0 and 1 may be clocked by one of five sources, determined by the Timer Mode Select bits (T1M– T0M) and the Clock Scale bits (SCA1–SCA0). The Clock Scale bits define a pre-scaled clock from which Timer 0 and/or Timer 1 may be clocked (See SFR Definition 21.3 for pre-scaled clock selection).

Timer 0/1 may then be configured to use this pre-scaled clock signal or the system clock. Timer 2 and Timer 3 may be clocked by the system clock, the system clock divided by 12, or the external oscillator clock source divided by 8.

Timer 0 and Timer 1 may also be operated as counters. When functioning as a counter, a counter/timer register is incremented on each high-to-low transition at the selected input pin (T0 or T1). Events with a frequency of up to one-fourth the system clock frequency can be counted. The input signal need not be periodic, but it should be held at a given level for at least two full system clock cycles to ensure the level is properly sampled.



#### 21.1. Timer 0 and Timer 1

Each timer is implemented as a 16-bit register accessed as two separate bytes: a low byte (TL0 or TL1) and a high byte (TH0 or TH1). The Counter/Timer Control register (TCON) is used to enable Timer 0 and Timer 1 as well as indicate status. Timer 0 interrupts can be enabled by setting the ET0 bit in the IE register (Section "10.4. Interrupt Register Descriptions" on page 110); Timer 1 interrupts can be enabled by setting the ET1 bit in the IE register (Section 10.4). Both counter/timers operate in one of four primary modes selected by setting the Mode Select bits T1M1–T0M0 in the Counter/Timer Mode register (TMOD). Each timer can be configured independently. Each operating mode is described below.

#### 21.1.1. Mode 0: 13-bit Counter/Timer

Timer 0 and Timer 1 operate as 13-bit counter/timers in Mode 0. The following describes the configuration and operation of Timer 0. However, both timers operate identically, and Timer 1 is configured in the same manner as described for Timer 0.

The TH0 register holds the eight MSBs of the 13-bit counter/timer. TL0 holds the five LSBs in bit positions TL0.4–TL0.0. The three upper bits of TL0 (TL0.7–TL0.5) are indeterminate and should be masked out or ignored when reading. As the 13-bit timer register increments and overflows from 0x1FFF (all ones) to 0x0000, the timer overflow flag TF0 (TCON.5) is set and an interrupt will occur if Timer 0 interrupts are enabled.

The C/T0 bit (TMOD.2) selects the counter/timer's clock source. When C/T0 is set to logic '1', high-to-low transitions at the selected Timer 0 input pin (T0) increment the timer register (Refer to Section "17.1. Priority Crossbar Decoder" on page 186 for information on selecting and configuring external I/O pins). Clearing C/T selects the clock defined by the T0M bit (CKCON.3). When T0M is set, Timer 0 is clocked by the system clock. When T0M is cleared, Timer 0 is clocked by the source selected by the Clock Scale bits in CKCON (see SFR Definition 21.3).

Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is logic '0' or the input signal /INT0 is active as defined by bit IN0PL in register IT01CF (see SFR Definition 10.7). Setting GATE0 to '1' allows the timer to be controlled by the external input signal /INT0 (see Section "10.4. Interrupt Register Descriptions" on page 110), facilitating pulse width measurements

TR0	GATE0	/INT0	Counter/Timer				
0	Х	Х	Disabled				
1	0	Х	Enabled				
1	1	0	Disabled				
1	1	1	Enabled				
Note: X = Don'	Note: X = Don't Care						

Setting TR0 does not force the timer to reset. The timer registers should be loaded with the desired initial value before the timer is enabled.

TL1 and TH1 form the 13-bit register for Timer 1 in the same manner as described above for TL0 and TH0. Timer 1 is configured and controlled using the relevant TCON and TMOD bits just as with Timer 0. The input signal /INT1 is used with Timer 1; the /INT1 polarity is defined by bit IN1PL in register IT01CF (see SFR Definition 10.7).



## C8051F360/1/2/3/4/5/6/7/8/9

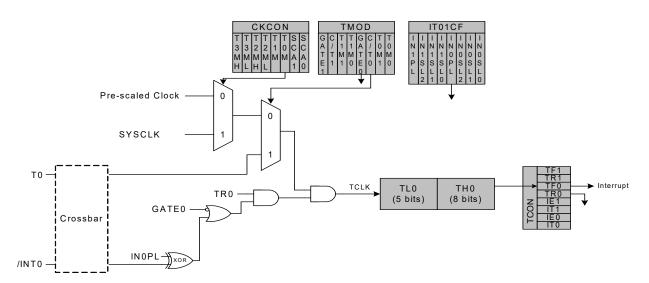


Figure 21.1. T0 Mode 0 Block Diagram

#### 21.1.2. Mode 1: 16-bit Counter/Timer

Mode 1 operation is the same as Mode 0, except that the counter/timer registers use all 16 bits. The counter/timers are enabled and configured in Mode 1 in the same manner as for Mode 0.

#### 21.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload

Mode 2 configures Timer 0 and Timer 1 to operate as 8-bit counter/timers with automatic reload of the start value. TL0 holds the count and TH0 holds the reload value. When the counter in TL0 overflows from all ones to 0x00, the timer overflow flag TF0 (TCON.5) is set and the counter in TL0 is reloaded from TH0. If Timer 0 interrupts are enabled, an interrupt will occur when the TF0 flag is set. The reload value in TH0 is not changed. TL0 must be initialized to the desired value before enabling the timer for the first count to be correct. When in Mode 2, Timer 1 operates identically to Timer 0.

Both counter/timers are enabled and configured in Mode 2 in the same manner as Mode 0. Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is logic '0' or when the input signal /INT0 is active as defined by bit IN0PL in register IT01CF (see Section "10.5. External Interrupts" on page 116 for details on the external input signals /INT0 and /INT1).



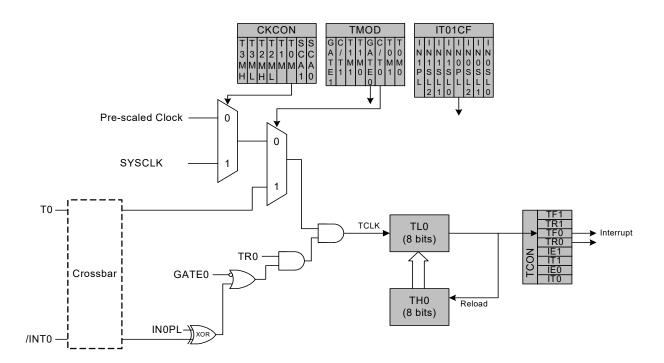


Figure 21.2. T0 Mode 2 Block Diagram



## C8051F360/1/2/3/4/5/6/7/8/9

#### 21.1.4. Mode 3: Two 8-bit Counter/Timers (Timer 0 Only)

In Mode 3, Timer 0 is configured as two separate 8-bit counter/timers held in TL0 and TH0. The counter/timer in TL0 is controlled using the Timer 0 control/status bits in TCON and TMOD: TR0, C/T0, GATE0 and TF0. TL0 can use either the system clock or an external input signal as its timebase. The TH0 register is restricted to a timer function sourced by the system clock or prescaled clock. TH0 is enabled using the Timer 1 run control bit TR1. TH0 sets the Timer 1 overflow flag TF1 on overflow and thus controls the Timer 1 interrupt.

Timer 1 is inactive in Mode 3. When Timer 0 is operating in Mode 3, Timer 1 can be operated in Modes 0, 1 or 2, but cannot be clocked by external signals nor set the TF1 flag and generate an interrupt. However, the Timer 1 overflow can be used to generate baud rates for the SMBus and/or UART, and/or initiate ADC conversions. While Timer 0 is operating in Mode 3, Timer 1 run control is handled through its mode settings. To run Timer 1 while Timer 0 is in Mode 3, set the Timer 1 Mode as 0, 1, or 2. To disable Timer 1, configure it for Mode 3.

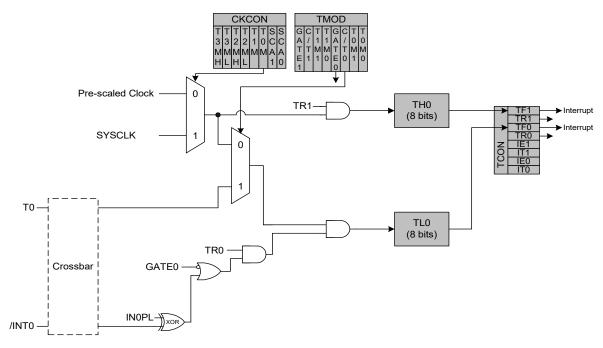


Figure 21.3. T0 Mode 3 Block Diagram



SFR Page: SFR Addres	all pages s: 0x88	(bit addr	essable)							
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0			
Bit 7:	TF1: Timer 1	1 Overflow F	lag.							
	Set by hardw	vare when 1	Timer 1 ove	rflows. This	flag can be	e cleared by	software	but is auto-		
	matically cle	ared when t	the CPU ve	ectors to the	Timer 1 inte	errupt servi	ce routine			
	0: No Timer									
	1: Timer 1 h									
Bit 6:	TR1: Timer		ol.							
	0: Timer 1 di									
	1: Timer 1 enabled.									
Bit 5:	TF0: Timer (		-	a —	<i>a</i> .		~			
	Set by hardw									
	matically cle			ectors to the	Timer 0 inte	errupt servi	ce routine			
	0: No Timer 1: Timer 0 ha									
Bit 4:	TR0: Timer 0 na									
DIL 4.	0: Timer 0 di		01.							
	1: Timer 0 e									
Bit 3:	IE1: Externa									
Dit 0.	This flag is s			in edge/leve	el of type de	fined by IT1	l is detecte	ed It can be		
	cleared by s									
	Interrupt 1 s									
	as defined b									
Bit 2:	IT1: Interrup	•	-	,		,				
	This bit sele	cts whether	the configu	ured /INT1 i	nterrupt will	be edge or	level sens	sitive. /INT1		
	is configured	active low	or high by	the IN1PL b	oit in the IT0	1CF registe	er (see SF	R Definition		
	10.7).									
	0: /INT1 is le									
	1: /INT1 is e									
Bit 1:	IE0: Externa	•				<b>.</b>				
	This flag is s									
	cleared by s									
	Interrupt 0 s							10 is active		
D:4 0.	as defined b		•	IT01CF (se	e SFR Defin	nition 10.7).				
Bit 0:	IT0: Interrup This bit sele			unad /INITO i	ntorrunt will					
	is configured					0				
	10.7).	a active IOW	or night by		ni in registel		CC OFR D			
	0: /INT0 is le	vel triagere	d							
	1: /INT0 is e									
	,	-95								

# SFR Definition 21.1. TCON: Timer Control



R/W	s: 0x89 R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value	
GATE1	C/T1	T1M1	T1M0	GATE0	C/T0	T0M1	T0M0	0000000	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_]	
Bit 7:	0: Timer 1 1: Timer 1 ter IT01CF	enabled or (see SFR	hen TR1 = 1 i nly when TR1 Definition 10.	= 1 AND /I			d by bit IN1	PL in regis	
Bit 6:	C/T1: Counter/Timer 1 Select. 0: Timer Function: Timer 1 incremented by clock defined by T1M bit (CKCON.4). 1: Counter Function: Timer 1 incremented by high-to-low transitions on external input pin (T1).								
Bits 5 <b>–</b> 4:			Mode Select Timer 1 opera						
	T1M1	T1M0		Mod					
	0	0	Mode 0: 13-bit counter/timer						
	0	1	Mod	le 1: 16-bit c	ounter/time	er			
	1	0	Mode 2: 8-b	it counter/ti	ner with au	to-reload			
	1	1	Mo	ode 3: Time	<sup>-</sup> 1 inactive				
Bit 3: Bit 2:	0: Timer 0 1: Timer 0 ter IT01CF C/T0: Cou 0: Timer F	enabled or (see SFR nter/Timer unction: Tir	hen TR0 = 1 i nly when TR0 Definition 10.	= 1 AND /IN 7).	JT0 is activ	e as define by T0M bit (	CKCON.3)		
Bits 1 <b>–</b> 0:	(T0). T0M1 <b>-</b> T0M	M0: Timer C	) Mode Select Timer 0 opera		ign-to-low t		on external	Πραι μπ	
	T0M1	T0M0		Mode	)				
	0	0	Mode	e 0: 13-bit c	ounter/time	r			
	0	1	Mode	e 1: 16-bit c	ounter/time	r			
	L .	0	Mode 2: 8-bi	t counter/tin	ner with aut	o-reload			
	1     0     Mode 2: 8-bit counter/timer with auto-reload       1     1     Mode 3: Two 8-bit counter/timers								

# SFR Definition 21.2. TMOD: Timer Mode



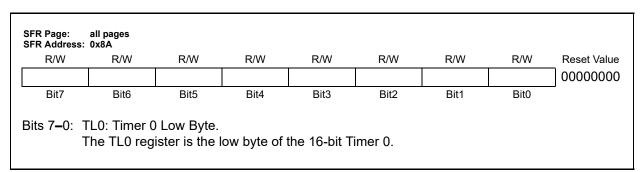
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
T3MH	T3ML	T2MH	T2ML	T1M	TOM	SCA1	SCA0	0000000				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0					
Bit 7:	T3MH: Timer	r 3 Hiah Bvi	e Clock Se	elect.								
	This bit selec				· 3 high byte	e if Timer 3	is configure	ed in split 8-				
	bit timer mode. T3MH is ignored if Time 3 is in any other mode. 0: Timer 3 high byte uses the clock defined by the T3XCLK bit in TMR3CN.											
							R3CN.					
	1: Timer 3 hig	• •										
Bit 6:	T3ML: Timer 3 Low Byte Clock Select.											
	This bit selects the clock supplied to Timer 3. If Timer 3 is configured in split 8-bit timer											
	mode, this bit selects the clock supplied to three 5. In time 5 is configured in spin o-bit time mode, this bit selects the clock supplied to the lower 8-bit timer.											
	0: Timer 3 low byte uses the clock defined by the T3XCLK bit in TMR3CN.											
	1: Timer 3 lov											
Bit 5:	T2MH: Timer	r 2 High Byt	e Clock Se	elect.								
	This bit selec				2 high byte	e if Timer 2	is configure	ed in split 8 <sup>,</sup>				
	bit timer mod						Ū.					
	0: Timer 2 hig						R2CN.					
	1: Timer 2 hig	gh byte use	s the syste	m clock.								
Bit 4:	T2ML: Timer											
	This bit selec				f Timer 2 is	configured	in split 8-b	it timer				
	mode, this bi	t selects the	e clock sup	plied to the	lower 8-bit	timer.						
	0: Timer 2 lov	w byte uses	the clock	defined by	the T2XCLk	k bit in TMF	R2CN.					
	1: Timer 2 lov	w byte uses	the syster	m clock.								
Bit 3:	T1M: Timer 1	1 Clock Sele	ect.									
	This select th logic '1'.	ne clock sou	irce supplie	ed to Timer	1. T1M is iç	nored whe	n C/T1 is s	et to				
	0: Timer 1 us	ses the cloc	k defined b	v the prese	ale bits. SC	A1-SCA0.						
	1: Timer 1 us			, ,								
Bit 2:	T0M: Timer (	•										
	This bit selec	ts the clock	source su	pplied to Ti	mer 0. T0M	is ignored	when C/T0	is set to				
	logic '1'.					U						
	0: Counter/Ti	imer 0 uses	the clock of	defined by t	he prescale	bits, SCA1	I-SCA0.					
	1: Counter/Ti			•								
Bits 1 <b>–</b> 0:	SCA1-SCA0											
	These bits co	ontrol the di	vision of th	e clock sup	plied to Tim	er 0 and/or	Timer 1 if	configured				
	to use presca	aled clock i	nputs.									
	SCA1	SCAO		Pr	escaled Clo	ock						
	0	0	Syste	m clock div	ided by 12							
	0	1	-	m clock div								
	1	0		m clock div								
	1	1	-	nal clock div								
	1 1			iai oloon ul								

### SFR Definition 21.3. CKCON: Clock Control

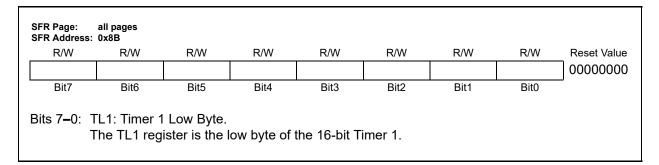


# C8051F360/1/2/3/4/5/6/7/8/9

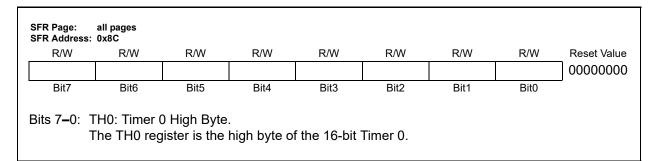
### SFR Definition 21.4. TL0: Timer 0 Low Byte



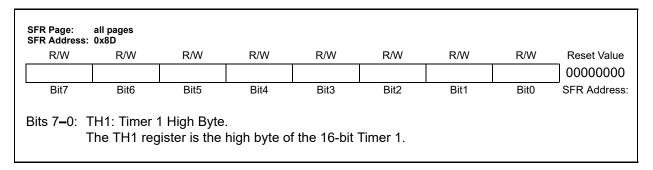
# SFR Definition 21.5. TL1: Timer 1 Low Byte



# SFR Definition 21.6. TH0: Timer 0 High Byte



# SFR Definition 21.7. TH1: Timer 1 High Byte





### 21.2. Timer 2

Timer 2 is a 16-bit timer formed by two 8-bit SFRs: TMR2L (low byte) and TMR2H (high byte). Timer 2 may operate in 16-bit auto-reload mode or (split) 8-bit auto-reload mode. The T2SPLIT bit (TMR2CN.3) defines the Timer 2 operation mode.

Timer 2 may be clocked by the system clock, the system clock divided by 12, or the external oscillator source divided by 8. The external clock mode is ideal for real-time clock (RTC) functionality, where the internal oscillator drives the system clock while Timer 2 (and/or the PCA) is clocked by an external precision oscillator. Note that the external oscillator source divided by 8 is synchronized with the system clock.

### 21.2.1. 16-bit Timer with Auto-Reload

When T2SPLIT (TMR2CN.3) is zero, Timer 2 operates as a 16-bit timer with auto-reload. Timer 2 can be clocked by SYSCLK, SYSCLK divided by 12, or the external oscillator clock source divided by 8. As the 16-bit timer register increments and overflows from 0xFFFF to 0x0000, the 16-bit value in the Timer 2 reload registers (TMR2RLH and TMR2RLL) is loaded into the Timer 2 register as shown in Figure 21.4, and the Timer 2 High Byte Overflow Flag (TMR2CN.7) is set. If Timer 2 interrupts are enabled (if IE.5 is set), an interrupt will be generated on each Timer 2 overflow. Additionally, if Timer 2 interrupts are enabled and the TF2LEN bit is set (TMR2CN.5), an interrupt will be generated each time the lower 8 bits (TMR2L) overflow from 0xFF to 0x00.

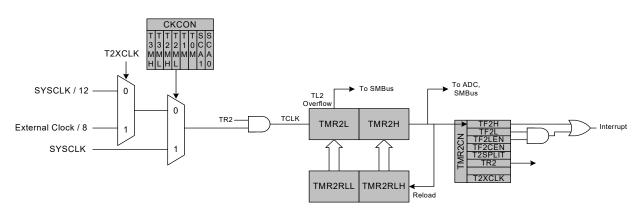


Figure 21.4. Timer 2 16-Bit Mode Block Diagram



### 21.2.2. 8-bit Timers with Auto-Reload

When T2SPLIT is set, Timer 2 operates as two 8-bit timers (TMR2H and TMR2L). Both 8-bit timers operate in auto-reload mode as shown in Figure 21.5. TMR2RLL holds the reload value for TMR2L; TMR2RLH holds the reload value for TMR2H. The TR2 bit in TMR2CN handles the run control for TMR2H. TMR2L is always running when configured for 8-bit Mode.

Each 8-bit timer may be configured to use SYSCLK, SYSCLK divided by 12, or the external oscillator clock source divided by 8. The Timer 2 Clock Select bits (T2MH and T2ML in CKCON) select either SYSCLK or the clock defined by the Timer 2 External Clock Select bit (T2XCLK in TMR2CN), as follows:

T2MH	T2XCLK	TMR2H Clock Source
0	0	SYSCLK/12
0	1	External Clock/8
1	X	SYSCLK

T2ML	T2XCLK	TMR2L Clock Source
0	0	SYSCLK/12
0	1	External Clock/8
1	Х	SYSCLK

The TF2H bit is set when TMR2H overflows from 0xFF to 0x00; the TF2L bit is set when TMR2L overflows from 0xFF to 0x00. When Timer 2 interrupts are enabled (IE.5), an interrupt is generated each time TMR2H overflows. If Timer 2 interrupts are enabled and TF2LEN (TMR2CN.5) is set, an interrupt is generated each time either TMR2L or TMR2H overflows. When TF2LEN is enabled, software must check the TF2H and TF2L flags to determine the source of the Timer 2 interrupt. The TF2H and TF2L interrupt flags are not cleared by hardware and must be manually cleared by software.

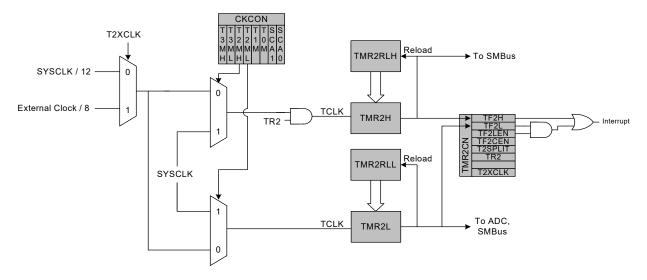


Figure 21.5. Timer 2 8-Bit Mode Block Diagram



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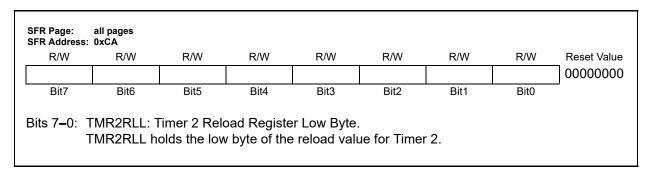
R/W	R/W	R/W	R/W	R/W	R/W	R	R/W	Reset Value
TF2H	TF2L	TF2LEN	TF2CEN	T2SPLIT	TR2	-	T2XCLK	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	,
Bit 7:	TF2H: Timer							
	Set by hardw this will occu enabled, set TF2H is not	r when Time ting this bit	er 2 overflo <sup>.</sup> causes the	ws from 0xF CPU to vec	FFF to 0x0 tor to the T	000. When ïmer 2 intei	the Timer 2 rrupt service	interrupt is routine.
Bit 6:	TF2L: Timer		•	•	and must i	Je clealeu	by sollware.	•
	Set by hardv				erflows fror	n 0xFF to 0	x00. When	this bit is
	set, an interr						•	
	will set wher			s regardless	of the Tim	er 2 mode.	This bit is n	ot automa
Bit 5:	ically cleared TF2LEN: Tin			at Enchlo				
511 5.	This bit enab				arrunts If T	F2I FN is s	et and Time	r 2 inter-
	rupts are ena							
	0: Timer 2 Lo		•	-		,		
	1: Timer 2 Lo	ow Byte inte	errupts enal	oled.				
Bit 4:	TF2CEN: Tir							
	This bit enab			•	•	•		2CEN is se
	and Timer 2	interrunts a	ro onablod					
							a falling edg	
	low-frequence	cy oscillator	output, and	d the curren	t 16-bit time	er value in <sup>-</sup>	TMR2H:TMF	R2L will be
	low-frequence copied to TM	cy oscillator IR2RLH:TM	output, and IR2RLL. Se	d the currentee Section "	t 16-bit time 16. Oscillat	er value in <sup>-</sup>	TMR2H:TMF	R2L will be
	low-frequenc copied to TM 0: Timer 2 Lo	cy oscillator IR2RLH:TM ow-Frequen	output, and IR2RLL. Se icy Oscillate	d the current ee Section " or Capture c	t 16-bit time 16. Oscillat lisabled.	er value in <sup>-</sup>	TMR2H:TMF	R2L will be
Bit 3 <sup>.</sup>	low-frequent copied to TM 0: Timer 2 Lo 1: Timer 2 Lo	cy oscillator IR2RLH:TM ow-Frequen ow-Frequen	output, and IR2RLL. Se icy Oscillate icy Oscillate	d the curren ee Section " or Capture c or Capture e	t 16-bit time 16. Oscillat lisabled.	er value in <sup>-</sup>	TMR2H:TMF	R2L will be
Bit 3:	low-frequence copied to TM 0: Timer 2 Lo 1: Timer 2 Lo T2SPLIT: Tim	cy oscillator IR2RLH:TM ow-Frequen ow-Frequen mer 2 Split I	output, and IR2RLL. Se icy Oscillate icy Oscillate Mode Enab	d the curren ee Section " or Capture c or Capture e le.	t 16-bit time 16. Oscillat lisabled. nabled.	er value in <sup>-</sup> ors" on pag	TMR2H:TMF le 170 for m	R2L will be
Bit 3:	low-frequence copied to TM 0: Timer 2 Lo 1: Timer 2 Lo T2SPLIT: Tir When this bi	cy oscillator IR2RLH:TM ow-Frequen ow-Frequen ner 2 Split I t is set, Tim	output, and IR2RLL. Se icy Oscillato icy Oscillato Mode Enab ier 2 operat	d the curren ee Section " or Capture c or Capture e le. es as two 8	t 16-bit time 16. Oscillat lisabled. nabled. bit timers v	er value in <sup>-</sup> ors" on pag	TMR2H:TMF le 170 for m	R2L will be
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	low-frequence copied to TM 0: Timer 2 Lo 1: Timer 2 Lo T2SPLIT: Tir When this bi 0: Timer 2 op 1: Timer 2 op TR2: Timer 2 This bit enab TMR2L is alw	cy oscillator IR2RLH:TM ow-Frequen ow-Frequen ner 2 Split I t is set, Tim perates in 1 perates as t 2 Run Contr bles/disable ways enable	output, and IR2RLL. Se icy Oscillato icy Oscillato Mode Enabler 2 operat 6-bit auto-r wo 8-bit au rol. s Timer 2. I	d the current ee Section " or Capture of or Capture e le. es as two 8 eload mode to-reload tin n 8-bit mode	t 16-bit time 16. Oscillat lisabled. nabled. bit timers v ners.	er value in <sup>-</sup> ors" on pag vith auto-re	TMR2H:TMF le 170 for m load.	R2L will be ore details
	low-frequence copied to TM 0: Timer 2 Lo 1: Timer 2 Lo T2SPLIT: Tir When this bi 0: Timer 2 op 1: Timer 2 op TR2: Timer 2 This bit enab TMR2L is alw 0: Timer 2 di	cy oscillator IR2RLH:TM ow-Frequen ow-Frequen ner 2 Split I t is set, Tim perates in 1 perates as t 2 Run Contr oles/disable ways enable sabled.	output, and IR2RLL. Se icy Oscillato icy Oscillato Mode Enabler 2 operat 6-bit auto-r wo 8-bit au rol. s Timer 2. I	d the current ee Section " or Capture of or Capture e le. es as two 8 eload mode to-reload tin n 8-bit mode	t 16-bit time 16. Oscillat lisabled. nabled. bit timers v ners.	er value in <sup>-</sup> ors" on pag vith auto-re	TMR2H:TMF le 170 for m load.	R2L will be ore details
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Bit 2: Bit 1:	low-frequence copied to TM 0: Timer 2 Lo 1: Timer 2 Lo T2SPLIT: Tir When this bi 0: Timer 2 op TR2: Timer 2 op	cy oscillator IR2RLH:TM ow-Frequen ow-Frequen ner 2 Split I t is set, Tim perates in 1 perates as t 2 Run Contri oles/disable ways enable sabled. ead = 0b. V ner 2 Extern cts the exte external osc I2MH and 1	output, and IR2RLL. Se icy Oscillato Mode Enab- er 2 operat 6-bit auto-r wo 8-bit au rol. s Timer 2. I ed in this m Vrite = don' nal Clock S rnal clock s illator clock C2ML in reg	d the current ee Section " or Capture of or Capture e le. es as two 8 eload mode to-reload tin n 8-bit mode ode. t care. elect. ource for The source for the ister CKCO	t 16-bit time 16. Oscillat isabled. nabled. bit timers v ners. e, this bit er poth timer b N) may still	er value in <sup>-</sup> ors" on pag with auto-re nables/disa mer 2 is in { bytes. Howe	TMR2H:TMF je 170 for m load. bles TMR2H 3-bit mode, f ever, the Tim	R2L will be ore details H only; this bit her 2 Cloc
Bit 2: Bit 1:	low-frequence copied to TM 0: Timer 2 Lo 1: Timer 2 Lo T2SPLIT: Tir When this bi 0: Timer 2 op 1: Timer 2 op 1: Timer 2 op TR2: Timer 2 This bit enab TMR2L is alw 0: Timer 2 di 1: Timer 2 ei UNUSED. R T2XCLK: Tir This bit selece selects the ei Select bits (T	cy oscillator IR2RLH:TM ow-Frequen ow-Frequen ner 2 Split I t is set, Tim perates as t 2 Run Contri oles/disable ways enable sabled. ead = 0b. V ner 2 Extern cts the exter external osc T2MH and T ck and the s	output, and IR2RLL. Se icy Oscillato Mode Enab- er 2 operat 6-bit auto-r wo 8-bit au rol. s Timer 2. I ed in this m Vrite = don' nal Clock S rnal clock s illator clock r2ML in reg ystem clocl	d the current ee Section " for Capture of for Capture e le. es as two 8 eload mode to-reload tim n 8-bit mode ode. t care. elect. ource for The source for The source for The ister CKCO < for either t	t 16-bit time 16. Oscillat isabled. onabled. obit timers v ners. e, this bit er ooth timer b N) may still mer.	er value in <sup>-</sup> ors" on pag with auto-re nables/disa mer 2 is in 8 bytes. Howe be used to	TMR2H:TMF je 170 for m load. bles TMR2F 3-bit mode, f ever, the Tim 9 select betw	R2L will be ore details H only; this bit her 2 Clocl
Bit 2: Bit 1:	low-frequence copied to TM 0: Timer 2 Lo 1: Timer 2 Lo T2SPLIT: Tir When this bi 0: Timer 2 op 1: Timer 2 op TR2: Timer 2 This bit enab TMR2L is alw 0: Timer 2 di 1: Timer 2 di 1: Timer 2 di 1: Timer 2 di 2: Timer 2 di 1: Timer 2 di Select bits (Texternal cloce 0: Timer 2 di 2: Timer 2 di	cy oscillator IR2RLH:TM ow-Frequen ow-Frequen mer 2 Split N t is set, Tim perates in 1 perates as t 2 Run Contro oles/disable ways enable sabled. ead = 0b. V mer 2 Extern cts the exter external osc F2MH and T ck and the s kternal clock	output, and IR2RLL. Se icy Oscillato Mode Enabler 2 operat 6-bit auto-r wo 8-bit au rol. s Timer 2. I ed in this m Vrite = don' nal Clock S rnal clock S rnal clock s illator clock S2ML in reg ystem clock k selection k selection	d the current ee Section " or Capture of or Capture e le. es as two 8- eload mode to-reload tim n 8-bit mode ode. t care. elect. ource for This source for This source for This source for This source for this ister CKCO < for either t is the system	t 16-bit time 16. Oscillat isabled. nabled. bit timers v ners. e, this bit er oth timer b N) may still mer. n clock divi al clock divi	er value in <sup>-</sup> ors" on pag with auto-re nables/disa mer 2 is in 8 bytes. Howe be used to ided by 12. vided by 8.	TMR2H:TMF je 170 for m load. bles TMR2F B-bit mode, f ever, the Tim select betw Note that th	R2L will be ore details H only; this bit her 2 Clock veen the

## SFR Definition 21.8. TMR2CN: Timer 2 Control

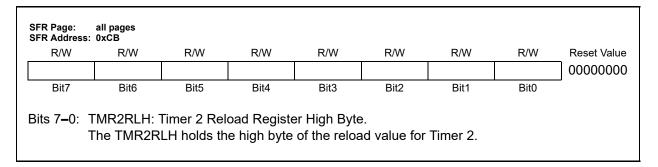


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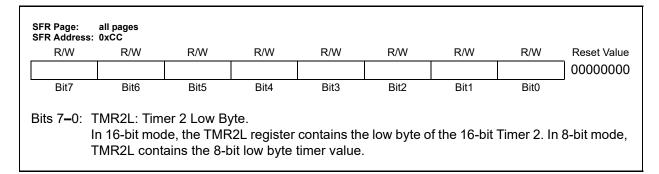
### SFR Definition 21.9. TMR2RLL: Timer 2 Reload Register Low Byte



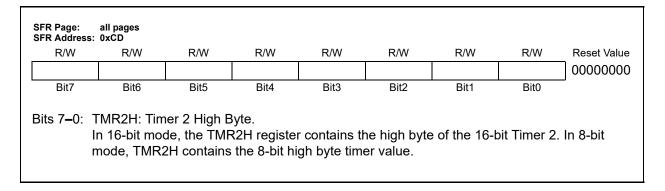
### SFR Definition 21.10. TMR2RLH: Timer 2 Reload Register High Byte



# SFR Definition 21.11. TMR2L: Timer 2 Low Byte



# SFR Definition 21.12. TMR2H Timer 2 High Byte





### 21.3. Timer 3

Timer 3 is a 16-bit timer formed by two 8-bit SFRs: TMR3L (low byte) and TMR3H (high byte). Timer 3 may operate in 16-bit auto-reload mode or (split) 8-bit auto-reload mode. The T3SPLIT bit (TMR3CN.3) defines the Timer 3 operation mode.

Timer 3 may be clocked by the system clock, the system clock divided by 12, or the external oscillator source divided by 8. The external clock mode is ideal for real-time clock (RTC) functionality, where the internal oscillator drives the system clock while Timer 3 (and/or the PCA) is clocked by an external precision oscillator. Note that the external oscillator source divided by 8 is synchronized with the system clock.

### 21.3.1. 16-bit Timer with Auto-Reload

When T3SPLIT (TMR3CN.3) is zero, Timer 3 operates as a 16-bit timer with auto-reload. Timer 3 can be clocked by SYSCLK, SYSCLK divided by 12, or the external oscillator clock source divided by 8. As the 16-bit timer register increments and overflows from 0xFFFF to 0x0000, the 16-bit value in the Timer 3 reload registers (TMR3RLH and TMR3RLL) is loaded into the Timer 3 register as shown in Figure 21.6, and the Timer 3 High Byte Overflow Flag (TMR3CN.7) is set. If Timer 3 interrupts are enabled (if EIE1.7 is set), an interrupt will be generated on each Timer 3 overflow. Additionally, if Timer 3 interrupts are enabled and the TF3LEN bit is set (TMR3CN.5), an interrupt will be generated each time the lower 8 bits (TMR3L) overflow from 0xFF to 0x00.

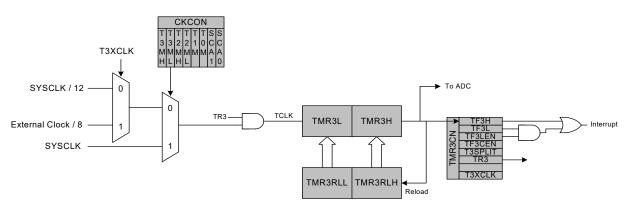


Figure 21.6. Timer 3 16-Bit Mode Block Diagram



### 21.3.2. 8-bit Timers with Auto-Reload

When T3SPLIT is set, Timer 3 operates as two 8-bit timers (TMR3H and TMR3L). Both 8-bit timers operate in auto-reload mode as shown in Figure 21.7. TMR3RLL holds the reload value for TMR3L; TMR3RLH holds the reload value for TMR3H. The TR3 bit in TMR3CN handles the run control for TMR3H. TMR3L is always running when configured for 8-bit Mode.

Each 8-bit timer may be configured to use SYSCLK, SYSCLK divided by 12, or the external oscillator clock source divided by 8. The Timer 3 Clock Select bits (T3MH and T3ML in CKCON) select either SYSCLK or the clock defined by the Timer 3 External Clock Select bit (T3XCLK in TMR3CN), as follows:

T3MH	T3XCLK	TMR3H Clock
		Source
0	0	SYSCLK/12
0	1	External Clock/8
1	Х	SYSCLK

T3ML	T3XCLK	TMR3L Clock Source
0	0	SYSCLK/12
0	1	External Clock/8
1	Х	SYSCLK

The TF3H bit is set when TMR3H overflows from 0xFF to 0x00; the TF3L bit is set when TMR3L overflows from 0xFF to 0x00. When Timer 3 interrupts are enabled, an interrupt is generated each time TMR3H overflows. If Timer 3 interrupts are enabled and TF3LEN (TMR3CN.5) is set, an interrupt is generated each time either TMR3L or TMR3H overflows. When TF3LEN is enabled, software must check the TF3H and TF3L flags to determine the source of the Timer 3 interrupt. The TF3H and TF3L interrupt flags are not cleared by hardware and must be manually cleared by software.

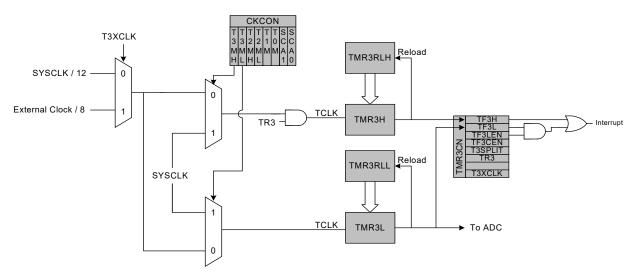


Figure 21.7. Timer 3 8-Bit Mode Block Diagram



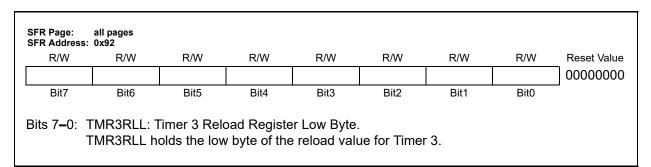
R/W	R/W	R/W	R/W	R/W	R/W	R	R/W	Reset Value
TF3H	TF3L	TF3LEN	TF3CEN	T3SPLIT	TR3	_	T3XCLK	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	J
Bit 7:	TF3H: Time	r 3 High Byt	e Overflow	Flag.				
	Set by hard	ware when t	the Timer 3	high byte o	verflows fro	om 0xFF to	0x00. In 16	bit mode,
	this will occu							•
	enabled, set	-					•	
	TF3H is not		•	•	and must l	be cleared	by software	
Bit 6:	TF3L: Timer			•				
	Set by hard							
	set, an inter		-				•	
	will set when	•		s regardless	s of the 1 im	er 3 mode	. This bit is n	not automat
):+ <b>C</b> .	ically cleare			4 <b>F</b> h l .				
Bit 5:	TF3LEN: Tir				orrupto If T		not and Time	r 2 intor
	This bit enal rupts are en							
	0: Timer 3 L		•	•				remows.
	1: Timer 3 L		•					
Bit 4:	TF3CEN: Ti	•	•		anture Enal	ble		
510 1.	This bit enal		•		•		Mode. If TE3	3CEN is se
	and Timer 3			•	•	•		
	low-frequen	•			-			
	copied to TM							
	0: Timer 3 L					•	0	
	1: Timer 3 L	ow-Frequer	ncy Oscillato	or Capture e	enabled.			
Bit 3:	T3SPLIT: Ti	mer 3 Split I	Mode Enabl	le.				
	When this b	it is set, Tim	ier 3 operat	es as two 8	-bit timers v	with auto-r	eload.	
	0: Timer 3 o	perates in 1	6-bit auto-r	eload mode				
	1: Timer 3 o	perates as t	wo 8-bit au	to-reload tir	ners.			
Bit 2:	TR3: Timer							
	This bit enal				e, this bit er	nables/disa	ables TMR3I	H only;
	TMR3L is al	•	ed in this m	ode.				
	0: Timer 3 d							
	1: Timer 3 e							
Bit 1:	UNUSED. R							
Bit 0:	T3XCLK: Til				man of If The	a a n O i a i n	0 hitmaada	this hit
	This bit sele							
	selects the e						ever, the Tin	
		TOMU and T		inter CI/CO		ne neen	o select delv	voon the
	Select bits (		-				0 001001 0011	veen the
	Select bits ( external close	ck and the s	system clock	k for either t	imer.			veen the
	Select bits (	ck and the s xternal cloc	ystem clock k selection	<pre>c for either t is the system</pre>	imer. m clock divi	ided by 12		

### SFR Definition 21.13. TMR3CN: Timer 3 Control

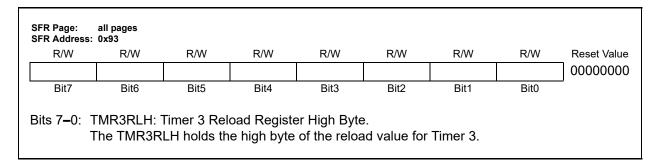


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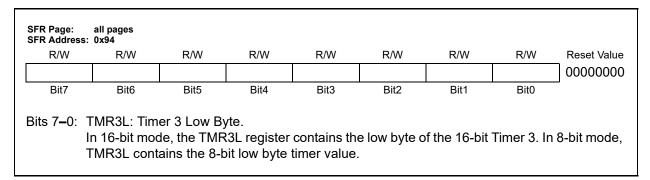
### SFR Definition 21.14. TMR3RLL: Timer 3 Reload Register Low Byte



### SFR Definition 21.15. TMR3RLH: Timer 3 Reload Register High Byte



# SFR Definition 21.16. TMR3L: Timer 3 Low Byte



# SFR Definition 21.17. TMR3H Timer 3 High Byte

R Address R/W	R/W	Reset Value						
								0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_



# 22. Programmable Counter Array

The Programmable Counter Array (PCA0) provides enhanced timer functionality while requiring less CPU intervention than the standard 8051 counter/timers. PCA0 consists of a dedicated 16-bit counter/timer and six 16-bit capture/compare modules. Each capture/compare module has its own associated I/O line (CEXn) which is routed through the Crossbar to Port I/O when enabled (See Section "17.3. General Purpose Port I/O" on page 191). The counter/timer is driven by a programmable timebase that can select between six inputs as its source: system clock, system clock divided by four, system clock divided by twelve, the external oscillator clock source divided by 8, Timer 0 overflow, or an external clock signal on the ECI line. Each capture/compare module may be configured to operate independently in one of six modes: Edge-Triggered Capture, Software Timer, High-Speed Output, Frequency Output, 8-Bit PWM, or 16-Bit PWM (each is described in Section 22.2). The PCA is configured and controlled through the system controller's Special Function Registers. The basic PCA block diagram is shown in Figure 22.1.

**Important Note:** The PCA Module 5 may be used as a watchdog timer (WDT), and is enabled in this mode following a system reset. Access to certain PCA registers is restricted while WDT mode is enabled. See Section 22.3 for details.

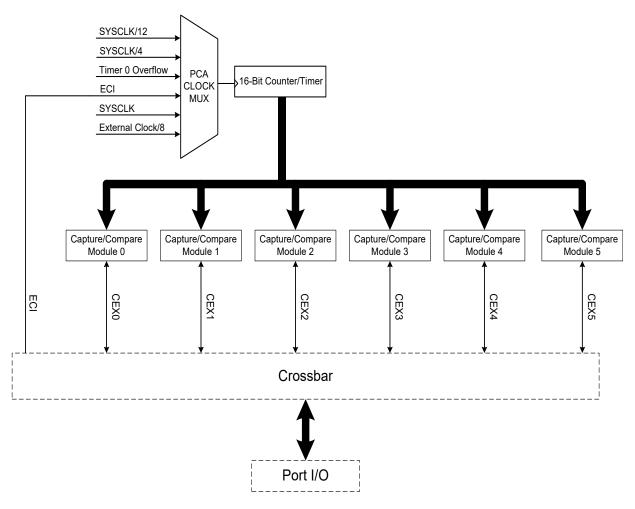


Figure 22.1. PCA Block Diagram



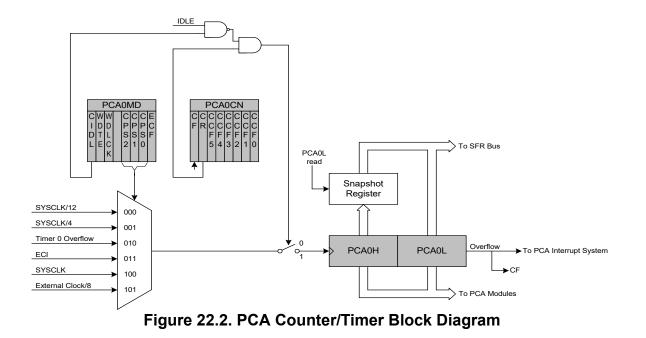
### 22.1. PCA Counter/Timer

The 16-bit PCA counter/timer consists of two 8-bit SFRs: PCA0L and PCA0H. PCA0H is the high byte (MSB) of the 16-bit counter/timer and PCA0L is the low byte (LSB). Reading PCA0L automatically latches the value of PCA0H into a "snapshot" register; the following PCA0H read accesses this "snapshot" register. Reading the PCA0L Register first guarantees an accurate reading of the entire 16-bit PCA0 counter. Reading PCA0H or PCA0L does not disturb the counter operation. The CPS2–CPS0 bits in the PCA0MD register select the timebase for the counter/timer as shown in Table 22.1.

When the counter/timer overflows from 0xFFFF to 0x0000, the Counter Overflow Flag (CF) in PCA0MD is set to logic '1' and an interrupt request is generated if CF interrupts are enabled. Setting the ECF bit in PCA0MD to logic '1' enables the CF flag to generate an interrupt request. The CF bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software (Note: PCA0 interrupts must be globally enabled before CF interrupts are recognized. PCA0 interrupts are globally enabled by setting the EA bit (IE.7) and the EPCA0 bit in EIE1 to logic '1'). Clearing the CIDL bit in the PCA0MD register allows the PCA to continue normal operation while the CPU is in Idle mode.

CPS2	CPS1	CPS0	Timebase
0	0	0	System clock divided by 12
0	0	1	System clock divided by 4
0	1	0	Timer 0 overflow
0	1	1	High-to-low transitions on ECI (max rate = system clock divided by 4)
1	0	0	System clock
1	0	1	External oscillator source divided by 8*
1	1	0	RESERVED
1	1	1	RESERVED
*Note: Ex	ternal clock	divided by	8 is synchronized with the system clock.

Table 22.1. PCA Timeb	ase Input Options
-----------------------	-------------------





### 22.2. Capture/Compare Modules

Each module can be configured to operate independently in one of six operation modes: Edge-triggered Capture, Software Timer, High Speed Output, Frequency Output, 8-Bit Pulse Width Modulator, or 16-Bit Pulse Width Modulator. Each module has Special Function Registers (SFRs) associated with it in the CIP-51 system controller. These registers are used to exchange data with a module and configure the module's mode of operation.

Table 22.2 summarizes the bit settings in the PCA0CPMn registers used to select the PCA0 capture/compare module's operating modes. Setting the ECCFn bit in a PCA0CPMn register enables the module's CCFn interrupt. Note: PCA0 interrupts must be globally enabled before individual CCFn interrupts are recognized. PCA0 interrupts are globally enabled by setting the EA bit (IE.7) and the EPCA0 bit (EIE1.3) to logic '1'. See Figure 22.3 for details on the PCA interrupt configuration.

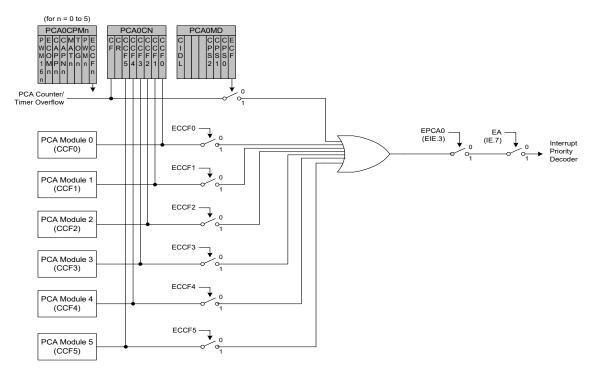


Figure 22.3. PCA Interrupt Block Diagram



PWM16	ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	Operation Mode
Х	Х	1	0	0	0	0	х	Capture triggered by positive edge on CEXn
Х	Х	0	1	0	0	0	х	Capture triggered by negative edge on CEXn
Х	Х	1	1	0	0	0	Х	Capture triggered by transition on CEXn
Х	1	0	0	1	0	0	Х	Software Timer
Х	1	0	0	1	1	0	Х	High Speed Output
Х	1	0	0	0	1	1	Х	Frequency Output
0	1	0	0	0	0	1	0	8-Bit Pulse Width Modulator
1	1	0	0	0	0	1	0	16-Bit Pulse Width Modulator

### Table 22.2. PCA0CPM Register Settings for PCA Capture/Compare Modules

X = Don't Care

### 22.2.1. Edge-triggered Capture Mode

In this mode, a valid transition on the CEXn pin causes PCA0 to capture the value of the PCA0 counter/ timer and load it into the corresponding module's 16-bit capture/compare register (PCA0CPLn and PCA0CPHn). The CAPPn and CAPNn bits in the PCA0CPMn register are used to select the type of transition that triggers the capture: low-to-high transition (positive edge), high-to-low transition (negative edge), or either transition (positive or negative edge). When a capture occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic '1' and an interrupt request is generated if CCF interrupts are enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. If both CAPPn and CAPNn bits are set to logic '1', then the state of the Port pin associated with CEXn can be read directly to determine whether a rising-edge or falling-edge caused the capture.

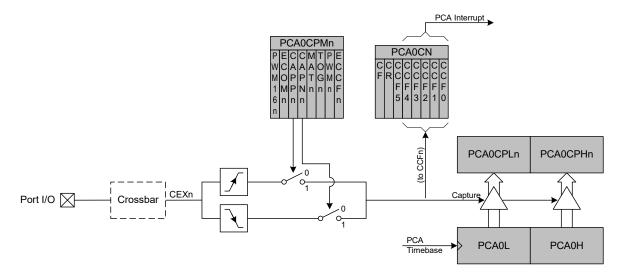


Figure 22.4. PCA Capture Mode Diagram

**Note:** The signal at CEXn must be high or low for at least 2 system clock cycles to be recognized by the hardware.



### 22.2.2. Software Timer (Compare) Mode

In Software Timer mode, the PCA0 counter/timer is compared to the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn). When a match occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic '1' and an interrupt request is generated if CCF interrupts are enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. Setting the ECOMn and MATn bits in the PCA0CPMn register enables Software Timer mode.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/ Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.

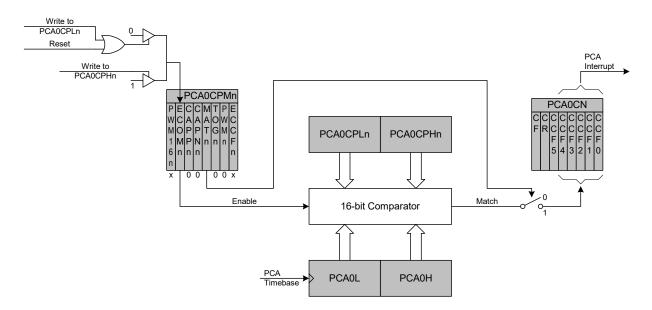


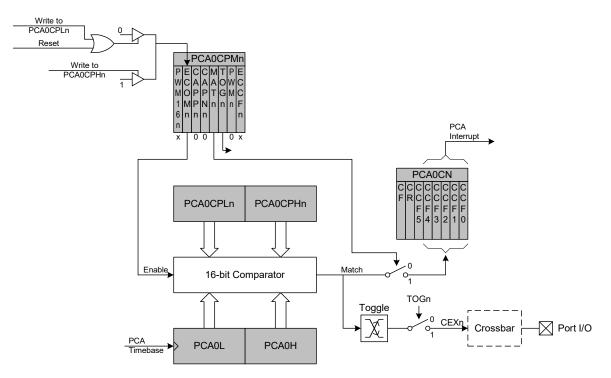
Figure 22.5. PCA Software Timer Mode Diagram



### 22.2.3. High Speed Output Mode

In High Speed Output mode, a module's associated CEXn pin is toggled each time a match occurs between the PCA Counter and the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn) Setting the TOGn, MATn, and ECOMn bits in the PCA0CPMn register enables the High-Speed Output mode.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/ Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.



### Figure 22.6. PCA High Speed Output Mode Diagram

**Note:** The initial state of the Toggle output is logic '1' and is initialized to this state when the module enters High Speed Output Mode.



### 22.2.4. Frequency Output Mode

Frequency Output Mode produces a programmable-frequency square wave on the module's associated CEXn pin. The capture/compare module high byte holds the number of PCA clocks to count before the output is toggled. The frequency of the square wave is then defined by Equation 22.1.

### Equation 22.1. Square Wave Frequency Output

$$F_{sqr} = \frac{F_{PCA}}{2 \times PCA0CPHn}$$

**Note:** A value of 0x00 in the PCA0CPHn register is equal to 256 for this equation.

Where  $F_{PCA}$  is the frequency of the clock selected by the CPS2–0 bits in the PCA mode register, PCA0MD. The lower byte of the capture/compare module is compared to the PCA0 counter low byte; on a match, CEXn is toggled and the offset held in the high byte is added to the matched value in PCA0CPLn. Frequency Output Mode is enabled by setting the ECOMn, TOGn, and PWMn bits in the PCA0CPMn register.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/ Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.

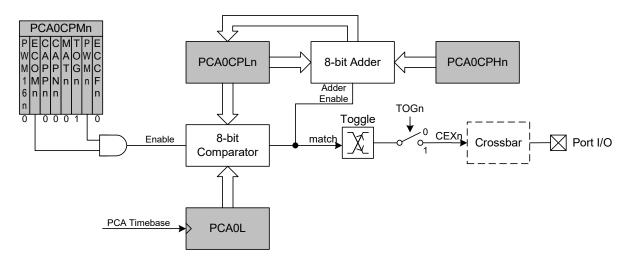


Figure 22.7. PCA Frequency Output Mode



### 22.2.5. 8-Bit Pulse Width Modulator Mode

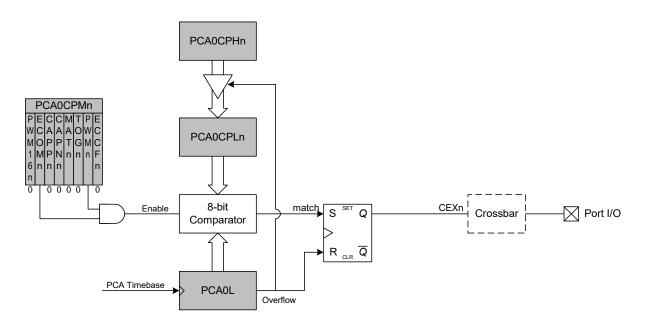
Each module can be used independently to generate pulse width modulated (PWM) outputs on its associated CEXn pin. The frequency of the output is dependent on the timebase for the PCA0 counter/timer. The duty cycle of the PWM output signal is varied using the module's PCA0CPLn capture/compare register. When the value in the low byte of the PCA0 counter/timer (PCA0L) is equal to the value in PCA0CPLn, the output on the CEXn pin will be high. When the count value in PCA0L overflows, the CEXn output will be low (see Figure 22.8). Also, when the counter/timer low byte (PCA0L) overflows from 0xFF to 0x00, PCA0CPLn is reloaded automatically with the value stored in the counter/timer's high byte (PCA0H) without software intervention. Setting the ECOMn and PWMn bits in the PCA0CPMn register enables 8-Bit Pulse Width Modulator mode. The duty cycle for 8-Bit PWM Mode is given by Equation 22.2.

Equation 22.2. 8-Bit PWM Duty Cycle

 $DutyCycle = \frac{(256 - PCA0CPHn)}{256}$ 

Using Equation 22.2, the largest duty cycle is 100% (PCA0CPHn = 0), and the smallest duty cycle is 0.39% (PCA0CPHn = 0xFF). A 0% duty cycle may be generated by clearing the ECOMn bit to '0'.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/ Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.





### 22.2.6. 16-Bit Pulse Width Modulator Mode

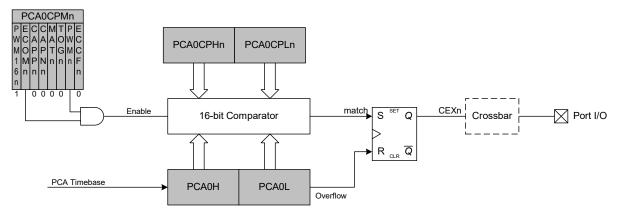
Each PCA0 module may also be operated in 16-Bit PWM mode. In this mode, the 16-bit capture/compare module defines the number of PCA0 clocks for the low time of the PWM signal. When the PCA0 counter matches the module contents, the output on CEXn is asserted high; when the counter overflows, CEXn is asserted low. To output a varying duty cycle, new value writes should be synchronized with PCA0 CCFn match interrupts. 16-Bit PWM Mode is enabled by setting the ECOMn, PWMn, and PWM16n bits in the PCA0CPMn register. For a varying duty cycle, CCFn should also be set to logic '1' to enable match interrupts. The duty cycle for 16-Bit PWM Mode is given by Equation 22.3.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/ Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.

### Equation 22.3. 16-Bit PWM Duty Cycle

 $DutyCycle = \frac{(65536 - PCA0CPn)}{65536}$ 

Using Equation 22.3, the largest duty cycle is 100% (PCA0CPn = 0), and the smallest duty cycle is 0.0015% (PCA0CPn = 0xFFFF). A 0% duty cycle may be generated by clearing the ECOMn bit to '0'.





### 22.3. Watchdog Timer Mode

A programmable watchdog timer (WDT) function is available through the PCA Module 5. The WDT is used to generate a reset if the time between writes to the WDT update register (PCA0CPH5) exceed a specified limit. The WDT can be configured and enabled/disabled as needed by software.

With the WDTE bit set in the PCA0MD register, Module 5 operates as a watchdog timer (WDT). The Module 5 high byte is compared to the PCA counter high byte; the Module 5 low byte holds the offset to be used when WDT updates are performed. The Watchdog Timer is enabled on reset. Writes to some PCA registers are restricted while the Watchdog Timer is enabled.

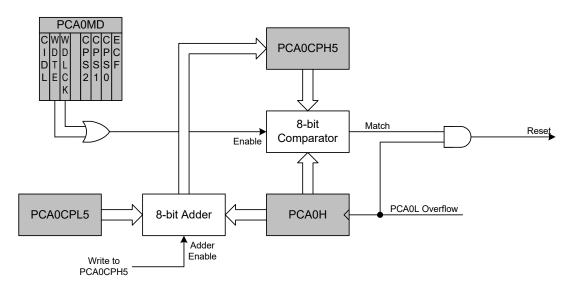


### 22.3.1. Watchdog Timer Operation

While the WDT is enabled:

- PCA counter is forced on.
- Writes to PCA0L and PCA0H are not allowed.
- PCA clock source bits (CPS2-CPS0) are frozen.
- PCA Idle control bit (CIDL) is frozen.
- Module 5 is forced into software timer mode.
- Writes to the Module 5 mode register (PCA0CPM5) are disabled.

While the WDT is enabled, writes to the CR bit will not change the PCA counter state; the counter will run until the WDT is disabled. The PCA counter run control (CR) will read zero if the WDT is enabled but user software has not enabled the PCA counter. If a match occurs between PCA0CPH5 and PCA0H while the WDT is enabled, a reset will be generated. To prevent a WDT reset, the WDT may be updated with a write of any value to PCA0CPH5. Upon a PCA0CPH5 write, PCA0H plus the offset held in PCA0CPL5 is loaded into PCA0CPH5 (See Figure 22.10).



### Figure 22.10. PCA Module 5 with Watchdog Timer Enabled



Note that the 8-bit offset held in PCA0CPH5 is compared to the upper byte of the 16-bit PCA counter. This offset value is the number of PCA0L overflows before a reset. Up to 256 PCA clocks may pass before the first PCA0L overflow occurs, depending on the value of the PCA0L when the update is performed. The total offset is then given (in PCA clocks) by Equation 22.4, where PCA0L is the value of the PCA0L register at the time of the update.

### Equation 22.4. Watchdog Timer Offset in PCA Clocks

 $Offset = (256 \times PCA0CPL5) + (256 - PCA0L)$ 

The WDT reset is generated when PCA0L overflows while there is a match between PCA0CPH5 and PCA0H. Software may force a WDT reset by writing a '1' to the CCF5 flag (PCA0CN.5) while the WDT is enabled.

### 22.3.2. Watchdog Timer Usage

To configure the WDT, perform the following tasks:

- Disable the WDT by writing a '0' to the WDTE bit.
- Select the desired PCA clock source (with the CPS2-CPS0 bits).
- Load PCA0CPL5 with the desired WDT update offset value.
- Configure the PCA Idle mode (set CIDL if the WDT should be suspended while the CPU is in Idle mode).
- Enable the WDT by setting the WDTE bit to '1'.
- Write a value to PCA0CPH5 to reload the WDT.

The PCA clock source and Idle mode select cannot be changed while the WDT is enabled. The watchdog timer is enabled by setting the WDTE or WDLCK bits in the PCA0MD register. When WDLCK is set, the WDT cannot be disabled until the next system reset. If WDLCK is not set, the WDT is disabled by clearing the WDTE bit.

The WDT is enabled following any reset. The PCA0 counter clock defaults to the system clock divided by 12, PCA0L defaults to 0x00, and PCA0CPL5 defaults to 0x00. Using Equation 22.4, this results in a WDT timeout interval of 3072 system clock cycles. Table 22.3 lists some example timeout intervals for typical system clocks.



System Clock (Hz)	PCA0CPL5	Timeout Interval (ms)
24,500,000	255	32.1
24,500,000	128	16.2
24,500,000	32	4.1
18,432,000	255	42.7
18,432,000	128	21.5
18,432,000	32	5.5
11,059,200	255	71.1
11,059,200	128	35.8
11,059,200	32	9.2
3,062,500 <sup>2</sup>	255	257
3,062,500 <sup>2</sup>	128	129.5
3,062,500 <sup>2</sup>	32	33.1
191,406	255	4109
191,406	128	2070
191,406	32	530
32,000	255	24576
32,000	128	12384
32,000	32	3168
Notes:		•
<ol> <li>Assumes SYSCLK/ of 0x00 at the updat</li> <li>Internal oscillator res</li> </ol>	e time.	source, and a PCA0L value

# Table 22.3. Watchdog Timer Timeout Intervals<sup>1</sup>



### 22.4. Register Descriptions for PCA0

Following are detailed descriptions of the special function registers related to the operation of PCA0.

## SFR Definition 22.1. PCA0CN: PCA Control

R/W	ss: 0xD8 R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu			
CF	CR	CCF5	CCF4	CCF3	CCF2	CCF1	CCF0	0000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
Bit 7:	CF: PCA Co	unter/Time	Overflow F								
Dit 7.	Set by hardv			•	or overflows	from 0xEE		00 When			
	the Counter/										
	tor to the CF										
	must be clea			ic. This bit	S not auton	latically cic	area by na				
Bit 6:	CR: PCA0 C			trol							
510.	This bit enab				mer						
	0: PCA0 Cou			Counter, II	iner.						
	1: PCA0 Col										
Bit 5:	CCF5: PCA			mpare Flag	I						
Dit 0.	This bit is se		•			s. When the	e CCF inte	rrupt is			
	enabled, set										
	bit is not aut	•									
Bit 4:	CCF4: PCA					<b>,</b> .					
	This bit is se					rs. When the	e CCF inte	rrupt is			
	enabled, set										
	bit is not aut	•									
Bit 3:						,					
		CCF3: PCA0 Module 3 Capture/Compare Flag.									
	This bit is set by hardware when a match or capture occurs. When the CCF interrupt is enabled, setting this bit causes the CPU to vector to the CCF interrupt service routine. This										
		t by hardwa		match or ca	pture occui			•			
		t by hardwa ting this bit	causes the	match or ca CPU to veo	pture occur	CF interrup	t service ro	•			
Bit 2:	enabled, set	t by hardwa ting this bit omatically o	causes the cleared by h	match or ca CPU to veo ardware an	pture occur tor to the C d must be c	CF interrup	t service ro	•			
Bit 2:	enabled, set bit is not aut	t by hardwa ting this bit omatically o Module 2	causes the cleared by h Capture/Co	match or ca CPU to veo ardware an ompare Flag	pture occu otor to the C d must be o	CF interrup cleared by s	t service ro oftware.	outine. This			
Bit 2:	enabled, set bit is not aut CCF2: PCA	t by hardwa ting this bit omatically o Module 2 t by hardwa	causes the cleared by h Capture/Co are when a	match or ca CPU to veo ardware an ompare Flag match or ca	pture occur ctor to the C d must be d pture occur	CF interrup cleared by s rs. When the	t service ro oftware. e CCF inte	outine. This rrupt is			
Bit 2:	enabled, set bit is not aut CCF2: PCA This bit is se	t by hardwa ting this bit omatically o ) Module 2 t by hardwa ting this bit	causes the cleared by h Capture/Co are when a causes the	match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo	pture occur stor to the C d must be c pture occur stor to the C	CF interrup cleared by s s. When the CF interrup	t service ro oftware. e CCF inte t service ro	outine. This rrupt is			
Bit 2: Bit 1:	enabled, set bit is not auto CCF2: PCA( This bit is se enabled, set bit is not auto CCF1: PCA(	t by hardwa ting this bit omatically o Module 2 t by hardwa ting this bit omatically o Module 1	causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co	match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag	pture occur otor to the C d must be c pture occur otor to the C d must be c	CF interrup cleared by s rs. When the CF interrup cleared by s	t service ro oftware. e CCF inte t service ro oftware.	outine. This rrupt is outine. This			
	enabled, set bit is not auto CCF2: PCA0 This bit is se enabled, set bit is not auto CCF1: PCA0 This bit is se	t by hardwa ting this bit omatically o ) Module 2 t by hardwa ting this bit omatically o ) Module 1 t by hardwa	causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co are when a	match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag match or ca	pture occur of to the C d must be c pture occur of to the C d must be c b pture occur	CF interrup cleared by s rs. When the CF interrup cleared by s rs. When the	t service ro oftware. e CCF inte t service ro oftware. e CCF inte	outine. This rrupt is outine. This rrupt is			
	enabled, set bit is not auto CCF2: PCA0 This bit is se enabled, set bit is not auto CCF1: PCA0 This bit is se enabled, set	t by hardwa ting this bit omatically o ) Module 2 t by hardwa ting this bit omatically o ) Module 1 t by hardwa ting this bit	causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co are when a causes the	match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo	pture occur of to the C d must be c pture occur of must be c d must be c pture occur of to the C	CF interrup cleared by s CF interrup cleared by s cleared by s CF interrup	t service ro oftware. e CCF inte t service ro oftware. e CCF inte t service ro	outine. This rrupt is outine. This rrupt is			
Bit 1:	enabled, set bit is not aut CCF2: PCA0 This bit is se enabled, set bit is not aut CCF1: PCA0 This bit is se enabled, set bit is not aut	t by hardwa ting this bit omatically o ) Module 2 t by hardwa ting this bit omatically o ) Module 1 t by hardwa ting this bit omatically o	causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co are when a causes the cleared by h	match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an	pture occur of to the C d must be c pture occur of must be c d must be c pture occur of to the C d must be c d must be c	CF interrup cleared by s CF interrup cleared by s cleared by s CF interrup	t service ro oftware. e CCF inte t service ro oftware. e CCF inte t service ro	outine. This rrupt is outine. This rrupt is			
	enabled, set bit is not aut CCF2: PCA0 This bit is se enabled, set bit is not aut CCF1: PCA0 This bit is se enabled, set bit is not aut CCF0: PCA0	t by hardwa ting this bit omatically o ) Module 2 t by hardwa ting this bit omatically o ) Module 1 t by hardwa ting this bit omatically o ) Module 0	causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co	match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag	pture occur of must be of pture occur of must be of tor to the C d must be of pture occur of to the C d must be of d must be of l.	CF interrup cleared by s rs. When the CF interrup cleared by s rs. When the CF interrup cleared by s	t service ro oftware. e CCF inte t service ro oftware. e CCF inte t service ro oftware.	outine. This rrupt is outine. This rrupt is outine. This			
Bit 1:	enabled, set bit is not aut CCF2: PCA0 This bit is se enabled, set bit is not aut CCF1: PCA0 This bit is se enabled, set bit is not aut CCF0: PCA0 This bit is se	t by hardwa ting this bit omatically o ) Module 2 t by hardwa ting this bit omatically o ) Module 1 t by hardwa ting this bit omatically o ) Module 0 t by hardwa	causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co are when a	match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag match or ca	pture occur of must be of a must be of pture occur of must be of a must be of a must be of d must be of a must be of a must be of a	CF interrup cleared by s rs. When the CF interrup cleared by s rs. When the cleared by s rs. When the	t service ro oftware. e CCF inte t service ro oftware. e CCF inte t service ro oftware. e CCF inte	outine. This rrupt is outine. This rrupt is outine. This rrupt is			
Bit 1:	enabled, set bit is not aut CCF2: PCA0 This bit is se enabled, set bit is not aut CCF1: PCA0 This bit is se enabled, set bit is not aut CCF0: PCA0	t by hardwa ting this bit omatically o ) Module 2 t by hardwa ting this bit omatically o ) Module 1 t by hardwa ting this bit omatically o ) Module 0 t by hardwa ting this bit	causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co are when a causes the cleared by h Capture/Co are when a causes the	match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo ardware an ompare Flag match or ca CPU to veo	pture occur d must be o pture occur tor to the C d must be o d must be o pture occur tor to the C d must be o d must be o pture occur tor to the C	CF interrup cleared by s rs. When the CF interrup cleared by s rs. When the CF interrup cleared by s rs. When the CF interrup	t service ro oftware. e CCF inte t service ro oftware. e CCF inte t service ro oftware. e CCF inte t service ro t service ro	outine. This rrupt is outine. This rrupt is outine. This rrupt is			



# C8051F360/1/2/3/4/5/6/7/8/9

R/W	R/W	R/W	/	R/W	R/W	R/W	R/W	R/W	Reset Value
CIDL	WDTE	E WDL	CK	_	CPS2	CPS1	CPS0	ECF	0100000
Bit7	Bit6	Bit5		Bit4	Bit3	Bit2	Bit1	Bit0	
Bit 7: Bit 6: Bit 5:	Specifies 0: PCA0 of 1: PCA0 of WDTE: W If this bit i 0: Watcho 1: PCA M WDLCK: This bit lo Timer ma 0: Watcho	continues operation i /atchdog T is set, PCA dog Timer lodule 5 er Watchdog ocks/unlocl	navior wh to function s susper Timer En A Module disabled a Timer L (s the W isabled u Enable u	hen CPl on norm nded wh able e 5 is us 5 Watch ock /atchdog until the unlocke	J is in Idle hally while t hile the sys and as the w hdog Timer g Timer Ena next syste	he system o tem controll vatchdog tir able. When	controller is ler is in Idle ner. WDLCK is s	Mode.	
3it 4: 3its 3–1:	CPS2-CP	s select th	Counte	r/Timer	Pulse Sele	PCA0 count	er nebase		
	0	0	0	System	n clock divid				
	0	0	1	-	n clock divid	•			
	0	1	0		) overflow	,			
	0	1	1	High-to divided		ions on EC	I (max rate :	= system o	clock
	1	0	0	System	• •				
		0	1			ded by 8 (s	ynchronized	with system	em clock)
	1						,		,
	1	1	0	Reserv	ed				
	-	1	0 1	Reserv Reserv					
	1 1	1	1	Reserv	ed	with the syst	em clock.		

### SFR Definition 22.2. PCA0MD: PCA0 Mode



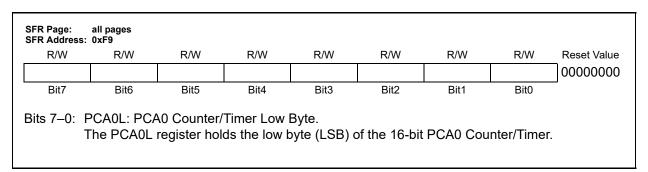
### SFR Definition 22.3. PCA0CPMn: PCA0 Capture/Compare Mode

SFR Address R/W	s: PCA0CPM0: 0x R/W	R/W	1: 0XDB, PCAUC R/W	R/W	R/W	D, PCA0CPM4: R/W	0xDE, PCA0CF R/W	M5: 0xDF Reset Value
PWM16r		CAPPn	CAPNn	MATn	TOGn	PWMn	ECCFn	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	] 0000000
Bit 7:	PWM16n: 16 This bit selec 0: 8-bit PWM	cts 16-bit m				n mode is e	nabled (PW	′Mn = 1).
<b>.</b>	1: 16-bit PW							
Bit 6:	ECOMn: Co	•				0		
	This bit enab	oles/disable	s the compa	arator funct	ion for PCA	0 module n	l.	
	0: Disabled.							
	1: Enabled.	tura Daaiti		Frabla				
Bit 5:	CAPPn: Cap				tura far DC		5	
	This bit enabled.	lies/disable	s the positiv	ve edge cap		AU module	Π.	
	1: Enabled.							
Bit 4:	CAPNn: Cap	turo Nogat	ivo Eupetior	Enable				
DIL 4.	This bit enab				nture for Pl		a n	
	0: Disabled.		s the negati	we eage ca			5 11.	
	1: Enabled.							
Bit 3:	MATn: Match	n Function I	Enable					
	This bit enab			function fo	r PCA0 moo	dule n. Whe	en enabled.	matches c
	the PCA0 co							
	register to be			•	1 0			
	0: Disabled.	0						
	1: Enabled.							
Bit 2:	TOGn: Togg	le Function	Enable.					
	This bit enab			function fo	r PCA0 moo	dule n. Whe	en enabled,	matches c
	the PCA0 co	ounter with a	a module's o	capture/con	npare regist	ter cause th	e logic leve	el on the
	CEXn pin to	toggle. If th	e PWMn bit	is also set	to logic '1', t	the module	operates in	Frequenc
	Output Mode	Э.						
	0: Disabled.							
	1: Enabled.							
Bit 1:	PWMn: Puls							_
	This bit enab							•
	width modula							
	16-bit mode		-	ic '1'. If the	TOGN bit is	s also set, ti	ne module (	operates ir
	Frequency C		Э.					
	0: Disabled.							
	1: Enabled.	turo/Com-	aro Elac Int	orrupt Ench				
Bit 0:	ECCFn: Cap This bit sets		•	•		CEn) intorr	unt	
	0: Disable C			Jule/Comp	are Flay (C		սրւ.	
	1: Enable a		pis.					

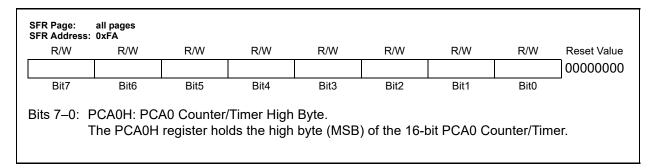


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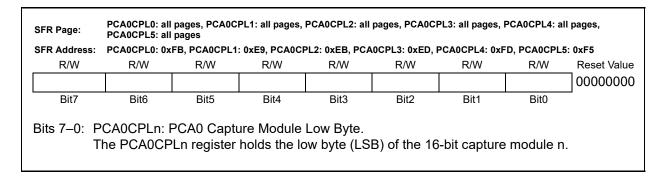
### SFR Definition 22.4. PCA0L: PCA0 Counter/Timer Low Byte



### SFR Definition 22.5. PCA0H: PCA0 Counter/Timer High Byte



### SFR Definition 22.6. PCA0CPLn: PCA0 Capture Module Low Byte





### SFR Definition 22.7. PCA0CPHn: PCA0 Capture Module High Byte

SFR Page:	PCA0CPH0: all PCA0CPH5: all		PH1: all pages	a, PCA0CPH2: a	III pages, PCA0	CPH3: all page	es, PCA0CPH4	: all pages,
SFR Address:	PCA0CPH0: 0x	FC, PCA0CPH	1: 0xEA, PCA0	CPH2: 0xEC, P	CA0CPH3: 0xEl	E, PCA0CPH4:	0xFE, PCA0C	PH5: 0xF6
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
	CA0CPHn: he PCA0CF	•		• •		e 16-bit cap	ture modu	le n.



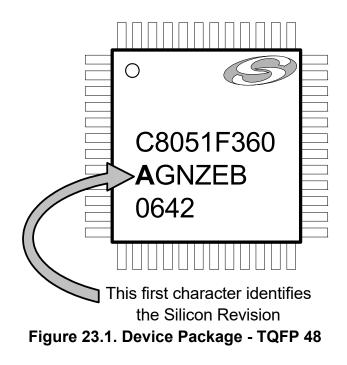
# 23. Revision Specific Behavior

This chapter contains behavioral differences between the C8051F36x hardware revisions and behavior as stated in the data sheet.

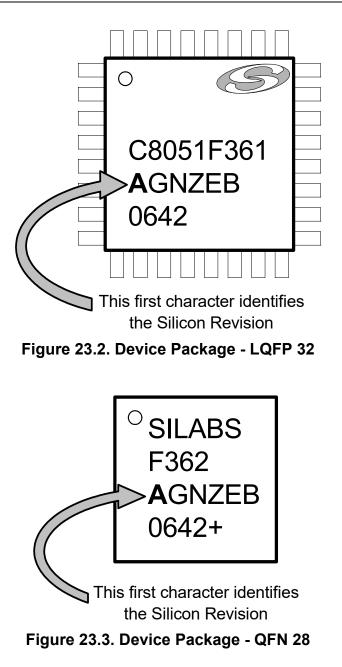
### 23.1. Revision Identification

The Lot ID Code on the top side of the device package can be used for decoding device revision information. On C8051F36x devices the revision letter is the first letter of the Lot ID Code.

Figures 23.1, 23.2, and 23.3 show how to find the Lot ID Code on the top side of the device package.







### 23.2. CPL C Instruction Behavior

### Problem

On Revision A and Revision B devices, a bug in the CPU causes an execution failure for the "CPL C" (Complement Carry bit) instruction under a narrow set of conditions involving an instruction order dependency. The probability of failure is increased at higher temperatures, lower power supply voltage, and higher system clock frequencies.

The failure mode is as follows: if the Carry bit contains a 1 prior to the execution phase of the "CPL C" opcode, the Carry bit will remain a 1 after the execution phase of the opcode has completed. If the Carry



# C8051F360/1/2/3/4/5/6/7/8/9

bit contained a '0' prior to the execution of the "CPL C" opcode, it will properly transition to a 1 when the execution phase of the opcode has completed. This is illustrated in the following table:

Correct operation	Correct operation	Failure case
initial state of C is 1	initial state of C is 0	initial state of C is 1
CPL C	CPL C	CPL C
final state of C is 0	final state of C is 1	final state of C is 1

The instruction order dependency is as follows:

In the failure case, the CPL C opcode must be immediately preceded by a JB, JNB, or JBC opcode.

JB, JNB, and JBC are all conditional branch instructions (JB is "Jump if bit is set", JNB is "Jump if bit is not set", and JBC is "Jump if bit is set and clear bit"). Because the branches are conditional, they have both a "branch taken" condition as well as a "branch not taken" condition. Both "branch taken" and "branch not taken" conditions may exhibit the error, as long as the CPL C opcode executes immediately after the branch instruction has executed.

#### Impacts

The CPL C opcode is often used in math operations, such as address calculations for pointer arithmetic. If present, this behavior can cause undesirable and unpredictable program execution.

The occurrence of this behavior is sensitive to system clock frequency, temperature, and power supply voltage as follows:

JB / JNB / JBC + CPL C opcode sequence present?	VDD	System clock frequency	Temperature range	Failure possible?
No	≥ 3.0 V	≤ 100 MHz	-40 to +85 °C	No
Yes	≥ 3.0 V	≤ 70 MHz	-40 to +85 °C	No

### Workaround

The bug can best be addressed by checking to see if the problematic instruction sequence is present in the device firmware and removing it if detected. In most cases, the firmware can be changed to insert a NOP instruction immediately before the CPL C opcode, so that the CPL C instruction does not immediately follow the JB / JNB / JBC opcode in the code execution path.

Silicon Labs has developed a hex file scanner that can be used to determine if a code project contains the instruction sequence above. Instructions for using the scanner, as well as details regarding the scanner's operation can be found here:

http://community.silabs.com/t5/Silicon-Labs-Knowledge-Base/C8051F360-Rev-B-Erratum-CPU-E101-CPL-C-HEX-Scanner/ta-p/133808

This behavior has been corrected on Revision C of this device.



### 23.3. C2D Port Pin Requirements

### Problem

The C2D debugging port pin (shared with P4.6 for C8051F360/3 and P3.0 for C8051F361/2/4/5/6/7/8/9) behaves differently on "REV A" devices than specified in the data sheet.

On "REV A" devices, a C2D port pin that is pulled low by the associated port pin driver will disrupt debugging capability. In order to communicate with the device through the C2 interface, the value in the port latch associated C2D port pin must be '1'.

#### Workaround

To workaround this problem, add a strong pull-up resistor to the C2D port pin to ensure the pin will be high unless explicitly driven low. Furthermore, the port pin should be left in open-drain mode with a '1' in the appropriate port latch (PnMDOUT bit = '0', Pn bit = '1') when not in use. This will allow the debugging software to transfer data via the C2D pin as often as possible.

This behavior has been corrected on "REV B" of this device.

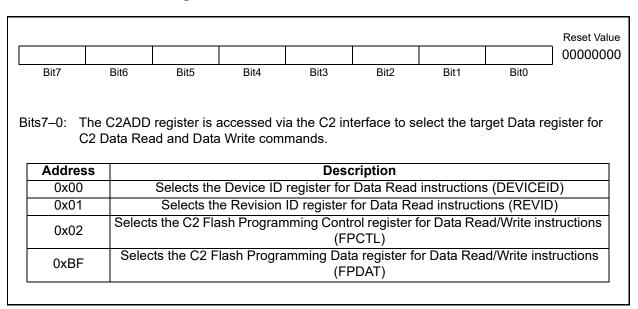


# 24. C2 Interface

C8051F36x devices include an on-chip Silicon Laboratories 2-Wire (C2) debug interface to allow Flash programming and in-system debugging with the production part installed in the end application. The C2 interface uses a clock signal (C2CK) and a bi-directional C2 data signal (C2D) to transfer information between the device and a host system. See the C2 Interface Specification for details on the C2 protocol.

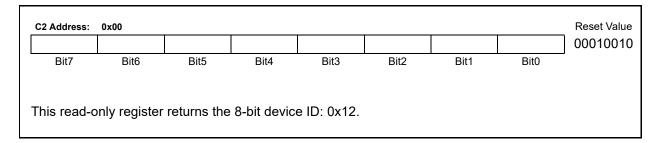
### 24.1. C2 Interface Registers

The following describes the C2 registers necessary to perform Flash programming functions through the C2 interface. All C2 registers are accessed through the C2 interface as described in the C2 Interface Specification.



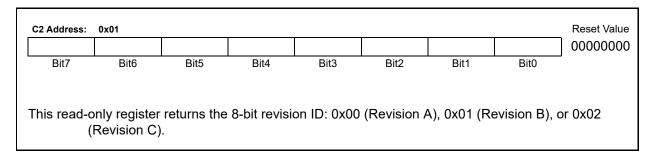
### C2 Register Definition 24.1. C2ADD: C2 Address

# C2 Register Definition 24.2. DEVICEID: C2 Device ID

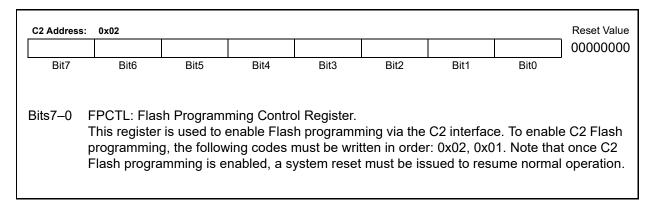




## C2 Register Definition 24.3. REVID: C2 Revision ID



# C2 Register Definition 24.4. FPCTL: C2 Flash Programming Control



# C2 Register Definition 24.5. FPDAT: C2 Flash Programming Data

C2 Address:	0xB4			1		T	1	Reset Valu
								0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
		C2 Flash Progi ister is used to				s, and data	during C2 F	lash
	This reg accesse	C2 Flash Prog ister is used to s. Valid comma	pass Flash ands are lis	commands, ted below.		s, and data	during C2 F	lash
	This reg accesse <b>Code</b>	ister is used to s. Valid comma	pass Flash ands are list <b>Con</b>	commands		s, and data	during C2 F	Flash
	This reg accesse	ister is used to	pass Flash ands are list <b>Con</b>	commands, ted below.		s, and data o	during C2 F	lash
	This reg accesse <b>Code</b>	ister is used to s. Valid comma	pass Flash ands are list <b>Con</b> ead	commands, ted below.		s, and data o	during C2 F	lash
	This reg accesse Code 0x06	ister is used to s. Valid comma Flash Block Re	pass Flash ands are list Con ead	commands, ted below.		s, and data (	during C2 F	lash



### 24.2. C2 Pin Sharing

The C2 protocol allows the C2 pins to be shared with user functions so that in-system debugging and Flash programming functions may be performed. This is possible because C2 communication is typically performed when the device is in the halt state, where all on-chip peripherals and user software are stalled. In this halted state, the C2 interface can safely 'borrow' the C2CK (/RST) and C2D (P4.6 on C8051F361/2/4/5/6/7/8/9 devices) pins. In most applications, external resistors are required to isolate C2 interface traffic from the user application. A typical isolation configuration is shown in Figure 24.1.

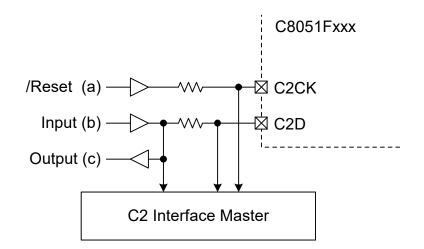


Figure 24.1. Typical C2 Pin Sharing

The configuration in Figure 24.1 assumes the following:

- 1. The user input (b) cannot change state while the target device is halted.
- 2. The /RST pin on the target device is used as an input only.

Additional resistors may be necessary depending on the specific application.



# **DOCUMENT CHANGE LIST**

### **Revision 0.1 to Revision 0.2**

- Updated specification tables with most recently available characterization data.
- Fixed an error with the SYSCLK specification in Table 3.1, "Global Electrical Characteristics," on page 34.
- Corrected the name of the PMAT bit in SFR Definition 10.2. IP: Interrupt Priority.
- Corrected the reset value for SFR Definition 22.2. PCA0MD: PCA0 Mode.

### Revision 0.2 to Revision 1.0

- Updated specification tables with characterization data.
- Fixed Table 1.1, "Product Selection Guide," on page 19 to reflect the correct number of Port I/O pins for the C8051F361/2/4/5.
- Updated Section "10. Interrupt Handler" on page 108.
- Added note describing EA change behavior when followed by single cycle instruction.
- Updated SFR Definition 11.1
  - Changed the MAC0SC (MAC0CF.5) bit description to correctly refer to the MAC0SD bit.
- Updated SFR Definition 15.2.
  - Changed the EMI0CF description to properly describe the 1k XRAM boundaries.
- Added Table 16.2, "Internal Low Frequency Oscillator Electrical Characteristics," on page 173.
- Updated SFR Definition 16.9:
  - Specified that the undefined states for PLLLP3–0 are RESERVED.
- Added Table 19.7 and Table 19.8 on page 234 for UART Baud Rates when using the PLL.
- Updated Table 22.1, "PCA Timebase Input Options," on page 266:
- Specified that the undefined states of CPS2–0 are RESERVED.
- Added Revision B to "Revision Specific Behavior" on page 282.

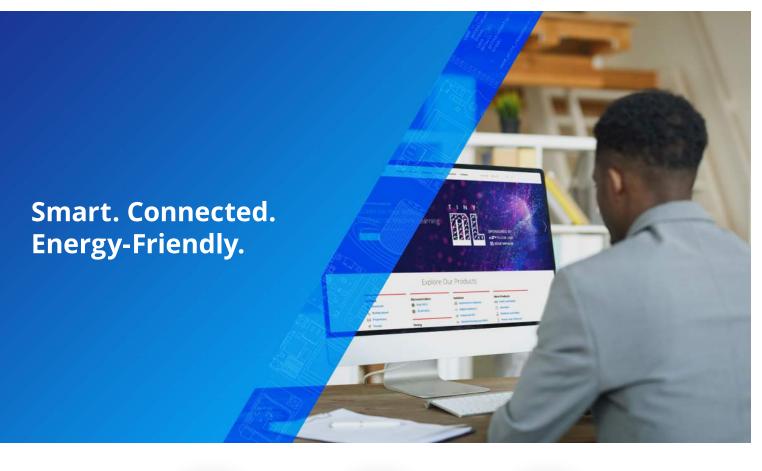
### Revision 1.0 to Revision 1.1

- Updated ordering table with Revision C part numbers.
- Updated Figure 17.2. 'Port I/O Cell Block Diagram' on page 185 to refer to VDD instead of VIO.
- Added Revision C to "Revision Specific Behavior" on page 282.
- Added Revision C to the REVID C2 register in C2 Register Definition 24.3.
- Updated "Digital Supply Current (Stop Mode, shutdown)" typical value in Table 3.1, "Global Electrical Characteristics," on page 34.
- Updated "Missing Clock Detector Timeout" typical value in Table 12.1, "Reset Electrical Characteristics," on page 135.

### **Revision 1.1 to Revision 1.2**

• Table 1.2 on page 20 added to highlight Not Recommended for New Designs OPNs.







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